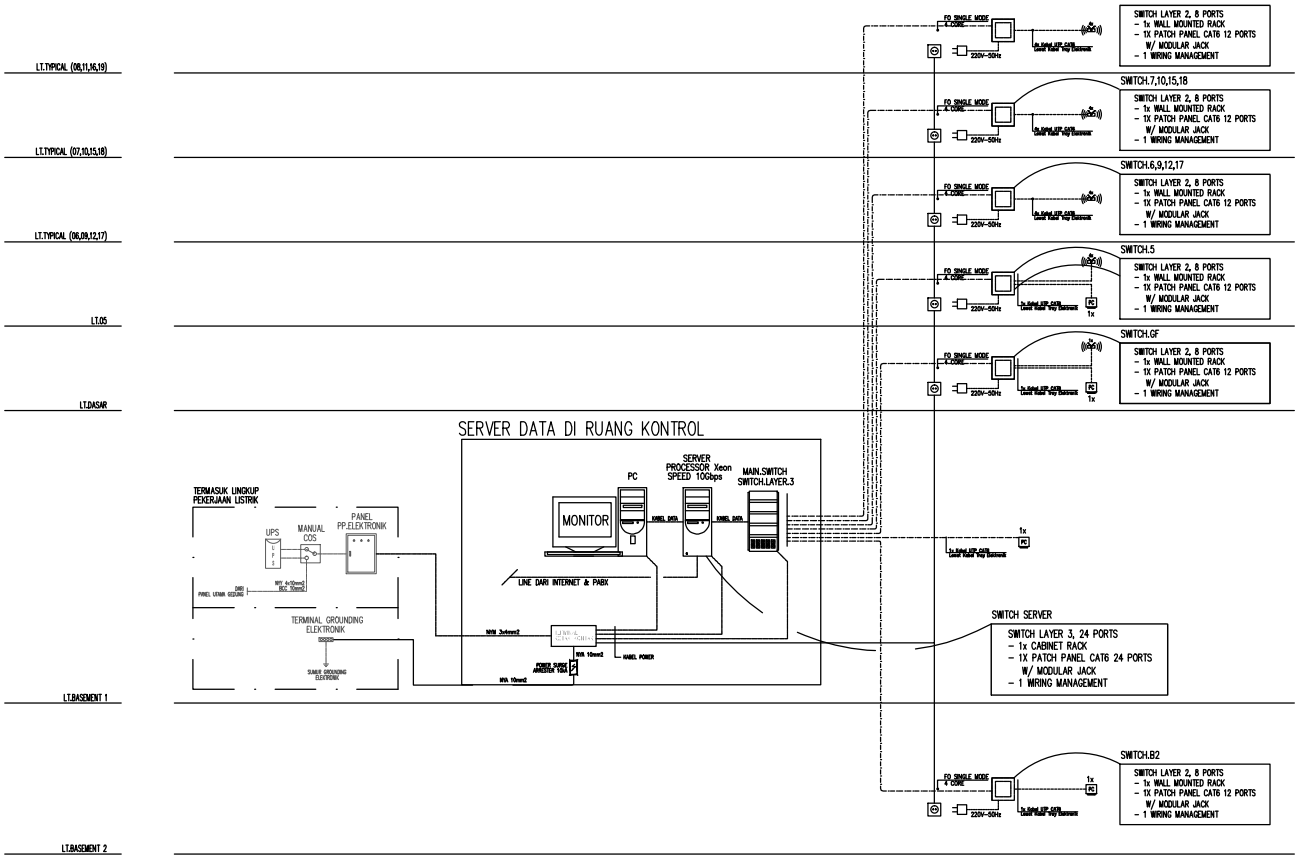
LAMPIRAN

PERANCANGAN

SISTEM JARINGAN DATA & Wi-Fi

APARTMENT THE YUDHISTIRA

YOGYAKARTA

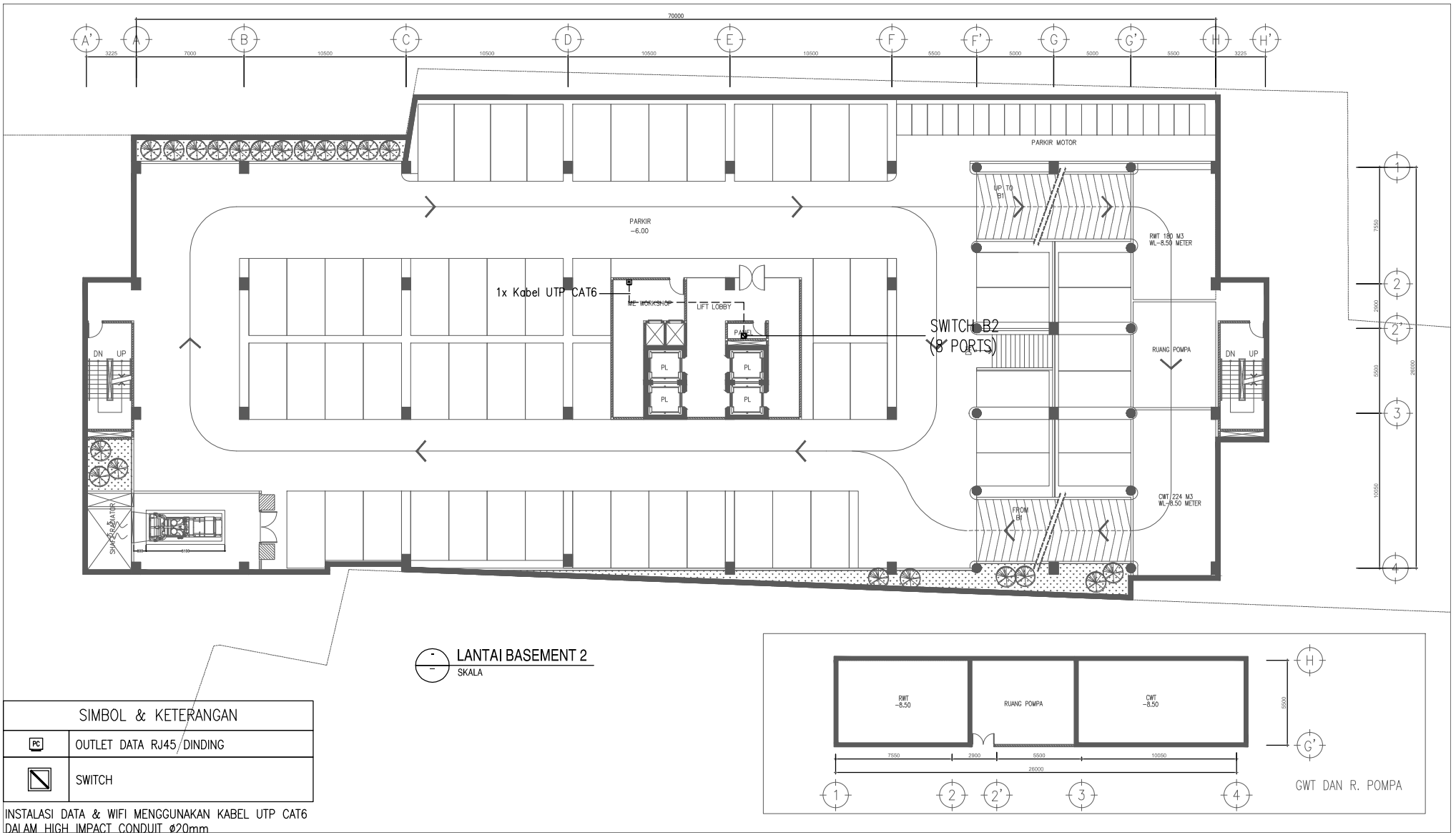


SIMBOL & KETERANGAN	
PC	OUTLET DATA RJ45 DINDING
	WIFI ACCESS POINT 802,11n 2,4GHz/5GHz–COVERAGE AREA R11meter
	SWITCH

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6 DALAM HIGH IMPACT CONDUIT ø20mm

DIAGRAM SKEMATIK DATA DAN WIFI

SKALA NTS



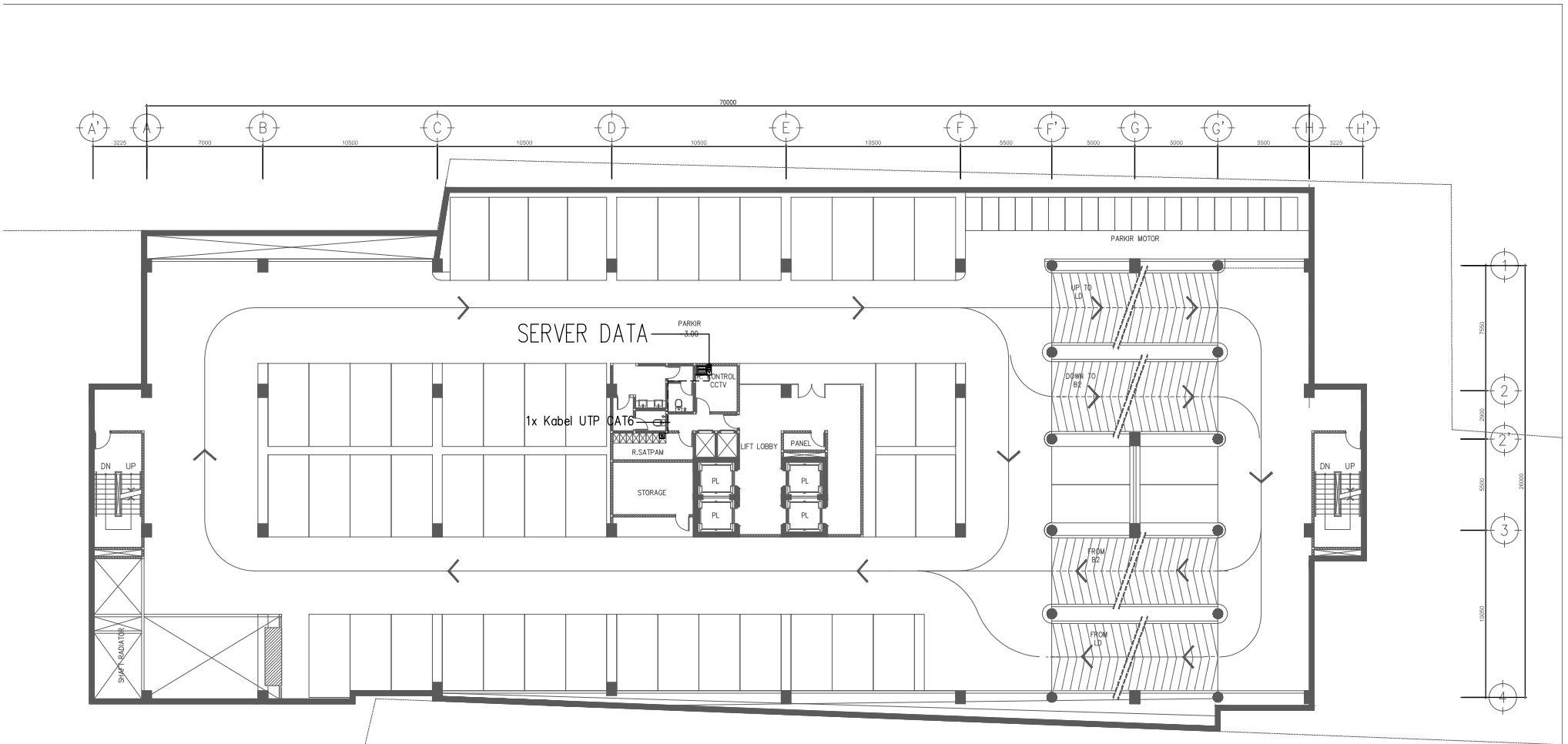
LANTAI BASEMENT 2

SKALA

GWT DAN R. POMPA

SIMBOL & KETERANGAN	
PC	OUTLET DATA RJ45 / DINDING
	SWITCH

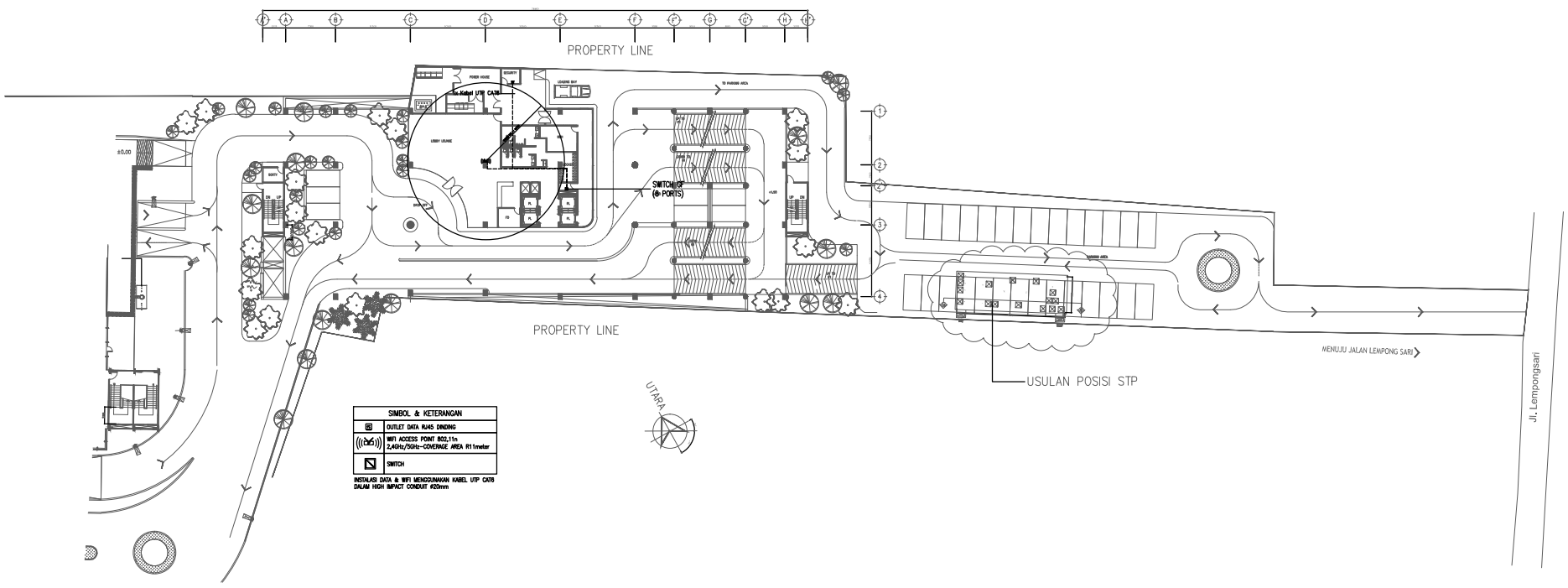
INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm



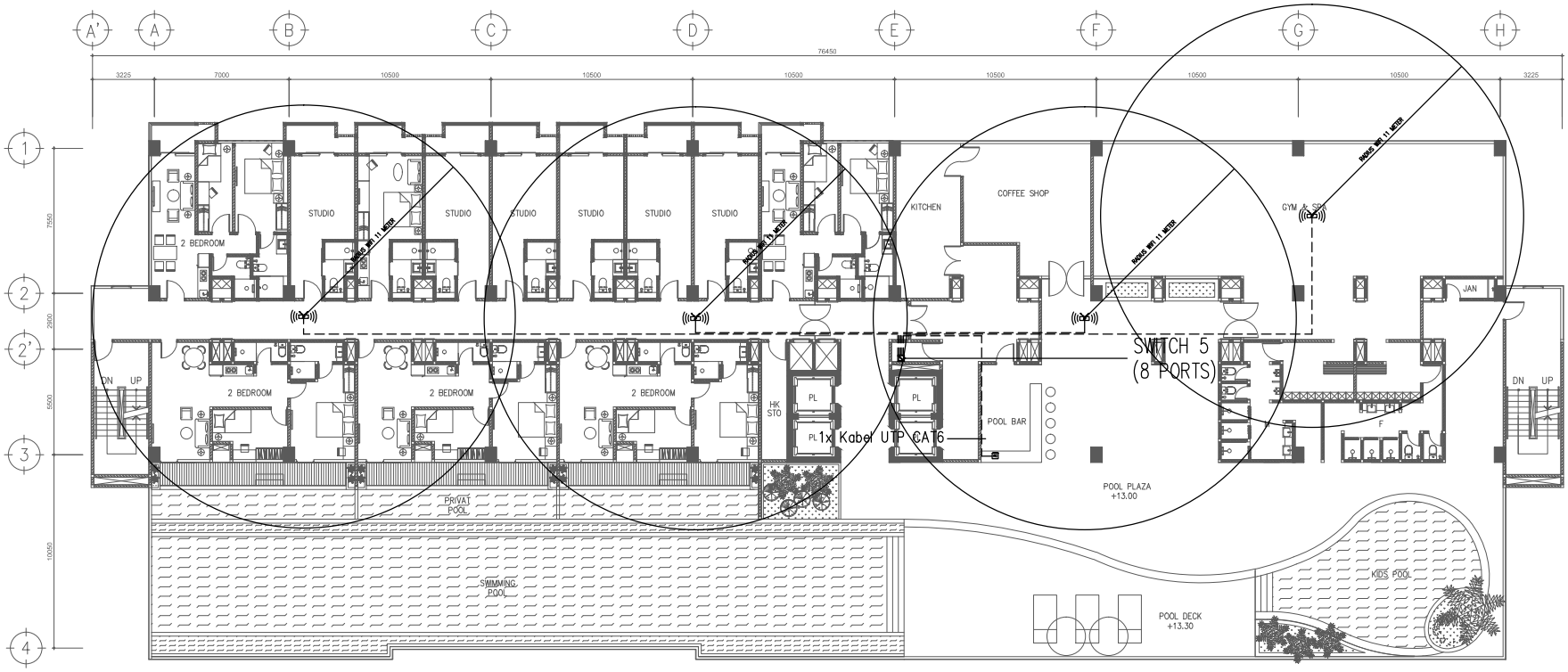
SIMBOL & KETERANGAN	
PC	OUTLET DATA RJ45 DINDING
	SERVER DATA

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm

LANTAI BASEMENT 1
SKALA



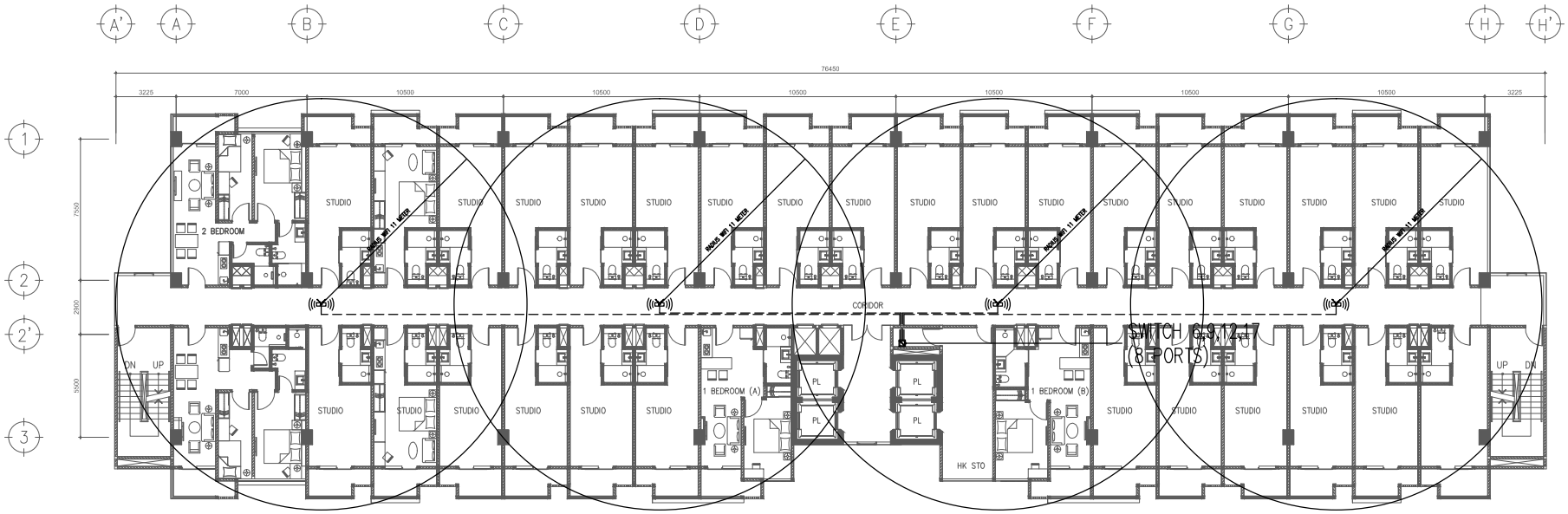
LANTAI DASAR
SKALA



SIMBOL & KETERANGAN	
PC	OUTLET DATA RJ45 DINDING
AP	WIFI ACCESS POINT 802,11n 2,4GHz/5GHz–COVERAGE AREA R11meter
	SWITCH

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm

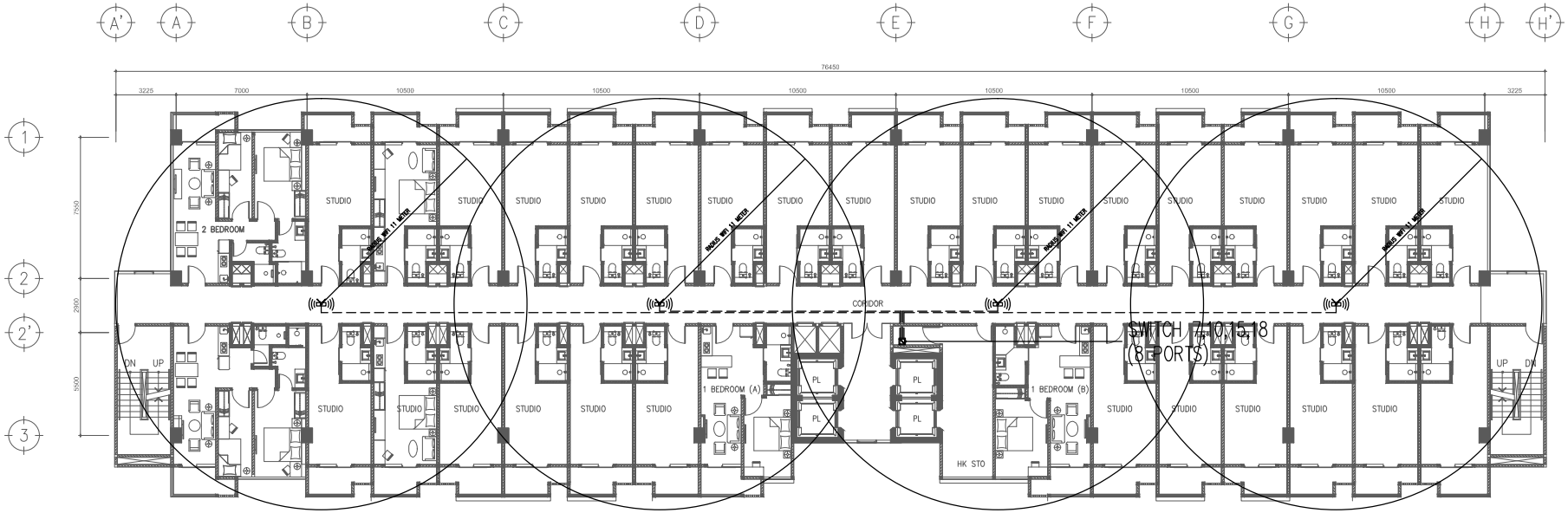
LANTAI 5
SKALA



SIMBOL & KETERANGAN	
AP	WIFI ACCESS POINT 802,11n 2,4GHz/5GHz–COVERAGE AREA R11meter
	SWITCH

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm

LANTAI TYPICAL (6, 9, 12 & 17)
SKALA 1 : 2

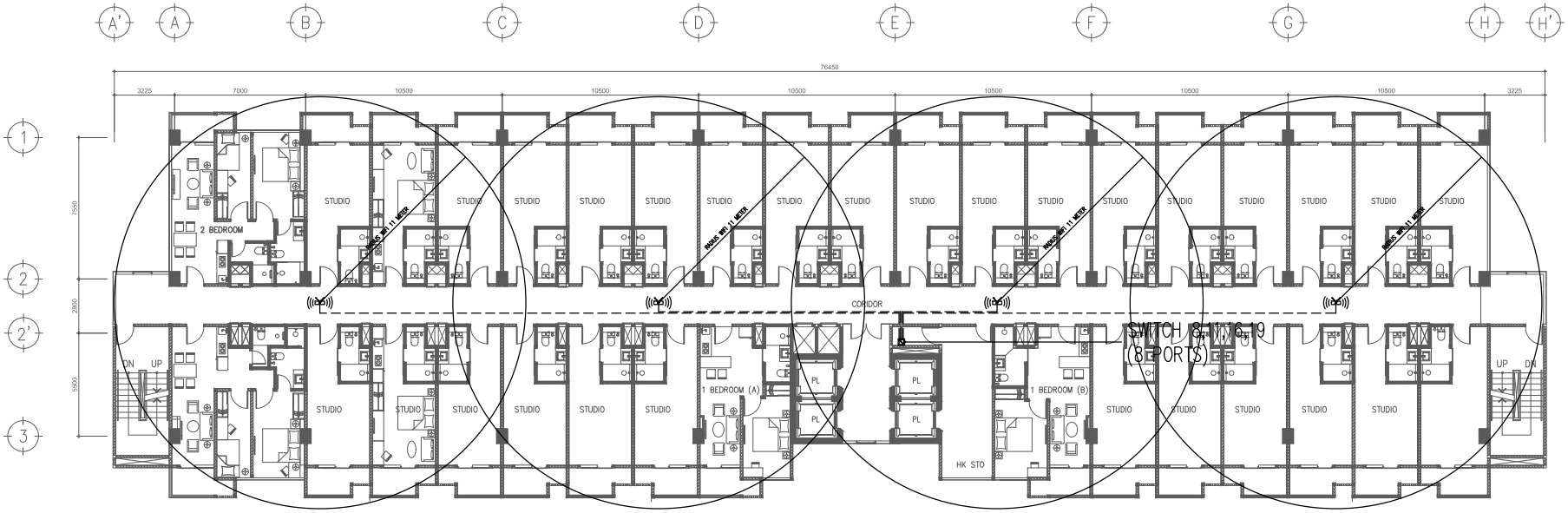


SIMBOL & KETERANGAN	
AP	WIFI ACCESS POINT 802,11n 2,4GHz/5GHz–COVERAGE AREA R11meter
	SWITCH

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm

LANTAI TYPICAL 7, 10, 15 & 18

SKALA 1 : 250



SIMBOL & KETERANGAN	
AP	WIFI ACCESS POINT 802,11n 2,4GHz/5GHz–COVERAGE AREA R11meter
	SWITCH

INSTALASI DATA & WIFI MENGGUNAKAN KABEL UTP CAT6
DALAM HIGH IMPACT CONDUIT ø20mm

LANTAI TYPICAL 8, 11, 16 & 19

SKALA 1 : 250

BROSUR &

SPESIFIKASI PRODUK

Cisco Catalyst 3560-CX and 2960-CX Series Compact Switches

The Cisco® Catalyst® Compact Switches easily expand your Ethernet and Multigigabit Ethernet infrastructure outside the wiring closet to enable new workspaces, extend wireless LANs, and connect PoE devices. These fanless, small form-factor switches are ideal for space-constrained deployments where multiple cable runs would be challenging. With speeds that reach 10Gbps, the Cisco Catalyst 3560CX Multigigabit Ethernet Switches support current and next-generation wireless speeds and standards (including 802.11ac Wave 2) on existing cabling infrastructure.

Cisco Catalyst 3560-CX and 2960-CX Switch Family.

Product Overview

The Cisco Catalyst 3560-CX and 2960-CX Series Compact Switches help optimize network deployments. These Gigabit Ethernet (GbE) and Multigigabit Ethernet (mGig) managed switches are ideal for high-speed data connectivity, Wi-Fi backhaul, and Power over Ethernet (PoE+) connectivity in places where space is at a premium. With a single copper or fiber cable from the wiring closet, Cisco Catalyst compact switches enable IP connectivity for devices such as IP phones, wireless access points, surveillance cameras, PCs, and video endpoints.

With their quiet, fanless design and compact footprint, these switches can come out of the data closet and be placed closer to the users. This means shorter cable runs and greater flexibility as you grow your network.

Cisco Catalyst 3560-CX and 2960-CX Series Compact Switch Highlights

- 8 or 12 Gigabit Ethernet ports with line rate forwarding performance
- 6 Gigabit Ethernet plus 2 Multigigabit Ethernet (100 Mbps/1/2.5/5/10 Gbps) ports with line rate forwarding performance (selected model)
- Gigabit and Multigigabit (100 Mbps/1/2.5/5/10 Gbps) copper, small form-factor pluggable (SFP) or 10G SFP+ uplinks
- Power over Ethernet Plus (PoE+) support with up to 240W of PoE budget
- Power over Ethernet (PoE) pass-through enables the compact switch to draw Cisco Universal PoE (Cisco UPOE™) power from the wiring closet and pass it to end devices (selected model) with the additional option to be powered by auxiliary AC-DC or DC-DC power adapter
- Cisco Instant Access mode to enable single point of management and simplify operation (selected models)
- Advanced Layer 2 (LAN Base) and Layer 3 (IP Base) support with an option to upgrade to IP services
- Fanless design and silent operation
- Enhanced Limited Lifetime Warranty (E-LLW)

Features and Benefits

Like the larger Cisco Catalyst switches typically used in wiring closets, the Cisco Catalyst Compact switches are a managed option for consistency across your LAN switching network. Unlike unmanaged switches and hubs, they provide advanced networking features for flexibility, security, and scale.

Table 1 lists many of the Cisco Catalyst 3560-CX and 2960-CX switch features and benefits.

Table 1. Compact Switch Features and Benefits Summary

Feature	Benefits
Hardware	
Small form factor; fanless design; silent operation	The switch can be used in open workspaces and other areas that cannot tolerate equipment noise and where multiple cable runs could be difficult, expensive, and intrusive.
Flexible mounting options	The switch can be mounted on the wall, under a desk, rack, DIN rail, or practically anywhere they are needed.
Cisco Multigigabit Ethernet	With the enormous growth of 802.11ac and new wireless applications, wireless devices are driving the demand for more network bandwidth. This creates a need for a technology that supports speeds higher than 1 Gbps on all cabling infrastructure. Cisco Multigigabit Ethernet technology is a unique Cisco innovation that allows you to achieve bandwidth between speeds of 100Mbps and 10 Gbps over traditional Cat 5e cabling or above. In addition, the Multigigabit ports on the Cisco Catalyst Compact switch support PoE+, which is increasingly important for next-generation workspaces and Internet of Things (IoT) ecosystems. The Multigigabit Ethernet ports can also be used as uplinks to connect to traditional access switches such as the Cisco Catalyst 3850/4500 switches. Cisco Multigigabit technology offers significant benefits for a diverse range of speeds, cable types, and PoE power. The benefits can be grouped into three different areas: • **Multiple speeds:** Cisco Multigigabit technology supports autonegotiation of multiple speeds on switch ports. The supported speeds are 100 Mbps, 1 Gbps, 2.5 Gbps, and 5 Gbps on Cat 5e cable and up to 10 Gbps over Cat 6a cabling. • **Cable type:** The technology supports a wide range of cable types, including Cat 5e, Cat 6, and Cat 6a or above. • **PoE power:** The technology supports PoE and PoE+ for all the supported speeds and cable types.
10-Gigabit SFP+ uplinks	Accommodates business growth and increased traffic, such as aggregate upstream gigabit traffic loads from 802.11ac Wi-Fi access points.
Increased PoE+ Scale	Provides up to 240W of PoE+ budget (twice the power per switch than previous series).
Perpetual PoE	Provides uninterrupted power to a powered-down device even when the switch is booting. This eliminates the need for a backup power source.

Feature	Benefits
PoE pass-through	**PoE pass-through** gives the ability to power PoE end devices through drawing Cisco UPOE from the wiring closet. The Cisco Catalyst WS-C3560CX-8PT-S has eight downlink ports with two Cisco UPOE input ports that allow it to be powered by another switch. These switches do not need a power supply and receive power over the uplink from an upstream PoE or Cisco UPOE device, providing deployment flexibility and availability. These switches are ideal for wiring-constrained and space-constrained applications.
Management and Operations	
Cisco Instant Access Mode	Available on Cisco Catalyst 3560-CX switches with 10 G SFP+ uplinks, this optional mode enables a single point of management and operation for campus networks. Multiple Cisco Catalyst 3560-CX compact switches with 10 G SFP+ uplinks can be connected to Cisco Catalyst 6500 or 6800 core switches, and the entire configuration can then work as a single extended switch with a common management domain. In this mode, compact switches inherit all the features of the Cisco Catalyst 6500 or 6800. Advanced Cisco Catalyst 6500 and 6800 features like MPLS and EVN can be extended to the access layer, so the Cisco Catalyst Instant Access solution can be deployed on all or a subset of the campus network.
Cisco Network Plug 'n Play (PnP)	Network Plug-n-Play (PnP) is a secure, scalable solution that accelerates network device deployments by automating the installation and configuration of Cisco IOS software. The Cisco Catalyst 3560-CX and 2960-CX switches are 'Network-PnP Ready' and can be used as part of the APIC-EM solution for automated switch deployments. This feature helps improve productivity, cut costs, reduce downtime, and enhance the user experience.
Cisco Catalyst Smart Operations	This comprehensive set of Cisco Catalyst technologies and Cisco IOS Software features simplify LAN deployment, configuration, and troubleshooting. • **Cisco Smart Install** enables the configuration of the Cisco IOS Software image and switch without user intervention. • **Cisco Auto Smartports** provides automatic configuration as end devices connect to the switch port, allowing autodetection and plug-and-play of the device onto the network. Interface templates containing configurations or policies that can be applied to ports are also supported. • **Cisco Smart Troubleshooting** is an extensive array of debug diagnostic commands and system health checks, including **Generic Online Diagnostics (GOLD)** and **Onboard Failure Logging (OBFL).** • **Embedded Event Manager (EEM),** supported on the Cisco Catalyst 3560-CX, provides real-time network event detection and onboard automation. You can adapt the behavior of your network devices to align with business needs.
Cloud and System Management	• Cisco Prime® Infrastructure provides comprehensive network lifecycle management with an extensive library of features that automate initial and day-to-day management. Cisco Prime integrates hardware and software platform expertise and operational experience into a powerful set of workflow-driven configuration, monitoring, troubleshooting, reporting, and administrative tools. • Cisco Network Assistant is a PC-based, centralized network management and configuration application for small and medium-sized business (SMB) with up to 250 users. An intuitive GUI lets you easily apply common services across Cisco switches, routers, and access points. • Cisco Active Advisor is a cloud-based service that provides essential lifecycle information about your network inventory. Available by itself or as a component of other Cisco network management applications, it helps you reduce your network's overall risk by keeping you up-to-date on the status of your products.
Operational Simplicity	• **Link Aggregation Control Protocol (LACP)** for creating Ethernet channeling with devices that conform to IEEE 802.3ad. Similar to Cisco EtherChannel technology and PAgP. • **Dynamic Host Configuration Protocol (DHCP)** autoconfiguration of multiple switches through a boot server. • **Multicast VLAN Registration (MVR)** continuously sends multicast streams in a multicast VLAN. Isolates streams from subscriber VLANs for bandwidth and security reasons. • **Voice VLAN** keeps voice traffic on a separate VLAN for easier administration and troubleshooting. • **Cisco VLAN Trunking Protocol (VTP)** supports dynamic VLANs and dynamic trunk configuration across all switches. • **Remote Switch Port Analyzer (RSPAN)** allows administrators to remotely monitor ports in a Layer 2 switch network from any other switch in the same network. • For enhanced traffic management, monitoring, and analysis, the Embedded **Remote Monitoring (RMON)** software agent supports four RMON groups (history, statistics, alarms, and events).
Security	
Cisco TrustSec®	A suite of components that secures networks, data, and resources with policy-based access control, identity, and role-aware networking with the following elements: • **Cisco TrustSec SXP** support to simplify security and policy enforcement throughout the network. For more information about Cisco TrustSec security solutions, visit cisco.com/go/TrustSec. • **Hardware on the Cisco Catalyst 3560-CX for IEEE 802.1AE MACsec** for Layer 2, line-rate Ethernet data confidentiality and integrity on host-facing ports. Protects against man-in-the-middle attacks (snooping, tampering, and replay). • Flexible authentication that supports multiple authentication mechanisms including **802.1X, MAC Authentication Bypass**, and **web authentication** using a single, consistent configuration. • **Monitor mode** that creates a user-friendly environment for 802.1X operations. • **RADIUS change of authorization and downloadable ACLs** for comprehensive policy management. • **802.1X supplicant with Network Edge Access Transport (NEAT)** for extended secure access; compact switches in the conference rooms have the same level of security as switches inside a locked wiring closet.

Feature	Benefits
Threat Defense	Advanced, integrated security features that provide threat defense capabilities for mitigating man-in-the-middle attacks and protecting your critical network infrastructure. • **Superior Layer 2 capabilities** for mitigating MAC, IP, and ARP spoofing risks. Also protects port security, guards against DHCP snooping, and supports Dynamic ARP Inspection and IP Source Guard. • **Ipv6 first-hop security** with Binding Integrity Guard, RA Guard, and DHCP Guard. • **Private VLAN** provides security and isolation between switch ports. • **Multidomain Authentication** allows an IP phone and a PC to authenticate on the same switch port while placing them on appropriate voice and data VLAN. • **Secure Shell (SSH), Kerberos, and Simple Network Management Protocol Version 3 (SNMPv3) that encrypt** administrator traffic during Telnet and SNMP sessions to keep access credentials secure. • **Port-based access control list (ACL)** to let the switch automatically allow or block packets based on policies for source and destination IP addresses. Rules can be set up differently on a port-by-port basis. • **Secure Boot** to make sure that only signed and authorized images can load on the switch. • **Cisco AutoSecure** to simplify security configurations with a single-line CLI.
Power Management and Energy Efficiency	
Switch Hibernate Mode	Innovative technology that puts the switch in an ultra-low power mode during periods of nonoperation such as nights and weekends. The switch can be configured to be in the hibernate mode using the Cisco Energy Management Suite.
IEEE 802.3az or Energy-Efficient Ethernet (EEE)	Ports dynamically sense idle periods between traffic bursts and quickly switch the interfaces into a low-power idle mode, reducing power consumption.
Perpetual PoE	Provides uninterrupted power to a powered-down device even when the switch is booting. This eliminates the need for a backup power source.
PoE pass-through	**PoE pass-through** gives the ability to power PoE end devices through drawing Cisco UPOE from the wiring closet. The Cisco Catalyst 3560CX-8PT-S has eight downlink ports with two Cisco UPOE input ports that allow it to be powered by another switch. These switches do not need a power supply and receive power over the uplink from an upstream PoE or Cisco UPOE device, providing deployment flexibility and availability.
Cisco Energy Management Suite (formerly EnergyWise)	Measures power consumption of network infrastructure and network-attached devices and enforces rules to reduce energy usage.
Power Supply	80-Plus Silver Certified.
Traffic Management and QoS	
Application Visibility	NetFlow Lite lets you maintain awareness of all application traffic on the network. It helps capture and record specific packet flows. Exports flow data in the NetFlow Version 9 format for analysis on a wide range of Cisco and third-party collectors.
Advanced Quality of Service	Intelligent traffic management with flexible mechanisms for marking, classifying, and scheduling traffic at wire speed. Includes: • Up to **eight egress queues** per port and strict priority queuing so that the highest priority packets are serviced ahead of all other traffic. • **Shaped Round Robin** (SRR) scheduling and **Weighted Tail Drop** (WTD) congestion avoidance. • **Flow-based rate limiting** and up to 256 aggregate or individual policers per port.

Product Details

Switch Models

The Cisco Catalyst Compact Switches are available in nine switch models. They vary by whether they support both Layer 2 and Layer 3 services or Layer 2 services only; whether they support Power over Ethernet Plus (PoE+); by the number of Gigabit Ethernet and Multigigabit Ethernet ports; the aggregate power provided, and the type of cabling connections they support.

Tables 2, 3, and 4 compare the available switch models and list the software package that ships by default with each model and how much PoE power is available for the downlink ports.

Table 2. Cisco Catalyst 3560-X Compact Switch Models and Default Software

Model	Ethernet Ports	PoE Output Ports	Available PoE Power	Uplinks	Default Software
3560CX-8TC-S	8 x 10/100/1000 Gigabit Ethernet	NA		2 x 1G copper plus 2 x 1G SFP	IP Base (IP Services with RTU License)
3560CX-12TC-S	12 x 10/100/1000 Gigabit Ethernet	NA		2 x 1G copper plus 2 x 1G SFP	IP Base (IP Services with RTU License)
3560CX-8PC-S	8 x 10/100/1000 Gigabit Ethernet	8 PoE+	240W	2 x 1G copper plus 2 x 1G SFP	IP Base (IP Services with RTU License)
3560CX-12PC-S	12 x 10/100/1000 Gigabit Ethernet	12 PoE+	240W	2 x 1G copper plus 2 x 1G SFP	IP Base (IP Services with RTU License)
3560CX-12PD-S	12 x 10/100/1000 Gigabit Ethernet	12 PoE+	240W	2 x 1G copper plus 2 x 10G SFP+	IP Base (IP Services with RTU License)
C3560CX-8PT-S	8 x 10/100/1000 Gigabit Ethernet	8 PoE+	Up to 146W	2 x 1G copper (Cisco UPOE+ uplinks)	IP Base (IP Services with RTU License)
C3560CX-8XPD-S	6 x 10/100/1000 Gigabit Ethernet plus 2 Multigigabit Ethernet 100/2500/5000/10000	8 PoE+	240W	2 x 10G SGP+	IP Base (IP Services with RTU License)

Table 3. C3560CX-8PT-S Switch PoE and PoE+ Power Capacity

Model	Powering Option	Available PoE Power (W)	Can Switch Be Powered with Uplinks?
3560CX-8TC-S	Internal power supply	0W	No
3560CX-12TC-S	Internal power supply	0W	No
3560CX-8PC-S	Internal power supply	240W	No
3560CX-12PC-S	Internal power supply	240W	No
3560CX-12PD-S	Internal power supply	240W	No
C3560CX-8PT-S	1 PoE uplink	0W	No
	2 PoE uplinks	0W	Yes
	1 PoE+ uplink	0W	Yes
	2 PoE+ uplinks	20W	Yes
	1 Cisco UPOE uplink	22W	Yes
	2 Cisco UPOE uplinks	68W	Yes
	Auxiliary input	54W	Yes
	1 PoE uplink plus auxiliary input	65W	Yes
	2 PoE uplinks plus auxiliary input	76W	Yes
	1 PoE+ uplink plus auxiliary input	76W	Yes
	2 PoE+ uplinks plus auxiliary input	98W	Yes
	1 Cisco UPOE uplink plus auxiliary input	100W	Yes
	2 Cisco UPOE uplinks plus auxiliary input	146W	Yes
3560CX-8XPD-S	Internal power supply	240W	No

Table 4. Cisco Catalyst 2960-X Compact Switch Models and Default Software

Model	Ethernet Ports	PoE Output Ports	Available PoE Power	Uplinks	Default Software
2960CX-8TC-L	8 x 10/100/1000 Gigabit Ethernet	N/A		2 x 1G copper plus 2 x 1G SFP	LAN Base
2960CX-8PC-L	8 x 10/100/1000 Gigabit Ethernet	8 PoE+	124W	2 x 1G copper plus 2 x 1G SFP	LAN Base

Note: All four uplink ports (two copper and two fiber) can be used simultaneously and also as downlinks.

Switch Software

Cisco Catalyst 3560-CX compact switches ship with the IP Base version of Cisco IOS® Software. The 3560-CX switches can be upgraded to use the IP Services version of IOS Software with a right-to-use (RTU) License. The IP Base and IP Services feature set on Cisco Catalyst 3560-CX switches provides baseline enterprise services in addition to all LAN Base features. They support Layer 3 networking features, including support for routed access, Cisco TrustSec, media access control security (MACsec), and other advanced network services. The IP Services feature set provides full Layer 3 routing capabilities with Open Shortest Path First (OSPF), Border Gateway Protocol (BGP), Enhanced Internal Gateway Routing Protocol (EIGRP), Policy-Based Routing (PBR), Multicast Routing, and Virtual Routing and Forwarding (VRF) Lite.

Cisco Catalyst 2960-CX Series compact switches ship with the LAN Base version of Cisco IOS Software. These switches deliver advanced Layer 2 switching with intelligent Layer 2 through 4 services for the network edge, such as voice, video, and wireless LAN services.

Licensing and Software Policy

Customers with Cisco Catalyst LAN Base and IP Base software feature sets will receive updates and bug fixes designed to maintain the compliance of the software with published specifications, release notes, and industry standards compliance as long as the original end user continues to own or use the product or for up to one year from the end-of-sale date for this product, whichever occurs earlier. This policy supersedes any previous warranty or software statement and is subject to change without notice.

Product Specifications

Table 5 provides hardware specifications for the Cisco Catalyst 3560-CX and 2960-CX compact switches.

Table 5. Cisco Catalyst 3560-CX and 2960-CX Series Compact Switch Hardware

Description	Specification		
Performance		**Cisco Catalyst 3560-CX**	**Cisco Catalyst 2960-CX**
	Forwarding Bandwidth	46 Gbps (with C3560CX-8XPD-S) 34 Gbps (with C3560CX-12PD-S) 16 Gbps (with 1 G uplinks)	12 Gbps
	Switching Bandwidth (full-duplex capacity)	92 Gbps (with C3560CX-8XPD-S) 68 Gbps (with C3560CX-12PD-S) 32 Gbps (with 1 G uplinks)	24 Gbps
	Flash memory	128 MB	128 MB
	Memory DRAM	512 MB	512 MB
	Max VLANs	1023	255
	VLAN IDs	4000	4000

Description	Specification		
	Maximum transmission unit (MTU)	Up to 9000 bytes	Up to 9000 bytes
	Jumbo frames	9198 bytes	9198 bytes
	Forwarding rate 64 Byte Packet Cisco Catalyst 3560-CX and 2960-CX		
	2960CX-8TC-L	17.9 mpps	
	2960CX-8PC-L	17.9 mpps	
	3560CX-8TC-S	17.9 mpps	
	3560CX-12TC-S	23.8 mpps	
	3560CX-8PC-S	17.9 mpps	
	3560CX-12PC-S	23.8 mpps	
	3560CX-12PD-S	50.6 mpps	
	3560CX-8PT-S	14.9 mpps	
	3560CX-8XPD-S	68.4 mpps	
	Resource Cisco Catalyst 3560-CX and 2960-CX		
	See the release notes for the SDM Templates for 3560-CX and 2960-CX: http://www.cisco.com/c/en/us/td/docs/switches/lan/catalyst2960cx_3650cx/software/release/15-2_3_e/release_notes/rn-1523e-2960cx-3560cx.html		
Connectors and cabling	**Cisco Catalyst 3560-CX and 2960-CX Ethernet Interfaces:** • 10BASE-T ports: RJ-45 connectors, 2-pair Category 3, 4, or 5 unshielded twisted-pair (UTP) cabling • 100BASE-TX ports: RJ-45 connectors, 2-pair Category 5 UTP cabling • 1000BASE-T ports: RJ-45 connectors, 4-pair Category 5 UTP cabling • 1000BASE-T SFP-based ports: RJ-45 connectors, 4-pair Category 5 UTP cabling **Cisco Catalyst 3560-CX and 2960-CX SFP and SFP+ interfaces:** For information about supported SFP/SFP+ modules, refer to the Transceiver Compatibility matrix tables at http://www.cisco.com/c/en/us/support/interfaces-modules/transceiver-modules/products-device-support-tables-list.html		
Power connectors	• Customers can provide power to a switch by using the internal power supply. The connector is located at the back of the switch. The internal power supply is an autoranging unit • The internal power supply supports input voltages between 100 and 240VAC • Use the supplied AC power cord to connect the AC power connector to an AC power outlet **Note:** The Cisco Catalyst WS-C3560CX-8PT-S has an option for an external AC-DC or DC-DC power adapter if desired.		
Indicators	Per-port status: Link integrity, disabled, activity, speed, full-duplex System status: System, link status, link duplex, link speed		
Dimensions (H x W x D)	**Cisco Catalyst 3560-CX and 2960-CX**	**Inches**	**Centimeters**
	2960CX-8TC-L	1.75 x 10.6 x 8.4	4.44 x 26.9 x 21.3
	2960CX-8PC-L	1.75 x 10.6 x 9.4	4.44 x 26.9 x 23.8
	3560CX-8TC-S	1.75 x 10.6 x 8.4	4.44 x 26.9 x 21.3
	3560CX-12TC-S	1.75 x 10.6 x 8.4	4.44 x 26.9 x 21.3
	3560CX-8PC-S	1.75 x 10.6 x 9.4	4.44 x 26.9 x 23.8
	3560CX-12PC-S	1.75 x 10.6 x 9.4	4.44 x 26.9 x 23.8
	3560CX-12PD-S	1.75 x 10.6 x 9.4	4.44 x 26.9 x 23.8
	3560CX-8PT-S	1.75 x 10.6 x 7.0	4.44 x 26.9 x 17.7
	3560CX-8XPD-S	1.75 x 10.6 x 10.4	4.44 x 26.9 x 26.4

Description	Specification					
Weight	**Cisco Catalyst 3560-CX and 2960-CX**	**Pounds**		**Kilograms**		
	2960CX-8TC-L	3.8		1.72		
	2960CX-8PC-L	5.0		2.27		
	3560CX-8TC-S	3.8		1.72		
	3560CX-12TC-S	3.9		1.77		
	3560CX-8PC-S	5.0		2.27		
	3560CX-12PC-S	5.1		2.31		
	3560CX-12PD-S	5.1		2.31		
	3560CX-8PT-S	3.5		1.58		
	3560CX-8XPD-S	6.0		2.72		
Environmental ranges		**Cisco Catalyst 3560-CX**		**Cisco Catalyst 2960-CX**		
	Operating* temperature up to 5000 ft (1524 m)	-5°C to +45°C**	+23°F to +113°F	-5°C to +45°C**	+23°F to +113°F	
	Operating* temperature up to 10,000 ft (3048 m)	-5°C to +45°C	+23°F to +113°F	-5°C to +45°C	+23°F to +113°F	
	Storage temperature up to 15,000 ft (4572 m)	-25°C to +70°C	-13°F to +158°F	-25°C to +70°C	-13°F to +158°F	
	Operating altitude	Up to 3048 m	Up to 10,000 ft	Up to 3048 m	Up to 10,000 ft	
	Storage altitude	Up to 4000 m	Up to 15,000 ft	Up to 4000 m	Up to 15,000 ft	
	Operating relative humidity	5% to 95% noncondensing		5% to 95% noncondensing		
	Storage relative humidity	5% to 95% noncondensing		5% to 95% noncondensing		
	* Minimum ambient temperature for cold start is 0°C (+32°F) ** 10G SKUs have a maximum operating temperature of 40°C. For WS-C3560CX-8XPD-S, the max operating temperature will be 35°C when installed inverted and under fully loaded conditions (max. POE and 10G SFP+ transceivers installed)					
Mean time between failure (MTBF)	**Cisco Catalyst 3560-CX**	**MTBF**	**Cisco Catalyst 2960-CX**	**MTBF**		
	3560CX-8TC-S	756,260	2960CX-8TC-L	756,260		
	3560CX-12TC-S	755,270	2960CX-8PC-L	569,530		
	3560CX-8PC-S	569,530				
	3560CX-12PC-S	553,140				
	3560CX-12PD-S	528,480				
	3560CX-8PT-S	737,740				
	3560CX-8XPD-S	528,480				

Table 6 describes the power specifications for Cisco Catalyst 3560-CX and 2960-CX switches.

Table 6. Power Specifications for Cisco Catalyst 3560-C and 2960-C Series Compact Switches

Description	Specification			
Measured 100% throughput power consumption	**Cisco Catalyst 3560-CX**	**Switch Power Consumption Watts**	**Cisco Catalyst 2960-CX**	**Switch Power Consumption Watts**
	3560CX-8TC-S	18.8W	2960CX-8TC-L	18.8W
	3560CX-12TC-S	20.8W	2960CX-8PC-L	24.5W
	3560CX-8PC-S	24.4W		
	3560CX-12PC-S	26.3W		
	3560CX-12PD-S	29.5W		

Description	Specification					
	3560CX-8PT-S	Single uplink = 22.9W[1] Dual uplink = 24.3W[1]				
	3560CX-8XPD-S	35.2W				
Measured 10% throughput power consumption	**Cisco Catalyst 3560-CX**	**Switch Power Consumption Watts**		**Cisco Catalyst 2960-CX**	**Switch Power Consumption Watts**	
	3560CX-8TC-S	18.6W		2960CX-8TC-L	18.7W	
	3560CX-12TC-S	20.6W		2960CX-8PC-L	24.3W	
	3560CX-8PC-S	24.2W				
	3560CX-12PC-S	26.1W				
	3560CX-12PD-S	28.9W				
	3560CX-8PT-S	Single uplink = 22.8W[1] Dual uplink = 24.2W[1]				
	3560CX-8XPD-S	34.5W				
Measured 0% throughput power consumption (with EEE)	**Cisco Catalyst 3560-CX**	**Switch Power Consumption Watts**		**Cisco Catalyst 2960-CX**	**Switch Power Consumption Watts**	
	3560CX-8TC-S	14.8W		2960CX-8TC-L	15W	
	3560CX-12TC-S	15.6W		2960CX-8PC-L	20.4W	
	3560CX-8PC-S	21.3W				
	3560CX-12PC-S	21.3W				
	3560CX-12PD-S	24.9W				
	3560CX-8PT-S	Single uplink = 20.1W[1] Dual uplink = 21.3W[1]				
	3560CX-8XPD-S	32.7W				
Measured 100% throughput power consumption (with maximum possible PoE loads)	**Cisco Catalyst 3560-CX**	**Switch Power Consumption Watts**		**Cisco Catalyst 2960-CX**	**Switch Power Consumption Watts**	
	3560CX-8TC-S	NA		2960CX-8TC-L	NA	
	3560CX-12TC-S	NA		2960CX-8PC-L	161.4W	
	3560CX-8PC-S	269.1W				
	3560CX-12PC-S	275.2W				
	3560CX-12PD-S	278W				
	3560CX-8PT-S	180W				
	3560CX-8XPD-S	285.1W				
AC/DC input voltage and current	**Cisco Catalyst 3560-CX**			**Cisco Catalyst 2960-CX**		
		I/P Voltage	I/P Current		I/P voltage	I/P Current
	3560CX-8TC-S	100-240 VAC	0.5-0.2A	2960CX-8TC-L	100-240 VAC	0.5-0.2A
	3560CX-12TC-S	100-240 VAC	0.5-0.2A	2960CX-8PC-L	100-240 VAC	3.25-1.5A
	3560CX-8PC-S	100-240 VAC	3.25-1.5A			
	3560CX-12PC-S	100-240 VAC	3.25-1.5A			.
	3560CX-12PD-S	100-240 VAC	3.25-1.5A			
	3560CX-8PT-S	18-60VDC	6.0-1.6A			
	3560CX-8XPD-S	100-240 VAC	3.25-1.5A			

Description	Specification							
Power rating	**Cisco Catalyst 3560-CX**				**Cisco Catalyst 2960-CX**			
		Watts	KVA	BTU		Watts	KVA	BTU
	3560CX-8TC-S	30	0.05	170.6	2960CX-8TC-L	30	0.05	170.6
	3560CX-12TC-S	30	0.05	170.6	2960CX-8PC-L	170	0.19	648.3[1]
	3560CX-8PC-S	280	0.3	1023.6[1]				
	3560CX-12PC-S	280	0.3	1023.6[1]				
	3560CX-12PD-S	290	0.31	1057.7[1]				
	3560CX-8PT-S	90	0.11	375.3[1]				
	3560CX-8XPD-S	290	0.31	1057.7[1]				
	[1] Switch dissipation only (excludes PoE, which is dissipated at the end device). Power measurements are best and worst case. Best case is 1 PoE+ connection. Worst case is 2 PoE connections.							
PoE and PoE+	• Maximum power supplied per Port for PoE+ is 30W • Maximum power supplied per port for PoE: 15.4W							
PoE Power Supply Characteristics	**Capacity**: 300W, Efficiency: 80 Plus Silver certified							
	% Load		**Efficiency**		**Power Factor**			
	• 20		• 85%		• 0.8			
	• 50		• 88%		• 0.9			
	• 100		• 90%		• 0.95			

Table 7 shows switch management and standards support.

Table 7. Management and Standards Support for Cisco Catalyst 3560-CX and 2960-CX Series Compact Switches

Description	Specification	
Management	• BRIDGE-MIB • CISCO-CABLE-DIAG-MIB • CISCO-CDP-MIB • CISCO-CLUSTER-MIB • CISCO-CONFIG-COPY-MIB • CISCO-CONFIG-MAN-MIB • CISCO-DHCP-SNOOPING-MIB • CISCO-ENTITY-VENDORTYPE-OID-MIB • CISCO-ENVMON-MIB • CISCO-ERR-DISABLE-MIB • CISCO-FLASH-MIB • CISCO-FTP-CLIENT-MIB • CISCO-IGMP-FILTER-MIB • CISCO-IMAGE-MIB • CISCO-IP-STAT-MIB • CISCO-LAG-MIB • CISCO-MAC-NOTIFICATION-MIB • CISCO-MEMORY-POOL-MIB • CISCO-PAGP-MIB • CISCO-PING-MIB • CISCO-POE-EXTENSIONS-MIB • CISCO-PORT-QOS-MIB • CISCO-PORT-SECURITY-MIB • CISCO-PORT-STORM-CONTROL-MIB • CISCO-PRODUCTS-MIB • CISCO-PROCESS-MIB • CISCO-RTTMON-MIB	• CISCO-TC-MIB • CISCO-TCP-MIB • CISCO-UDLDP-MIB • CISCO-VLAN-IFTABLE • RELATIONSHIP-MIB • CISCO-VLAN-MEMBERSHIP-MIB • CISCO-VTP-MIB • ENTITY-MIB • ETHERLIKE-MIB • IEEE8021-PAE-MIB • IEEE8023-LAG-MIB • IF-MIB • INET-ADDRESS-MIB • OLD-CISCO-CHASSIS-MIB • OLD-CISCO-FLASH-MIB • OLD-CISCO-INTERFACES-MIB • OLD-CISCO-IP-MIB • OLD-CISCO-SYS-MIB • OLD-CISCO-TCP-MIB • OLD-CISCO-TS-MIB • RFC1213-MIB • RMON-MIB • RMON2-MIB • SNMP-FRAMEWORK-MIB • SNMP-MPD-MIB • SNMP-NOTIFICATION-MIB • SNMP-TARGET-MIB

Description	Specification	
	• CISCO-SMI-MIB • CISCO-STP-EXTENSIONS-MIB • CISCO-SYSLOG-MIB	• SNMPv2-MIB • TCP-MIB • UDP-MIB • ePM MIB
Standards	• IEEE 802.1D Spanning Tree Protocol • IEEE 802.1p CoS Prioritization • IEEE 802.1Q VLAN • IEEE 802.1s • IEEE 802.1w • IEEE 802.1x • IEEE 802.1AB (LLDP) • IEEE 802.3ad • IEEE 802.3af • IEEE 802.3ah (100BASE-X single/multimode fiber only) • IEEE 802.3x full duplex on 10BASE-T, 100BASE-TX, and 1000BASE-T ports • IEEE 802.3 10BASE-T specification • IEEE 802.3u 100BASE-TX specification • IEEE 802.3ab 1000BASE-T specification • IEEE 802.3z 1000BASE-X specification	• 100BASE-BX (SFP) • 100BASE-FX (SFP) • 100BASE-LX (SFP) • 1000BASE-BX (SFP) • 1000BASE-SX (SFP) • 1000BASE-LX/LH (SFP) • 1000BASE-ZX (SFP) • 1000BASE-CWDM SFP 1470 nm • 1000BASE-CWDM SFP 1490 nm • 1000BASE-CWDM SFP 1510 nm • 1000BASE-CWDM SFP 1530 nm • 1000BASE-CWDM SFP 1550 nm • 1000BASE-CWDM SFP 1570 nm • 1000BASE-CWDM SFP 1590 nm • 1000BASE-CWDM SFP 1610 nm • RMON I and II standards • SNMPv1, SNMPv2c, and SNMPv3
RFC compliance	• RFC 768: UDP • RFC 783: TFTP • RFC 791: IP • RFC 792: ICMP • RFC 793: TCP • RFC 826: ARP • RFC 854: Telnet • RFC 951: Bootstrap Protocol • RFC 1542: BOOTP Extensions • RFC 959: FTP • RFC 1058: RIP Routing • RFC 1112: IP Multicast and IGMP • RFC 1157: SNMPv1 • RFC 1166: IP Addresses • RFC 1253: OSPF Routing • RFC 1256: ICMP Router Discovery • RFC 1305: NTP • RFC 1492: TACACS+ • RFC 1493: Bridge MIB • RFC 1542: Bootstrap Protocol • RFC 1583: OSPFv2 • RFC 1643: Ethernet Interface MIB • RFC 1723: RIPv2 Routing • RFC 1757: RMON	• RFC 1812: IP Routing • RFC 1901: SNMPv2C • RFC 1902-1907: SNMPv2 • RFC 1981: MTU Path Discovery IPv6 • FRC 2068: HTTP • RFC 2080: RIP for IPv6 • RFC 2131: DHCP • RFC 2138: RADIUS • RFC 2233: IF MIB • RFC 2236: IP Multicast • RFC 2328: OSPFv2 • RFC 2273-2275: SNMPv3 • RFC 2373: IPv6 Aggregatable Addrs • RFC 2453: RIPv2 Routing • RFC 2460: IPv6 protocol • RFC 2461: IPv6 Neighbor Discovery • RFC 2462: IPv6 Autoconfiguration • RFC 2463: ICMP IPv6 • RFC 2474: DiffServ Precedence • RFC 2597: Assured Forwarding • RFC 2598: Expedited Forwarding • RFC 2571: SNMP Management • RFC 2740: OSPF for IPv6 • RFC 3046: DHCP Relay Agent Information Option • RFC 3101, 1587: NSSAs • RFC 3376: IGMPv3 • RFC 3580: 802.1x RADIUS
Note: RFC, MIB and Standards compliance is dependent on IOS Level.		

Table 8 shows safety and compliance information.

Table 8. Safety and Compliance Support

Description	Specification
Safety standards	• UL 60950-1 • CAN/CSA 22.2 No. 60950-1 • EN 60950-1 • IEC 60950-1 • CE Marking • GB 4943 • IEC 60825
Electromagnetic emissions certifications	• FCC Part 15, CFR 47, Class A, North America • EN/IEC 61000-4-5 • EN 55022 (CISPR22) and EN 55024 (CISPR24), CE marking, European Union • AS/NZS, Class A, CISPR22:2004 or EN55022, Australia and New Zealand • VCCI Class A, V-3/2007.04, Japan • KCC (Formerly MIC, GB17625.1-1998) Class A, KN24/KN22, Korea • ANATEL, Brazil • CCC, China • GOST, Russia
Environmental	Reduction of Hazardous Substances (ROHS) 6
Telco	Common Language Equipment Identifier (CLEI) code

Ordering Information

To place an order, consult Table 9 for ordering information and visit Cisco Commerce Workspace.

Table 9. Ordering Information for Cisco Catalyst 3560-CX and 2960-CX Series Compact Switches

Cisco Catalyst 3560-CX Compact Switches	
Part Number	**Description**
WS-C3560CX-8TC-S	3560-CX Switch 8 GE, uplinks: 2 x 1G SFP and 2 x 1G copper, IP Base
WS-C3560CX-12TC-S	3560-CX Switch 12 GE, uplinks: 2 x 1G SFP and 2 x 1G copper, IP Base
WS-C3560CX-8PC-S	3560-CX Switch 8 GE PoE+, uplinks: 2 x 1G SFP and 2 x 1G copper, IP Base
WS-C3560CX-12PC-S	3560-CX Switch 12 GE PoE+, uplinks: 2 x 1G SFP and 2 x 1G copper, IP Base
WS-C3560CX-12PD-S	3560-CX Switch 12 GE PoE+, uplinks: 2 x 10G SFP+ and 2 x 1G copper, IP Base
WS-C3560CX-8PT-S	3560-CX PD PSE Switch 8 GE PoE+, uplinks: 2 x 1G copper (Cisco UPOE powered input), IP Base
WS-C3560CX-8XPD-S	3560-CX Switch 6 GE PoE+, 2 MultiGE PoE+, uplinks: 2 x 10G SFP+, IP Base
Cisco Catalyst 2960-CX Compact Switches	
Part Number	**Description**
WS-C2960CX-8TC-L	2960-CX Switch 8 GE, uplinks: 2 x 1G SFP and 2 x 1G copper LAN Base
WS-C2960CX-8PC-L	2960-CX Switch, 8 GE PoE+, uplinks: 2 x 1G SFP and 2 x 1G copper LAN Base
Cisco Catalyst 3560-CX and 2960-CX Accessories	
Part Number	**Description**
PWR-CLP=	Power clip for the 3560-CX and 2960-CX compact switches
PWR-ADPT=	AC-DC power adapter for the WS-C3560CX-8PT-S compact switch
PWR-ADPT-DC=	DC-DC power adapter for the WS-C3560CX-8PT-S compact switch
PWR-ADPT-BRKT=	Power adapter bracket for the WS-C3560CX-8PT-S compact switch (needs either CMPCT-DIN-MNT= or CMPCT-MGNT-TRAY =) to work
CMPCT-CBLE-GRD=	Cable guard for the 3560-CX and 2960-CX compact switches

CMPCT-MGNT-TRAY =	Magnet and Mounting Tray for 3560-CX and 2960-CX compact switches
Cisco Catalyst 3560-CX and 2960-CX Accessories	
Part Number	**Description**
CMPCT-DIN-MNT=	DIN Rail Mount for 3560-CX and 2960-CX compact switches
RCKMNT-19-CMPCT=	19-Inch Rack Mounting Brackets for 3560-CX and 2960-CX compact switches
RCKMNT-23-CMPCT=	23- and 24-Inch Rack Mounting Brackets for 3560-CX and 2960-CX compact switches
Cisco Catalyst 3560-CX Software Licenses	
Part Number	**Description**
L-C3560CX-RTU=	Cisco Catalyst 3560-CX IP Base to IP Services RTU electronic license
C3560CX-RTU=	Cisco Catalyst 3560-CX IP Base to IP Services RTU paper license

Warranty Information

Cisco Catalyst 3560-CX and 2960-CX Series Switches come with an enhanced limited lifetime hardware warranty that includes 90 days of Cisco Technical Assistance Center (TAC) support and next-business-day hardware replacement free of change (see Table 10 for details).

Table 10. Enhanced Limited Lifetime Hardware Warranty

	Cisco Enhanced Limited Lifetime Hardware Warranty
Device covered	Applies to Cisco Catalyst 3560-CX and 2960-CX Series compact switches.
Warranty duration	As long as the original customer owns the product.
EoL policy	In the event of discontinuance of product manufacture, Cisco warranty support is limited to 5 years from the announcement of discontinuance.
Hardware replacement	Cisco or its service center will use commercially reasonable efforts to ship a replacement for next business day delivery, where available. Otherwise, a replacement will be shipped within 10 working days after receipt of the RMA request. Actual delivery times might vary depending on customer location.
Effective date	Hardware warranty commences from the date of shipment to customer (and in case of resale by a Cisco reseller, not more than 90 days after original shipment by Cisco).
TAC support	Cisco will provide during business hours, 8 hours per day, 5 days per week basic configuration, diagnosis, and troubleshooting of device-level problems for up to a 90-day period from the date of shipment of the originally purchased Cisco Catalyst 2960 and 3560 product. This support does not include solution or network-level support beyond the specific device under consideration.
Cisco.com access	Warranty allows guest access only to Cisco.com.

Your formal warranty statement, including the warranty applicable to Cisco software, appears in the Cisco information packet that accompanies your Cisco product. We encourage you to review carefully the warranty statement shipped with your specific product before use. Cisco reserves the right to refund the purchase price as its exclusive warranty remedy.

Adding a Cisco technical services contract to your device coverage provides access to the Cisco Technical Assistance Center (TAC) beyond the 90-day period allowed by the warranty. It also can provide a variety of hardware replacement options to meet critical business needs, as well as updates for licensed premium Cisco IOS Software, and registered access to the extensive Cisco.com knowledge base and support tools.

For additional information about warranty terms, visit http://www.cisco.com/go/warranty.

Cisco and Partner Services

Enable the innovative, secure, intelligent edge using personalized services from Cisco and our partners. Through a discovery process that begins with understanding your business objectives, we help you integrate the next-generation Cisco Catalyst fixed switches into your architecture and incorporate network services onto those

platforms. Sharing knowledge and leading practices, we support your success every step of the way as you deploy, absorb, manage, and scale new technology.

Choose from a flexible suite of support services (Table 11), designed to meet your business needs and help you maintain high-quality network performance while controlling operational costs.

Table 11. Technical Services Available for Cisco Catalyst 3560-CX and 2960-CX Series Compact Switches

Technical Services
Cisco SMARTnet® Service • Around-the-clock, global access to the Cisco Technical Assistance Center (TAC) • Unrestricted access to the extensive Cisco.com knowledge base and tools • Next-business-day, 8x5x4, 24x7x4, and 24x7x2 advance hardware replacement and onsite parts replacement and installation available • Ongoing operating system software updates within the licensed feature set • Proactive diagnostics and real-time alerts on Smart Call Home-enabled devices
Cisco Smart Foundation Service • Next business day advance hardware replacement as available • Business hours access to SMB TAC (access levels vary by region) • Access to Cisco.com SMB knowledge base • Online technical resources through Smart Foundation Portal • Operating system software bug fixes and patches
Cisco Focused Technical Support Services • 3 levels of premium, high-touch services are available • Cisco High-Touch Operations Management Service • Cisco High-Touch Technical Support Service • Cisco High-Touch Engineering Service • Valid Cisco SMARTnet or SP Base contracts on all network equipment are required

Cisco Capital

Financing to Help You Achieve Your Objectives

Cisco Capital can help you acquire the technology you need to achieve your objectives and stay competitive. We can help you reduce CapEx. Accelerate your growth. Optimize your investment dollars and ROI. Cisco Capital financing gives you flexibility in acquiring hardware, software, services, and complementary third-party equipment. And there's just one predictable payment. Cisco Capital is available in more than 100 countries. Learn more.

Learn More

For more information, contact your Cisco sales account rep or visit http://www.cisco.com/go/compactswitches.

Americas Headquarters
Cisco Systems, Inc.
San Jose, CA

Asia Pacific Headquarters
Cisco Systems (USA) Pte. Ltd.
Singapore

Europe Headquarters
Cisco Systems International BV Amsterdam,
The Netherlands

Cisco has more than 200 offices worldwide. Addresses, phone numbers, and fax numbers are listed on the Cisco Website at www.cisco.com/go/offices.

Printed in USA C78-733229-07 12/16

Cisco Aironet 3800 Series Access Points

The Cisco® Aironet® 3800 Series Wi-Fi access points are highly versatile and deliver the most functionality of any access points in the industry.

Product overview

For organizations paving the way for the new 802.11ac Wave 2 standard, the Cisco Aironet 3800 Series is the perfect solution. The access points go beyond getting ready for the new standard, providing the ultimate in flexibility and versatility.

For large enterprise organizations that rely on Wi-Fi to engage with customers, the 3800 Series is a hands-off product that's intelligent enough to make decisions based on end-device activities and usage. This automation allows you to devote time to other pressing matters, secure in the knowledge that your Wi-Fi network is performing to its utmost potential.

The Aironet 3800 Series is packed with the features and capabilities that have made Cisco the industry leader, at a price point that is ideal for managing wireless growth, capacity, and coverage gaps in dense indoor environments.

Features and benefits

Feature	Benefit
802.11ac Wave 2 support	Provides a theoretical connection rate of up to 2.6 Gbps per radio—roughly double the rates offered by today's high-end 802.11ac access points.
High-density experience	Best-in-class RF architecture that provides high-performance coverage for a high density of client devices, giving the end user a seamless wireless experience. Features include custom hardware in 802.11ac Wave 2 radios, Cisco CleanAir®, Cisco ClientLink 4.0, cross-access point noise reduction, and an optimized client roaming experience.
Multiuser Multiple-Input Multiple-Output (MU-MIMO) technology	Supporting three spatial streams, MU-MIMO enables access points to split spatial streams between client devices, to maximize throughput.
Multigigabit Ethernet support	Providing multiple gigabit uplink speeds of 2.5 Gbps and 5 Gbps in addition to 100-Mbps and 1-Gbps speeds. All speeds are supported on Category 5e cabling for an industry first, as well as 10GBASE-T(IEEE 802.3bz) cabling.

Feature	Benefit
Flexible Radio Assignment	Allows the access points to intelligently determine the operating mode of serving radios based on the RF environment. The access points can operate in the following modes: • **2.4-GHz and 5-GHz mode:** One radio serves clients in 2.4-GHz mode, while the other serves clients in 5-GHz mode • **Dual 5-GHz mode:** Both radios inside the access point operate on the 5-GHz band, maximizing the benefits of 802.11ac Wave 2 and increasing client device capacity • **Wireless Security Monitoring and 5-GHz mode:** One radio serves 5-GHz clients while the other is scanning the full spectrum for attackers, RF interference, and rogue devices
Dual 5-GHz radio support	Enables both radios to operate in 5-GHz client serving mode, allowing an industry-leading 5.2 Gbps (2 x 2.6 Gbps) over-the-air speed while increasing client capacity.
Smart antenna connector	An intelligent second physical antenna connector is included on 3800 Series models with an external antenna. This connector provides advanced network design flexibility for high-density and large open-area environments such as auditoriums, convention centers, libraries, cafeteria, and arenas/stadiums, allowing two sets of antennas to be connected and active on a single access point.
Modular architecture	Second-generation modular architecture first introduced by the 3600 Series access points. New side-mount connection allows companies to add and remove modules as needed without having to dismount the access point from the ceiling, further simplifying the customer's time and dollars when performing network upgrades. The new side-mount architecture allows for additional flexibility in the form factor of a 3800 Series module, and in the choice of solutions with integrated or even external antennas of their own. We have doubled the amount of power available to 3800 Series modules from 9W to 18W, broadening the potential module applications and solutions.
160-MHz channel support	Supporting channels up to 160 MHz wide, Dynamic Bandwidth Selection allows the access point to dynamically switch between 20-, 40-, 80-, and 160-MHz channels, depending on the RF channel conditions, providing the industry's best-performing wireless network.
Zero-impact Application Visibility and Control*	Uses dedicated hardware acceleration to improve the performance of line-speed applications such as Cisco Application Visibility and Control.
Cisco ClientLink 4.0	Cisco ClientLink 4.0 technology improves downlink performance to all mobile devices, including one-, two-, and three-spatial-stream devices on 802.11a/b/g/n/ac while improving battery life on mobile devices such as smartphones and tablets.
Cisco CleanAir 160 MHz*	Cisco CleanAir technology, enhanced with 160-MHz channel support, provides proactive, high-speed spectrum intelligence across 20-, 40-, 80-, and 160-MHz-wide channels to combat performance problems due to wireless interference.
Cross-access point noise reduction	A Cisco innovation that enables access points to intelligently collaborate in real time about RF conditions so that users connect with optimized signal quality and performance.
Optimized access point roaming	Helps ensure that client devices associate with the access point in their coverage range that offers the fastest data rate available.
Automatic link aggregation (LAG) support	802.3ad (Link Aggregation Control Protocol [LACP]) compliant, allowing both Ethernet interfaces to automatically enable LAG, increasing overall throughput to the access point.
Cisco Mobility Express	Flexible deployment mode through the Cisco Mobility Express solution is ideal for high density environments and can support up to 100 access points. Easy setup allows the 3800 Series access points to be deployed on networks without a physical controller.
Apple Features	Apple and Cisco have responded to this challenge by partnering to create an optimal mobile experience for iOS devices on corporate networks based on Cisco® technologies. Specifically, using new features in iOS 10 in combination with the latest software and hardware from Cisco, businesses can now more effectively use their network infrastructure to deliver an enhanced user experience across all business applications. At the center of the collaboration is a unique handshake between Cisco WLAN and Apple devices. This handshake enables Cisco WLAN to provide an optimal Wi-Fi roaming experience to Apple devices. Additionally, Cisco WLAN trusts Apple devices and gives priority treatment for business-critical applications specified by the Apple device.

802.11ac Wave 2 and beyond

The Aironet 3800 Series extends 802.11ac speed and features to a new generation of smartphones, tablets, and high-performance laptops, providing a greater end-user experience. Whether your project involves wholesale changes to your current wireless network or upgrading your legacy Wi-Fi deployments (802.11a/b/g/n/ac Wave 1 deployments), the Aironet 3800 Series can handle the job.

The Aironet 3800 Series supports 802.11ac Wave 2, providing a theoretical connection rate of up to 5.2 Gbps—that's roughly four times the rate offered by today's high-end 802.11ac access points. The boost helps you stay ahead of the performance and bandwidth expectations of today's mobile worker, who usually uses multiple Wi-Fi devices instead of just one. As such, users are adding proportionally larger traffic loads to the wireless LAN, which has outpaced Ethernet as the default enterprise access network.

Cisco DNA support

Pairing the 3800 Series access points with the Cisco Digital Network Architecture (Cisco DNA™) allows for a total network transformation. Cisco DNA allows you to truly understand your network with real-time analytics, quickly detect and contain security threats, and easily provide networkwide consistency through automation and virtualization. By decoupling network functions from the hardware, you can build and manage your entire wired and wireless network from a single user interface.

Working together, the 3800 Series and Cisco DNA offer such features as:

- Flexible Radio Assignment
- Cisco Connected Mobile Experiences
- Cisco High Density Experience
- Apple FastLane
- Cisco Identity Services Engine
- And much more

The result? Your network stays relevant, becomes digital-ready, and is the lifeblood of your organization.

High-density experience

Building on the Cisco Aironet heritage of RF excellence, the Cisco Aironet 3800 Series Access Points run on a purpose-built, innovative chipset with a best-in-class RF architecture. This chipset provides a high-density experience for enterprise networks designed for mission-critical, high-performance applications. The 3800 Series is part of Cisco's flagship portfolio of 802.11ac-enabled access points, delivering a robust mobility experience. It features 802.11ac Wave 2 with 4x4 MU-MIMO technology supporting three spatial streams. MU-MIMO enables access points to split spatial streams between client devices, to maximize throughput.

With two radios built into each access point, the Aironet 3800 Series is more versatile than any access point currently on the market. These radios are outfitted with Flexible Radio Assignment, which means that the access points automatically self-optimize to better serve the environment. For example, one of the radios broadcasts its signal on the 5-GHz channel and the other sends out a 2.4-GHz signal. The access point understands the wireless environment and will automatically switch the 2.4-GHz signal to a 5-GHz signal, increasing the reliability of your customers' Wi-Fi use. This setting automatically works in reverse too: the access point can recognize that the RF environment has changed and revert back to its original configuration.

The 3800 Series also dynamically changes the radio settings based on the wireless environment. The access point will allow one of the radios to operate in Wireless Security Monitoring mode, allowing you to detect wireless security threats and interference and combat rogue access. This valuable information can be culled in an easy-to-understand matrix to inform you about your wireless users. Flexible Radio Assignment also allows you to convert a radio into Wireless Service Assurance mode, providing proactive health monitoring of the network.

- **Optimized access point roaming** helps ensure that client devices associate with the access point in their coverage range that offers the fastest data rate available
- **Cisco ClientLink 4.0** improves downlink performance to all mobile devices, including one-, two-, and three-spatial-stream devices on 802.11a/b/g/n/ac. At the same time, the technology improves battery life on mobile devices
- **Cisco CleanAir** is technology enhanced with 160-MHz channel support. It delivers proactive, high-speed spectrum intelligence across 20-, 40-, and 80-, and 160-MHz-wide channels to combat performance problems due to wireless interference
- **MIMO equalization capabilities** optimize uplink performance and reliability by reducing the impact of signal fade
- **Apple roaming features** such as 802.11r Fast Transition, 802.11v BSS Transition, and Assisting Roaming enables Cisco WLAN to provide an optimal Wi-Fi roaming experience to Apple devices

Modular architecture

The 3800 Series carries forward the modular architecture first introduced with the Aironet 3600 Series, providing unparalleled investment protection for forward-looking modular solutions. The 3800 Series delivers an enhanced second-generation modular architecture in the following ways:

- **Moving the module connection from the bottom to the side of the access point.** This allows for easier addition and removal of a module without having to dismount the access point and also allows for flexibility in module design with respect to size and appropriate antenna placement
- **Increasing the power available to a module to 18W**, providing additional flexibility for future module solutions
- The **Cisco Aironet Developer Platform** framework works in tandem with the Aironet 3800 Series as the perfect solution, allowing your network to work for you. Modularity brings intent-based networking to the edge, customizing your ability to tackle new use cases and emerging technology standards, so that your deployments are ready for the future. The Cisco Aironet Developer Platform program transforms the access point into a powerful development platform for mobility and IoT convergence.
- The **Cisco Beacon Point Module** is the virtual beacon solution that is leading the way in the indoor location-based services space. Cisco technology brings both easy deployment and superior location accuracy to the industry. All it takes to move a virtual beacon is a mouse click and technologies that can identify assets from 1 to 3 meters away. The Cisco Beacon Point Module is the perfect add-on to augment your Cisco Aironet 3800 Series Access Point and will strengthen your wireless network. This solution is well suited to industries such as retail (properly engage customers), healthcare (accurately track assets), and offices (optimize workspaces).

As wireless LAN continues to grow as the dominant method of connecting to private and public networks, the access point becomes a perfect integration point into an enterprise corporate network or carrier service network for a wide variety of solutions. Companies can use a single Ethernet cable drop from their wired network to provide high-speed network access and also typically for Power over Ethernet (PoE) to the access point and solutions that are integrated with and interconnected through the 3800 Series access points.

Product specifications

Item	Specification
Part numbers	**Cisco Aironet 3800i Access Point: Indoor environments, with internal antennas** ● AIR-AP3802I-**x**-K9: Dual-band, controller-based 802.11a/b/g/n/ac ● AIR-AP3802I-**x**K910: Eco-pack (dual-band 802.11a/b/g/n/ac) 10 quantity access points ● AIR-AP3802I-D-K9I: Dual-band, controller-based 802.11a/b/g/n/ac (India only) **Cisco Aironet 3800i Access Point Configurable: Indoor environments, with internal antennas** ● AIR-AP3802I-x-K9C: Dual-band, controller-based 802.11a/g/n/ac, configurable ● AIR-AP3802I-xK910C: Eco-pack (dual-band 802.11a/g/n/ac) 10 quantity access points, configurable **Cisco Aironet 3800e Access Point: Indoor, challenging environments, with external antennas** ● AIR-AP3802e-**x**-K9: Dual-band controller-based 802.11a/b/g/n/ac ● AIR-AP3802e-**x**K910: Eco-pack (dual-band 802.11a/b/g/n/ac), 10 quantity access points **Cisco Aironet 3800e Access Point Configurable: Indoor, challenging environments, with external antennas** ● AIR-AP3802E-**x**-K9C: Dual-band controller-based 802.11a/g/n/ac, configurable ● AIR-AP3802E-**x**K910C: Eco-pack (dual-band 802.11a/g/n/ac), 10 quantity access points, configurable **Cisco Aironet 3800p Access Point: Indoor, challenging environments, with external antennas** ● AIR-AP3802p-**x**-K9: Dual-band controller-based 802.11a/b/g/n/ac ● AIR-AP3802p-**x**K910: Eco-pack (dual-band 802.11a/b/g/n/ac), 10 quantity access points **Cisco Aironet 3800p Access Point Configurable: Indoor, challenging environments, with external antennas** ● AIR-AP3802p-**x**-K9C: Dual-band controller-based 802.11a/g/n/ac, configurable ● AIR-AP3802p-**x**K910C: Eco-pack (dual-band 802.11a/g/n/ac), 10 quantity access points, configurable **Cisco Smart Net Total Care™ for the Cisco Aironet 3800i Access Point with internal antennas** ● CON-SNT-AIRPIBK9: SNTC-8X5XNBD 802.11ac Ctrlr AP 4x Duration: 12 Month(s) **Cisco Smart Net Total Care for the Cisco Aironet 3800e Access Point with external antennas** ● CON-SNT-AIRPID38E: SNTC-8X5XNBD 802.11ac Ctrlr AP 4x4:3SS w/ CleanAir; Ex Duration: 12 Month(s) **Cisco Smart Net Total Care for the Cisco Aironet 3800p Access Point with external antennas** ● CON-SNT-AIRAP382: SNTC-8X5XNBD 802.11ac Ctrlr AP 4x Duration: 12 Month(s) **Regulatory domains: (x = regulatory domain)** Customers are responsible for verifying approval for use in their individual countries. To verify approval, and to identify the regulatory domain that corresponds to a particular country, visit https://www.cisco.com/go/aironet/compliance. Not all regulatory domains have been approved. As they are approved, the part numbers will be available on the Global Price List. **Cisco Smart Net Total Care Service:** https://www.cisco.com/go/sntc **Cisco Wireless LAN Services** ● AS-WLAN-CNSLT: Cisco Wireless LAN Network Planning and Design Service ● AS-WLAN-CNSLT: Cisco Wireless LAN 802.11n Migration Service ● AS-WLAN-CNSLT: Cisco Wireless LAN Performance and Security Assessment Service
Software and supported wireless LAN controllers	● Cisco Unified Wireless Network Software Release 8.2.111.0 or later ● Cisco 2500 Series Wireless Controllers, Cisco Wireless Controller Module for ISR G2, Cisco Wireless Services Module 2 (WiSM2) for Catalyst® 6500 Series Switches, Cisco 5500 Series Wireless Controllers, Cisco Flex® 7500 Series Wireless Controllers, Cisco 8500 Series Wireless Controllers, Cisco Virtual Wireless Controller ● Cisco IOS® XE Software Release 16.3 ● Cisco Catalyst 3850 Series and 3650 Series Switches

Item	Specification
802.11n version 2.0 (and related) capabilities	• 4x4 MIMO with three spatial streams • Maximal Ratio Combining (MRC) • 802.11n and 802.11a/g beamforming • 20- and 40-MHz channels • PHY data rates up to 450 Mbps (40 MHz with 5 GHz) • Packet aggregation: A-MPDU (Tx/Rx), A-MSDU (Tx/Rx) • 802.11 Dynamic Frequency Selection (DFS) • Cyclic Shift Diversity (CSD) support
802.11ac Wave 1 capabilities	• 4x4 MIMO with three spatial streams • MRC • 802.11ac beamforming • 20-, 40-, and 80-MHz channels • PHY data rates up to 1.3 Gbps (80 MHz in 5 GHz) • Packet aggregation: A-MPDU (Tx/Rx), A-MSDU (Tx/Rx) • 802.11 DFS • CSD support
802.11ac Wave 2 capabilities	• 4x4 MU-MIMO with three spatial streams • MRC • 802.11ac beamforming • 20-, 40-, 80, 160-MHz channels • PHY data rates up to 5.2 Gbps • Packet aggregation: A-MPDU (Tx/Rx), A-MSDU (Tx/Rx) • 802.11 DFS • CSD support
Wi-Fi Alliance Certified	• Wi-Fi Certified a, b, g, n, ac • Wi-Fi Vantage • WMM • Passpoint
Integrated antenna	**Flexible radio (either 2.4 GHz or 5 GHz)** • 2.4 GHz, gain 4 dBi, internal antenna, omnidirectional in azimuth • 5 GHz, gain 6 dBi, internal directional antenna, elevation plane beamwidth 90° **Dedicated 5-GHz radio** • 5 GHz, gain 5 dBi, internal antenna, omnidirectional in azimuth
External antenna (sold separately)	• 3802e Series access points are certified for use with antenna gains up to 6 dBi (2.4 GHz and 5 GHz) • 3802p Series access points are certified for use with antenna gains up to 13 dBi (2.4 GHz and 5 GHz) with the AIR-ANT2513-P4M-N= antenna • Cisco offers the industry's broadest selection of antennas, delivering optimal coverage for a variety of deployment scenarios
Smart Antenna Connector	• Available on the 3802e Series and 3802p Series access points only • Requires the AIR-CAB002-DART-R= 2 ft smart antenna connector to RP-TNC connectors to connect a second antenna to the access point • Required when running the flexible radio as either a: ◦ Second 5-GHz serving radio ◦ Wireless Security Monitoring radio
Interfaces	◦ 2 Ethernet ports ◦ 100/1000/2500/5000 Multigigabit Ethernet (RJ-45) – IEEE 802.3bz ◦ CAT 5e cabling ◦ Higher-quality 10GBASE-T (CAT 6/6a) cabling ◦ 100/1000BASE-T autosensing (RJ-45 - AUX port) ◦ Management console port (RJ-45)
Indicators	• Status LED indicates boot loader status, association status, operating status, boot loader warnings, boot loader errors

Item	Specification	
Dimensions (W x L x H)	• Access point (without mounting brackets): 3802I: 8.66 x 8.68 x 2.46 in. (22 x 22 x 6.25 cm), 3802E: 8.66 x 8.68 x 2.62 in. (22 x 22 x 6.7 cm), 3802P: 8.66 x 8.68 x 2.62 in. (22 x 22 x 6.7 cm)	
Weight	• 4.6 lb (2.09 kg)	
Input power requirements	• 802.3at PoE+, Cisco Universal Power over Ethernet (Cisco UPOE®) • 802.3at power injector (AIR-PWRINJ6=) • 50W power supply (AIR-PWR-50=)	
Power draw	• 30W at the PSE (25.5W at the PD) with all features enabled except for the USB 2.0 port • 34W at the PSE (31.1W at the PD) with the USB 2.0 port enabled	
Environmental	**Cisco Aironet 3800i** • Nonoperating (storage) temperature: -22° to 158°F (-30° to 70°C) • Nonoperating (storage) altitude test: 25˚C, 15,000 ft. • Operating temperature: 32° to 104°F (0° to 40°C) • Operating humidity: 10% to 90% percent (noncondensing) • Operating altitude test: 40˚C, 9843 ft. **Cisco Aironet 3800e** • Nonoperating (storage) temperature: -22° to 158°F (-30° to 70°C) • Nonoperating (storage) altitude test: 25˚C, 15,000 ft. • Operating temperature: -4° to 122°F (-20° to 50°C) • Operating humidity: 10% to 90% (noncondensing) • Operating altitude test: 40˚C, 9843 ft. **Cisco Aironet 3800p** • Nonoperating (storage) temperature: -22° to 158°F (-30° to 70°C) • Nonoperating (storage) altitude test: 25˚C, 15,000 ft. • Operating temperature: -4° to 122°F (-20° to 50°C) • Operating humidity: 10% to 90% (noncondensing) Operating altitude test: 40˚C, 9843 ft.	
System memory	• 1024 MB DRAM • 256 MB flash	
Available transmit power settings	**2.4 GHz** • 23 dBm (200 mW) • 20 dBm (100 mW) • 17 dBm (50 mW) • 14 dBm (25 mW) • 11 dBm (12.5 mW) • 8 dBm (6.25 mW) • 5 dBm (3.13 mW) • 2 dBm (1.56 mW)	**5 GHz** • 23 dBm (200 mW) • 20 dBm (100 mW) • 17 dBm (50 mW) • 14 dBm (25 mW) • 11 dBm (12.5 mW) • 8 dBm (6.25 mW) • 5 dBm (3.13 mW) • 2 dBm (1.56 mW)
Frequency band and 20-MHz operating channels	**A (A regulatory domain):** • 2.412 to 2.462 GHz; 11 channels • 5.180 to 5.320 GHz; 8 channels • 5.500 to 5.700 GHz; 8 channels (excludes 5.600 to 5.640 GHz) • 5.745 to 5.825 GHz; 5 channels **B (B regulatory domain):** • 2.412 to 2.462 GHz; 11 channels • 5.180 to 5.320 GHz; 8 channels • 5.500 to 5.720 GHz; 12 channels • 5.745 to 5.825 GHz; 5 channels **C (C regulatory domain):** • 2.412 to 2.472 GHz; 13 channels • 5.745 to 5.825 GHz; 5 channels	**I (I regulatory domain):** • 2.412 to 2.472 GHz; 13 channels • 5.180 to 5.320 GHz; 8 channels **K (K regulatory domain):** • 2.412 to 2.472 GHz; 13 channels • 5.180 to 5.320 GHz; 8 channels • 5.500 to 5.620 GHz; 7 channels • 5.745 to 5.805 GHz; 4 channels **N (N regulatory domain):** • 2.412 to 2.462 GHz; 11 channels • 5.180 to 5.320 GHz; 8 channels • 5.745 to 5.825 GHz; 5 channels **Q (Q regulatory domain):** • 2.412 to 2.472 GHz; 13 channels • 5.180 to 5.320 GHz; 8 channels • 5.500 to 5.700 GHz; 11 channels

Item	Specification	
	D (D regulatory domain): ● 2.412 to 2.462 GHz; 11 channels ● 5.180 to 5.320 GHz; 8 channels ● 5.745 to 5.825 GHz; 5 channels **E (E regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.180 to 5.320 GHz; 8 channels ● 5.500 to 5.700 GHz; 8 channels (excludes 5.600 to 5.640 GHz) **F (F regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.745 to 5.805 GHz; 4 channels **G (G regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.745 to 5.825 GHz; 5 channels **H (H regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.150 to 5.320 GHz; 8 channels ● 5.745 to 5.825 GHz; 5 channels	**R (R regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.180 to 5.320 GHz; 8 channels ● 5.660 to 5.700 GHz; 3 channels ● 5.745 to 5.805 GHZ; 4 channels **S (S regulatory domain):** ● 2.412 to 2.472 GHz; 13 channels ● 5.180 to 5.320 GHz; 8 channels ● 5.500 to 5.700 GHz;, 11 channels ● 5.745 to 5.825 GHz; 5 channels **T (T regulatory domain):** ● 2.412 to 2.462 GHz; 11 channels ● 5.280 to 5.320 GHz; 3 channels ● 5.500 to 5.700 GHz; 8 channels (excludes 5.600 to 5.640 GHz) ● 5.745 to 5.825 GHz; 5 channels **Z (Z regulatory domain):** ● 2.412 to 2.462 GHz; 11 channels ● 5.180 to 5.320 GHz; 8 channels ● 5.500 to 5.700 GHz; 8 channels (excludes 5.600 to 5.640 GHz) ● 5.745 to 5.825 GHz; 5 channels
Note: Customers are responsible for verifying approval for use in their individual countries. To verify approval and to identify the regulatory domain that corresponds to a particular country, visit https://www.cisco.com/go/aironet/compliance.		
Maximum number of nonoverlapping channels	**2.4 GHz** ● 802.11b/g: ◦ 20 MHz: 3 ● 802.11n: ◦ 20 MHz: 3	**5 GHz** ● 802.11a: ◦ 20 MHz: 25 FCC, 16 EU ● 802.11n: ◦ 20 MHz: 25 FCC, 16 EU ◦ 40 MHz: 12 FCC, 7 EU ● 802.11ac: ◦ 20 MHz: 25 FCC, 16 EU ◦ 40 MHz: 12 FCC, 7 EU ◦ 80 MHz: 6 FCC, 3 EU ◦ 160 MHz 2 FCC, 1 EU
Note: This varies by regulatory domain. Refer to the product documentation for specific details for each regulatory domain.		
Compliance standards	◦ UL 60950-1 ◦ CAN/CSA-C22.2 No. 60950-1 ◦ UL 2043 ◦ IEC 60950-1 ◦ EN 60950-1 ◦ EN 50155 ● Radio approvals: ◦ FCC Part 15.107, 15.109, 15.247, 15.407, 14-30 ◦ RSS-247 (Canada) ◦ EN 300.328, EN 301.893 (Europe) ◦ ARIB-STD 66 (Japan) ◦ ARIB-STD T71 (Japan) ◦ EMI and susceptibility (Class B) ◦ ICES-003 (Canada) ◦ VCCI (Japan) ◦ EN 301.489-1 and -17 (Europe) ◦ EN 60601-1-2 EMC requirements for the Medical Directive 93/42/EEC	

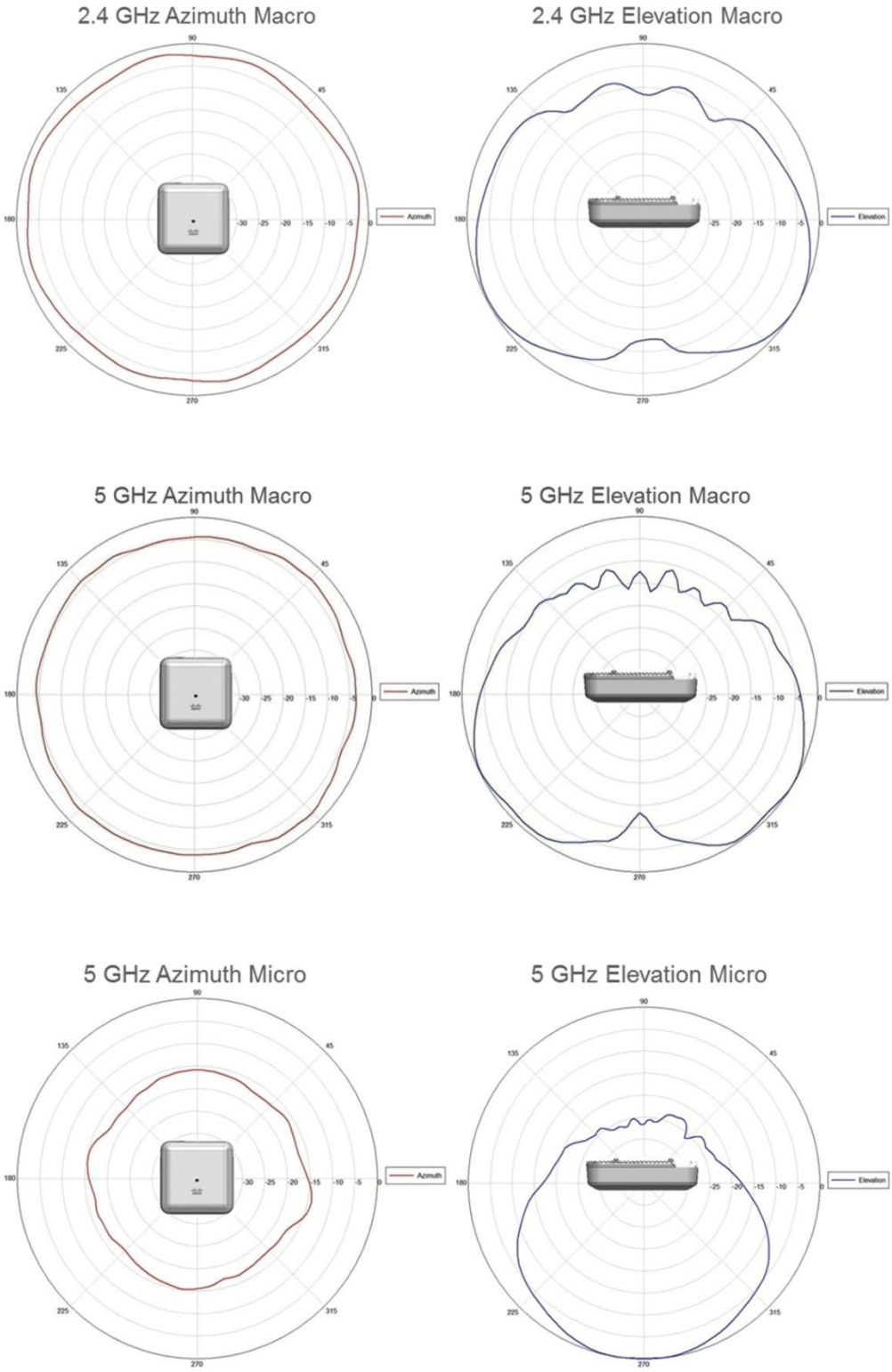
Item	Specification
	● IEEE standards: ◦ IEEE 802.11a/b/g, 802.11n, 802.11h, 802.11d, 802.11r, 802.11k, 802.11v, 802,11u, 802.11w ◦ IEEE 802.11ac ● Security: ◦ 802.11i, Wi-Fi Protected Access 2 (WPA2), WPA ◦ 802.1X ◦ Advanced Encryption Standards (AES), Temporal Key Integrity Protocol (TKIP) ● Extensible Authentication Protocol (EAP) types: ◦ EAP-Transport Layer Security (TLS) ◦ EAP-Tunneled TLS (TTLS) or Microsoft Challenge Handshake Authentication Protocol Version 2 (MSCHAPv2) ◦ Protected EAP (PEAP) v0 or EAP-MSCHAPv2 ◦ EAP-Flexible Authentication via Secure Tunneling (FAST) ◦ PEAP v1 or EAP-Generic Token Card (GTC) ◦ EAP-Subscriber Identity Module (SIM) ● Multimedia: ◦ Wi-Fi Multimedia (WMM) ● Other: ◦ FCC Bulletin OET-65C ◦ RSS-102
Warranty	Limited lifetime hardware warranty
Data rates supported	802.11b: 1, 2, 5.5, and 11 Mbps
	802.11a/g: 6, 9, 12, 18, 24, 36, 48, and 54 Mbps
	802.11n HT20: 6.5 to 216.7 Mbps (MCS0 to MCS23)
	802.11n HT40: 13.5 to 450 Mbps (MCS0 to MCS23)
	802.11ac VHT20: 6.5 to 288.9 Mbps (MCS0 to 8 – SS 1, MCS0 to 9 – SS 2 and 3)
	802.11ac VHT40: 13.5 to 600 Mbps (MCS0 to 9 – SS 1 to 3)
	802.11ac VHT80: 29.3 to 1300 Mbps (MCS0 to 9 – SS 1 to 3)
	802.11ac VHT160: 58.5 to 2304 Mbps (MCS0 to 9 – SS 1 and 2, MCS0 to 8 – SS 3)

Transmit power and receive sensitivity

		5-GHz radio		2.4-GHz flexible radio		5-GHz flexible radio	
	Spatial streams	**Total Tx power (dBm)**	**Rx sensitivity (dBm)**	**Total Tx power (dBm)**	**Rx sensitivity (dBm)**	**Total Tx power (dBm)**	**Rx sensitivity (dBm)**
802.11/11b							
1 Mbps	1	NA	NA	23	-101	NA	NA
11 Mbps	1	NA	NA	23	-88	NA	NA
802.11a/g							
6 Mbps	1	23	-93	23	-91	23	-92
24 Mbps	1	23	-89	23	-87	23	-89
54 Mbps	1	23	-81	23	-77	22	-80
802.11n HT20							
MCS0	1	23	-93	23	-91	23	-93
MCS4	1	23	-88	23	-86	23	-87
MCS7	1	23	-79	23	-77	22	-78
MCS8	2	23	-93	23	-91	21	-93
MCS12	2	23	-86	23	-85	23	-86
MCS15	2	23	-79	23	-77	21	-78
MCS16	3	23	-93	23	-91	23	-92
MCS20	3	23	-85	23	-84	22	-84

Item		Specification					
MCS23	3	23	-78	23	-76	18	-77
802.11n HT40							
MCS0	1	23	-90			23	-89
MCS4	1	23	-85			23	-84
MCS7	1	23	-76			23	-75
MCS8	2	23	-90			23	-89
MCS12	2	23	-83			23	-83
MCS15	2	23	-76			21	-76
MCS16	3	23	-90			23	-89
MCS20	3	23	-82			23	-81
MCS23	3	23	-75			20	-74
802.11ac VHT20							
MCS0	1	23	-93			23	-92
MCS4	1	23	-88			23	-87
MCS7	1	23	-82			22	-80
MCS8	1	23	-77			21	-75
MCS0	2	23	-93			23	-91
MCS4	2	23	-86			23	-84
MCS7	2	23	-79			21	-77
MCS8	2	23	-75			20	-73
MCS9	2	NA	NA			NA	NA
MCS0	3	23	-93			23	-91
MCS4	3	23	-85			22	-83
MCS7	3	23	-78			20	-76
MCS8	3	23	-74			19	-72
MCS9	3	23	-72			18	-70
802.11ac VHT40							
MCS0	1	23	-90			23	-89
MCS4	1	23	-85			23	-84
MCS7	1	23	-78			22	-77
MCS8	1	23	-75			21	-73
MCS9	1	23	-73			20	-72
MCS0	2	23	-90			23	-89
MCS4	2	23	-83			23	-82
MCS7	2	23	-76			21	-75
MCS8	2	23	-73			20	-72
MCS9	2	23	-71			19	-69
MCS0	3	23	-90			23	-89
MCS4	3	23	-82			23	-80
MCS7	3	23	-74			20	-73
MCS8	3	23	-70			19	-68
MCS9	3	23	-69			18	-67

Item		Specification					
802.11ac VHT80							
MCS0	1	23	-87			23	-86
MCS4	1	23	-83			23	-81
MCS7	1	23	-76			22	-74
MCS8	1	23	-72			21	-70
MCS9	1	23	-69			20	-68
MCS0	2	23	-87			23	-86
MCS4	2	23	-80			23	-79
MCS7	2	23	-73			21	-72
MCS8	2	23	-69			20	-68
MCS9	2	23	-67			19	-66
MCS0	3	23	-87			23	-86
MCS4	3	23	-77			23	-77
MCS7	3	23	-72			20	-70
MCS8	3	23	-67			19	-66
MCS9	3	22	-65			18	-64
802.11ac VHT160							
MCS0	1	23	-83			23	-83
MCS4	1	23	-78			23	-78
MCS7	1	23	-71			22	-71
MCS8	1	23	-67			21	-68
MCS9	1	23	-66			20	-66
MCS0	2	23	-83			23	-83
MCS4	2	23	-76			23	-76
MCS7	2	23	-69			21	-69
MCS8	2	23	-65			20	-66
MCS9	2	23	-63			19	-63
MCS0	3	23	-82			23	-83
MCS4	3	23	-74			22	-74
MCS7	3	23	-67			20	-68
MCS8	3	23	-62			19	-62



Warranty information

The Cisco Aironet 3800 Series Access Points come with a limited lifetime warranty that provides full warranty coverage of the hardware for as long as the original end user continues to own or use the product. The warranty includes 10-day advance hardware replacement and ensures that software media are defect-free for 90 days. For more details, visit https://www.cisco.com/go/warranty.

Cisco Capital

Financing to help you achieve your objectives

Cisco Capital® can help you acquire the technology you need to achieve your objectives and stay competitive. We can help you reduce CapEx. Accelerate your growth. Optimize your investment dollars and ROI. Cisco Capital financing gives you flexibility in acquiring hardware, software, services, and complementary third-party equipment. And there's just one predictable payment. Cisco Capital is available in more than 100 countries. Learn more.

* Post FCS

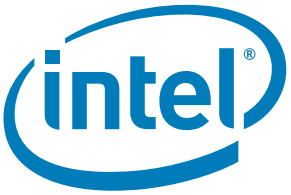
Americas Headquarters
Cisco Systems, Inc.
San Jose, CA

Asia Pacific Headquarters
Cisco Systems (USA) Pte. Ltd.
Singapore

Europe Headquarters
Cisco Systems International BV Amsterdam,
The Netherlands

Cisco has more than 200 offices worldwide. Addresses, phone numbers, and fax numbers are listed on the Cisco Website at **https://www.cisco.com/go/offices**.

Printed in USA C78-736498-10 10/17

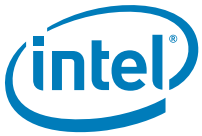


Intel® Xeon Processor Scalable Family

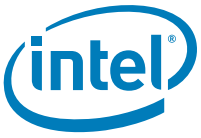
Datasheet, Volume One: Electrical

January 2018

Reference Number: 336062-001



Contents



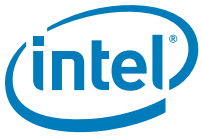
Figures

Tables

Revision History

Document Number	Revision Number	Description	Date
336062	001	• Initial Release	July 2017
336062	002	• Updated Table 2-14, "Current (ICCIN_MAX and ICCIN_TDC) Specification" on page 36	January 2018

§



1 Introduction

The Datasheet Volume 2 provides configuration space registers (CSRs).

This document is distributed as a part of the complete datasheets consisting of two volumes.

Note: Unless specified otherwise, "processor" will represent the following processors throughout the rest of the document.

- Intel® Xeon® Bronze 3XXX processor
- Intel® Xeon® Gold 6XXF processor
- Intel® Xeon® Platinum 6XXF processor
- Intel® Xeon® Platinum 8XXF processor
- Intel® Xeon® Silver 4XXX processor
- Intel® Xeon® Gold 5XXX processor
- Intel® Xeon® Platinum 6XXX processor
- Intel® Xeon® Platinum 8XXX processor
- Intel® Xeon® processor E Family
- Intel® Xeon® processor W Family
- Intel® Core X-Series Processor Family i7 78xx and i9-79xx Series

The Intel Xeon Processor Scalable Family is the next generation of 64-bit, multi-core server processor built on 14-nm process technology. The processor supports up to 46 bits of physical address space and 48 bits of virtual address space. The processor is designed for a platform consisting of at least one Intel Xeon Scalable Family processor and the Platform Controller Hub (PCH). Included in this family of processors are integrated memory controller (IMC) and an Integrated I/O (IIO) on a single silicon die.

Note: Features within this document may not be available on all platform segments, processor types, and processor SKUs.

For supported processor configurations refer to:

- Intel® Xeon® Processor Scalable Family Datasheet: Volume 2 - Registers, 336063

1.1 Electrical Specification Introduction

This is volume provides DC electrical specifications, signal integrity, differential signaling specifications, and land and signal definitions of the processor.

This document may be used by system test engineers, board designers, and BIOS developers.

1.2 Related Publications

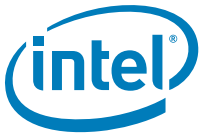
See the following documents for additional information.

Table 1-1. Related Publications

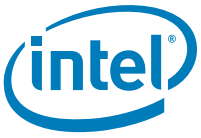
Document	Document Number / Location
• Intel® Xeon® Processor Scalable Family Datasheet: Volume 2 - Registers	336063
• Intel® Xeon® Processor Scalable Family Specification Update	336065
• Intel® Xeon® Processor Scalable Family Thermal Mechanical Design Guidelines	336064
• Intel® C620 Series Chipset Datasheet	336067
• Intel® C620 Series Chipset Thermal Mechanical Design Guidelines	336068
Intel®64and IA-32Architectures Software Developer's Manuals *Volume 1: Basic Architecture* *Volume 2A: Instruction Set Reference, A-M* Volume 2B: Instruction Set Reference, N-Z Volume 3A: System Programming Guide Volume 3B: System Programming Guide Intel® 64 and IA-32Architectures Optimization Reference Manual	325462 http://www.intel.com/products/processor/manuals/index.htm
Intel® Virtualization Technology Specification for Directed I/O Architecture Specification	http://www.intel.com/content/www/us/en/intelligent-systems/intel-technology/vt-directed-io-spec.html
Intel®Trusted Execution Technology Software Development Guide	http://www.intel.com/technology/security/

1.3 Terminology

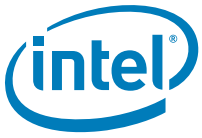
Term	Description
ASPM	Active State Power Management
BMC	Baseboard Management Controller
CA	Coherency Agent. In some cases this is referred to as a Caching Agent though a CA is not actually required to have a cache. It is a term used for the internal logic providing mesh interface to LLC and Core.
CHA	The functional module that includes the CA (Coherency Agent) and HA (Home Agent).
DDR4	Fourth generation Double Data Rate SDRAM memory technology.
DDR-T	DDR-T (transactional) protocol which enables Apache Pass.Communication to far memory protocol running on the DDR4physical layer.
DMA	Direct Memory Access
DMI3	Direct Media Interface Gen3 operating at PCI Express 3.0 speed.
DTLB	Data Translation Look-aside Buffer; part of the processor core architecture.
DTS	Digital Thermal Sensor



Term	Description
ECC	Error Correction Code
Enhanced Intel SpeedStep®Technology	Allows the operating system to reduce power consumption when performance is not needed.
Execute Disable Bit	The Execute Disable bit allows memory to be marked as executable or non-executable, when combined with a supporting operating system. If code attempts to run in non-executable memory the processor raises an error to the operating system. This feature can prevent some classes of viruses or worms that exploit buffer overrun vulnerabilities and can thus help improve the overall security of the system.See the *Intel®64and IA-32ArchitecturesSoftware Developer's Manuals* for more detailed information.
FLIT	Flow Control Unit. The Intel® UPI Link layer's unit of transfer. A FLIT is made of multiple PHITS. A Flit is always a fixed amount of information (192 bits).
Functional Operation	Refers to the normal operating conditions in which all processor specifications, including DC, system bus, signal quality, mechanical, and thermal, are satisfied.
GSSE	Extension of the SSE/SSE2 (Streaming SIMD Extensions) floating point instruction set to 256b operands.
HA	A Home Agent (HA) orders read and write requests to a piece of coherent memory. The HA is implemented in the CHA logic.
ICU	Instruction Cache Unit. Part of the processor core architecture.
IFU	Instruction Fetch Unit. Part of the processor core.
IIO	Integrated I/O Controller. An I/O controller that is integrated in the processor die. The IIO consists of the DMI3 module, PCIe modules, and MCP modules (Intel Xeon processor-F SKUs only).
IMC	Integrated Memory Controller. A Memory Controller that is integrated in the processor die.
IQ	Instruction Queue. Part of the core architecture.
Intel® ME	Intel® Management Engine
Intel® QuickData Technology	Intel® QuickData Technology is a platform solution designed to maximize the throughput of server data traffic across a broader range of configurations and server environments to achieve faster, scalable, and more reliable I/O.
Intel® Ultra Path Interconnect (Intel® UPI)	A cache-coherent, link-based Interconnect specification for Intel processors. Also known as Intel® UPI.
Intel® 64Technology	64-bit memory extensions to the IA-32 architecture. Further details on Intel 64 architecture and programming model can be found at http://developer.intel.com/technology/intel64/.
Intel® Turbo Boost Technology	A feature that opportunistically enables the processor to run a faster frequency. This results in increased performance of both single and multi-threaded applications.
Intel® TXT	Intel® Trusted Execution Technology
Intel® Virtualization Technology (Intel® VT)	Processor Virtualization which when used in conjunction with Virtual Machine Monitor software enables multiple, robust independent software environments inside a single platform.
Intel® VT-d	Intel® Virtualization Technology (Intel® VT) for Directed I/O. Intel VT-d is a hardware assist, under system software (Virtual Machine Manager or OS) control, for enabling I/O device Virtualization. Intel VT-d also brings robust security by providing protection from errant DMAs by using DMA remapping, a key feature of Intel VT-d.



Term	Description
Integrated Heat Spreader (IHS)	A component of the processor package used to enhance the thermal performance of the package. Component thermal solutions interface with the processor at the IHS surface.
IOV	I/O Virtualization
IVR	Integrated Voltage Regulation (IVR): The processor supports several integrated voltage regulators.
Intel UPI	Intel® Ultra Path Interconnect (Intel® UPI) Agent. An internal logic block providing interface between internal mesh and external Intel® UPI.
LLC	Last Level Cache
LRDIMM	Load Reduced Dual In-line Memory Module
LRU	Least Recently Used. A term used in conjunction with cache allocation policy.
M2M	Mesh to Memory. Logic in the IMC which interfaces the IMC to the mesh.
M2PCIe	The logic in the IIO modules which interface the modules to the mesh.
MESH	The on die interconnect which connects modules in the processor.
MESI	Modified/Exclusive/Shared/Invalid. States used in conjunction with cache coherency
MLC	Mid Level Cache
NCTF	Non-Critical to Function: NCTF locations are typically redundant ground or non-critical reserved, so the loss of the solder joint continuity at end of life conditions will not affect the overall product functionality.
NID \ NodeID	Node ID (NID) or NodeID (NID). The processor implements up to 4-bits of NodeID (NID).
Pcode	Pcode is microcode which is run on the dedicated microcontroller within the PCU.
PCH	Platform Controller Hub. The next generation chipset with centralized platform capabilities including the main I/O interfaces along with display connectivity, audio features, power management, manageability, security and storage features.
PCU	Power Control Unit.
PCI Express 3.0	The third generation PCI Express specification that operates at twice the speed of PCI Express 2.0 (8 Gb/s); PCI Express 3.0 is completely backward compatible with PCI Express 1.0 and 2.0.
PCI Express 2.0	PCI Express* Generation 2.0
PECI	Platform Environment Control Interface
Phit	The data transfer unit on Intel® UPI at the Physical layer is called a phit (physical unit). A Phit will be either 20 bits, or 8 bits depending on the number of active lanes.
Processor	Includes the 64-bit cores, uncore, I/Os and package
Processor Core	The term “processor core” refers to Si die itself which can contain multiple execution cores. Each execution core has an instruction cache and data cache and MLC cache. All execution cores share the L3 cache.
Rank	A unit of DRAM corresponding four to eight devices in parallel, ignoring ECC. These devices are usually, but not always, mounted on a single side of a DDR4 DIMM.

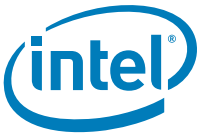


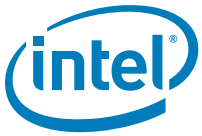
Term	Description
RDIMM \ LRDIMM	Registered Dual In-line Memory Module \ Load Reduced DIMM
RTID	Request Transaction IDs are credits issued by the CHA to track outstanding transaction, and the RTIDs allocated to a CHA are topology dependent.
SCI	System Control Interrupt. Used in ACPI protocol.
SKU	Stock Keeping Unit (SKU) is a subset of a processor type with specific features, electrical, power and thermal specifications. Not all features are supported on all SKUs. A SKU is based on specific use condition assumption.
SSE	Intel® Streaming SIMD Extensions (Intel®SSE)
SMBus	System Management Bus. A two-wire interface through which simple system and power management related devices can communicate with the rest of the system.
Storage Conditions	A non-operational state. The processor may be installed in a platform, in a tray, or loose. Processors may be sealed in packaging or exposed to free air. Under these conditions, processor landings should not be connected to any supply voltages, have any I/Os biased or receive any clocks. Upon exposure to "free air" (that is, unsealed packaging or a device removed from packaging material) the processor must be handled in accordance with moisture sensitivity labeling (MSL) as indicated on the packaging material.
TAC	Thermal Averaging Constant
TDP	Thermal Design Power
TSOD	Temperature Sensor On DIMM
UDIMM	Unbuffered Dual In-line Memory Module
Uncore	The portion of the processor comprising the shared LLC cache, CHA, IMC, PCU, Ubox, IIO and Intel® UPI modules.
Unit Interval	Signaling convention that is binary and unidirectional. In this binary signaling, one bit is sent for every edge of the forwarded clock, whether it be a rising edge or a falling edge. If a number of edges are collected at instances t_1, t_2, t_n,....,$t_k$then the UI at instance "n" is defined as: $UI_n = t_n - t_{n-1}$
Volume Management Device (VMD)	Volume Management Device (VMD) is a new technology used to improve PCIe management. VMD maps the PCIe configuration space for child devices/adapters for a particular PCIe x16 module into its own address space, controlled by a VMD driver.
V_{CCIN}	Primary voltage input to the voltage regulators integrated into the processor.
V_{SS}	Processor ground
V_{SSA}	System agent supply for Intel UPI and PCIe
V_{CCIO}	IO voltage supply input
V_{CCD}	DDR power rail
x1, x4, x8, x16	Refers to a Link or Port with one, two, four or eight Physical Lane(s)

1.4 Statement of Volatility (SOV)

Intel® Xeon® Processor Scalable Family do not retain any end-user data when powered down and/or the processor is physically removed from the socket.

§





2 Electrical Specifications

This chapter describes processor signaling, DC and DC specifications, and signal quality. References to various interfaces (memory, PCIe*, Intel® UPI, PECI, and so forth) are also described.

2.1 Integrated Voltage Regulation

The platform voltage regulator is integrated into the processor. Due to this integration, the processor has one main voltage rail (V_{CCIN}) and a voltage rail for the memory interface (V_{CCD012}, V_{CCD345} - one for each memory channel pair). The V_{CCIN} voltage rail will supply the integrated voltage regulators which in turn will regulate to the appropriate voltages for the cores, cache, and system agents. This integration allows the processor to better control on-die voltages to optimize for both performance and power savings. The processor V_{CCIN} rail will remain a VID -based voltage with a loadline similar to the core voltage rail (called V_{CC}) in previous processors. In addition to the above, the processor has voltage rails VCCIO for IO, VCCSA for the System Agent, and VCC33 for PIROM.

2.2 Processor Signaling

The Intel® Xeon® Processor Scalable Family includes 3647 lands, which utilize various signaling technologies. Signals are grouped by electrical characteristics and buffer type into various signal groups. These include DDR4 (Reference Clock, Command, Control, and Data), PCI Express*, DMI3, Intel® Ultra Path Interconnect (Intel® UPI), Platform Environmental Control Interface (PECI), System Reference Clock, SMBus, JTAG and Test Access Port (TAP), SVID Interface, Processor Asynchronous Sideband, Miscellaneous, and Power/ Other signals. See Table 2-7 for details.

Intel strongly recommends performing analog simulations of all interfaces. Please refer to Section 1.2 for signal integrity model availability.

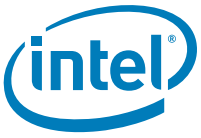
2.2.1 System Memory Interface Signal Groups

The system memory interface utilizes DDR4 technology, which consists of numerous signal groups. These include: Reference Clocks, Command Signals, Control Signals, and Data Signals. Each group consists of numerous signals, which may utilize various signaling technologies. See Table 2-7 for further details.

Throughout this chapter the system memory interface may be referred to as DDR4.

2.2.2 PCI Express* Signals

The PCI Express Signal Group consists of PCI Express* ports 1, 2, and 3, and PCI Express miscellaneous signals. See Table 2-7 for further details.



2.2.3 DMI3/ PCI Express Signals

The Direct Media Interface Gen 3(DMI3) sends and receives packets and/or commands to the PCH. The DMI3 is an extension of the standard PCI Express Specification. The DMI3/PCI Express Signals consist of DMI3 receive and transmit input/output signals and a control signal to select DMI3 or PCIe* 3.0 operation for port 0. See Table 2-7 for further details.

2.2.4 Intel® Ultra Path Interconnect (Intel® UPI)

Intel® Xeon® Processor Scalable Family two socket provides two Intel® Ultra Path Interconnect (Intel® UPI) ports for high-speed serial transfer between other processors, whereas the Intel® Xeon® Processor Scalable Family four socket and above provides three Intel® UPI links. Each port consists of two uni-directional links (for transmit and receive). A differential signaling scheme is utilized, which consists of opposite-polarity (DP, DN) signal pairs. See Table 2-7 for further details.

2.2.5 Platform Environmental Control Interface (PECI)

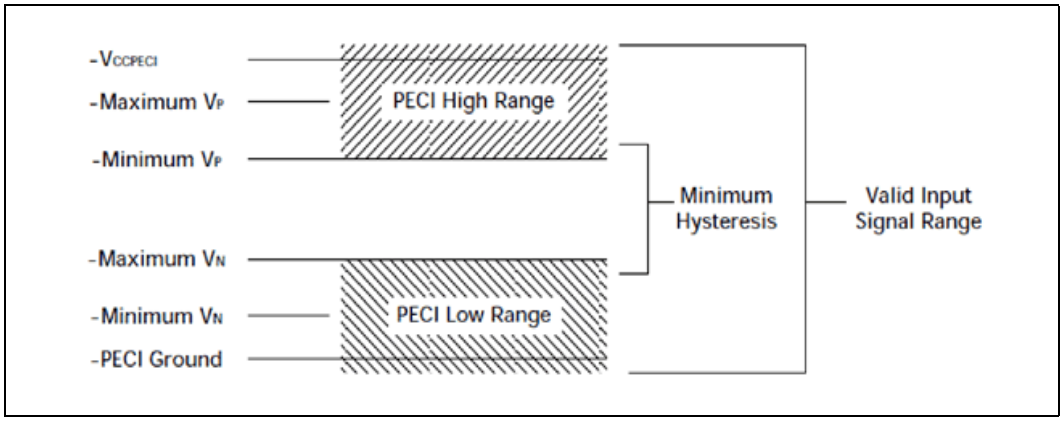
PECI is an Intel proprietary interface that provides a communication channel between Intel processors and chipset components to external system management logic and thermal monitoring devices. The processor contains a Digital Thermal Sensor (DTS) that reports a relative die temperature as an offset from Thermal Control Circuit (TCC) activation temperature. Temperature sensors located throughout the die are implemented as analog-to-digital converters calibrated at the factory. PECI provides an interface for external devices to read processor temperature, perform processor manageability functions, and manage processor interface tuning and diagnostics.

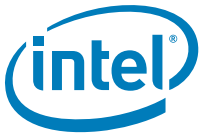
The PECI interface operates at a nominal voltage. The set of DC electrical specifications shown in Section 2.8.3.2 is used with devices normally operating from a PECI interface supply.

2.2.5.1 Input Device Hysteresis

The PECI client and host input buffers must use a Schmitt-triggered input design for improved noise immunity. Please refer to the following image and Section 2.8.3.2.

Figure 2-1. Input Device Hysteresis





2.2.6 System Reference Clocks (BCLK{0/1/2}_DP, BCLK{0/1/2}_DN)

The processor Core, processor Uncore, Intel® UPI, PCI Express* and DDR4 memory interface frequencies are generated from BCLK{0/1/2}_DP and BCLK{0/1/2}_DN signals. There is no direct link between core frequency and Intel UPI link frequency (e.g., no core frequency to Intel® UPI multiplier). The processor maximum core frequency, Intel® UPI link frequency and DDR memory frequency are set during manufacturing. It is possible to override the processor core frequency setting using software. This permits operation at lower core frequencies than the factory set maximum core frequency.

The processor core frequency is configured during reset by using values stored within the device during manufacturing. The stored value sets the lowest core multiplier at which the particular processor can operate. If higher speeds are desired, the appropriate ratio can be configured via the IA32_PERF_CTL MSR (MSR 199h); Bits [14:0]. For details of operation at core frequencies lower than the maximum rated processor speed.

Clock multiplying within the processor is provided by the internal phase locked loop (PLL), which requires a constant frequency BCLK{0/1/2}_DP, BCLK{0/1/2}_DN input, with exceptions for spread spectrum clocking. DC specifications for the BCLK{0/1/2}_DP, BCLK{0/1/2}_DN inputs are provided in Section 2.8.3.7.

These specifications must be met while also meeting the associated signal quality specifications outlined in Section 2.10.

Details regarding BCLK{0/1/2}_DP, BCLK{0/1/2}_DN driver specifications are provided in the CK420BQ Clock Synthesizer/Driver Specification.

2.2.7 JTAG and Test Access Port (TAP) Signals

Due to the voltage levels supported by other components in the JTAG and Test Access Port (TAP) logic, Intel recommends the processor be first in the TAP chain, followed by any other components within the system. Please refer to the *Intel® Xeon® Processor Scalable Family Boundary Scan Description Language (BSDL)* file more details. A translation buffer should be used to connect to the rest of the chain unless one of the other components is capable of accepting an input of the appropriate voltage. Two copies of each signal may be required with each driving a different voltage level.

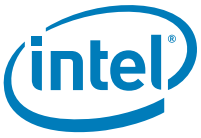
2.2.8 Processor Sideband Signals

Intel® Xeon® Processor Scalable Family includes asynchronous sideband signals that provide asynchronous input, output or I/O signals between the processor and the platform or Platform Controller Hub. Details can be found in Table 2-7.

All Processor Asynchronous Sideband input signals are required to be asserted/deasserted for a defined number of BCLKs in order for the processor to recognize the proper signal state, these are outlined in Section 2.8.3.7. Refer to Section 2.10 for applicable signal integrity specifications.

2.2.9 Power, Ground and Sense Signals

Processors also include various other signals including power/ground and sense points. Details can be found in Table 2-7.



2.2.9.1 Power and Ground Lands

All V_{CCD}, V_{CCIN}, and V_{CCSA}, and V_{CC33} lands must be connected to their respective processor power planes, while all V_{SS} lands must be connected to the system ground plane. Refer to the PDG for decoupling, voltage plane and routing guidelines for each power supply voltage.

For clean on-chip power distribution, processors include lands for all required voltage supplies. These are listed in the following table.

Table 2-1. Power and Ground Lands

Power and Ground Lands	Comments
CD_VCC_CORE,CD_VPP CD_VCC_IN, CD_VCCP,	Power supplies for Intel® Xeon® Processor Scalable Family-F SKU
V_{CCIN}	Each V_{CCIN} land must be supplied with the voltage determined by the SVID Bus signals. VR 13.0 defines the voltage level associated with each core SVID pattern.
V_{CCD012} V_{CCD345}	Each V_{CCD} land is connected to a switchable 1.20 V supply, provide power to the processor DDR4 interface. V_{CCD} is also controlled by the SVID Bus. V_{CCD} is the generic term for V_{CCD012} and V_{CCD345}..
V_{CCSA}	IO voltage supply input
V_{CC33}	Power supply for PIROM.
V_{SS}	Ground
V_{CCIO}	IO voltage supply input

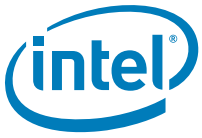
2.2.9.2 Decoupling Guidelines

Due to its large number of transistors and high internal clock speeds, the processor is capable of generating large current swings between low and full power states. This may cause voltages on power planes to sag below their minimum values if bulk decoupling is not adequate. Large electrolytic bulk capacitors (CBULK), help maintain the output voltage during current transients, for example coming out of an idle condition. Care must be taken in the baseboard design to ensure that the voltages provided to the processor remain within the specifications listed in Table 2-13. Failure to do so can result in timing violations or reduced lifetime of the processor.

2.2.9.3 Voltage Identification (VID)

The Voltage Identification (VID) specification for the V_{CCIN},VSA, CD_VCC_CORE voltage is defined by the VR13.0 PWM: Server VR Vendor PWM Enabling Specification. The reference voltage or the VID setting is set via the SVID communication bus between the processor and the voltage regulator controller chip. The VID settings are the nominal voltages to be delivered to the processor's lands. The VR 13.0 Reference Code Voltage Identification Table specifies the reference voltage level corresponding to the VID value transmitted over serial VID. The VID codes will change due to temperature and/or current load changes in order to minimize the power and to maximize the performance of the part. The specifications are set so that a voltage regulator can operate with all supported frequencies.

Individual processor VID values may be calibrated during manufacturing such that two processor units with the same core frequency may have different default VID settings.



The processor uses voltage identification signals to support automatic selection of a power supply voltage. If the processor socket is empty (SKTOCC_N high), or a "not supported" response is received from the SVID bus, then the voltage regulation circuit cannot supply the voltage that is requested, the voltage regulator must disable itself or not power on. Vout MAX register (30h) is programmed by the processor to set the maximum supported VID code and if the programmed VID code is higher than the VID supported by the VR, then VR will respond with a "not supported" acknowledgment. See the VR13.0 PWM: Server VR Vendor PWM Enabling Specification for further details.

2.2.9.4 SVID Commands

The processor provides the ability to operate while transitioning to a new VID setting and its associated processor voltage rail. This is represented by a DC shift. It should be noted that a low-to-high or high-to-low voltage state change may result in as many VID transitions as necessary to reach the target voltage. Transitions above the maximum specified VID are not supported. The processor supports the following VR commands:

- SetVID_Fast (25 mV/µs for V_{CCIN}, 10mV for VSA,V_{CCIO} and CD_VCC_CORE)
- SetVID_Slow is 1/4 of SetVID_Fast
- SetVID_Decay (downward voltage only and it's a function of the output capacitance's time constant) commands. The VR 13.0 Reference Code Voltage Identification Table includes SVID step sizes and DC shift ranges. Minimum and maximum voltages must be maintained as shown in Table 2-13. This is a CSR configuration option.

The VRM or EVRD utilized must be capable of regulating its output to the value defined by the new VID. The VR13.0 PWM: Server VR Vendor PWM Enabling Specification contains further details.

Power source characteristics must be guaranteed to be stable whenever the supply to the voltage regulator is stable.

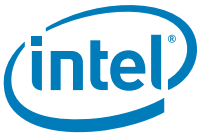
2.2.9.5 SetWP Working Point Command

The SetWP is a command that invokes a look up table for VID set points. During the initial power on phase the CPU will program the WPx registers (WP0=3Ah..WP7=41h) on a per rail address basis. When use with the AllCall address, SetWP acts as a group command that moves all voltage rails on the bus to new voltages in the look up table index. The SetWP command can also be used with an individual VR rail address and that rail moves to the voltage in the loop up table index. Each VR domain address has registers WP0-WPx (3Ah..41h) which stores the VID code for that domain's work points.

The Work Point command is encoded to support up to 8 VID targets, slew rate for the command, and alert function. The PWM should use its auto power state or auto-phase shedding functions to select appropriate # phases, CCM/DCM operation, and so forth. based on output load current after the SetWP command target has been reached.

Typical SetWP usage will be:

1. Processor writes VID codes to WP registers WP0 (3Ah) -WP4 (3Dh) in each VR domain. Normally done during SVID enumeration phase of system boot.
2. If a WP0-7 register is not programmed by the CPU, the VR stays at its present VID setting when it receives a SetWP (WPn) command.
3. Processor sends SetWP (WPn) command to one of the AllCall addresses 0Eh or 0Fh. See PWM guideline for more information on AllCall address mapping.



4. Voltage rails change VID to their corresponding VID code stored in their WPx register
5. CPU polls each VR addresses reading stutus1 to clear the alerts from the VRs
6. SVID error handling described in section 4.3.2

WP0 = State 0, programed by master

WP1 = State 1, programmed by master

WP2 = State 2, programmed by master

WP3 = State 3, programmed by master

WP4 = State 4, programmed by master

…

WP7 = State 7

2.2.9.6 SetVID Fast Command

The SetVID_Fast command contains the target VID in the payload byte. The range of voltage is defined in the VID table. The VR should ramp to the new VID setting with a fast slew rate as defined in the slew rate data register. It is minimum of 25 mV/µs for VCCIN and 10 mV/µs for other rails, depending on the amount of decoupling capacitance.

The SetVID_Fast command is preemptive. The VR interrupts its current processes and moves to the new VID. The SetVID_Fast command operates on 1 VR address at a time. This command is used in the processor for package C6 fast exit.

2.2.9.7 SetVID Slow

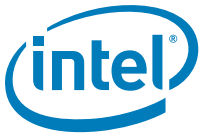
The SetVID_Slow command contains the target VID in the payload byte. The range of voltage is defined in the VID table. The VR should ramp to the new VID setting with a "slow" slew rate as defined in the slow slew rate data register. The SetVID_Slow is nominally 4x slower than the SetVID_Fast slew rate.

The SetVID_Slow command is preemptive, the VR interrupts its current processes and moves to the new VID. This is the instruction used for normal P-state voltage change. This command is used in the processor for the Intel Enhanced SpeedStep Technology transitions.

2.2.9.8 SetVID Decay

The SetVID_Decay command is the slowest of the DVID transitions. It is only used for VID down transitions. The VR does not control the slew rate, the output voltage declines with the output load current only.

The SetVID_Decay command is preemptive, the VR interrupts its current processes and moves to the new VID. This command is used in the processor for package C6 entry, allowing capacitor discharge by the leakage, thus saving energy.This command is only used in VID down direction in the processor package C6 entry.



2.2.9.9 SVID Voltage Rail Addressing

The processor addresses 4 different voltage rail control segments within VR13.0 (V_{CCIN}, V_{CCD}, V_{CCSA},V_{CCIO} and CD_VCC_CORE). The SVID data packet contains a 4-bit addressing code:

Table 2-2. SVID Address Usage Bus 1

PWM Address (HEX)	Protocol ID	Intel® Xeon® Processor Scalable Family
00	04H(10 mV VID)	V_{CCIN}
01	07H(5 mV VID)	V_{CCSA}
02	07H(5 mV VID)	V_{CCIO}
03	07H(5 mV VID)	CD_VCC_CORE
04		Reserved for optional rail
05		Reserved for optional rail

Notes:
1. Check with VR vendors for determining the physical address assignment method for their controllers.
2. VR addressing is assigned on a per voltage rail basis.
3. Dual VR controllers will have two addresses with the lowest order address, always being the higher phase count.
4. For future platform flexibility, the VR controller should include an address offset, as shown with +1 not used.

Table 2-3. SVID Address Usage Bus 2

PWM Address (HEX)	Protocol ID	Intel® Xeon® Processor Scalable Family
00	04H(10mV VID) or 07H(5mV VID)	V_{CCD012}
01		NA
02	04H(10mV VID) or 07H(5mV VID)	V_{CCD345}
03		NA

Notes:
1. Check with VR vendors for determining the physical address assignment method for their controllers.
2. VR addressing is assigned on a per voltage rail basis.
3. Dual VR controllers will have two addresses with the lowest order address, always being the higher phase count.

Table 2-4. VR13.0 Reference Code VCCIN Voltage Identification (VID) (Sheet 1 of 2)

HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN
00	0.00	20	0.81	40	1.13	60	1.45	80	1.77	A0	2.09	C0	2.41	E0	2.73
01	0.50	21	0.82	41	1.14	61	1.46	81	1.78	A1	2.10	C1	2.42	E1	2.74
02	0.51	22	0.83	42	1.15	62	1.47	82	1.79	A2	2.11	C2	2.43	E2	2.75
03	0.52	23	0.84	43	1.16	63	1.48	83	1.80	A3	2.12	C3	2.44	E3	2.76
04	0.53	24	0.85	44	1.17	64	1.49	84	1.81	A4	2.13	C4	2.45	E4	2.77
05	0.54	25	0.86	45	1.18	65	1.50	85	1.82	A5	2.14	C5	2.46	E5	2.78
06	0.55	26	0.87	46	1.19	66	1.51	86	1.83	A6	2.15	C6	2.47	E6	2.79
07	0.56	27	0.88	47	1.20	67	1.52	87	1.84	A7	2.16	C7	2.48	E7	2.80
08	0.57	28	0.89	48	1.21	68	1.53	88	1.85	A8	2.17	C8	2.49	E8	2.81
09	0.58	29	0.90	49	1.22	69	1.54	89	1.86	A9	2.18	C9	2.50	E9	2.82
0A	0.59	2A	0.91	4A	1.23	6A	1.55	8A	1.87	AA	2.19	CA	2.51	EA	2.83

Table 2-4. VR13.0 Reference Code VCCIN Voltage Identification (VID) (Sheet 2 of 2)

HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN	HEX	VCCIN
0B	0.60	2B	0.92	4B	1.24	6B	1.56	8B	1.88	AB	2.20	CB	2.52	EB	2.84
0C	0.61	2C	0.93	4C	1.25	6C	1.57	8C	1.89	AC	2.21	CC	2.53	EC	2.85
0D	0.62	2D	0.94	4D	1.26	6D	1.58	8D	1.90	AD	2.22	CD	2.54	ED	2.86
0E	0.63	2E	0.95	4E	1.27	6E	1.59	8E	1.91	AE	2.23	CE	2.55	EE	2.87
0F	0.64	2F	0.96	4F	1.28	6F	1.60	8F	1.92	AF	2.24	CF	2.56	EF	2.88
10	0.65	30	0.97	50	1.29	70	1.61	90	1.93	B0	2.25	D0	2.57	F0	2.89
11	0.66	31	0.98	51	1.30	71	1.62	91	1.94	B1	2.26	D1	2.58	F1	2.90
12	0.67	32	0.98	52	1.31	72	1.63	92	1.95	B2	2.27	D2	2.59	F2	2.91
13	0.68	33	1.00	53	1.32	73	1.64	93	1.96	B3	2.28	D3	2.60	F3	2.92
14	0.69	34	1.01	54	1.33	74	1.65	94	1.97	B4	2.29	D4	2.61	F4	2.93
15	0.70	35	1.02	55	1.34	75	1.66	95	1.98	B5	2.30	D5	2.62	F5	2.94
16	0.71	36	1.03	56	1.35	76	1.67	96	1.99	B6	2.31	D6	2.63	F6	2.95
17	0.72	37	1.04	57	1.36	77	1.68	97	2.00	B7	2.32	D7	2.64	F7	2.96
18	0.73	38	1.05	58	1.37	78	1.69	98	2.01	B8	2.33	D8	2.65	F8	2.97
19	0.74	39	1.06	59	1.38	79	1.70	99	2.02	B9	2.34	D9	2.66	F9	2.98
1A	0.75	3A	1.07	5A	1.39	7A	1.71	9A	2.03	BA	2.35	DA	2.67	FA	2.99
1B	0.76	3B	1.08	5B	1.40	7B	1.72	9B	2.04	BB	2.36	DB	2.68	FB	3.00
1C	0.77	3C	1.09	5C	1.41	7C	1.73	9C	2.05	BC	2.37	DC	2.69	FC	3.01
1D	0.78	3D	1.10	5D	1.42	7D	1.74	9D	2.06	BD	2.38	DD	2.70	FD	3.02
1E	0.79	3E	1.11	5E	1.43	7E	1.75	9E	2.07	BE	2.39	DE	2.71	FE	3.03
1F	0.80	3F	1.12	5F	1.44	7F	1.76	9F	2.08	BF	2.40	DF	2.72	FF	3.04

Notes:
1. 00h = Off State
2. VID Range HEX 65-97 are used by the Intel® Xeon® processor E5-1600 and E5-2600 v5 product families
3. VCCD can use Protocol ID of 10 mV or 5 mV,.
4. VCCD can use VID Table 2-4 or VID Table 2-5.

Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 1 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
0 0	0	NA	0	NA	All
0 1	0.25	±8 mV	0.5	±10 mV	All
0 2	0.255	±8 mV	0.51	±10 mV	All
0 3	0.26	±8 mV	0.52	±10 mV	All
0 4	0.265	±8 mV	0.53	±10 mV	All
0 5	0.27	±8 mV	0.54	±10 mV	All
0 6	0.275	±8 mV	0.55	±10 mV	All
0 7	0.28	±8 mV	0.56	±10 mV	All
0 8	0.285	±8 mV	0.57	±10 mV	All
0 9	0.29	±8 mV	0.58	±10 mV	All
0 A	0.295	±8 mV	0.59	±10 mV	All
0 B	0.3	±8 mV	0.6	±10 mV	All
0 C	0.305	±8 mV	0.61	±10 mV	All

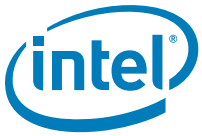


Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 2 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
0 D	0.31	±8 mV	0.62	±10 mV	All
0 E	0.315	±8 mV	0.63	±10 mV	All
0 F	0.32	±8 mV	0.64	±10 mV	All
1 0	0.325	±8 mV	0.65	±10 mV	All
1 1	0.33	±8 mV	0.66	±10 mV	All
1 2	0.335	±8 mV	0.67	±10 mV	All
1 3	0.34	±8 mV	0.68	±10 mV	All
1 4	0.345	±8 mV	0.69	±10 mV	All
1 5	0.35	±8 mV	0.7	±10 mV	All
1 6	0.355	±8 mV	0.71	±10 mV	All
1 7	0.36	±8 mV	0.72	±10 mV	All
1 8	0.365	±8 mV	0.73	±10 mV	All
1 9	0.37	±8 mV	0.74	±10 mV	All
1 A	0.375	±8 mV	0.75	±10 mV	All
1 B	0.38	±8 mV	0.76	±10 mV	All
1 C	0.385	±8 mV	0.77	±10 mV	All
1 D	0.39	±8 mV	0.78	±10 mV	All
1 E	0.395	±8 mV	0.79	±10 mV	All
1 F	0.4	±8 mV	0.8	±10 mV	All
2 0	0.405	±8 mV	0.81	±10 mV	All
2 1	0.41	±8 mV	0.82	±10 mV	All
2 2	0.415	±8 mV	0.83	±10 mV	All
2 3	0.42	±8 mV	0.84	±10 mV	All
2 4	0.425	±8 mV	0.85	±10 mV	All
2 5	0.43	±8 mV	0.86	±10 mV	All
2 6	0.435	±8 mV	0.87	±10 mV	All
2 7	0.44	±8 mV	0.88	±10 mV	All
2 8	0.445	±8 mV	0.89	±10 mV	All
2 9	0.45	±8 mV	0.9	±10 mV	All
2 A	0.455	±8 mV	0.91	±10 mV	All
2 B	0.46	±8 mV	0.92	±10 mV	All
2 C	0.465	±8 mV	0.93	±10 mV	All
2 D	0.47	±8 mV	0.94	±10 mV	All
2 E	0.475	±8 mV	0.95	±10 mV	All
2 F	0.48	±8 mV	0.96	±10 mV	All
3 0	0.485	±8 mV	0.97	±10 mV	All
3 1	0.49	±8 mV	0.98	±10 mV	All
3 2	0.495	±8 mV	0.99	±10 mV	All

Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 3 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
3 3	0.5	±8 mV	1	±8 mV	All
3 4	0.505	±8 mV	1.01	±8 mV	All
3 5	0.51	±8 mV	1.02	±8 mV	All
3 6	0.515	±8 mV	1.03	±8 mV	All
3 7	0.52	±8 mV	1.04	±8 mV	All
3 8	0.525	±8 mV	1.05	±8 mV	All
3 9	0.53	±8 mV	1.06	±8 mV	All
3 A	0.535	±8 mV	1.07	±8 mV	All
3 B	0.54	±8 mV	1.08	±8 mV	All
3 C	0.545	±8 mV	1.09	±8 mV	All
3 D	0.55	±8 mV	1.1	±8 mV	All
3 E	0.555	±8 mV	1.11	±8 mV	All
3 F	0.56	±8 mV	1.12	±8 mV	All
4 0	0.565	±8 mV	1.13	±8 mV	All
4 1	0.57	±8 mV	1.14	±8 mV	All
4 2	0.575	±8 mV	1.15	±8 mV	All
4 3	0.58	±8 mV	1.16	±8 mV	All
4 4	0.585	±8 mV	1.17	±8 mV	All
4 5	0.59	±8 mV	1.18	±8 mV	All
4 6	0.595	±8 mV	1.19	±8 mV	All
4 7	0.6	±8 mV	1.2	±8 mV	All
4 8	0.605	±8 mV	1.21	±8 mV	All
4 9	0.61	±8 mV	1.22	±8 mV	All
4 A	0.615	±8 mV	1.23	±8 mV	All
4 B	0.62	±8 mV	1.24	±8 mV	All
4 C	0.625	±8 mV	1.25	±8 mV	All
4 D	0.63	±8 mV	1.26	±8 mV	All
4 E	0.635	±8 mV	1.27	±8 mV	All
4 F	0.64	±8 mV	1.28	±8 mV	All
5 0	0.645	±8 mV	1.29	±8 mV	All
5 1	0.65	±8 mV	1.3	±8 mV	All
5 2	0.655	±8 mV	1.31	±8 mV	All
5 3	0.66	±8 mV	1.32	±8 mV	All
5 4	0.665	±8 mV	1.33	±8 mV	All
5 5	0.67	±8 mV	1.34	±8 mV	All
5 6	0.675	±8 mV	1.35	±8 mV	All

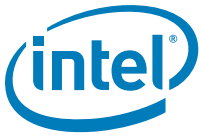


Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 4 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
5 7	0.68	±8 mV	1.36	±8 mV	All
5 8	0.685	±8 mV	1.37	±8 mV	All
5 9	0.69	±8 mV	1.38	±8 mV	All
5 A	0.695	±8 mV	1.39	±8 mV	All
5 B	0.7	±8 mV	1.4	±8 mV	All
5 C	0.705	±8 mV	1.41	±8 mV	All
5 D	0.71	±8 mV	1.42	±8 mV	All
5 E	0.715	±8 mV	1.43	±8 mV	All
5 F	0.72	±8 mV	1.44	±8 mV	All
6 0	0.725	±8 mV	1.45	±8 mV	All
6 1	0.73	±8 mV	1.46	±8 mV	All
6 2	0.735	±8 mV	1.47	±8 mV	All
6 3	0.74	±8 mV	1.48	±8 mV	All
6 4	0.745	±8 mV	1.49	±8 mV	All
6 5	0.75	±8 mV	1.5	±0.5% of VID	All
6 6	0.755	±8 mV	1.51	±0.5% of VID	All
6 7	0.76	±8 mV	1.52	±0.5% of VID	All
6 8	0.765	±8 mV	1.53	±0.5% of VID	All
6 9	0.77	±8 mV	1.54	±0.5% of VID	All
6 A	0.775	±8 mV	1.55	±0.5% of VID	All
6 B	0.78	±8 mV	1.56	±0.5% of VID	All
6 C	0.785	±8 mV	1.57	±0.5% of VID	All
6 D	0.79	±8 mV	1.58	±0.5% of VID	All
6 E	0.795	±8 mV	1.59	±0.5% of VID	All
6 F	0.8	±5 mV	1.6	±0.5% of VID	All
7 0	0.805	±5 mV	1.61	±0.5% of VID	All
7 1	0.81	±5 mV	1.62	±0.5% of VID	All
7 2	0.815	±5 mV	1.63	±0.5% of VID	All
7 3	0.82	±5 mV	1.64	±0.5% of VID	All
7 4	0.825	±5 mV	1.65	±0.5% of VID	All
7 5	0.83	±5 mV	1.66	±0.5% of VID	All
7 6	0.835	±5 mV	1.67	±0.5% of VID	All
7 7	0.84	±5 mV	1.68	±0.5% of VID	All
7 8	0.845	±5 mV	1.69	±0.5% of VID	All
7 9	0.85	±5 mV	1.7	±0.5% of VID	All
7 A	0.855	±5 mV	1.71	±0.5% of VID	All

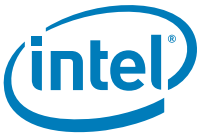


Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 5 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
7 B	0.86	±5 mV	1.72	±0.5% of VID	All
7 C	0.865	±5 mV	1.73	±0.5% of VID	All
7 D	0.87	±5 mV	1.74	±0.5% of VID	All
7 E	0.875	±5 mV	1.75	±0.5% of VID	All
7 F	0.88	±5 mV	1.76	±0.5% of VID	All
8 0	0.885	±5 mV	1.77	±0.5% of VID	All
8 1	0.89	±5 mV	1.78	±0.5% of VID	All
8 2	0.895	±5 mV	1.79	±0.5% of VID	All
8 3	0.9	±5 mV	1.8	±0.5% of VID	All
8 4	0.905	±5 mV	1.81	±0.5% of VID	All
8 5	0.91	±5 mV	1.82	±0.5% of VID	All
8 6	0.915	±5 mV	1.83	±0.5% of VID	All
8 7	0.92	±5 mV	1.84	±0.5% of VID	All
8 8	0.925	±5 mV	1.85	±0.5% of VID	All
8 9	0.93	±5 mV	1.86	±0.5% of VID	All
8 A	0.935	±5 mV	1.87	±0.5% of VID	All
8 B	0.94	±5 mV	1.88	±0.5% of VID	All
8 C	0.945	±5 mV	1.89	±0.5% of VID	All
8 D	0.95	±5 mV	1.9	±0.5% of VID	All
8 E	0.955	±5 mV	1.91	±0.5% of VID	All
8 F	0.96	±5 mV	1.92	±0.5% of VID	All
9 0	0.965	±5 mV	1.93	±0.5% of VID	All
9 1	0.97	±5 mV	1.94	±0.5% of VID	All
9 2	0.975	±5 mV	1.95	±0.5% of VID	All
9 3	0.98	±5 mV	1.96	±0.5% of VID	All
9 4	0.985	±5 mV	1.97	±0.5% of VID	All
9 5	0.99	±5 mV	1.98	±0.5% of VID	All
9 6	0.995	±5 mV	1.99	±0.5% of VID	All
9 7	1	±0.5% of VID	2	±0.5% of VID	All
9 8	1.005	±0.5% of VID	2.01	±0.5% of VID	Optional
9 9	1.01	±0.5% of VID	2.02	±0.5% of VID	Optional
9 A	1.015	±0.5% of VID	2.03	±0.5% of VID	Optional
9 B	1.02	±0.5% of VID	2.04	±0.5% of VID	Optional
9 C	1.025	±0.5% of VID	2.05	±0.5% of VID	Optional
9 D	1.03	±0.5% of VID	2.06	±0.5% of VID	Optional
9 E	1.035	±0.5% of VID	2.07	±0.5% of VID	Optional

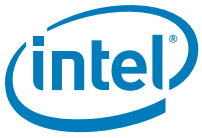


Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 6 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
9 F	1.04	±0.5% of VID	2.08	±0.5% of VID	Optional
A 0	1.045	±0.5% of VID	2.09	±0.5% of VID	Optional
A 1	1.05	±0.5% of VID	2.1	±0.5% of VID	Optional
A 2	1.055	±0.5% of VID	2.11	±0.5% of VID	Optional
A 3	1.06	±0.5% of VID	2.12	±0.5% of VID	Optional
A 4	1.065	±0.5% of VID	2.13	±0.5% of VID	Optional
A 5	1.07	±0.5% of VID	2.14	±0.5% of VID	Optional
A 6	1.075	±0.5% of VID	2.15	±0.5% of VID	Optional
A 7	1.08	±0.5% of VID	2.16	±0.5% of VID	Optional
A 8	1.085	±0.5% of VID	2.17	±0.5% of VID	Optional
A 9	1.09	±0.5% of VID	2.18	±0.5% of VID	Optional
A A	1.095	±0.5% of VID	2.19	±0.5% of VID	Optional
A B	1.1	±0.5% of VID	2.2	±0.5% of VID	Optional
A C	1.105	±0.5% of VID	2.21	±0.5% of VID	Optional
A D	1.11	±0.5% of VID	2.22	±0.5% of VID	Optional
A E	1.115	±0.5% of VID	2.23	±0.5% of VID	Optional
A F	1.12	±0.5% of VID	2.24	±0.5% of VID	Optional
B 0	1.125	±0.5% of VID	2.25	±0.5% of VID	Optional
B 1	1.13	±0.5% of VID	2.26	±0.5% of VID	Optional
B 2	1.135	±0.5% of VID	2.27	±0.5% of VID	Optional
B 3	1.14	±0.5% of VID	2.28	±0.5% of VID	Optional
B 4	1.145	±0.5% of VID	2.29	±0.5% of VID	Optional
B 5	1.15	±0.5% of VID	2.3	±0.5% of VID	>2.3 not required in any segment
B 6	1.155	±0.5% of VID	2.31	±0.5% of VID	>2.3 not required in any segment
B 7	1.16	±0.5% of VID	2.32	±0.5% of VID	>2.3 not required in any segment
B 8	1.165	±0.5% of VID	2.33	±0.5% of VID	>2.3 not required in any segment
B 9	1.17	±0.5% of VID	2.34	±0.5% of VID	>2.3 not required in any segment
B A	1.175	±0.5% of VID	2.35	±0.5% of VID	>2.3 not required in any segment
B B	1.18	±0.5% of VID	2.36	±0.5% of VID	>2.3 not required in any segment
B C	1.185	±0.5% of VID	2.37	±0.5% of VID	>2.3 not required in any segment
B D	1.19	±0.5% of VID	2.38	±0.5% of VID	>2.3 not required in any segment
B E	1.195	±0.5% of VID	2.39	±0.5% of VID	>2.3 not required in any segment
B F	1.2	±0.5% of VID	2.4	±0.5% of VID	>2.3 not required in any segment
C 0	1.205	±0.5% of VID	2.41	±0.5% of VID	>2.3 not required in any segment
C 1	1.21	±0.5% of VID	2.42	±0.5% of VID	>2.3 not required in any segment
C 2	1.215	±0.5% of VID	2.43	±0.5% of VID	>2.3 not required in any segment

Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 7 of 8)

HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
C 3	1.22	±0.5% of VID	2.44	±0.5% of VID	>2.3 not required in any segment
C 4	1.225	±0.5% of VID	2.45	±0.5% of VID	>2.3 not required in any segment
C 5	1.23	±0.5% of VID	2.46	±0.5% of VID	>2.3 not required in any segment
C 6	1.235	±0.5% of VID	2.47	±0.5% of VID	>2.3 not required in any segment
C 7	1.24	±0.5% of VID	2.48	±0.5% of VID	>2.3 not required in any segment
C 8	1.245	±0.5% of VID	2.49	±0.5% of VID	>2.3 not required in any segment
C 9	1.25	±0.5% of VID	2.5	±0.5% of VID	>2.3 not required in any segment
C A	1.255	±0.5% of VID	2.51	±0.5% of VID	>2.3 not required in any segment
C B	1.26	±0.5% of VID	2.52	±0.5% of VID	>2.3 not required in any segment
C C	1.265	±0.5% of VID	2.53	±0.5% of VID	>2.3 not required in any segment
C D	1.27	±0.5% of VID	2.54	±0.5% of VID	>2.3 not required in any segment
C E	1.275	±0.5% of VID	2.55	±0.5% of VID	>2.3 not required in any segment
C F	1.28	±0.5% of VID	2.56	±0.5% of VID	>2.3 not required in any segment
D 0	1.285	±0.5% of VID	2.57	±0.5% of VID	>2.3 not required in any segment
D 1	1.29	±0.5% of VID	2.58	±0.5% of VID	>2.3 not required in any segment
D 2	1.295	±0.5% of VID	2.59	±0.5% of VID	>2.3 not required in any segment
D 3	1.3	±0.5% of VID	2.6	±0.5% of VID	>2.3 not required in any segment
D 4	1.305	±0.5% of VID	2.61	±0.5% of VID	>2.3 not required in any segment
D 5	1.31	±0.5% of VID	2.62	±0.5% of VID	>2.3 not required in any segment
D 6	1.315	±0.5% of VID	2.63	±0.5% of VID	>2.3 not required in any segment
D 7	1.32	±0.5% of VID	2.64	±0.5% of VID	>2.3 not required in any segment
D 8	1.325	±0.5% of VID	2.65	±0.5% of VID	>2.3 not required in any segment
D 9	1.33	±0.5% of VID	2.66	±0.5% of VID	>2.3 not required in any segment
D A	1.335	±0.5% of VID	2.67	±0.5% of VID	>2.3 not required in any segment
D B	1.34	±0.5% of VID	2.68	±0.5% of VID	>2.3 not required in any segment
D C	1.345	±0.5% of VID	2.69	±0.5% of VID	>2.3 not required in any segment
D D	1.35	±0.5% of VID	2.7	±0.5% of VID	>2.3 not required in any segment
D E	1.355	±0.5% of VID	2.71	±0.5% of VID	>2.3 not required in any segment
D F	1.36	±0.5% of VID	2.72	±0.5% of VID	>2.3 not required in any segment
E 0	1.365	±0.5% of VID	2.73	±0.5% of VID	>2.3 not required in any segment
E 1	1.37	±0.5% of VID	2.74	±0.5% of VID	>2.3 not required in any segment
E 2	1.375	±0.5% of VID	2.75	±0.5% of VID	>2.3 not required in any segment
E 3	1.38	±0.5% of VID	2.76	±0.5% of VID	>2.3 not required in any segment
E 4	1.385	±0.5% of VID	2.77	±0.5% of VID	>2.3 not required in any segment
E 5	1.39	±0.5% of VID	2.78	±0.5% of VID	>2.3 not required in any segment
E 6	1.395	±0.5% of VID	2.79	±0.5% of VID	>2.3 not required in any segment

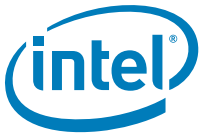


Table 2-5. VSA, VCCIO, CD_VCC_CORE or VCCD VID Table (Sheet 8 of 8)

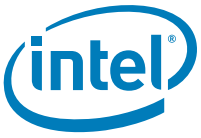
HEX	5 mV step mode voltage	5 mV step recommended accuracy	10 mV step mode voltage	10 mV step mode recommended accuracy	10 mV mode market segment
E 7	1.4	±0.5% of VID	2.8	±0.5% of VID	>2.3 not required in any segment
E 8	1.405	±0.5% of VID	2.81	±0.5% of VID	>2.3 not required in any segment
E 9	1.41	±0.5% of VID	2.82	±0.5% of VID	>2.3 not required in any segment
E A	1.415	±0.5% of VID	2.83	±0.5% of VID	>2.3 not required in any segment
E B	1.42	±0.5% of VID	2.84	±0.5% of VID	>2.3 not required in any segment
E C	1.425	±0.5% of VID	2.85	±0.5% of VID	>2.3 not required in any segment
E D	1.43	±0.5% of VID	2.86	±0.5% of VID	>2.3 not required in any segment
E E	1.435	±0.5% of VID	2.87	±0.5% of VID	>2.3 not required in any segment
E F	1.44	±0.5% of VID	2.88	±0.5% of VID	>2.3 not required in any segment
F 0	1.445	±0.5% of VID	2.89	±0.5% of VID	>2.3 not required in any segment
F 1	1.45	±0.5% of VID	2.9	±0.5% of VID	>2.3 not required in any segment
F 2	1.455	±0.5% of VID	2.91	±0.5% of VID	>2.3 not required in any segment
F 3	1.46	±0.5% of VID	2.92	±0.5% of VID	>2.3 not required in any segment
F 4	1.465	±0.5% of VID	2.93	±0.5% of VID	>2.3 not required in any segment
F 5	1.47	±0.5% of VID	2.94	±0.5% of VID	>2.3 not required in any segment
F 6	1.475	±0.5% of VID	2.95	±0.5% of VID	>2.3 not required in any segment
F 7	1.48	±0.5% of VID	2.96	±0.5% of VID	>2.3 not required in any segment
F 8	1.485	±0.5% of VID	2.97	±0.5% of VID	>2.3 not required in any segment
F 9	1.49	±0.5% of VID	2.98	±0.5% of VID	>2.3 not required in any segment
F A	1.495	±0.5% of VID	2.99	±0.5% of VID	>2.3 not required in any segment
F B	1.5	±0.5% of VID	3	±0.5% of VID	>2.3 not required in any segment
F C	1.505	±0.5% of VID	3.01	±0.5% of VID	>2.3 not required in any segment
F D	1.51	±0.5% of VID	3.02	±0.5% of VID	>2.3 not required in any segment
F E	1.515	±0.5% of VID	3.03	±0.5% of VID	>2.3 not required in any segment
F F	1.52	±0.5% of VID	3.04	±0.5% of VID	>2.3 not required in any segment

Note:
1. DAC accuracy is a recommendation only. Total tolerance band must be met, that is, DAC set point + current sense AVP droop accuracy. VCCD may use 5 mV or 10 mV VID tables, this is set by selecting the protocol ID bit in the PWM controller, which is read by BIOS at boot.
2. VCCD can use VID Table 2-4 or VID Table 2-5.

2.2.10 Reserved or Unused Signals

All Reserved (RSVD) signals must not be connected. Connection of these signals to V_{CCIN}, V_{CCD}, V_{SS}, or to any other signal (including each other) can result in component malfunction or incompatibility with future processors.

For reliable operation, always connect unused inputs or bi-directional signals to an appropriate signal level. Unused active high inputs should be connected through a resistor to ground (V_{SS}). Unused outputs maybe left unconnected; however, this may interfere with some Test Access Port (TAP) functions, complicate debug probing, and



prevent boundary scan testing. A resistor must be used when tying bi-directional signals to power or ground. When tying any signal to power or ground, a resistor will also allow for system testability. Resistor values should be within ± 20% of the impedance of the baseboard trace, unless otherwise noted in the appropriate platform design guidelines.

2.3 Signal Group Summary

Signals are grouped by buffer type and similar characteristics as listed in the following table. The buffer type indicates which signaling technology and specifications apply to the signals.

Table 2-6. Signal Description Buffer Types

Signal	Description
Analog	Analog reference or output. May be used as a threshold voltage or for buffer compensation
Asynchronous	Signal has no timing relationship with any system reference clock.
CMOS	CMOS Output buffers: 1.05 V tolerant / CMOS Input buffers
DDR4	CMOS Output buffers 1.2 V tolerant
DMI3	Direct Media Interface Gen 3 signals. These signals are compatible with PCI Express* 3.0 Signaling Environment AC Specifications.
Intel® UPI	Current-mode 9.6 GT/s or 10.4 GT/s. Nominal voltage is 1.0 V.
Open Drain	Open Drain buffers: 1.05 V tolerant
PCI Express*	PCI Express interface signals. These signals are compatible with PCI Express 3.0 Signaling Environment AC Specifications and are AC coupled. The buffers are not 3.3–V tolerant. Refer to the PCIe specification.
Reference	Voltage reference signal.
SSTL	Source Series Terminated Logic (JEDEC SSTL_15)

Note: Qualifier for a buffer type.

Table 2-7. Signal Groups (Sheet 1 of 4)

Differential/ Single Ended	Buffer Type	Signal
DDR4 Reference Clocks		
Differential	SSTL Output	DDR{0/1/2/3/4/5}_CLK_D[N/P] [3:0]
DDR4 Command Signals		
Single-ended	SSTL Output	DDR{0/1/2/3/4/5}_ACT_N DDR{0/1/2/3/4/5}_BA[1:0] DDR{0/1/2/3/4/5}_BG[1:0] DDR{0/1/2/3/4/5}_MA[17:0] DDR{0/1/2/3/4/5}_PAR
DDR4 Control Signals		
Single-ended	SSTL Output	DDR{0/1/2/3/4/5}_CS_N[7:0] DDR{0/1/2/3/4/5}_CID[2] DDR{0/1/2/3/4/5}_ODT[3:0] DDR{0/1/2/3/4/5}_CKE[3:0]
DDR4 Data Signals		
Differential	SSTL Input/Output	DDR{0/1/2/3/4/5}_DQS_D[N/P] [17:0]

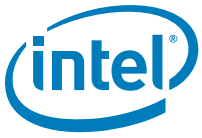


Table 2-7. Signal Groups (Sheet 2 of 4)

Differential/ Single Ended	Buffer Type	Signal
Single-ended	SSTL Input/Output	DDR{0/1/2/3/4/5}_DQ[63:0] DDR{0/1/2/3/4/5}_ECC[7:0]
DDR4 Miscellaneous Signals		
Single-ended	SSTL Input	DDR{0/1/2/3/4/5}_ALERT_N
	CMOS Input ***Note:*** Input voltage from platform cannot exceed 1.2 V max. Refer to PDG for implementation details.	DDR{012,345}_DRAM_PWR_OK
	CMOS 1.2 V Output	DDR{012,345}_RESET_N
	Open Drain Output / CMOS Input	DDR[012,345]_SPDSCL DDR[012,345]_SPDSDA
	DC Output	DDR{5:0}_CAVREF
	DDR Compensation resistance control	DDR{012,345}_RCOMP[2:0]
PCI Express* Port 1, 2, & 3 Signals		
Differential	PCI Express* Input	PE{3:1}_RX_DN/DP[15:0]
Differential	PCI Express* Output	PE{3:1}_TX_DN/DP[15:0]
PCI Express* Miscellaneous Signals		
Single-ended	Open Drain Output	PE_HP_SCL
	Open Drain Output /CMOS	PE_HP_SDA
DMI3/ PCI Express* Signals		
Differential	DMI3 Input	DMI3_RX_D[N/P][3:0]
	DMI3 Output	DMI3_TX_D[N/P][3:0]
Single-ended	DMI Miscellaneous	DMIMODE_OVERRIDE
Intel® UPI Signals		
Differential	Intel® UPI Input Output	UPI{2:1}_RX/TX_DN/DP[19:0]
Single-ended	Intel® UPI Miscellaneous	UPI{01,2}_RBIAS
Single-ended	Intel® UPI Power	UPI{01,2}_VCCQ
Platform Environmental Control Interface (PECI)		
Single-ended	PECI Input/Output	PECI
System Reference Clock (BCLK{0/1/2})		
Differential	CMOS 1.05 V Input	BCLK{0/1/2}_D[N/P]

Table 2-7. Signal Groups (Sheet 3 of 4)

Differential/ Single Ended	Buffer Type	Signal
JTAG & TAP Signals		
Single ended	CMOS Input	TCK,TDI,TMS,TRST_N,PREQ_N
	Open Drain Output /CMOS	BPM_N[7:0]
	Open Drain Output	TDO, PRDY_N
Serial VID Interface (SVID) Signals		
Single ended	CMOS Input	SVIDALERT_N[1:0]
	Open Drain Output / CMOS	SVIDDATA [1:0]
	Open Drain Output	SVIDCLK [1:0]
Processor Asynchronous Sideband Signals		
Single ended	CMOS Input	BIST_ENABLE, BMCINIT, DEBUG_EN_N
		FRMAGENT, PWRGOOD, PMSYNC RESET_N, SAFE_MODE_BOOT, SOCKET_ID[1:0], TXT_AGENT TXT_PLTEN
	CMOS Output	FIVR_FAULT
	Open Drain Output / CMOS Input	CATERR_N, MEM_HOT_C01_N, MEM_HOT_C23_N, MSMI_N, PM_FAST_WAKE_N, PROCHOT_N
	Open Drain Output	ERROR_N[2:0], THERMTRIP_N
Miscellaneous Signals		
	CMOS Input	EAR_N,LEGACY_SKT,NMI,PMSYNCPMSYNC_CLK,PROCDIS_N, PWR_DEBUG_N,SOCKET_ID2
	Open Drain Output / CMOS Input	TSC_SYNC
	Not connected to Silicon	SKTOCC_N,PKGID[2:0], PROC_ID[1:0]
Intel Omni-Path Host Fabric Interface (Intel® OP HFI) Signals		
	Open Drain Output / CMOS 2.5 Input	CD_HFI[1:0]_I2CCLK, CD_HFI[1:0]_I2CDAT
	CMOS 2.5V Input	CD_HFI[1:0]_INT_N, CD_HFI[1:0]_MODPRST_N
	CMOS 1.8V Input	CD_TCLK, CD_TDI, CD_TMS, CD_TRST_N
	Open Drain Output	CD_HFI[1:0]_RESET_N, CD_HFI[1:0]_LED_N
	CMOS 1.8V Output	CD_TDO
	CMOS Input	CD_HFI_REFCLK_DN/DP
		CD_POR_N
		MCP01_RBIAS

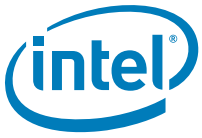


Table 2-7. Signal Groups (Sheet 4 of 4)

Differential/ Single Ended	Buffer Type	Signal
Power/ Other Signals		
	Power / Ground	V_{CCIN}, V_{CCD_012}, V_{CCD_345}, V_{CCIO}, V_{CC33}, V_{CC33}, V_{SS}
	Sense Points	VCCIN_SENSE, VCCIO_SENSE, VCCSA_SENSE, VSS_VCCIN_SENSE, VSS_VCCIO_SENSE, VSS_VCCSA_SENSE, VCCIN_PMAX, VSENSEPMAX

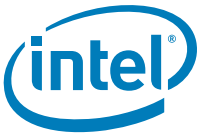
Notes:
1. Refer to "Signal Descriptions" for signal description details.
2. DDR{0/1/2/3/4/5} refers to DDR4 Channel 0, DDR4 Channel 1, DDR4 Channel 2, DDR4 Channel 3, DDR4 Channel 4 and DDR4 Channel 5.

Table 2-8. Signals with On-Die Weak PU/ PD

Signal Name	Pull Up/ Pull Down	Rail	Value	Units
BIST_ENABLE	Pull Up	V_{CCIO}	3K-8K	ohm
BMCINIT	Pull Down	VSS	3K-8K	ohm
DEBUG_EN_N	Pull Up	V_{CCIO}	3K-8K	ohm
DMIMODE_OVERRIDE	Pull Up	V_{CCIO}	3K-8K	ohm
EAR_N	Pull Up	V_{CCIO}	3K-8K	ohm
FRMAGENT	Pull Down	VSS	3K-8K	ohm
LEGACY_SKT	Pull Down	VSS	3K-8K	ohm
MSMI_N	Pull Up	V_{CCIO}	3K-8K	ohm
NMI	Pull Down	VSS	3K-8K	ohm
PM_FAST_WAKE_N	Pull Up	V_{CCIO}	3K-8K	ohm
PROCDIS_N	Pull Up	V_{CCIO}	3K-8K	ohm
SAFE_MODE_BOOT	Pull Down	VSS	3K-8K	ohm
SOCKET_ID[2:0]	Pull Down	VSS	3K-8K	ohm
TCK	Pull Down	VSS	3K-8K	ohm
TDI	Pull Up	V_{CCIO}	3K-8K	ohm
TMS	Pull Up	V_{CCIO}	3K-8K	ohm
TRST_N	Pull Up	V_{CCIO}	3K-8K	ohm
TXT_AGENT	Pull Down	VSS	3K-8K	ohm
TXT_PLTEN	Pull Up	V_{CCIO}	3K-8K	ohm

2.4 Fault Resilient Booting (FRB)

FRB is a RASM (Reliability, Availability, Serviceability, and Manageability) feature and this section describes the processor implementation.



The processor supports both socket and core level Fault Resilient Booting (FRB), which provides the ability to boot the system as long as there is one processor functional in the system. One limitation to socket level FRB is that the system cannot boot if the legacy socket that connects to an active PCH becomes unavailable since this is the path to the system BIOS. See the table below for a list of output tri-state FRB signals.

Socket level FRB will tri-state processor outputs via the PROCDIS_N signal. Assertion of the PROCDIS_N signal through RESET_N de-assertion will tri-state processor outputs. Note, that individual core disabling is also supported for those cases where disabling the entire package is not desired.

The processor extends the FRB capability to the core granularity by maintaining a register in the Uncore so that BIOS or another entity can disable one or more specific processor cores.

Table 2-9. Fault Resilient Booting (Output Tri-State) Signals

Output Tri-State Signal Groups	Tri-State Signals
Intel® UPI	KTI{2:1}TX_DN/DP[19:0]
PCI Express*	PE_TX_DN[15:0] PE_TX_DP[15:0] PE_HP_SCL PE_HP_SDA
DDR4	Control, Address and DQ, DDR4 RESET_N asserted
DMI3	DMI_TX_DN[3:0] DMI_TX_DP[3:0]
SMBus (SPD)	DDR[012,345]_SPDSCL DDR[012,345]_SPDSDA
Processor Sideband	CATERR_N, ERROR_N[2:0], BPM_N[7:0], THERMTRIP_N, PROCHOT_N, PECI, PM_FAST_WAKE_N, MSMI_N, TSC_SYNC, FIVR_FAULT
SVID	SVIDCLK, SVIDDATA

2.4.1 Power-On Configuration (POC) Options

Several configuration options can be configured by hardware. The processor samples its hardware configuration at reset, on the active-to-inactive transition of RESET_N, or upon assertion of PWRGOOD (inactive-to-active transition). For specifics on these options, please see the following table.

The sampled information configures the processor for subsequent operation. These configuration options cannot be changed except by another reset transition of the latching signal (RESET_N or PWRGOOD).

Table 2-10. Power-On Configuration Option Lands (Sheet 1 of 2)

Configuration Option	Land Name	Notes
Output tri state	PROCDIS_N	1
Execute BIST (Built-In Self Test)	BIST_ENABLE	2
Enable Service Processor Boot Mode	BMCINIT	3
Power-up Sequence Halt	EAR_N	3
Enable Intel® Trusted Execution Technology (Intel® TXT) Platform	TXT_PLTEN	3
Enable Bootable Firmware Agent	FRMAGENT	3
Enable Intel Trusted Execution Technology (Intel TXT) Agent	TXT_AGENT	3

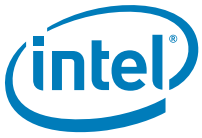


Table 2-10. Power-On Configuration Option Lands (Sheet 2 of 2)

Configuration Option	Land Name	Notes
Enable Safe Mode Boot	SAFE_MODE_BOOT	3
Configure Socket ID	SOCKET_ID[1:0]	3
Enable legacy socket boot	LEGACY_SKT	3

Notes:
1. Output tri-state option enables Fault Resilient Booting (FRB), for FRB details see the Fault Resilient Booting (FRB) Section. The signal used to latch PROCDIS_N for enabling FRB mode is RESET_N.
2. BIST_ENABLE is sampled at RESET_N de-assertion
3. This signal is sampled after PWRGOOD assertion.

2.5 Mixing Processors

Intel supports and validates two and four processor configurations only where all processors operate with the same Intel® UPI frequency, core frequency, power segment, and have the same internal cache sizes. Mixing components operating at different internal clock frequencies is not supported and will not be validated by Intel. Combining processors from different power segments is also not supported.

Note: All processors within a system must run at a common maximum non-Turbo ratio. The system BIOS may be required to program the FLEX_RATIO register if mixed frequency processors are populated.

Not all operating systems can support dual processors with mixed frequencies. Mixing processors of different steppings but the same model (as per CPUID instruction) is supported, provided there is no more than one stepping delta between the processors, for example, S and S+1.

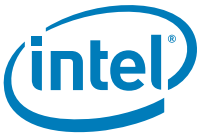
S and S+1 is defined as mixing of two CPU steppings in the same platform where one CPU is S (stepping) = CPUID.(EAX=01h):EAX[3:0], and the other is S+1 = CPUID.(EAX=01h):EAX[3:0]+1. The stepping ID is found in EAX[3:0] after executing the CPUID instruction with Function 01h. Details regarding the CPUID instruction are provided in the *Intel® 64 and IA-32 Architectures Software Developer's Manuals, Volume 2A: Instruction Set Reference, A-M*.

2.6 Flexible Motherboard Guidelines (FMB)

The Flexible Motherboard (FMB) guidelines are estimates of the maximum values the processor will have over certain time periods. The values are only estimates and actual specifications for future processors may differ. Processors may or may not have specifications equal to the FMB value in the foreseeable future. System designers should meet the FMB values to ensure their systems will be compatible with future processors.

2.7 Absolute Maximum and Minimum Ratings

The table below specifies absolute maximum and minimum ratings. At conditions outside functional operation condition limits, but within absolute maximum and minimum ratings, neither functionality nor long-term reliability can be expected. If a device is returned to conditions within functional operation limits after having been subjected to conditions outside these limits, but within the absolute maximum



and minimum ratings, the device may be functional, but with its lifetime degraded depending on exposure to conditions exceeding the functional operation condition limits.

Although the processor contains protective circuitry to resist damage from Electro-Static Discharge (ESD), precautions should always be taken to avoid high static voltages or electric fields.

Table 2-11. Processor Absolute Minimum and Maximum Ratings

Symbol	Parameter	Min	Max	Unit
V_{CCIN}	Processor input voltage with respect to Vss	-0.3	2.15	V
V_{CCD}	Processor IO supply voltage for DDR4 (standard voltage) with respect to V_{SS}	-0.3	1.50	V
V_{CCIO}	IO voltage supply input with respect to V_{SS}	-0.3	1.45	V
V_{CCSA}	IO voltage supply input with respect to V_{SS}	-0.3	1.45	V

Notes:
1. For functional operation, all processor electrical, signal quality, mechanical, and thermal specifications must be satisfied.
2. Overshoot and undershoot voltage guidelines for input, output, and I/O signals are outlined in Section 2.10.5, "Overshoot/Undershoot Tolerance". Excessive Overshoot or undershoot on any signal will likely result in permanent damage to the processor.

2.7.1 Storage Conditions Specifications

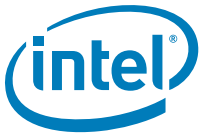
Environmental storage condition limits define the temperature and relative humidity limits to which the device is exposed to while being stored in a Moisture Barrier Bag. The specified storage conditions are for component level prior to board attach (see notes in the following table for post board attach limits).

The table below specifies absolute maximum and minimum storage temperature limits which represent the maximum or minimum device condition beyond which damage, latent or otherwise, may occur. The table also specifies sustained storage temperature, relative humidity, and time-duration limits. These limits specify the maximum or minimum device storage conditions for a sustained period of time. At conditions outside sustained limits, but within absolute maximum and minimum ratings, quality and reliability may be affected.

Table 2-12. Storage Condition Ratings

Symbol	Parameter	Min	Max	Unit
$T_{absolute\ storage}$	The minimum/maximum device storage temperature beyond which damage (latent or otherwise) may occur when subjected to for any length of time.	-25	125	°C
$T_{sustained\ storage}$	The minimum/maximum device storage temperature for a sustained period of time.	-5	40	°C
$T_{short\ term\ storage}$	The ambient storage temperature (in shipping media) for a short period of time.	-20	85	°C
$RH_{sustained\ storage}$	The maximum device storage relative humidity for a sustained period of time.Unopened bag, includes 6 months storage time by customer.	60% @ 24		°C
$Time_{short\ term\ storage}$	A short period of time (in shipping media).	0	72	hours

Notes:



1. Storage conditions are applicable to storage environments only. In this scenario, the processor must not receive a clock, and no lands can be connected to a voltage bias. Storage within these limits will not affect the long-term reliability of the device. For functional operation, please refer to the processor case temperature specifications.
2. These ratings apply to the Intel component and do not include the tray or packaging.
3. Failure to adhere to this specification can affect the long-term reliability of the processor.
4. Non-operating storage limits post board attach: Storage condition limits for the component once attached to the application board are not specified. Intel does not conduct component level certification assessments post board attach given the multitude of attach methods, socket types and board types used by customers. Provided as general guidance only, Intel board products are specified and certified to meet the following temperature and humidity limits (Non-Operating Temperature Limit: -40C to 70C & Humidity: 50% to 90%, non condensing with a maximum wet bulb of 28°C).
5. Device storage temperature qualification methods follow JEDEC High and Low Temperature Storage Life Standards: *JESD22-A119* (low temperature) and *JESD22-A103* (high temperature).

2.8 DC Specifications

DC specifications are defined at the processor pads, unless otherwise noted. DC specifications are only valid while meeting specifications for case temperature (TCASE specified in the *Intel® Xeon® Processor Scalable Family Thermal/Mechanical Specification and Design Guide (TMSDG)*), clock frequency, and input voltages. Care should be taken to read all notes associated with each specification.

2.8.1 Voltage and Current Specifications

Table 2-13. Voltage Specification

Symbols	Parameter	Voltage Plane	Min	Nom	Max	Unit	Notes[1]
V_{CCIN}	Input to Integrated Voltage Regulator (Launch - FMB)	V_{CCIN}	= VID - RII*Iout-0.022V	= VID - RII*Iout	= VID - RII*Iout+0.022V	V	2, 3, 4, 5, 8, 12
V_{CCIN} VID Range		V_{CCIN}	1.60	1.80	1.83	V	2, 3, 4, 5, 8, 12
V_{VID_STEP} (V_{CCIN})	VID step size during a transition	V_{CCIN}		10.0		mV	6
V_{VID_STEP} (V_{CCD})	VID step size during a transition		5		10	mV	
V_{CCD} (V_{CCD_012}, V_{CCD_345})	I/O Voltage for DDR4 (Standard Voltage)	V_{CCD}	1.17	1.2	1.26	V	7, 9, 10, 11
V_{ccSA}	Power supply for Intel® UPI and IIO	VccSA	VID - 0.111	VID	VID + 0.100	V	
V_{CCSA} VID Range			0.5	0.85	1.1	V	
V_{CCIO}	IO voltage supply input		0.937	1.00	1.057	V	
V_{CC33}	Power supply for PIROM		3.14	3.3	3.47	V	
CD_VCC_CORE			0.814	0.9	0.974	V	

Notes:
1. Unless otherwise noted, all specifications in this table apply to all processors. These specifications are based on pre-silicon characterization and will be updated as further data becomes available.
2. These voltages are targets only. A variable voltage source should exist on systems in the event that a different voltage is required.
3. The VCCIN voltage specification requirements are measured across the remote sense pin pairs (VCCIN_SENSE and VSS_VCCIN_SENSE) on the processor package. Voltage measurement should be taken with a DC to 100 MHz bandwidth oscilloscope limit (or DC to 20 MHz for older model oscilloscopes), using a 1.5 pF maximum probe capacitance, and 1 Mohm minimum impedance. The maximum length of the ground wire on the probe should be less than 5 mm to ensure external noise from the system is not coupled in the scope probe.
4. Refer to VCCIN Static and Transient Tolerance Intel® Xeon® Processor Scalable Family and corresponding Figure 2-3, "VCCIN Static and Transient Tolerance Load Lines 1.0 mOHM" on page 40. The processor should not be subjected to any static VCCIN level that exceeds the VCCIN_MAX associated with any particular current. Failure to adhere to this specification can shorten processor lifetime.
5. Minimum VCCIN and maximum ICCIN are specified at the maximum processor case temperature (TCASE) shown in the Intel® Xeon® Processor Scalable Familyr Thermal/Mechanical Specification and Design Guide (TMSDG). ICCIN_MAX is specified at the relative VCC_MAX point on the VCCIN load line. The processor is capable of drawing ICCIN_MAX for up to 2 ms.
6. This specification represents the VCCIN reduction or VCCIN increase due to each VID transition. For Voltage Identification (VID) see Table 2-4, "VR13.0 Reference Code VCCIN Voltage Identification (VID)".
7. Baseboard bandwidth is limited to 20 MHz.
8. FMB is the flexible motherboard guidelines. See Section 2.4, "Fault Resilient Booting (FRB)" for details.
9. DC + AC + Ripple = Tolerance
10. VCCD tolerance at processor pins. Required in order to meet ±5% tolerance at processor die.
11. The VCCD012, VCCD345 voltage specification requirements are measured across vias on the platform. Choose VCCD012 or VCCD345 vias close to the socket and measure with a DC to 100 MHz bandwidth oscilloscope limit (or DC to 20 MHz for older model oscilloscopes), using 1.5 pF maximum probe capacitance, and 1M ohm minimum impedance. The maximum length of the ground wire on the probe should be less than 5 mm to ensure external noise from the system is not coupled in the scope probe.
12. VCCIN has a Vboot setting of 1.7 V and is not included in the PWRGOOD indication. Refer to the VR13.0 PWM - Server VR Vendor PWM Enabling Specification.

Table 2-14. Current (ICCIN_MAX and ICCIN_TDC) Specification (Sheet 1 of 2)

TDP (W)	205	200	165	150	145	140	135	130	125	120	115	105	85	70
Segment	Single Die Package													
VCCIN ICCMAX (A)	228	228	228	205	205	190	190	177	160	160	154	132	102	85
VCCSA ICCMAX (A)	16	16	16	16	16	16	16	16	16	16	16	16	16	16
VCCIO ICCMAX (A)	21	21	21	21	21	21	21	21	21	21	21	21	21	21
VCCD ICCMAX (A)	8	8	8	8	8	8	8	8	8	8	8	8	8	8
VCC33 ICCMAX(A)	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075
VCCIN TDC (A)	112	112	89	80	77	73	70	68	65	62	54	54	42	33
VCCSA TDC (A)	15	15	15	15	15	15	15	15	15	15	15	15	15	15
VCCIO TDC (A)	14	14	14	14	14	14	14	14	14	14	14	14	14	14
VCCD TDC (A)	6	6	6	6	6	6	6	6	6	6	6	6	6	6
VCC33 TDC (A)	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075	.075
Pmax Package (W)	413	413	363	319	319	297	297	286	264	264	253	231	187	154
TDP (W)	165	160	145	135	120	105	85							
Segment	Fabric													
VCCIN ICCMAX (A)	228	221	205	190	160	132	102							
VCCSA ICCMAX (A)	16	16	16	16	16	16	16							
VCCIO ICCMAX (A)	21	21	21	21	21	21	21							
VCCD ICCMAX (A)	8	8	8	8	8	8	8							
VCC33 ICCMAX(A)	.075	.075	.075	.075	.075	.075	.075							
VCCIN TDC (A)	89	86	77	70	62	54	42							
VCCSA TDC (A)	15	15	15	15	15	15	15							

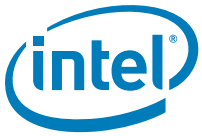


Table 2-14. Current (ICCIN_MAX and ICCIN_TDC) Specification (Sheet 2 of 2)

VCCIO TDC (A)	14	14	14	14	14	14	14						
VCCD TDC (A)	6	6	6	6	6	6	6						
VCC33 TDC (A)	.075	.075	.075	.075	.075	.075	.075						
Pmax Package (W)	363	352	319	297	264	231	187						
CD_VCC_CORE ICCMAX (A)			10										
CD_VCCIN ICCMAX (A)			.01										
CD_VCCP ICCMAX (A)			.015										
CD_VPP ICCMAX (A)			7										
CD_VCC_CORE TDC (A)			9										
CD_VCCIN TDC (A)			.01										
CD_VCCP TDC (A)			.01										
CD_VPP TDC (A)			6										

Notes:
1. Unless otherwise noted, all specifications in this table apply to all processors. These specifications are based on pre-silicon characterization and will be updated as further data becomes available.
2. FMB is the flexible motherboard guidelines. See Flexible Motherboard Guidelines (FMB) on page 31 for further details.
3. I_{CCIN_TDC} (Thermal Design Current) is the sustained (DC equivalent) current that the processor is capable of drawing indefinitely and should be used for the voltage regulator thermal assessment. The voltage regulator is responsible for monitoring its temperature and asserting the necessary signal to inform the processor of a thermal excursion. Please refer to the VR13.0 PWM Server VR Vendor PWM Enabling Specification for further details.
4. Minimum V_{CCIN} and maximum I_{CCIN} are specified at the maximum processor case temperature (TCASE) shown in the VR13.0 PWM Server VR Vendor PWM Enabling Specification for further details. ICCIN_MAX is specified at the relative VCCIN_MAX point on the VCCIN load line. The processor is capable of drawing ICCIN_MAX for up to 2ms.
5. Values on this table correspond to SKT-P.

Table 2-15. V_{CCIN} Static and Transient Tolerance for 0.9LL (Sheet 1 of 2)

I_{CCIN} (A)	V_{CCIN_Max} (V)	V_{CCIN_Nom} (V)	V_{CCIN_Min} (V)	Notes
0	VID +0.022	VID -0.000	VID -0.022	
10	VID +0.013	VID -0.009	VID -0.031	
20	VID +0.004	VID -0.018	VID -0.040	
30	VID -0.005	VID -0.027	VID -0.049	
40	VID -0.014	VID -0.036	VID -0.058	
50	VID -0.023	VID -0.045	VID -0.067	
60	VID -0.032	VID -0.054	VID -0.076	
70	VID -0.041	VID -0.063	VID -0.085	
80	VID -0.050	VID -0.072	VID -0.094	
90	VID -0.059	VID -0.081	VID -0.103	
100	VID -0.068	VID -0.090	VID -0.112	
110	VID -0.077	VID -0.099	VID -0.121	
120	VID -0.086	VID -0.108	VID -0.130	
130	VID -0.095	VID -0.117	VID -0.139	
140	VID -0.104	VID -0.126	VID -0.148	
150	VID -0.113	VID -0.135	VID -0.157	
160	VID -0.122	VID -0.144	VID -0.166	
170	VID -0.131	VID -0.153	VID -0.175	

Table 2-15. V_{CCIN} Static and Transient Tolerance for 0.9LL (Sheet 2 of 2)

I_{CCIN} (A)	V_{CCIN_Max} (V)	V_{CCIN_Nom} (V)	V_{CCIN_Min} (V)	Notes
180	VID -0.140	VID -0.162	VID -0.184	
190	VID -0.149	VID -0.171	VID -0.193	
200	VID -0.158	VID -0.180	VID -0.202	
210	VID -0.167	VID -0.189	VID -0.211	
220	VID -0.176	VID -0.198	VID -0.220	
230	VID -0.185	VID -0.207	VID -0.229	

Notes:
1. The V_{CCIN_MIN} and V_{CCIN_MAX} loadlines represent static and transient limits. Please see for Section 2.8.2.1, "VCCIN Overshoot Specifications."
2. This table is intended to aid in reading discrete points on graph in Figure 2-2, "VCCIN Static and Transient Tolerance Load Lines 0.9 mOHM" on page 39.
3. The loadlines specify voltage limits at the die measured at the V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. Refer to the VR13.0 PWM Server VR Vendor PWM Enabling Specification for loadline guidelines and VR implementation details.

Table 2-16. V_{CCIN} Static and Transient Tolerance for 1.0LL (Sheet 1 of 2)

I_{CCIN} (A)	V_{CCIN_Max} (V)	V_{CCIN_Nom} (V)	V_{CCIN_Min} (V)	Notes
0	VID +0.022	VID -0.000	VID -0.022	
10	VID +0.012	VID -0.010	VID -0.032	
20	VID +0.002	VID -0.020	VID -0.042	
30	VID -0.008	VID -0.030	VID -0.052	
40	VID -0.018	VID -0.040	VID -0.062	
50	VID -0.028	VID -0.050	VID -0.072	
60	VID -0.038	VID -0.060	VID -0.082	
70	VID -0.048	VID -0.070	VID -0.092	
80	VID -0.058	VID -0.080	VID -0.102	
90	VID -0.068	VID -0.090	VID -0.112	
100	VID -0.078	VID -0.100	VID -0.122	
110	VID -0.088	VID -0.110	VID -0.132	
120	VID -0.098	VID -0.120	VID -0.142	
130	VID -0.108	VID -0.130	VID -0.152	
140	VID -0.118	VID -0.140	VID -0.162	
150	VID -0.128	VID -0.150	VID -0.172	
160	VID -0.138	VID -0.160	VID -0.182	
170	VID -0.148	VID -0.170	VID -0.192	
180	VID -0.158	VID -0.180	VID -0.202	
190	VID -0.168	VID -0.190	VID -0.212	
200	VID -0.178	VID -0.200	VID -0.222	

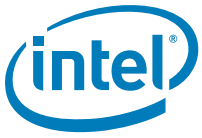


Table 2-16. V_{CCIN} Static and Transient Tolerance for 1.0LL (Sheet 2 of 2)

I_{CCIN} (A)	V_{CCIN_Max} (V)	V_{CCIN_Nom} (V)	V_{CCIN_Min} (V)	Notes
210	VID -0.188	VID -0.210	VID -0.232	
220	VID -0.198	VID -0.220	VID -0.242	
230	VID - 0.208	VID - 0.230	VID - 0.252	

Notes:
1. The V_{CCIN_MIN} and V_{CCIN_MAX} loadlines represent static and transient limits. Please see Section 2.8.2.1, "VCCIN Overshoot Specifications."
2. This table is intended to aid in reading discrete points on graph in Figure 2-3, "VCCIN Static and Transient Tolerance Load Lines 1.0 mOHM" on page 40.
3. The loadlines specify voltage limits at the die measured at the V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. Voltage regulation feedback for voltage regulator circuits must also be taken from processor V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. Refer to the VR13.0 PWM Server VR Vendor PWM Enabling Specification for loadline guidelines and VR implementation details.
4. The Adaptive Loadline Positioning slope is 1.00 m? (mohm) with ±22mV TOB (Tolerance of Band).

Figure 2-2. VCCIN Static and Transient Tolerance Load Lines 0.9 mOHM

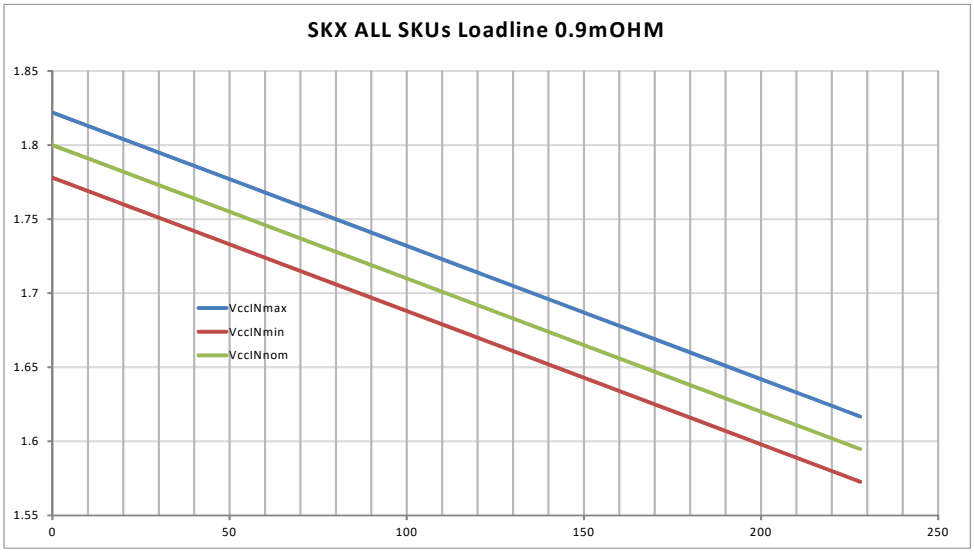
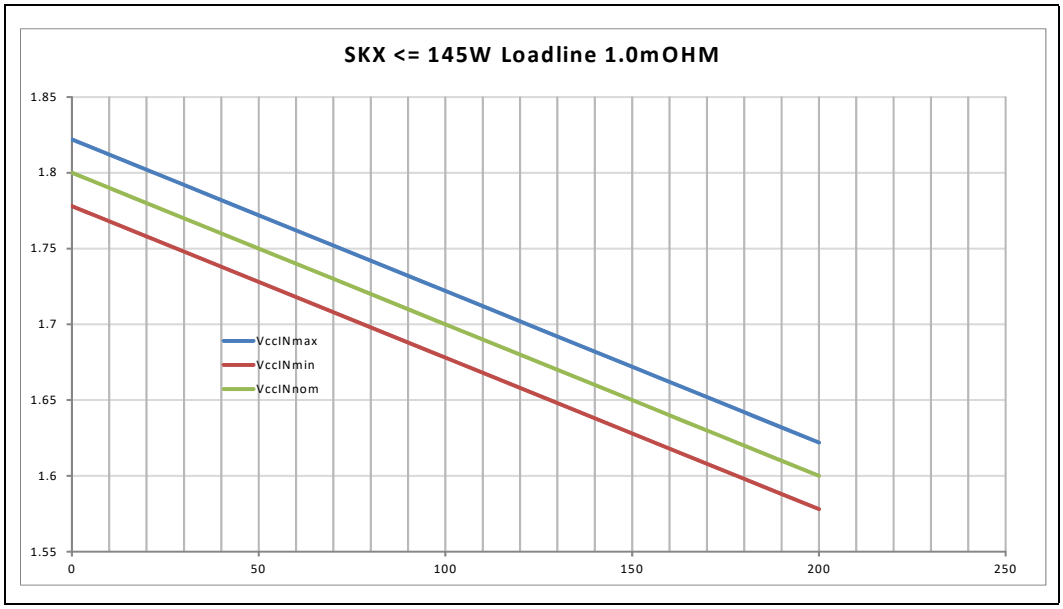


Figure 2-3. VCCIN Static and Transient Tolerance Load Lines 1.0 mOHM



2.8.2 Die Voltage Validation

Overshoot events at the processor must meet the specifications in Table 2-17, "VCCIN Overshoot Specifications" when measured across the V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. Overshoot events that are < 10 ns in duration may be ignored. These measurements of processor die level overshoot should be taken with a 100 MHz bandwidth limited oscilloscope.

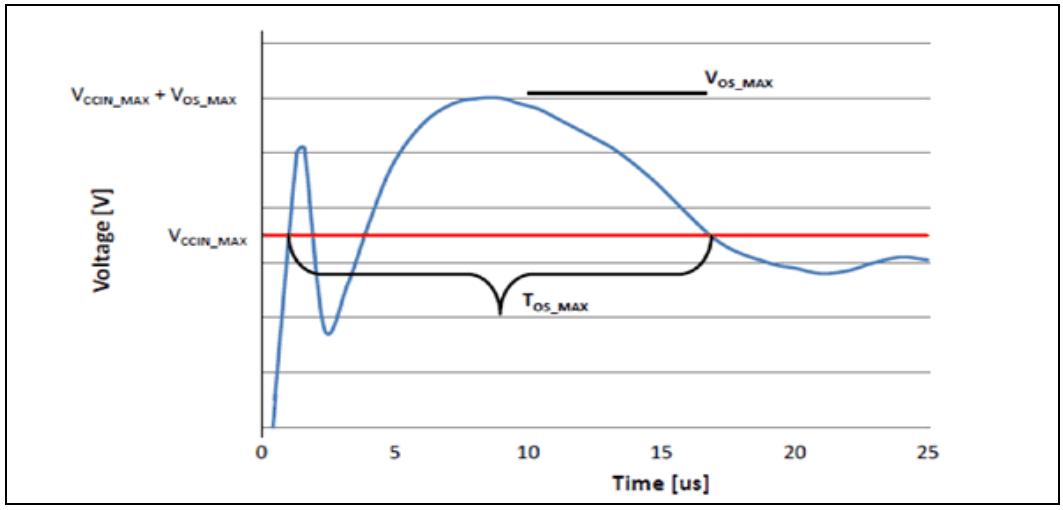
2.8.2.1 V_{CCIN} Overshoot Specifications

The processor can tolerate short transient overshoot events where V_{CCIN} exceeds the VID voltage when transitioning from a high-to-low current load condition. This overshoot cannot exceed VID + V_{OS_MAX} (V_{OS_MAX} is the maximum allowable overshoot above VID). These specifications apply to the processor die voltage as measured across the V_{CCIN_SENSE} and $V_{SS\_VCCIN\_SENSE}$ lands. The processor can tolerate overshoot to phase added bumps as well.

Table 2-17. V_{CCIN} Overshoot Specifications

Symbol	Parameter	Min	Max	Units	Figure	Notes
V_{OS_MAX}	Magnitude of V_{CCIN} overshoot above VID		92 from VID, 70 from VccMAX	mV	Figure 2-4	
T_{OS_MAX}	Time duration of V_{CCIN} overshoot above V_{CCIN_Max} value at the new lighter load		25	µs	Figure 2-4	

Figure 2-4. VCCIN Overshoot Example Waveform



Notes:
1. VOS_MAX is the measured overshoot voltage above VCCIN_MAX.
2. TOS_MAX is the measured time duration above VCCIN_MAX.
3. VCCIN_MAX = VID + TOB

2.8.3 Signal DC Specifications

For additional specifications, refer to Section 1.2, "Related Publications."

2.8.3.1 DDR4 Signal DC Specifications

For the next table please use Signal Group Table 2-7, "Signal Groups" to identify which signals belong to each group.

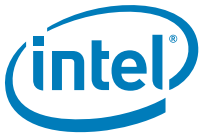
Symbol	Parameter	Min	Nom	Max	Units	Notes[1]
I_{IL}	Input Leakage Current	-1.4		+1.4	mA	9
Data Signals						
R_{ON}	DDR4 Data Buffer On Resistance	25.5	30	34.5	ohm	6
Data ODT	On-Die Termination for Data Signals	42.5	50	57.5	ohm	8
Reference Clock and Command Signals						
V_{OL}	Output Low Voltage		$(V_{CCD} / 2)* (R_{ON} /(R_{ON} +R_{VTT\_TERM}))$		V	2, 7
V_{OH}	Output High Voltage		$V_{CCD} - ((V_{CCD} / 2)* (R_{ON} /(R_{ON} +R_{VTT\_TERM})))$		V	2, 5, 7
Data Signals						
V_{OL}	Output Low Voltage		$Vol=(Ron / (Ron + R_{VDD\_TERM})) *V_{CCD}$			10
V_{OH}	Output High Voltage		V_{CCD}			
Reference Clock Signal						

Symbol	Parameter	Min	Nom	Max	Units	Notes[1]
R_{ON}	DDR4 Clock Buffer On Resistance	25.5	30	34.5	ohm	6
Command Signals						
R_{ON}	DDR4 Command Buffer On Resistance	15.3	18	20.7	ohm	6,11
R_{ON}	DDR4 Reset Buffer On Resistance	76.5	90	103.5	ohm	6
$V_{OL\_CMOS1.2V}$	Output Low Voltage, Signals DDR_RESET_C{01/23}_N			$0.2*V_{CCD}$	V	1, 2
$V_{OH\_CMOS1.2V}$	Output High Voltage, Signals DDR_RESET_C{01/23}_N	$0.9*V_{CCD}$			V	1, 2
Control Signals						
R_{ON}	DDR4 Control Buffer On Resistance	25.5	30	34.5	ohm	6
DDR4 Miscellaneous Signals						
DRAM_PWR_OK_C{01/23}						
V_{IL}	Input Low Voltage		0.3*VCCD		mV	2, 3
V_{IH}	Input High Voltage		0.7*VCCD		mV	2, 4, 5
ALERT_N						
V_{IL}	Input Low Voltage	Vref-90		Vref - 70	mV	3
V_{IH}	Input High Voltage	Vref+70		Vref+90	mV	4
ODT	On Die Termination	36	45	54	ohms	

Notes:
1. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
2. The voltage rail V_{CCD} which will be set to 1.2 V nominal depending on the voltage of all DIMMs connected to the processor.
3. V_{IL} is the maximum voltage level at a receiving agent that will be interpreted as a logical low value.
4. V_{IH} is the minimum voltage level at a receiving agent that will be interpreted as a logical high value.
5. V_{IH} and V_{OH} may experience excursions above V_{CCD}. However, input signal drivers must comply with the signal quality specifications. Refer to Section 2.10.
6. This is the pull down driver resistance. Refer to processor signal integrity models for I/V characteristics. Reset drive does not have a termination.
7. R_{VTT_TERM} is the termination on the DIMM and not controlled by the processor. Please refer to the applicable DIMM datasheet.
8. The minimum and maximum values for these signals are programmable by BIOS to one of the pairs.
9. Input leakage current is specified for all DDR4 signals.
10. Vol = Ron * [VCCD/(Ron + Rtt_Eff)], where Rtt_Eff is the effective pull-up resistance of all DIMMs in the system, including ODTs and series resistors on the DIMMs.
11. This Ron value is only for UDIMM, otherwise the Ron Value is 30 ohm.

2.8.3.2 PECI DC Specifications

Symbol	Definition and Conditions	Min	Max	Units	Figure	Notes[1]
V_{In}	Input Voltage Range	-0.15	$0.15 + V_{CCIO}$	V		1
$V_{Hysteresis}$	Hysteresis	$0.1*V_{CCIO}$		V		
V_N	Negative-edge threshold voltage	$0.275*V_{CCIO}$	$0.500*V_{CCIO}$	V	Figure 2-1	2
V_P	Positive-edge threshold voltage	$0.550*V_{CCIO}$	$0.725*V_{CCIO}$	V	Figure 2-1	2
I_{Source}	Pullup Resistance (V_{OH} = $0.75*V_{CCIO}$)	-6.00		mA		
I_{Leak+}	High impedance state leakage to V_{CCIO} (V_{leak} = V_{OL})	±50	±200	µA		3, 4



Symbol	Definition and Conditions	Min	Max	Units	Figure	Notes[1]
R_{ON}	High impedance leakage to GND (V_{leak} = V_{OH})	41	11	ohm		
C_{Bus}	Bus capacitance per node		10	pF		5
V_{Noise}	Signal noise immunity above 300 MHz	0.100*V_{CCIO}		V_{p-p}		
	Output Edge Rate (50 ohm to V_{SS}, between V_{IL} and V_{IH})	5	15	V/ns		

Notes:
1. The input voltage range specifies an overshoot/undershoot that applies only to the PECI data signal and not to the V_{TT} reference itself.
2. It is expected that the PECI driver will take into account, the variance in the receiver input thresholds and consequently, be able to drive its output within safe limits (-0.150 V to 0.275*V_{CCIO} for the low level and 0.725*V_{CCIO} to V_{CCIO}+0.150 V for the high level).
3. V_{CCIO} nominal levels will vary between processor families. All PECI devices will operate at the V_{CCIO} level determined by the processor installed in the system.
4. The leakage specification applies to powered devices on the PECI bus.
5. Excessive capacitive loading on the PECI line may slow down the signal rise/fall times and consequently limit the maximum bit rate at which the interface can operate.

2.8.3.3 System Reference Clock (BCLK{0/1/2}) DC Specifications

Symbol	Parameter	Signal	Min	Max	Unit	Figure	Notes[1]
$V_{BCLK\_diff\_ih}$	Differential Input High Voltage	Differential	0.150	N/A	V	Figure 2-5	9
$V_{BCLK\_diff\_il}$	Differential Input Low Voltage	Differential		-0.150	V	Figure 2-5	9
V_{cross} (abs)	Absolute Crossing Point	Single Ended	0.250	0.550	V	Figure 2-6 and Figure 2-7	2, 4, 7, 9
V_{cross} (rel)	Relative Crossing Point	Single Ended	0.250 + 0.5*(VH avg - 0.700)	0.550 + 0.5*(VH avg - 0.700)	V	Figure 2-6	3, 4, 5, 9
V_{cross}	Range of Crossing Points	Single Ended	N/A	0.140	V	Figure 2-8	6, 9
V_{TH}	Threshold Voltage	Single Ended	Vcross - 0.1	Vcross + 0.1	V		9
I_{IL}	Input Leakage	N/A		1.50	mA		8, 9
C_{pad}	Pad Capacitance	N/A	1.90	1.72	pF		9

Notes:
1. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
2. Crossing Voltage is defined as the instantaneous voltage value when the rising edge of BCLK{0/1}_DN is equal to the falling edge of BCLK{0/1}_DP.
3. V_{Havg} is the statistical average of the VH measured by the oscilloscope.
4. The crossing point must meet the absolute and relative crossing point specifications simultaneously.
5. V_{Havg} can be measured directly using "Vtop" on Agilent* and "High" on Tektronix oscilloscopes.
6. V_{CROSS} is defined as the total variation of all crossing voltages as defined in Note 3.
7. The rising edge of BCLK{0/1}_DN is equal to the falling edge of BCLK{0/1}_DP.
8. For Vin between 0 and Vih.
9. Specifications can be validated at the pin.

Figure 2-5. BCLK{0/1/2} Differential Clock Measurement Point for Ringback

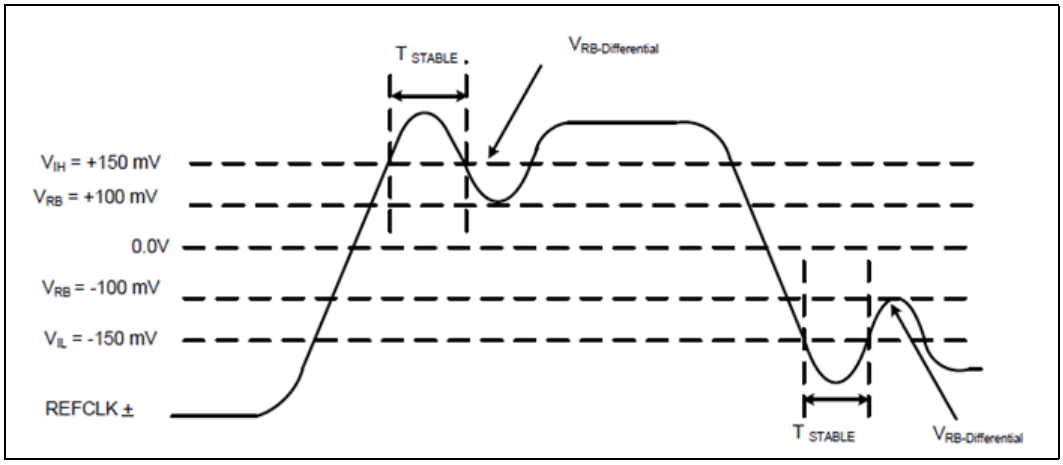


Figure 2-6. BCLK{0/1/2} Differential Clock Crosspoint Specification

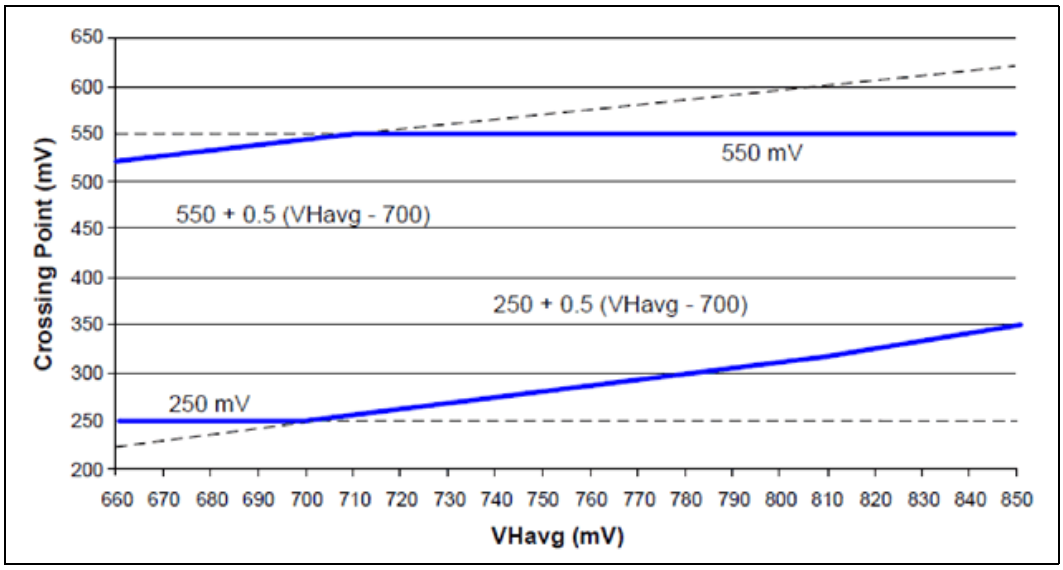


Figure 2-7. BCLK{0/1/2} Single Ended Clock Measurement Points for Absolute Cross Point and Swing

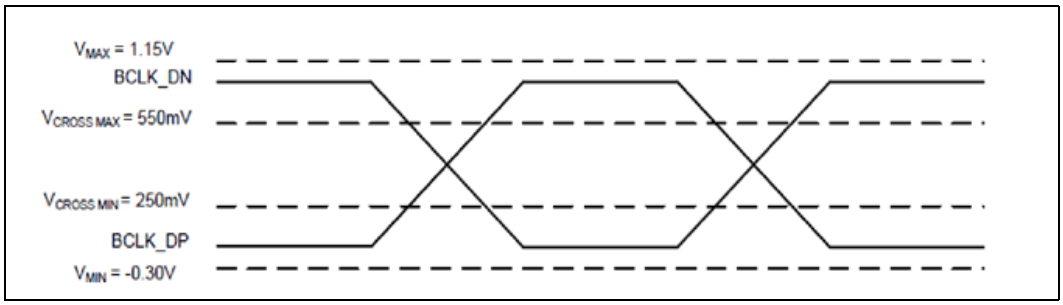
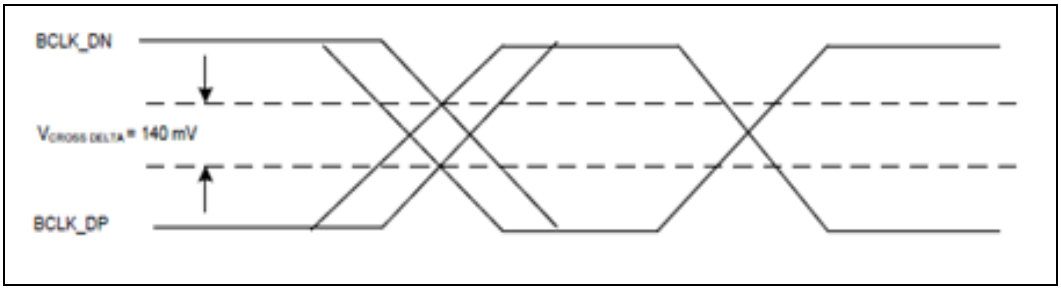


Figure 2-8. BCLK{0/1/2} Single Ended Clock Measure Points for Delta Cross Point



2.8.3.4 SMBus DC Specifications

Symbol	Parameter	Min	Max	Units	Notes
V_{IL}	Input Low Voltage		0.3*V_{CCIO}	V	
V_{IH}	Input High Voltage	0.7*V_{CCIO}		V	
$V_{Hysteresis}$	Hysteresis	0.1*V_{CCIO}		V	
V_{OL}	Output Low Voltage		0.2*V_{CCIO}	V	1
R_{ON}	Buffer On Resistance	14	4	ohm	
I_L	Leakage Current Signals	±50	±200	µA	
	Output Edge Rate (50 ohm to V_{CCIO}, between V_{IL} and V_{IH})	1.13	5	V/ns	1

Note:
1. Value obtained through test bench with 50 ohm pull up to V_{CCIO}.

2.8.3.5 JTAG and TAP Signals DC Specifications

Symbol	Parameter	Min	Max	Units	Notes
V_{IL}	Input Low Voltage		0.3*V_{CCIO}	V	
V_{IH}	Input High Voltage	0.7*V_{CCIO}		V	
V_{OL}	Output Low Voltage		0.2*V_{CCIO}	V	
$V_{Hysteresis}$	Hysteresis	0.1*V_{CCIO}			
SR	Input Slew Rate: TCK0, TCK1, BPM_N[7:0],TDI	0.05		V/ns	2
R_{ON}	Buffer On Resistance Signals BPM_N[7:0], TDO	14	4	ohm	
I_{IL}	Input Leakage Current Signals	±50	±200	µA	
SR	Output Edge Rate (50 ohm to V_{CCIO}) Signal: BPM_N[7:0], PRDY_N, TDO	1.13	5	V/ns	1

Notes:
1. These are measured between V_{IL} and V_{IH}.
2. The signal edge rate must be met or the signal must transition monotonically to the asserted state.

2.8.3.6 Serial VID Interface (SVID) DC Specifications

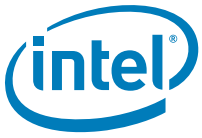
Symbol	Parameter	Min	Nom	Max	Units	Notes
V_{CCIO}	CPU I/O Voltage	V_{CCIO} - 5%	1.0	V_{CCIO} + 5%	V	1
V_{IL}	Input Low Voltage Signals SVIDDATA, SVIDALERT_N			0.3*V_{CCIO}	V	1
V_{IH}	Input High Voltage Signals SVIDDATA, SVIDALERT_N	0.7*V_{CCIO}			V	1
V_{OL}	Output Low Voltage Signals: SVIDCLK, SVIDDATA			0.2*V_{CCIO}	V	1, 6
$V_{Hysteresis}$	Hysteresis	0.1*V_{CCIO}			V	1
R_{ON}	Buffer On Resistance Signals SVIDCLK, SVIDDATA	14		4	ohm	2
I_{IL}	Input Leakage Current	±50		±200	µA	3,4
	Input Edge Rate Signal: SVIDALERT_N	0.05			V/ns	5
	Output Edge Rate	1.13		5	V/ns	5, 6

Notes:
1. V_{CCIO} refers to instantaneous V_{CCIO}.
2. Measured at 0.31*V_{CCIO}.
3. Vin between 0V and V_{CCIO} (applies to SVIDDATA and SVIDALERT_N only).
4. These are measured between V_{IL} and V_{IH}.
5. Value obtained through test bench with 50? pull up to V_{CCIO}.

2.8.3.7 Processor Asynchronous Sideband DC Specifications

Symbol	Parameter	Min	Max	Units	Notes
CMOS output buffers					
I_{IL}	Input Leakage Current	±50	±200	µA	1,2,4
V_{OL}	Low Output Voltage		0.2*V_{CCIO}	V	1,2,4
V_{OH}	High Output Voltage	0.9*V_{CCIO}		V	1,2,4
R_{PD}	Pull down Resistance		50	ohm	1,2,4
R_{PU}	Pull up Resistance:		50	ohm	1,2,4
SR	Output Edge Rate:	0.8	3	V/ns	
CMOS input buffers					
V_{IL}	Input Low Voltage		0.3*V_{CCIO}	V	1, 2,4
V_{IH}	Input High Voltage	0.7*V_{CCIO}		V	1, 2,4
$V_{Hysteresis}$	Hysteresis Signals	0.1*V_{CCIO}		V	1,2,4
SR_1	Input Slew Rate	0.005		V/ns	
SR_2	Input Slew Rate: PMSYNC	0.05		V/ns	
Open Drain Output buffers					
I_L	Input Leakage Current	±50	±200	µA	1,2,4
R_{ON}	Buffer On Resistance	14	4	ohm	1, 2,4
SR	Output Edge Rate	1.13	5	V/ns	3,5

Notes:
1. This table applies to the processor sideband and miscellaneous signals specified in Table 2-7, "Signal Groups".
2. Unless otherwise noted, all specifications in this table apply to all processor frequencies.
3. These are measured between V_{IL} and V_{IH}.
4. In the case of bidirectional signals they use either a CMOS output /CMOS input buffer or they use Open Drain / CMOS input buffer.



5. VOL level for open drain buffers may be obtained with the Buffer ON Resistance and the external 50 ohm pull up to VCCIO.

2.8.3.8 Miscellaneous Signals DC Specifications

Symbol	Parameter	Min	Nominal	Max	Units
SKTOCC_N Signal					
$V_{O\_ABS\_MAX}$	Output Absolute Max Voltage		3.30	3.50	V
I_{OMAX}	Output Max Current			1	mA

2.8.3.9 Intel® Omni-Path Host Fabric Interface (Intel® OP HFI) DC Specifications

Symbol	Parameter	Min	Max	Units	Notes
CMOS 2.5V Inputs					
V_{IL}	Input Low Voltage		0.7	V	
V_{IH}	Input High Voltage	1.7		V	
CMOS 1.8V Inputs					
V_{IL}	Input Low Voltage		0.63	V	
V_{IH}	Input High Voltage	1.17		V	
Open Drain 2.5 Output					
I_L	Input Leakage Current	±50	±200	uA	
R_{ON}	Buffer On Resistance	32	20	ohm	
CMOS 1.8 Output					
V_{OL}	Low Output Voltage		0.45	V	
V_{OH}	High Output Voltage	1.3		V	
R_{PD}	Pull down Resistance	32	20	ohm	
R_{PU}	Pull up Resistance:	32	20	ohm	

2.9 Package C-State Power Specifications

The table below lists the processor package C-state power specifications for the various processor SKUs.

Die Type	C6 (W)
XCC	13
HCC	12
LCC	12

Notes:
1. SKUs are subject to change. Please contact your Intel Field Representative to obtain the latest SKU information.
2. Package C6 power specified at Tcase = 50°C.

2.10 Signal Quality

Data transfer requires the clean reception of data signals and clock signals. Ringing below receiver thresholds, non-monotonic signal edges, and excessive voltage swings will adversely affect system timings. Ringback and signal non-monotonicity cannot be tolerated since these phenomena may inadvertently advance receiver state machines. Excessive signal swings (overshoot and undershoot) are detrimental to silicon gate oxide integrity, and can cause device failure if absolute voltage limits are exceeded.

Overshoot and undershoot can also cause timing degradation due to the build up of inter-symbol interference (ISI) effects.

For these reasons, it is crucial that the designer work towards a solution that provides acceptable signal quality across all systematic variations encountered in volume manufacturing.

This section documents signal quality metrics used to derive topology and routing guidelines through simulation. All specifications are specified at the processor die (pad measurements).

Specifications for signal quality are for measurements at the processor core only and are only observable through simulation. Therefore, proper simulation is the only way to verify proper timing and signal quality.

2.10.1 DDR Signal Quality Specifications

Various scenarios for the DDR Signals have been simulated to generate a set of layout guidelines.

Overshoot (or undershoot) is the absolute value of the maximum voltage above or below VSS. The overshoot/undershoot specifications limit transitions beyond specified maximum voltages or VSS due to the fast signal edge rates. The processor can be damaged by single and/or repeated overshoot or undershoot events on any input, output, or I/O buffer if the charge is large enough (i.e., if the over/undershoot is great enough). Baseboard designs which meet signal integrity and timing requirements and which do not exceed the maximum overshoot or undershoot limits listed in Table 2-18, "Processor I/O Overshoot/Undershoot Specifications" will ensure reliable IO performance for the lifetime of the processor.

2.10.2 PCIe Signal Quality Specifications

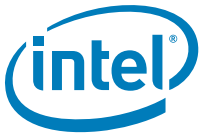
Signal Quality specifications for PCIe Signals are included as part of the PCIe DC specifications and PCIe AC specifications. Various scenarios have been simulated to generate a set of layout guidelines.

2.10.3 Intel® Ultra Path Interconnect (Intel® UPI) Signal Quality Specifications

Signal Quality specifications for Differential Intel® UPI Signals are included as part of the Intel® UPI defined in the Intel® Ultra Path Interconnect (Intel® UPI) Specifications.

2.10.4 Input Reference Clock Signal Quality Specifications

Overshoot/Undershoot and Ringback specifications for BCLK{0/1}_D[N/P] are found in Table 2-18. Overshoot/Undershoot and Ringback specifications for the DDR4 Reference Clocks are specified by the DIMM manufacturer.



2.10.5 Overshoot/ Undershoot Tolerance

Overshoot (or undershoot) is the absolute value of the maximum voltage above or below VSS, see Figure 2-9, "Maximum Acceptable Overshoot/Undershoot Waveform" on page 50. The overshoot/undershoot specifications limit transitions beyond VCCD or VSS due to the fast signal edge rates. The processor can be damaged by single and/or repeated overshoot or undershoot events on any input, output, or I/O buffer if the charge is large enough (i.e., if the over/undershoot is great enough). Baseboard designs which meet signal integrity and timing requirements and which do not exceed the maximum overshoot or undershoot limits listed in the following table will insure reliable IO performance for the lifetime of the processor.

Table 2-18. Processor I/O Overshoot/ Undershoot Specifications

Signal Group	Maximum Undershoot	Maximum Overshoot	Overshoot Duration	Undershoot Duration	Notes
DDR4	-0.22*V_{CCD}	1.22*V_{CCD}	0.25*T_{CH}	0.1*T_{CH}	1,2,3,5
Processor Asynchronous Sideband Signals, SVID, miscellaneous and JTAG/Tap Signals	-0.35*V_{CCIO}	1.35*V_{CCIO}	1.25ns	0.5ns	1,2,5
System Reference Clock (BCLK{0/1/2})	-0.15V	1.15V	N/A	N/A	1,2,5
PWRGOOD Signal	-0.42V	V_{CCIO} + 0.28 V	5ns	5ns	1,2,4
PMSYNC Signal	-0.35*V_{CCIO}	1.35*V_{CCIO}	5ns	5ns	1,2
PMSYNC_CLK Signal	-0.3V	1.35V	5ns	5ns	1,2
PECI Signal	-0.35V	1.35V	5ns	5ns	1,2
SVIDDATA Signal	-0.3V	1.3V	10ns	10ns	1,2

Notes:
1. These specifications are computer simulated at the processor pad (inside the CPU package).
2. Refer to Figure 2-9, "Maximum Acceptable Overshoot/Undershoot Waveform" on page 50 for description of allowable Overshoot/Undershoot magnitude and duration.
3. T_{CH} is the minimum high pulse width duration.
4. For PWRGOOD DC specifications see Section 2.8.3.7, "Processor Asynchronous Sideband DC Specifications"
5. Refer to Table 2-7, "Signal Groups" for a list of signals under the different signal groups, except for the signals that are explicitly listed on this table.

2.10.5.1 Overshoot/ Undershoot Magnitude

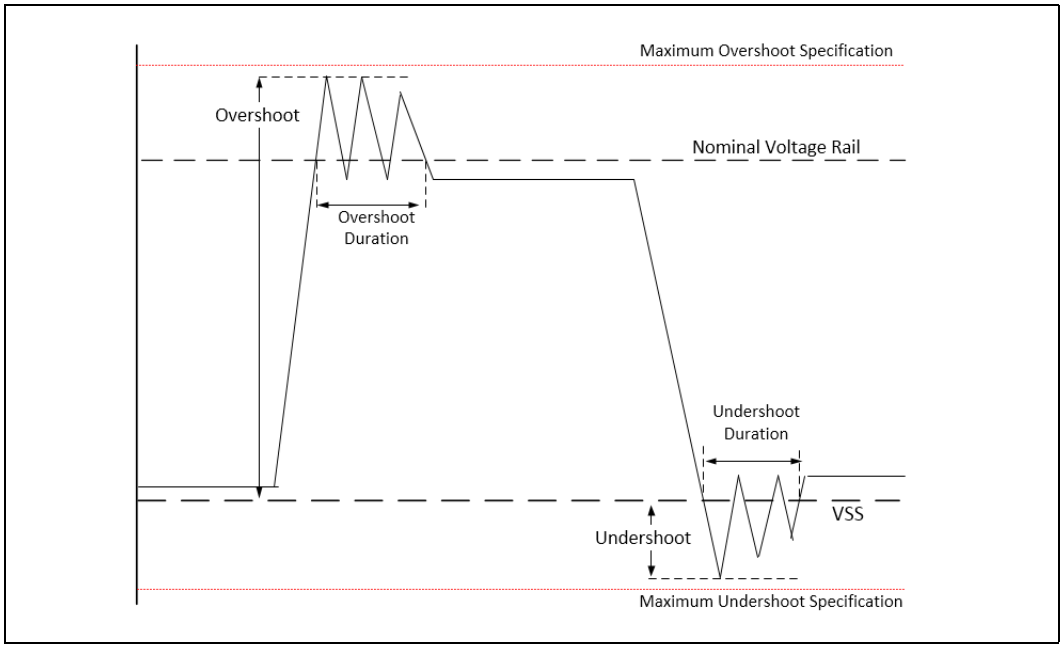
Magnitude describes the maximum potential difference between a signal and its voltage reference level. For the processor, both are referenced to VSS. It is important to note that the overshoot and undershoot conditions are separate and their impact must be determined independently.

2.10.5.2 Overshoot/ Undershoot Pulse Duration

Pulse duration describes the total amount of time that an overshoot/undershoot event exceeds the overshoot/undershoot reference voltage. The total time could encompass several oscillations above the reference voltage. Multiple overshoot/undershoot pulses within a single overshoot/undershoot event may need to be measured to determine the total pulse duration.

Note: Oscillations below the reference voltage cannot be subtract the total overshoot/ undershoot pulse duration.

Figure 2-9. Maximum Acceptable Overshoot/ Undershoot Waveform

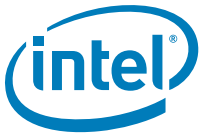


2.10.5.3 Reading Overshoot/ Undershoot Specification Tables

The overshoot/undershoot specification for the processor is not a simple single value. Instead, many factors are needed to determine the over/undershoot specification. In addition to the magnitude of the overshoot the width of the overshoot is needed. To determine the allowed overshoot for a particular overshoot event, the following must be done:

1. Determine the signal group a particular signal falls into.
2. Determine the magnitude of the overshoot or the undershoot (relative to nominal Voltage or VSS).
3. Determine the duration of the undershoot or the overshoot.
4. Compare the values obtained with the maximum overshoot/undershoot magnitude and duration specification.

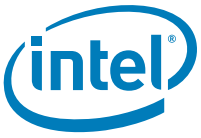
Undershoot events must be analyzed separately from overshoot events as they are mutually exclusive.

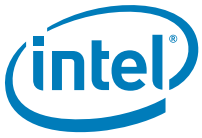


2.10.5.4 Determining if a System Meets the Overshoot/ Undershoot Specifications

The overshoot/undershoot specifications listed in the table specify the allowable overshoot/undershoot for a single overshoot/undershoot event. However most signals will have multiple overshoot and/or undershoot events that each have their own set of parameters (duration and magnitude). To ensure a signal passes the overshoot and undershoot specifications, measure the worst case pulse duration and the worst case magnitude and compare the results against the specifications. If all of these worst case overshoot or undershoot events meet the specifications then the signal passes. If they do not meet the specification, please contact the Intel Representative.

§

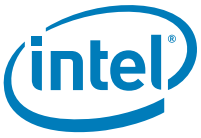


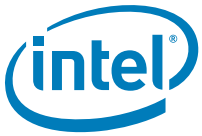


3 Processor Land Listing

Please refer to Appendix A, “Pin Listing.”

§





4 Signal Descriptions

This chapter describes the Intel® Xeon® Processor Scalable Family signals. They are arranged in functional groups according to their associated interface or category.

4.1 System Memory Interface

Table 4-1. Memory Channel DDR0, DDR1, DDR2, DDR3, DDR4, DDR5

Signal Name	Description
DDR{5:0}_ACT_N	Activate. When asserted, indicates MA[16:14] are command signals (RAS_N, CAS_N, WE_N).
DDR{5:0}_ALERT_N	Parity Error detected by the DIMM (one for each channel).
DDR{5:0}_BA[1:0]	Bank Address. Defines which bank is the destination for the current Activate, Read, Write, or Precharge command.
DDR{5:0}_BG[1:0]	Bank Group: Defines which bank group is the destination for the current Active, Read, Write or Precharge command. BG0 also determines which mode register is to be accessed during a MRS cycle.
DDR{5:0}_CID[2]	3DS DRAM Chip ID signal
DDR{5:0}_CKE[3:0]	Clock Enable.
DDR{5:0}_CLK_DN[3:0] DDR{5:0}_CLK_DP[3:0]	Differential clocks to the DIMM. All command and control signals are valid on the rising edge of clock.
DDR{5:0}_CS_N[7:0]	Chip Select. Each signal selects one rank as the target of the command and address. CS_N[7:6] are MUXed with CID[4:3], respectively. CS_N[3:2] are MUXed with CID[1:0], respectively.
DDR{5:0}_DQ[63:0]	Data Bus. DDR4 Data bits.
DDR{5:0}_DQS_DP[17:0] DDR{5:0}_DQS_DN[17:0]	Data strobes. Differential pair, Data/ECC Strobe. Differential strobes latch data/ECC for each DRAM. Different numbers of strobes are used depending on whether the connected DRAMs are x4,x8. Driven with edges in center of data, receive edges are aligned with data edges.
DDR{5:0}_ECC[7:0]	Check bits. An error correction code is driven along with data on these lines for DIMMs that support that capability
DDR{5:0}_MA[17:0]	Memory Address. Selects the Row address for Reads and writes, and the column address for activates. Also used to set values for DRAM configuration registers. MA[16], MA[15], and MA[14] are multi-function and MUXed with RAS_N, CAS_N, and WE_N, respectively. *Note:* MA[17] is not used on Intel® Xeon® Processor Scalable Family It is reserved for future processor implementations on the platform. The pin still requires to be routed appropriately on the board to support future drop-in compatibility.
DDR{5:0}_PAR	Even parity across Address and Command.
DDR{5:0}_ODT[3:0]	On Die Termination. Enables DRAM on die termination during Data Write or Data Read transactions.

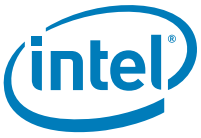


Table 4-2. Memory Channel Miscellaneous

Signal Name	Description
DDR {012,345}_RESET_N	System memory reset: Reset signal from processor to DRAM devices on the DIMMs. DDR012_RESET_N is used for memory channels 0, 1 and 2 while DDR345_RESET_N is used for memory channels 3, 4 and 5.
DDR{012,345}_SPDSCL	SMBus clock for the dedicated interface to the serial presence detect (SPD) and thermal sensors (TSoD) on the DIMMs. DDR_SCL_C012 is used for memory channels 0, 1 and 2 while DDR_SCL_C345 is used for memory channels 3, 4 and 5.
DDR{012,345}_SPDSDA	SMBus data for the dedicated interface to the serial presence detect (SPD) and thermal sensors (TSoD) on the DIMMs. DDR_SDA_C012 is used for memory channels 0, 1 and 2 while DDR_SDA_C345 is used for memory channels 3, 4 and 5.
DDR{5:0}_CAVREF	DIMM Command address VREF signal
DDR{012,345}_DRAM_PWR_OK	Power good for VCCD rail used by the DRAM. This is an input signal used to indicate the VCCD power supply is stable for memory channels 0, 1, 2 and channels 3, 4, 5.
DDR{012,345}_RCOMP[2:0]	DDR Compensation resistance control

4.2 PCI Express* Based Interface Signals

Note: PCI Express* Ports 1, 2 and 3 Signals are receive and transmit differential pairs.

Table 4-3. PCI Express Signals

Signal Name	Description
PE{3:1}_RX_DN/DP[15:0]	PCIe Receive Data Input
PE{3:1}_TX_DN/DP[15:0]	PCIe Transmit Data Output

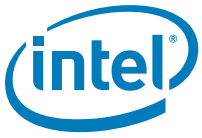
Table 4-4. PCI Express Miscellaneous Signals

Signal Name	Description
PE_HP_SCL	PCI Express Hot-Plug SMBus Clock: Provides PCI Express* hot-plug support via a dedicated SMBus interface. Requires an external general purpose input/output (GPIO) expansion device on the platform.
PE_HP_SDA	PCI Express Hot-Plug SMBus Data: Provides PCI Express* hot-plug support via a dedicated SMBus interface. Requires an external general purpose input/output (GPIO) expansion device on the platform.
PE{012,3}_RBIAS	50 ohm bias resistor for PCI Express

4.3 DMI3 Signals

Table 4-5. DMI3 Signals

Signal Name	Description
DMI_RX_DN/DP[3:0]	DMI3 Receive Data Input
DMI_TX_DN/DP[3:0]	DMI3 Transmit Data Output



4.4 Intel® UPI Signals

Table 4-6. Intel® UPI Signals

Signal Name	Description
UPI{2:1}_RX_DN/DP[19:0]	Intel® UPI Receive data input.
UPI{2:1}_TX_DN/DP[19:0]	Intel® UPI Transmit data output.
UPI{01,2}_RBIAS	50 ohm bias resistor for Intel® UPI

4.5 PECI Signal

Table 4-7. PECI Signal

Signal Name	Description
PECI	PECI (Platform Environment Control Interface) is the serial sideband interface to the processor and is used primarily for thermal, power and error management. Details regarding the PECI electrical specifications, protocols and functions can be found in the *RS - Platform Environment Control Interface (PECI) Specification, Rev 3.1*.

4.6 System Reference Clock Signals

Table 4-8. System Reference Clock (BCLK{0/1/2}) Signals

Signal Name	Description
BCLK{0,1,2}_DN/DP	Reference Clock Differential input. These pins provide the required reference inputs to various PLLs inside the processor, such as Intel® UPI and PCIe. BCLK0, BCLK1 and BCLK2 run at 100 MHz from the same clock source.

4.7 JTAG and TAP Signals

Table 4-9. JTAG and TAP Signals (Sheet 1 of 2)

Signal Name	Description
BPM_N[7:0]	Breakpoint and Performance Monitor Signals: I/O signals from the processor that indicate the status of breakpoints and programmable counters used for monitoring processor performance. These are 100 MHz signals.
PRDY_N	Probe Mode Ready is a processor output used by debug tools to determine processor debug readiness.
PREQ_N	Probe Mode Request is used by debug tools to request debug operation of the processor.
TCK	TCK (Test Clock) provides the clock input for the processor Test Bus (also known as the Test Access Port).
TDI	TDI (Test Data In) transfers serial test data into the processor. TDI provides the serial input needed for JTAG specification support.

Table 4-9. JTAG and TAP Signals (Sheet 2 of 2)

Signal Name	Description
TDO	TDO (Test Data Out) transfers serial test data out of the processor. TDO provides the serial output needed for JTAG specification support.
TMS	TMS (Test Mode Select) is a JTAG specification support signal used by debug tools.
TRST_N	TRST_N (Test Reset) resets the Test Access Port (TAP) logic. TRST_N must be driven low during power on Reset.

4.8 Serial VID Interface (SVID) Signals

Table 4-10. SVID Signals

Signal Name	Description
SVIDALERT_N [1:0]	Serial VID alert.
SVIDCLK [1:0]	Serial VID clock.
SVIDDATA [1:0]	Serial VID data out.

4.9 Processor Asynchronous Sideband and Miscellaneous Signals

Table 4-11. Processor Asynchronous Sideband Signals (Sheet 1 of 2)

Signal Name	Description
CATERR_N	Indicates that the system has experienced a fatal or catastrophic error and cannot continue to operate. The processor will assert CATERR_N for unrecoverable machine check errors and other internal unrecoverable errors. It is expected that every processor in the system will wire-OR CATERR_N for all processors. Since this is an I/O land, external agents are allowed to assert this land which will cause the processor to take a machine check exception. The CATERR_N signal can be sampled any time after 1.5 ms after the assertion of PWRGOOD. On Intel® Xeon® Processor Scalable Family, CATERR_N is used for signaling the following types of errors: • Legacy MCERR's, CATERR_N is asserted for 16 BCLKs.
ERROR_N[2:0]	Error status signals for integrated I/O (IIO) unit: 0 = Hardware correctable error (no operating system or firmware action necessary) 1 = Non-fatal error (operating system or firmware action required to contain and recover) 2 = Fatal error (system reset likely required to recover)
MEM_HOT_C{012/345}_N	Memory throttle control. Signals external BMC-less controller that DIMM is exceeding temperature limit and needs to increase to max fan speed. MEM_HOT_C012_N and MEM_HOT_C345_N signals have two modes of operation - input and output mode. Input mode is externally asserted and is used to detect external events such as VR_HOT# from the memory voltage regulator and causes the processor to throttle the appropriate memory channels. Output mode is asserted by the processor known as level mode. In level mode, the output indicates that a particular branch of memory subsystem is hot. MEM_HOT_C012_N is used for memory channels 0,1 & 2 while MEM_HOT_C345_N is used for memory channels 3, 4 & 5.

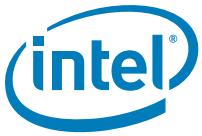


Table 4-11. Processor Asynchronous Sideband Signals (Sheet 2 of 2)

Signal Name	Description
MSMI_N	Machine Check Exception (MCE) is signaled via this pin when eMCA2 is enabled. The MSMI_N signal can be sampled any time after 1.5 ms after the assertion of PWRGOOD
PMSYNC	Power Management Sync. A sideband signal to communicate power management status from the Platform Controller Hub (PCH) to the processor.
PMSYNC_CLK	24 MHz SE Clock used for PCH PMSYNC.
PROCHOT_N	PROCHOT_N will go active when the processor temperature monitoring sensor detects that the processor has reached its maximum safe operating temperature. This indicates that the processor Thermal Control Circuit has been activated, if enabled. This signal can also be driven to the processor to activate the Thermal Control Circuit. This signal is sampled after PWRGOOD assertion.
PWRGOOD	PWRGOOD is a processor input. The processor requires this signal to be a clean indication that all processor clocks and power supplies are stable and within their specifications. "Clean" implies that the signal will remain low (capable of sinking leakage current), without glitches, from the time that the power supplies are turned on until they come within specification. The signal must then transition monotonically to a high state. PWRGOOD can be driven inactive at any time, but clocks and power must again be stable before a subsequent rising edge of PWRGOOD. PWRGOOD transitions from inactive to active when all supplies except VCCIN are stable. The signal must be supplied to the processor; it is used to protect internal circuits against voltage sequencing issues. It should be driven high throughout boundary scan operation.
RESET_N	Global reset signal. Asserting the RESET_N signal resets the processor to a known state and invalidates its internal caches without writing back any of their contents. Note some PLL, Intel UPI and error states are not affected by reset and only PWRGOOD forces them to a known state.
THERMTRIP_N	Assertion of THERMTRIP_N (Thermal Trip) indicates one of two possible critical over-temperature conditions: One, the processor junction temperature has reached a level beyond which permanent silicon damage may occur and Two, the system memory interface has exceeded a critical temperature limit set by BIOS. Measurement of the processor junction temperature is accomplished through multiple internal thermal sensors that are monitored by the Digital Thermal Sensor (DTS). Simultaneously, the Power Control Unit (PCU) monitors external memory temperatures via the dedicated SMBus interface to the DIMMs. If any of the DIMMs exceed the BIOS defined limits, the PCU will signal THERMTRIP_N to prevent damage to the DIMMs. Once activated, the processor will stop all execution and shut down all PLLs. To further protect the processor, its core voltage (V_{CCIN}), V_{CCD}, V_{CCIO}, V_{CCIO} supplies must be removed following the assertion of THERMTRIP_N. Once activated, THERMTRIP_N remains latched until RESET_N is asserted. While the assertion of the RESET_N signal may de-assert THERMTRIP_N, if the processor's junction temperature remains at or above the trip level, THERMTRIP_N will again be asserted after RESET_N is de-asserted. This signal can also be asserted if the system memory interface has exceeded a critical temperature limit set by BIOS. The THERMTRIP_N signal can be sampled any time after 1.5 ms after the assertion of PWRGOOD

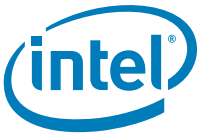


Table 4-12. Miscellaneous Signals (Sheet 1 of 2)

Signal Name	Description
BIST_ENABLE	BIST Enable Strap. Input which allows the platform to enable or disable built-in self test (BIST) on the processor. This signal is pulled up on the die. Refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
BMCINIT	BMC Initialization Strap. Indicates whether Service Processor Boot Mode should be used. Used in combination with FRMAGENT and SOCKET_ID inputs. 0: Service Processor Boot Mode Disabled. Example boot modes: Local PCH (this processor hosts a legacy PCH with firmware behind it) 1: Service Processor Boot Mode Enabled. In this mode of operation, the processor performs the absolute minimum internal configuration and then waits for the Service Processor to complete its initialization. The socket boots after receiving a "GO" handshake signal via a firmware scratchpad register. This signal is pulled down on the die, refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
DEBUG_EN_N	This pin is used to force debug to be enabled when the ITP is connected to the main board. This allows debug to occur beginning from cold boot.
DMIMODE_OVERRIDE	BMCINIT, DMIMODE_OVERRIDE, FRMAGENT, and LEGACY_SKT, whether local or remote, whether the boot PCH is attached, whether the socket is legacy and whether port0 is DMI or PCIe.
EAR_N	External Alignment of Reset, used to bring the processor up into a deterministic state. This signal is pulled up on the die, refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
FIVR_FAULT	Indicates an internal error has occurred with the integrated voltage regulator. The FIVR_FAULT signal can be sampled any time after 1.5 ms after the assertion of PWRGOOD. FIVR_FAULT must be qualified by THERMTRIP_N assertion.
FRMAGENT	Bootable Firmware Agent Strap. This input configuration strap used in combination with SOCKET_ID to determine whether the socket is a legacy socket, bootable firmware agent is present, and DMI links are used in PCIe* mode (instead of DMI3 mode). The firmware flash ROM is located behind the local PCH attached to the processor via the DMI3 interface.This signal is pulled down on the die, refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
PM_FAST_WAKE_N	Power Management Fast Wake. Enables quick package C3 - C6 exits of all sockets. Asserted if any socket detects a break from package C3 - C6 state requiring all sockets to exit the low power state to service a snoop, memory access, or interrupt. Expected to be wired-OR among all processor sockets within the platform.
PROC_ID [1:0]	This output can be used by the platform to determine if the installed processor is a Intel® Xeon® Processor Scalable Family or a future processor. There is no connection to the processor silicon for this signal. The processor package grounds or floats the pin to set '0' or '1', respectively. Intel® Xeon® Processor Scalable Family 00: Skylake 01: Reserved 10: Reserved 11: Reserved Intel Xeon processor-W Family 00: Reserved 01: Reserved 10: Future Processor 11: Intel Xeon processor-W Family
RSVD	RESERVED. All signals that are RSVD must be left unconnected on the board.

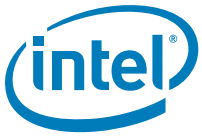


Table 4-12. Miscellaneous Signals (Sheet 2 of 2)

Signal Name	Description
SAFE_MODE_BOOT	Safe Mode Boot Strap. SAFE_MODE_BOOT allows the processor to wake up safely by disabling all clock gating. This allows BIOS to load registers or patches if required. This signal is sampled after PWRGOOD assertion. The signal is pulled down on the die. Refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
SKTOCC_N	SKTOCC_N (Socket Occupied) is used to indicate that a processor is present. This is pulled to ground on the processor package; there is no connection to the processor silicon for this signal.
SOCKET_ID[2:0]	SOCKET_IDStrap. Socket identification configuration straps for establishing the PECI address and Intel UPI Node ID. This signal is used in combination with FRMAGENT to determine whether the socket is a legacy socket, bootable firmware agent is present, and DMI links are used in PCIe* mode (instead of DMI3 mode). Each processor socket consumes one Node ID, and there are 128 Home Agent tracker entries. This signal is pulled down on the die. Refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details. SOCKET_ID[1:0] is used for 2S platforms and SOCKET_ID[2:0] is implemented on 4S/8S platforms. This is an asynchronous signal to other clocks in the processor.
TEST[15:1]	TEST[14:13], TEST[2:1]] must be individually connected to an appropriate power source or ground through a resistor for proper processor operation.
TXT_AGENT	Intel® Trusted Execution Technology (Intel® TXT) Agent Strap. 0 = Default. The socket is not the Intel® TXT Agent. 1 = The socket is the Intel® TXT Agent. The legacy socket (identified by SOCKET_ID[1:0] = 00b) with Intel® TXT Agent should always set the TXT_AGENT to 1b. This signal is pulled down on the die, refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
TXT_PLTEN	Intel® Trusted Execution Technology (Intel® TXT) Platform Enable Strap. 0 = The platform is not Intel® TXT enabled. All sockets should be set to zero. Scalable DP (sDP) platforms should choose this setting if the Node Controller does not support Intel® TXT. 1 = Default. The platform is Intel® TXT enabled. All sockets should be set to one. In a non-Scalable DP platform this is the default. When this is set, Intel® TXT functionality requires user to explicitly enable Intel® TXT via BIOS setup. This signal is pulled up on the die, refer to Table 2-8, "Signals with On-Die Weak PU/PD" for details.
LEGACY_SKT	BMCINIT, FRMAGENT, LEGACY_SKT together determine the boot mode (SSP, Intel® UPI Link boot modes, DCF boot), whether local or remote, whether the boot PCH is attached, whether the socket is legacy and whether port0 is DMI or PCIe (Gen1/2. With one exception, this input configuration strap indicates to the processor that it is the legacy socket. The legacy SKT must be strapped for NODE ID 0, via the SKIT ID pins. There is only 1 legacy SKT in a partition.
PKGID[2:0]	An indicator to the Purley platform of the Intel® OmniPath configuration.
PROCDIS_N	PROCDIS_N assert initiates FRB and tri-states the processor.
PWR_DEBUG_N	This is a debug signal for power debug using Intel® ITP on the processor.
SOCKET_ID2	Asynchronous to other clocks in the processor.
TSC_SYNC	Time stamp counter sync. Used to help align the time stamp counters of a newly socket to the time stamp counters of existing sockets.

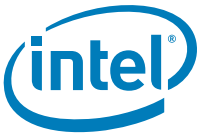


Table 4-13. PIROM Signals

Signal Name	Description
PIROM_ADDR[2:0]	Address for PIROM (Processor Information ROM/OEM scratch pad).
SM_WP	WP (Write Protect) can be used to write protect the Scratch EEPROM. The Scratch EEPROM is write-protected when this input is pulled high to VCCSTBY33.
SMBCLK	The SMBus Clock (SMBCLK) signal is an input clock which is required for operation of PIROM. This clock is driven by the SMBus controller and is asynchronous to other clocks in the processor.
SMBDAT	The SMBus Data (SMBDAT) signal is the data signal for the SMBus. This signal provides the single-bit mechanism for transferring data between SMBus devices.

Table 4-14. Intel® Omni-Path Host Fabric Interface (Intel® OP HFI) Signals

Signal Name	Description
CD_HFI[1:0]_I2CCLK	2-wire serial interface clock
CD_HFI[1:0]_I2CDAT	2-wire serial interface data
CD_HFI[1:0]_INT_N	Interrupt. Used to inform the CPU that the module has encountered a potential error condition
CD_HFI[1:0]_LED_N	Indicates activity on the link
CD_HFI[1:0]_MODPRST_N	Module present
CD_HFI[1:0]_RESET_N	Module reset
CD_HFI_REFCLK_DN/DP	HFI Reference Clock
CD_POR_N	Power on reset for HFI ASIC
MCP01_RBIAS	Multi-chip Bus RBIAS

4.10 Processor Power and Ground Supplies

Table 4-15. Power and Ground Signals (Sheet 1 of 2)

Signal Name	Description
V_{CCIN}	1.8 V - 1.55 V input to the Integrated Voltage Regulator (IVR) for the processor cores, lowest level caches (LLC), ring interface, PLL, IO, and home agent. It is provided by a VR 13.0 compliant motherboard voltage regulator (MBVR) for each CPU socket. The output voltage of this MBVR is controlled by the processor, using the serial voltage ID (SVID) bus.
VCCIN_SENSE VSS_VCCIN_SENSE	VCCIN_SENSE and VSS_VCCIN_SENSE are remote sense signals for V_{CCIN} MBVR13.0 and are used by the voltage regulator to ensure accurate voltage regulation. These signals must be connected to the voltage regulator feedback circuit, which insures the output voltage remains within specification.
VCCIO_SENSE VSS_VCCIO_SENSE	VCCIO_SENSE and VSS_VCCIO_SENSE are remote sense signals for VCCIO and are used by the voltage regulator to ensure accurate voltage regulation. These signals must be connected to the voltage regulator feedback circuit, which insures the output voltage remains within specification.
VCCSA_SENSE VSS_VCCSA_SENSE	VCCSA_SENSE and VSS_VCCSA_SENSE are remote sense signals, and are used by the voltage regulator to ensure accurate voltage regulation. These signals must be connected to the voltage regulator feedback circuit, which insures the output voltage remains within specification.

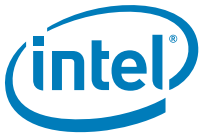
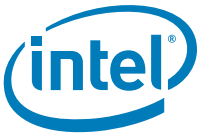
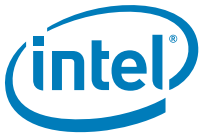


Table 4-15. Power and Ground Signals (Sheet 2 of 2)

Signal Name	Description
CD_VCC_CORE	Companion die 0.9 V core supply
CD_VCCP	Companion die 1.0 V IO supply. Connects to memory voltage regulator.
CD_VCCIN	Companion die voltage rail tied to VCCIN through filter
CD_VPP	Companion die 2.5 V supply
CD_VCCP	Companion die 1.0 V IO supply
VCCIO	.95V-1.0V power supply for the processor IO.
VCC33	VCC33 supplies 3.3 V to PIROM/OEM Scratch ROM. This supply is required for PIROM usage.
VCCIO	.95 V - 1.0 V power supply for the processor IO.
VCCINPMAX	Pmax detect VCCIN supply through board R2 thermistor for VCCIN loadline temperature compensation
VCCSA	1.05 V - 0.55 V supply for Intel® UPI and IIO
VSENSEPMAX	Pmax detect circuit output voltage
V_{CCD_012} V_{CCD_345}	1.2 V - 1.05 V power supply for the processor system memory interface.
V_{SS}	Processor ground return.
V_{CCIO}	IO voltage supply input.

§





5 PI ROM

5.1 Processor Information ROM

The Processor Information ROM (PIROM) is a memory device located on the processor and is accessible via the System Management Bus (SMBus) which contains information regarding the processor's features. These features are listed in Table 5-1, "Processor Information ROM Table".

The PIROM resides in the lower half of the memory component (addresses 00 to 7Fh), which is permanently write-protected by Intel. The upper half comprises the Scratch EEPROM (addresses 80 to FFh).

Table 5-1. Processor Information ROM Table (Sheet 1 of 3)

Offset/ Section	# of Bits	Function	Notes	Examples
Header				
00h	8	Data Format Revision	Two 4-bit hex digits	Start with 00h
02-01h	16	PIROM Size	Size in bytes (LSB first)	Use a decimal to hex transfer; 128 bytes = 0080h:
03h	8	Processor Data Address	Byte pointer, 00h if not present	0Dh
04h	8	Processor Core Data Address	Byte pointer, 00h if not present	19h
05h	8	Processor Uncore Data Address	Byte pointer, 00h if not present	21h
06h	8	Cache Data Address	Byte pointer, 00h if not present	2Bh
07h	8	Package Data Address	Byte pointer, 00h if not present	31h
08h	8	Voltage Data Address	Byte pointer, 00h if not present	34h
09h	8	Part Number Data Address	Byte pointer, 00h if not present	56h
0Ah	8	Thermal Data Address	Byte pointer, 00h if not present	65h
0Bh	8	Feature Data Address	Byte pointer, 00h if not present	6Ch
0Ch	8	PPIN Data Address	Byte pointer, 00h if not present	77h
Processor Data				
0D to 12h	48	S-spec/QDF Number	Six 8-bit ASCII characters	
13h	7/1	Sample/Production	First seven bits reserved	0b = Sample, 1b = Production 00000001 = production
14h	8	Number of Cores	Binary Coded Decimal	24h=24 Cores
15	7/1	Hyper-Threading Support	First seven bits reserved	0b = no Hyper-Threading, 1b = Hyper-Threading 00000001 = Hype- Threading
17 to 16h	16	System Clock Speed	Binary Coded Decimal (Mhz)	0100h = 100MHz[1]
18h	8	Reserved	Reserved for future use	00000000
Processor Core Data				
1A to 19h	16	CPUID	4 bit Binary Coded Decimal	
1B to 1Ch	16	Reserved	Reserved for future use	0000000000000000
1E to 1Dh	16	Maximum P1 Core Frequency	4 bit Binary Coded Decimal	2500h = 2500 MHz[1]
20 to 1Fh	16	Maximum P0 Core Frequency	4 bit Binary Coded Decimal	2800h = 2800 MHz[1]

Table 5-1. Processor Information ROM Table (Sheet 2 of 3)

Offset/ Section	# of Bits	Function	Notes	Examples
Processor Uncore Data				
21h	8	Number of Intel® UPI Links	4 bit Binary Coded Decimal	03h=3 UPI links
23 to 22h	16	Maximum Intel® UPI Link Transfer Rate	4 bit Binary Coded Decimal	1040h = 10.4 GT/s[1]
25 to 24h	16	Maximum PCIe Link Transfer Rate	4 bit Binary Coded Decimal	8000h = 8000 MT/s[1]
27 to 26h	16	Maximum DDR 1DPC Speed	4 bit Binary Coded Decimal	2666h = 2666 MT/S
29 to 28h	16	Maximum DDR 2DPC Speed	4 bit Binary Coded Decimal	2400h = 2400 MT/s
2Ah	8	Reserved	Reserved for future use	00000000
Cache Data				
2C to 2Bh	16	MLC Cache Size	Binary (KB) Per CPU Core	0000010000000000h = 1024KB
2E to 2Dh	16	LLC Cache Size	Binary (KB)	011000000000h = 24576KB
30 to 2Fh	16	NVM DIMM Max Capacity	Binary	Multiplier of 96 = 6TB
Package Data				
31h	8	Package Type	4 bit Binary Coded Decimal	First 4 bits reserved Output decode is below
32 to 33h	16	Reserved	Reserved for future use	0000000000000000
Voltage Data				
35 to 34h	16	Maximum VCCIN	4 bit Binary Coded Decimal	1800h = 1800 mV[1]
37 to 36h	16	Minimum VCCIN	4 bit Binary Coded Decimal	0600h = 600 mV[1]
39 to 38h	16	Maximum VCCSA	4 bit Binary Coded Decimal	1350h = 1350 mV[1]
3B to 3Ah	16	Minimum VCCSA	4 bit Binary Coded Decimal	0800h = 800 mV[1]
3D to 3Ch	16	VCCD	4 bit Binary Coded Decimal	1200h = 1200mV[1]
3F to 3Eh	16	VCCIO	4 bit Binary Coded Decimal	1000h = 1000mV[1]
40 to 43h	32	Reserved	Reserved for future use	00000000000000000000000000000000
45 to 44h	16	CD_VCC_CORE	4 bit Binary Coded Decimal	1000h = 1000mV[1]
47 to 46h	16	CD_VCCIN	4 bit Binary Coded Decimal	1000h = 1000mV[1]
49 to 48h	16	CD_VCCP	4 bit Binary Coded Decimal	1000h = 1000mV[1]
4B to 4A	16	CD_VPP	4 bit Binary Coded Decimal	1000h = 1000mV[1]
4D to 4C	16	RC_VCC_CORE	4 bit Binary Coded Decimal	1000h = 1000mV[1]
4F to 4Eh	16	RC_VCCH	4 bit Binary Coded Decimal	1000h = 1000 mV[1]
50 to 55h	48	Reserved	Reserved for future use	00000000000000000000000000000000 00000000000000000000
Part Numbers				
5C to 56h	56	Processor Family Number	Seven 8-bit ASCII characters	CM80645
64 to 5Dh	64	Processor SKU Number	Eight 8-bit ASCII characters	41272834
Thermal Reference				
65h	8	Tcase Maximum	4 bit Binary Coded Decimal	69h = 69°C[1]
67 to 66h	16	Thermal Design Power	4 bit Binary Coded Decimal	0130h = 130 Watts[1]
69 to 68h	16	DTS Maximum	4 bit Binary Coded Decimal	102h = 102°C[1]
6B to 6Ah	16	Pn Limit	4 bit Binary Coded Decimal	53h = 53 Watts[1]

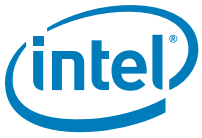


Table 5-1. Processor Information ROM Table (Sheet 3 of 3)

Offset/ Section	# of Bits	Function	Notes	Examples
Features				
6F to 6Ch	32	Processor Core Feature Flags	From CPUID function 1, EDX contents	4387FBFFh
70 to 71h	16	Processor Feature Flags	Up to 16 features - Binary 1 indicates functional feature	0000000000001111
72	6/2	Multiprocessor Support	000b=1S, 001b = 2S, 010b=4S GLULS, 011b=S4S, 100b=Reserved, and 101b=S8S.	00000101b=S8S
73h	4/4	Number of Devices in TAP Chain	First four bits reserved One 4-bit hex digit - Bits	*0h[1]
74 to 75h	16	Reserved	Reserved for future use	0000h
76h	8	Static Checksum	1 byte checksum	Add up by byte and take 2's complement.
Other				
7E to 77h	64	PPIN	Coded binary	See description
7Fh	8	Reserved	Reserved for future use	00000000

Notes:

1. Uses Binary Coded Decimal (BCD) translation.

5.2 Scratch EEPROM

Also available in the memory component on the processor SMBus is an EEPROM which may be used for other data at the system or processor vendor's discretion. The data in this EEPROM, once programmed, can be write-protected by asserting the active-high SM_WP signal. This signal has a weak pull-down (10 Kohm) to allow the EEPROM to be programmed in systems with no implementation of this signal. The Scratch EEPROM resides in the upper half of the memory component (addresses 80 - FFh). The lower half comprises the Processor Information ROM (addresses 00 - 7Fh), which is permanently write-protected by Intel.

5.3 PIROM and Scratch EEPROM Supported SMBus Transactions

The PIROM responds to two SMBus packet types: Read Byte and Write Byte. However, since the PIROM is write-protected, it will acknowledge a Write Byte command but ignore the data. The Scratch EEPROM responds to Read Byte and Write Byte commands. Table 5-2, "Read Byte SMBus Packet" illustrates the Read Byte command. Table 5-3, "Write Byte SMBus Packet" illustrates the Write Byte command.

In the tables, 'S' represents a SMBus start bit, 'P' represents a stop bit, 'A' represents an acknowledge (ACK), and '///' represents a negative acknowledge (NACK). The shaded bits are transmitted by the PIROM or Scratch EEPROM, and the bits that aren't shaded are transmitted by the SMBus host controller. In the tables, the data addresses indicate 8 bits.

The SMBus host controller should transmit 8 bits with the most significant bit indicating which section of the EEPROM is to be addressed: the PIROM (MSB = 0) or the Scratch EEPROM (MSB = 1).

Table 5-2. Read Byte SMBus Packet

S	Slave Address	Write	A	Command Code	A	S	Slave Address	Read	A	Data	/ / /	P
1	7-bits	1	1	8-bits	1	1	7-bits	1	1	8-bits	1	1

Table 5-3. Write Byte SMBus Packet

S	Slave Address	Write	A	Command Code	A	Data	A	P
1	7-bits	1	1	8-bits	1	8-bits	1	1

5.4 SMBus Memory Component Addressing

Of the addresses broadcast across the SMBus, the memory component claims those of the form "10100XXZb". The "XX" bits are defined by pull-up and pull-down of the PIROM_ADDR[2:0] pins. These address pins are pulled down weakly (10 k) on the processor substrate to ensure that the memory components are in a known state in systems which do not support the SMBus (or only support a partial implementation). The "Z" bit is the read/write bit for the serial bus transaction.

Note that addresses of the form "0000XXXXb" are Reserved and should not be generated by an SMBus master.

Table 5-4, "Memory Device SMBus Addressing" describes the address pin connections and how they affect the addressing of the memory component.

Table 5-4. Memory Device SMBus Addressing

Address (Hex)	Upper Address[1]	Device Select			R/ W
	Bits 7-4	SKTID[2]	SKTID[1] Bit 2	SKTID[0] Bit 1	Bit 0
A0h/A1h	10100	10100	0	0	X
A2h/A3h	10100	10100	0	1	X
A4h/A5h	10100	10100	1	0	X
A6h/A7h	10100	10100	1	1	X

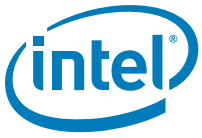
Notes:

1. This addressing scheme will support up to four processors on a single SMBus.

5.4.1 Managing Data in the PIROM

The PIROM consists of the following sections:

- Header
- Processor Data
- Processor Core Data
- Processor Uncore Data
- Cache Data
- Package Data
- Part Number Data



- Thermal Reference Data
- Feature Data
- Other Data

Details on each of these sections are described below.

Note: Reserved fields or bits SHOULD be programmed to zeros. However, OEMs should not rely on this model.

5.4.2 Header

To maintain backward compatibility, the Header defines the starting address for each subsequent section of the PIROM. Software should check for the offset before reading data from a particular section of the ROM.

Example: Code looking for the processor uncore data of a processor would read offset 05h to find a value of 21. 21 is the first address within the 'Processor Uncore Data' section of the PIROM.

5.4.2.1 DFR: Data Format Revision

This location identifies the data format revision of the PIROM data structure. Writes to this register have no effect.

Offset: 00h	
Bit	**Description**
7:0	**Data Format Revision** The data format revision is used whenever fields within the PIROM are redefined. The initial definition will begin at a value of 1. If a field, or bit assignment within a field, is changed such that software needs to discern between the old and new definition, then the data format revision field will be incremented. 00h:Reserved 01h:Initial definition 02h:Second revision 03h:Third revision 04h:Fourth revision 05h:Fifth revision 06h:Sixth revision 07h:Seventh revision *(Defined by this document)* 08h-FFh: Reserved

5.4.2.2 PISIZE: PIROM Size

This location identifies the PIROM size. Writes to this register have no effect.

Offset: 02h-01h	
Bit	**Description**
15:0	**PIROM Size** The PIROM size provides the size of the device in hex bytes. The LSB is at location 01h; the MSB is at location 02h. 0000h - 007Fh: Reserved 0080h: 128 byte PIROM size 0081- FFFFh: Reserved

5.4.2.3 PDA: Processor Data Address

This location provides the offset to the Processor Data Section. Writes to this register have no effect.

Offset: 03h	
Bit	**Description**
7:0	**Processor Data Address** Byte pointer to the Processor Data section 0Dh: Processor Data section pointer value

5.4.2.4 PCDA: Processor Core Data Address

This location provides the offset to the Processor Core Data Section. Writes to this register have no effect.

Offset: 04h	
Bit	**Description**
7:0	**Processor Core Data Address** Byte pointer to the Processor Core Data section 19h: Processor Core Data section pointer value

5.4.2.5 PUDA: Processor Uncore Data Address

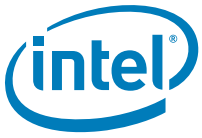
This location provides the offset to the Processor Uncore Data Section. Writes to this register have no effect.

Offset: 05h	
Bit	**Description**
7:0	**Processor Uncore Data Address** Byte pointer to the Processor Uncore Data section 21h: Processor Uncore Data section pointer value

5.4.2.6 CDA: Cache Data Address

This location provides the offset to the Cache Data Section. Writes to this register have no effect.

Offset: 06h	
Bit	**Description**
7:0	**Cache Data Address** Byte pointer to the Cache Data section 2Bh: Cache Data section pointer value



5.4.2.7 PNDA: Package Data Address

This location provides the offset to the Package Data Section. Writes to this register have no effect.

Offset: 07h	
Bit	**Description**
7:0	**Package Data Address** Byte pointer to the Package Data section 31h: Package Data section pointer value

5.4.2.8 VDA: Voltage Data Address

This location provides the offset to the Voltage Data Section. Writes to this register have no effect.

Offset: 08h	
Bit	**Description**
7:0	**Voltage Data Address** Byte pointer to the Voltage Data section 34h: Voltage Data section pointer value

5.4.2.9 PNDA: Part Number Data Address

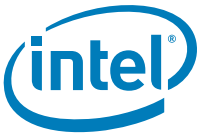
This location provides the offset to the Part Number Data Section. Writes to this register have no effect.

Offset: 09h	
Bit	**Description**
7:0	**Part Number Data Address** Byte pointer to the Part Number Data section 56h: Part Number Data section pointer value

5.4.2.10 TRDA: Thermal Reference Data Address

This location provides the offset to the Thermal Reference Data Section. Writes to this register have no effect.

Offset: 0Ah	
Bit	**Description**
7:0	**Thermal Reference Data Address** Byte pointer to the Thermal Reference Data section 65h: Thermal Reference Data section pointer value



5.4.2.11 FDA: Feature Data Address

This location provides the offset to the Feature Data Section. Writes to this register have no effect.

Offset: 0Bh	
Bit	**Description**
7:0	**Feature Data Address** Byte pointer to the Feature Data section 6Ch: Feature Data section pointer value

5.4.2.12 PPIN: Protected Processor Inventory Number

This location provides the offset to the PPIN Data Section. Writes to this register have no effect.

Offset: 0Ch	
Bit	**Description**
7:0	**PPIN Data Address** Byte pointer to the PPIN Data section 77h: PPIN Data section pointer value

5.4.3 Processor Data

This section contains five pieces of data:

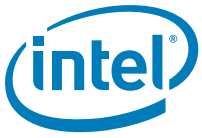
- The S-spec/QDF of the part in ASCII format
- (1) 2-bit field to declare if the part is a preproduction sample or a production unit
- Core count
- Intel® Hyper-threading Technology support status
- The system bus speed in BCD format

5.4.3.1 SAMPROD: Sample/ Production

This location contains the sample/production field, which is a two-bit field and is LSB aligned. All S-spec material will use a value of 01b. All other values are reserved. Writes to this register have no effect.

A processor with an Sxxxx mark (production unit) will use 01h at offset 14h.

Offset: 13h	
Bit	**Description**
7:2	**RESERVED** 000000b-111111b: Reserved
1:0	**Sample/ Production** Sample or Production indicator 00b: Sample 01b: Production 10b-11b: Reserved



5.4.3.2 Processor Core Information

This location contains information regarding the number of cores on the processor. Writes to this register have no effect. Data format is binary coded decimal.

Offset: 14h	
Bit	**Description**
7:0	**Number of cores** 0000h-FFFFh: Cores

5.4.3.3 Processor Thread Information

This location contains information regarding the number of cores and threads on the processor. Writes to this register have no effect. Data format is binary coded decimal.

Offset: 15h	
Bit	**Description**
7:0	**Number of threads per core** 0000h-FFFFh: Threads

5.4.3.4 SCS: System Clock Speed

This location contains the system clock frequency information. Systems may need to read this offset to decide if all installed processors support the same system clock speed. The data provided is the speed, rounded to a whole number, and reflected in binary coded decimal. Writes to this register have no effect.

For example, a processor with system bus speed of 100 MHz will have a value of 0100h.

Offset: 17h-16h	
Bit	**Description**
15:0	**System Bus Speed** 0000h-FFFFh: MHz

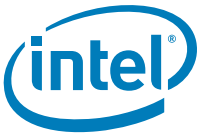
5.4.3.5 RES1: Reserved 1

This location is reserved. Writes to this register have no effect.

Offset: 18h	
Bit	**Description**
7:0	**RESERVED** 00h-FFh: Reserved

5.4.4 Processor Core Data

This section contains silicon-related data relevant to the processor cores.



5.4.4.1 CPUID: CPUID

This location contains the CPUID, Processor Type, Family, Model and Stepping. The CPUID field is a copy of the results in EAX[15:0] from Function 1 of the CPUID instruction. For example, bit 15 is MSB in offset 1Ah and bit 0 is LSB in offset 19h. Writes to this register have no effect. Data format is hexadecimal.

Offset: 1Ah-19h		
Bit	**Byte**	**Description**
15:13	1Ah	**Reserved** 00b-11b: Reserved
12:12		**Processor Type** 0b-1b: Processor Type
11:8		**Processor Family** 0h-Fh: Processor Family
7:4	19h	**Processor Model** 0h-Fh: Processor Model
3:0		**Processor Stepping** 0h-Fh: Processor Stepping

5.4.4.2 RES2: Reserved 2

This locations are reserved. Writes to this register have no effect.

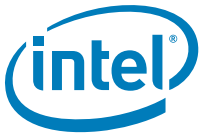
Offset: 1Bh-1Ch	
Bit	**Description**
15:0	**RESERVED** 0000h-FFFFh: Reserved

5.4.4.3 MP1CF: Maximum P1 Core Frequency

This location contains the maximum non-Intel Turbo Boost Technology core frequency for the processor. The frequency should equate to the markings on the processor and/or the QDF/S-spec speed even if the parts are not limited or locked to the intended speed. Format of this field is in megahertz, rounded to a whole number, and encoded in binary coded decimal. Writes to this register have no effect.

Example: A 2.6 GHz processor will have a value of 2600h.

Offset: 1Eh-1Dh	
Bit	**Description**
15:0	**Maximum P1 Core Frequency** 0000h-FFFFh: MHz



5.4.4.4 MP0CF: Maximum P0 Core Frequency

This location contains the maximum Intel Turbo Boost Technology core frequency for the processor. This is the maximum intended speed for the part under any functional conditions. Format of this field is in megahertz, rounded to a whole number, and encoded in binary coded decimal. Writes to this register have no effect.

Example: A processor with a maximum Intel Turbo Boost Technology frequency of 2.8 GHz will have a value of 2800h.

Offset: 20h-1Fh	
Bit	**Description**
15:0	**Maximum P0 Core Frequency** 0000h-FFFFh: MHz

5.4.5 Processor Uncore Data

This section contains silicon-related data relevant to the processor Uncore.

5.4.5.1 UPIL: Number of Intel® UPI Links

Systems may need to read this offset to decide if the device has enough Intel® UPI Links to operate the number of processors your system is capable of supporting. The data provided is the number of links, and reflected in binary coded decimal. Writes to this register have no effect.

Example: The Intel® Xeon® Processor Scalable Family supports a maximum of three links. Therefore, offset 21h could have a value of 03.

Offset: 21h	
Bit	**Description**
7:0	**Number of Intel® UPI links** 00h-FFh: Links

5.4.5.2 MAXUPI: Maximum Intel® UPI Transfer Rate

Systems may need to read this offset to decide if all installed processors support the same Intel® UPI link transfer rate. The data provided is the transfer rate, rounded to a whole number, and reflected in binary coded decimal. Writes to this register have no effect.

Example: The Intel® Xeon® Processor Scalable Family supports a maximum Intel® UPI link transfer rate of 10.4 GT/s. Therefore, offset 23h-22h has a value of 1040.

Offset: 23h-22h	
Bit	**Description**
15:0	**Maximum Intel® UPI Transfer Rate** 0000h-FFFFh: 10 MHz

5.4.5.3 MAXPCI: Maximum PCIe Transfer Rate

Systems may need to read this offset to decide if all installed processors support the same Intel PCIe Link Transfer Rate. The data provided is the transfer rate, rounded to a whole number, and reflected in binary coded decimal. Writes to this register have no effect.

For example, the Intel® Xeon® Processor Scalable Family supports a maximum Intel PCIe2 link transfer rate of 8.0 GT/s. Therefore, offset 25h-24h has a value of 8000.

Offset: 25h-24h	
Bit	**Description**
15:0	**Minimum PCIe Transfer Rate** 0000h-FFFFh: MHz

5.4.5.4 DDR1DPC: Maximum Intel DDR4 1 DPC DIMM Speed

Systems may need to read this offset to set maximum DIMM speeds supporting the 1 DPC usage. The data provided is maximum supported DIMM frequency, rounded to a whole number, and reflected in binary coded decimal. Writes to this register have no effect.

Example: The Intel® Xeon® Processor Scalable Family supports a maximum DDR4 frequency of 2667Gh/s. Therefore, offset 27h-26h has a value of 2667h.

Offset: 27h-26h	
Bit	**Description**
15:0	**Maximum Intel SMI Transfer Rate** 0000h-FFFFh: MHz

5.4.5.5 DDR2DPC: Maximum Intel DDR4 2 DPC DIMM Speed

Systems may need to read this offset to set maximum DIMM speeds supporting the 2DPC usage. The data provided is maximum supported DIMM frequency, rounded to a whole number, and reflected in binary coded decimal. Writes to this register have no effect.

Offset: 29h-28h	
Bit	**Description**
15:0	**Minimum Intel SMI Transfer Rate** 0000h-FFFFh: MHz

5.4.5.6 RES3: Reserved 3

This locations are reserved. Writes to this register have no effect.

Offset: 2Ah	
Bit	**Description**
8:0	**RESERVED** 00h-FFh: Reserved

5.4.6 Processor Cache Data

This section contains silicon-related data relevant to the processor caches.

5.4.6.1 MLC: Mid Level Cache Size

This location contains the size of the level-two cache in kilobytes per core. Writes to this register have no effect. Data format is decimal.

Example: The Skylake processor has a 1 MB MLC cache per core. Thus, offset 2Ch-2Bh will contain a value of 0400h, which is 1024.

Offset: 2Ch-2Bh	
Bit	**Description**
15:0	**Mid Level Cache Size** 0000h-FFFFh: KB

5.4.6.2 LLC: Low Level Cache Size

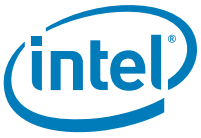
This location contains the size of the level-three cache in megabytes per package. Writes to this register have no effect. Data format is decimal.

Example: The Intel® Xeon® Processor Scalable Family has a 33 MB LLC cache. Thus, offset 2Eh-2Dh will contain a value of 8400h.

Offset: 2Eh-2Dh	
Bit	**Description**
15:0	**Low Level Cache Size** 0000h-FFFFh: KB

5.4.6.3 RES2 and RES3: Reserved 2 and Reserved 3

This location contains NVM DIMM Max Capacity information. Bit 15:0 is binary value representation of multiplier of 64 GB to indicate NVM DIMM Max Capacity. Writes to this register have no effect.



Offset: 30h-2Fh	
Bit	**Description**
15:8	**Offset 30h: NVM DIMM Max Capacity** 00h-FFh:
7:0	**Offset 2Fh: NVM DIMM Max Capacity** 00h-FFh:

5.4.7 Package Data

This section contains substrate and other package related data.

5.4.7.1 PKGT: Package Type

This location tracks the whether the part is a multi-chip package, and which type if so. 0 = non-MCP package. 1 = fabric. Writes to this register have no effect.

Offset: 31h	
Bit	**Description**
7:0	**Package Type** 00h-FFh:

5.4.7.2 RES5: Reserved 5

This location is reserved. Writes to this register have no effect.

Offset: 32h-33h	
Bit	**Description**
15:0	**RESERVED** 0000h-FFFFh: Reserved

5.4.8 Processor Voltage Data

This section contains silicon-related data relevant to the processor voltage rails.

5.4.8.1 MXVCCIN: MAX VCCIN VID

Offset 35h-34h is the Processor VCCIN maximum VID (Voltage Identification) field and contains the maximum voltage requested via the VID pins. This field, rounded to the next thousandth, is in mV and is reflected in binary coded decimal. Some systems read this offset to determine if all processors support the same default VID setting. Writes to this register have no effect.

Example: A voltage of 1.800 V maximum core VID would contain 1800h in offset 35- 34h.

Offset: 35h-34h	
Bit	**Description**
15:0	**MAX VCCIN VID** 0000h-FFFFh: mV

5.4.8.2 MNVCCIN: MIN VCCIN VID

Offset 37h-36h is the Processor Vsa minimum VID (Voltage Identification) field and contains the minimum voltage requested via the VID pins. This field, rounded to the next thousandth, is in mV and is reflected in binary coded decimal. Some systems read this offset to determine if all processors support the same default VID setting. Writes to this register have no effect.

Example: A voltage of 0.600 V maximum core VID would contain 0600h in offset 37h- 36h.

Offset: 37-36h	
Bit	**Description**
15:0	**MIN VCCIN VID** 0000h-FFFFh: mV

5.4.8.3 MXSAVD: MAX VSA VID

Offset 39h-38h is the Processor Vsa maximum VID (Voltage Identification) field and contains the maximum voltage requested via the VID pins. This field, rounded to the next thousandth, is in mV and is reflected in binary coded decimal. Some systems read this offset to determine if all processors support the same default VID setting. Writes to this register have no effect.

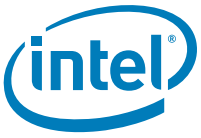
Example: A voltage of 1.000 V maximum core VID would contain 1000h in offset 39h- 38h.

Offset: 39h-38h	
Bit	**Description**
15:0	**MAX VSA VID** 0000h-FFFFh: mV

5.4.8.4 MNSAVD: MIN VSA VID

Offset 3Bh-3Ah is the Processor Vsa minimum VID (Voltage Identification) field and contains the minimum voltage requested via the VID pins. This field, rounded to the next thousandth, is in mV and is reflected in binary coded decimal. Some systems read this offset to determine if all processors support the same default VID setting. Writes to this register have no effect.

Example: A voltage of 0.600 V maximum core VID would contain 0600h in offset 3Bh-3Ah.



Offset: 3Bh-3Ah	
Bit	**Description**
15:0	**MIN VSA VID** 0000h-FFFFh: mV

5.4.8.5 VCCD: VCCD

This field contains the voltage requested for the VCCD pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default VCCD settings. Writes to this register have no effect.

Example: A voltage of 1.200 VCCD would contain an offset 3D-3Ch value of 1200h.

Offset: 3Dh-3Ch	
Bit	**Description**
15:0	**VCCD** 0000h-FFFFh: mV

5.4.8.6 VCCIO: VCCIO

This field contains the voltage requested for the VccIO pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default VccIO settings. Writes to this register have no effect.

Example: A voltage of 1.000 VccIO_IN would contain an offset 3Fh-3Eh value of 1000h.

Offset: 3Fh-3Eh	
Bit	**Description**
15:0	**VCCIO** 0000h-FFFFh: mV

5.4.8.7 RES6: Reserved 6

This location is reserved. Writes to this register have no effect.

Offset: 43h-40h	
Bit	**Description**
31:0	**RESERVED** 00000000h-FFFFFFFFh:

5.4.8.8 CDVCORE: CD Vcc Core

This field contains the voltage requested for the CD Vcc Core pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default CD Vcc Core settings. Writes to this register have no effect.

Example: A voltage of 1.000 CD Vcc Core would contain an offset 45-44h value of 1000h.

Offset: 45h-44h	
Bit	**Description**
15:0	**CD Vcc Core** 0000h-FFFFh: mV

5.4.8.9 CDVCCIN: CD Vcc In

This field contains the voltage requested for the CD Vcc In pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default CD Vcc In settings. Writes to this register have no effect.

Example: A voltage of 1.000 VccIO_IN would contain an offset 47-46h value of 1000h.

Offset: 47E-46h	
Bit	**Description**
15:0	**CD Vcc In** 0000h-FFFFh: mV

5.4.8.10 CDVCCP: CD VCCP

This field contains the voltage requested for the CDVCCP pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default CDVCCP settings. Writes to this register have no effect.

Example: A voltage of 1.000 CDVCCP would contain an offset 49h-48h value of 1000h.

Offset: 49h-48h	
Bit	**Description**
15:0	**CDVCCP** 0000h-FFFFh: mV

5.4.8.11 CDVPP: CD VPP

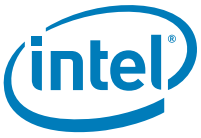
This field contains the voltage requested for the CD VPP pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default CD VPP settings. Writes to this register have no effect.

Example: A voltage of 1.000 CD VPP would contain an offset 4Bh-4Ah value of 1000h.

Offset: 4B-4Ah	
Bit	**Description**
15:0	**CD VPP** 0000h-FFFFh: mV

5.4.8.12 RCVCORE: RC VCORE

This field contains the voltage requested for the RC VCORE pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default RC VCORE settings. Writes to this register have no effect.



Example: A voltage of 1.000 VCCD would contain an offset 4Dh-4Ch value of 1000h.

Offset: 4Dh-4Ch	
Bit	**Description**
15:0	**RC VCORE** 0000h-FFFFh: mV

5.4.8.13 RCVCCH: RC VCCH

This field contains the voltage requested for the RC VCCH pins. This field is in mV and is reflected in hex. Some systems read this offset to determine if all processors support the same default RC VCCH settings. Writes to this register have no effect.

Example: A voltage of 1.000 RC VCCH would contain an offset 4Eh-4Fh value of 1000h.

Offset: 4Fh-4Eh	
Bit	**Description**
15:0	**RC VCCH** 0000h-FFFFh: mV

5.4.8.14 RES7: Reserved 7

This location is reserved. Writes to this register have no effect.

Offset: 50h-55h	
Bit	**Description**
39:0	**RESERVED** 0000000000h-FFFFFFFFFFh: Reserved

5.4.9 Part Number Data

This section provides device traceability.

5.4.9.1 PFN: Processor Family Number

This location contains seven ASCII characters reflecting the Intel® family number for the processor. This number is the same on all Intel® Xeon® E7 v3 processors. Combined with the Processor SKU Number below, this is the complete processor part number. This information is typically marked on the outside of the processor. If the part number is less than 15 total characters, a leading space is inserted into the value. The part number should match the information found in the marking specification. Writes to this register have no effect.

For example, a processor with a part number of AT80604******** will have the following data found at offset 5Ch-56h: 41h, 54h, 38h, 30h, 36h, 30h, 34h.

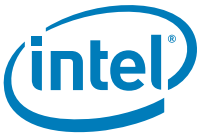
Offset: 5Ch-56h	
Bit	**Description**
55:48	**Character 1** ASCII character 00h-0FFh: ASCII character
47:40	**Character 2** ASCII character 00h-0FFh: ASCII character
39:32	**Character 3** ASCII character 00h-0FFh: ASCII character
31:24	**Character 4** ASCII character 00h-0FFh: ASCII character
23:16	**Character 5** ASCII character or 20h 00h-0FFh: ASCII character
15:8	**Character 6** ASCII character or 20h 00h-0FFh: ASCII character
7:0	**Character 7** ASCII character or 20h 00h-0FFh: ASCII character

5.4.9.2 PSN: Processor SKU Number

This location contains eight ASCII characters reflecting the SKU number for the processor. Added to the end of the Processor Family Number above, this is the complete processor part number. This information is typically marked on the outside of the processor. If the part number is less than 15 total characters, a leading space is inserted into the value. The part number should match the information found in the marking specification. Writes to this register have no effect.

Example: A processor with a part number of *******003771AA will have the following data found at offset 64h-5Dh: 30h, 30h, 33h, 37h, 37h, 31h, 41h, 41h.

Offset: 64h-5Dh	
Bit	**Description**
63:56	**Character 1** ASCII character 00h-0FFh: ASCII character
55:48	**Character 2** ASCII character 00h-0FFh: ASCII character
47:40	**Character 3** ASCII character 00h-0FFh: ASCII character



Offset: 64h-5Dh	
Bit	**Description**
39:32	**Character 4** ASCII character or 20h 00h-0FFh: ASCII character
31:24	**Character 5** ASCII character or 20h 00h-0FFh: ASCII character
23:16	**Character 6** ASCII character or 20h 00h-0FFh: ASCII character
15:8	**Character 7** ASCII character or 20h 00h-0FFh: ASCII character
7:0	**Character 8** ASCII character 00h-0FFh: ASCII character

5.4.10 Thermal Reference Data

5.4.10.1 TCASE: T_{CASE} Maximum

This location provides the maximum T_{CASE} for the processor. The field reflects temperature in degrees Celsius in binary coded decimal format. The thermal specifications are specified at the case Integrated Heat Spreader (IHS). Writes to this register have no effect.

Example: A temperature of 66°C would contain a value of 66h.

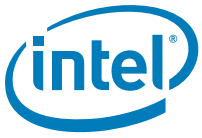
Offset: 65h	
Bit	**Description**
7:0	**T_{CASE} Maximum** 00h-FFh: Degrees Celsius

5.4.10.2 TDP: Thermal Design Power

This location contains the maximum Thermal Design Power for the part. The field reflects power in watts in binary coded decimal format. Writes to this register have no effect. A zero value means that the value was not programmed.

Example: A 130 W TDP would be saved as 0130h. Offset 67h is 01h and offset 66h is 30h.

Offset: 67h-66h	
Bit	**Description**
15:0	**Thermal Design Power** 0000h-FFFFh: Watts



5.4.10.3 DTSMAX: Digital Thermal Sensor Maximum

This location provides the Digital Thermal Sensor Maximum temperature for the processor. The field reflects temperature in degrees Celsius in binary coded decimal format. The thermal specifications are specified at the sensor nearest the CPU hot spot. Writes to this register have no effect.

Example: A temperature of 103°C would contain a value of 0103h.

Offset: 69h-68h	
Bit	**Description**
15:0	**Digital Thermal Sensor Maximum** 0000h-FFFFh: Degrees Celsius

5.4.10.4 PN: Pn Power Limit

This location contains the maximum Pn power for the part. The field reflects power in watts in binary coded decimal format. Writes to this register have no effect. A zero value means that the value was not programmed.

Example: A 35 W would be saved as 0035h. Offset 6Ah is 00h and offset 69h is 35h.

Offset: 6Ah-69h	
Bit	**Description**
15:0	**Pn Power Limit** 0000h-FFFFh: Watts

5.4.11 Feature Data

This section provides information on key features that the platform may need to understand without powering on the processor.

5.4.11.1 PCFF: Processor Core Feature Flags

This location contains a copy of results in EDX[31:0] from Function 1 of the CPUID instruction. These details provide instruction and feature support by product family. Writes to this register have no effect.

Example: A value of BFEBFBFFh can be found at offset 6Ch - 6Fh.

Offset: 6Ch-6Fh	
Bit	**Description**
31:0	**Processor Core Feature Flags** 00000000h-FFFFFFFFF: Feature Flags

5.4.11.2 PFF: Processor Feature Flags

This location contains additional feature information from the processor. Writes to this register have no effect.

Offset: 71h-70h		
Bit	**Byte**	**Description**
	71h	Reserved
		Reserved
		Reserved
		Reserved
		Reserved
		Reserved
		Reserved
		Reserved
7	70h	Reserved
6		Reserved
5		Reserved
4		AEP Enabled
3		TXT Enabled
2		EMCA2 Enabled
1		Turbo Enabled
0		avx512_2ndFMA

Bits are set when a feature is present, and cleared when they are not.

5.4.11.3 MPSUP: Multiprocessor Support

This location contains 2 bits for representing the supported number of physical processors on the bus. These two bits are LSB aligned where 000b equates to non-scalable 1socket (1S) operation, 001b to non-scalable 2 socket (2S), 010b to 4 socket glueless (4S GLULS), 011b to scalable 4 socket (S4S), and 101b scalable 8 socket (S8S). The is a 1S, 2S, 4S GLULS, S4S, or S8S processor. The first six bits in this field are reserved for future use. Writes to this register have no effect.

Example: A scalable 8-socket processor will have a value of 100h at offset 72h.

Offset: 72h	
Bit	**Description**
7:3	**RESERVED** 000000b-111111b: Reserved
2:0	**Multiprocessor Support** 1S, 2S, 4S GLULS, S4S, or S8S indicator 000b: Nonscalable, 1 Socket 001b: Nonscalable, up to 2 Socket Glueless 010b: Nonscalable, up to 4 Socket Glueless in Ring. 011b: Scalable, up to 4 Socket Glueless Fully Connected. 100b: Reserved 101b: Scalable, up to 8 Socket Glueless

5.4.11.4 TCDC: Tap Chain Device Count

At offset 73, a 4-bit hex digit is used to tell how many devices are in the TAP Chain. A Intel® Xeon® Processor Scalable Family with ten cores, this field would be set to Bh.

Offset: 73h	
Bit	**Description**
7:0	**TAP Chain Device Count** 0000h-FFFFh: Reserved

5.4.11.5 RES9: Reserved 9

This location is reserved. Writes to this register have no effect.

Offset: 74h-75h	
Bit	**Description**
15:0	**RESERVED** 0000h-FFFFh: Reserved

5.4.11.6 STTCKS: Static Checksum

This location provides the checksum of the static values per SKU. Writes to this register have no effect.

Offset: 76h	
Bit	**Description**
7:0	**Static Checksum** One-byte checksum of the Static Checksum 00h- FFh: See Section 5.4.13 for calculation of this value.

5.4.12 Protected Processor Inventory Number

This section contains the Protected Processor Inventory Number.

5.4.12.1 PPIN: Protected Processor Inventory Number

This location contains a 64-bit identification number. The value in this field is the PPIN number, which will be the same value as the PPIN accessed through the BIOS MSR. Writes to this register have no effect.

Offset: 7Eh-77h	
Bit	**Description**
63:0	**PPIN** 0000000000000000h-FFFFFFFFFFFFFFFFh: PPIN

5.4.12.2 RES10: Reserved 10

This location is reserved. Writes to this register have no effect.

Offset: 7Fh	
Bit	**Description**
7:0	**RESERVED** 00h- FFh: Reserved.

5.4.13 Checksums

The PIROM includes checksums. Table 5-5 includes the checksum values for each section defined in the 128-byte ROM.

Table 5-5. 128-Byte ROM Checksum Values

Section	Checksum Address
Static Features	76h

Checksums are automatically calculated and programmed by Intel. The first step in calculating the checksum is to add each byte from the field to the next subsequent byte. This result is then negated to provide the checksum.

Example: For a byte string of AA445Ch, the resulting checksum will be B6h.

AA = 10101010 44 = 01000100 5C = 01011100

AA + 44 + 5C = 01001010

Negate the sum: 10110101 +1 = **10110110 (B6h)**

§

A Pin Listing

Table A-1. Pin List By Name (Sheet 1 of 90)

Pin Name	Location	Type	I/O
BCLK0_DN	AU24	CMOS	I
BCLK0_DP	AW24	CMOS	I
BCLK1_DN	CR26	CMOS	I
BCLK1_DP	CP27	CMOS	I
BCLK2_DN	CT25	CMOS	I
BCLK2_DP	CU26	CMOS	I
BIST_ENABLE	BA20	CMOS	I
BMCINIT	BD23	CMOS	I
BPM_N[0]	AJ10	ODCMOS	I/O
BPM_N[1]	AH11	ODCMOS	I/O
BPM_N[2]	AG10	ODCMOS	I/O
BPM_N[3]	AF11	ODCMOS	I/O
BPM_N[4]	AA12	ODCMOS	I/O
BPM_N[5]	Y11	ODCMOS	I/O
BPM_N[6]	AE12	ODCMOS	I/O
BPM_N[7]	AC12	ODCMOS	I/O
CATERR_N	AL14	ODCMOS	I/O
CD_HFI_REFCLK_DN	BE16	CMOS	I
CD_HFI_REFCLK_DP	BG16	CMOS	I
CD_HFI0_I2CCLK	BN22	ODCMOS	I/O
CD_HFI0_I2CDAT	BP23	ODCMOS	I/O
CD_HFI0_INT_N	BP19	CMOS	I
CD_HFI0_LED_N	BK21	OD	O
CD_HFI0_MODPRST_N	BR20	CMOS	I
CD_HFI0_RESET_N	BN24	OD	O
CD_HFI1_I2CCLK	BJ22	ODCMOS	I/O
CD_HFI1_I2CDAT	BH23	ODCMOS	I/O
CD_HFI1_INT_N	BM21	CMOS	I
CD_HFI1_LED_N	BM23	OD	O
CD_HFI1_MODPRST_N	BT19	CMOS	I
CD_HFI1_RESET_N	BK23	OD	O
CD_PE_REFCLK_DN	BU24	CMOS	I
CD_PE_REFCLK_DP	BW24	CMOS	I
CD_POR_N	CF25		

Table A-1. Pin List By Name (Sheet 2 of 90)

Pin Name	Location	Type	I/O
CD_TCLK	CB23		
CD_TDI	BY21	GTL	I
CD_TDO	CC22	OD	O
CD_TMS	CE24	GTL	I
CD_TRST_N	CD23	GTL	I
CD_VCC_CORE	BD13	PWR	
CD_VCC_CORE	BE12	PWR	
CD_VCC_CORE	BE14	PWR	
CD_VCC_CORE	BF11	PWR	
CD_VCC_CORE	BF13	PWR	
CD_VCC_CORE	BG12	PWR	
CD_VCC_CORE	BG14	PWR	
CD_VCC_CORE	BH13	PWR	
CD_VCC_CORE	BJ12	PWR	
CD_VCC_CORE	BJ14	PWR	
CD_VCC_CORE	BK13	PWR	
CD_VCC_CORE	BK15	PWR	
CD_VCC_CORE	BL14	PWR	
CD_VCC_CORE_SENSE	BN16	PWR	
CD_VCCIN	BT27	PWR	
CD_VCCIN	BU26	PWR	
CD_VCCIN	BV27	PWR	
CD_VCCIN	BY27	PWR	
CD_VCCP	BM11	PWR	
CD_VCCP	BN12	PWR	
CD_VCCP	BN14	PWR	
CD_VCCP	BP11	PWR	
CD_VCCP	BP13	PWR	
CD_VCCP	BP15	PWR	
CD_VCCP	BR12	PWR	
CD_VCCP	BR14	PWR	
CD_VCCP	BT11	PWR	
CD_VCCP	BT13	PWR	
CD_VCCP	BT15	PWR	
CD_VCCP	BU12	PWR	

Table A-1. Pin List By Name (Sheet 3 of 90)

Pin Name	Location	Type	I/O
CD_VCCP	BU14	PWR	
CD_VCCP	BV11	PWR	
CD_VCCP	BV13	PWR	
CD_VCCP	BV15	PWR	
CD_VCCP_SENSE	BT17	PWR	
CD_VPP	A10	PWR	
CD_VPP	A12	PWR	
CD_VPP	B11	PWR	
CD_VSS_VCC_CORE_SENSE	BL16	PWR	
CD_VSS_VCCP_SENSE	BU16	PWR	
DDR0_ACT_N	J60	SSTL	O
DDR0_ALERT_N	B61	SSTL	I
DDR0_BA[0]	C52	SSTL	O
DDR0_BA[1]	G54	SSTL	O
DDR0_BG[0]	D61	SSTL	O
DDR0_BG[1]	F63	SSTL	O
DDR0_CAVREF	AJ64	SSTL	O
DDR0_CID[2]	G46	SSTL	O
DDR0_CKE[0]	C62	SSTL	O
DDR0_CKE[1]	C64	SSTL	O
DDR0_CKE[2]	B63	SSTL	O
DDR0_CKE[3]	D63	SSTL	O
DDR0_CLK_DN[0]	F55	SSTL	O
DDR0_CLK_DN[1]	C54	SSTL	O
DDR0_CLK_DN[2]	J56	SSTL	O
DDR0_CLK_DN[3]	C56	SSTL	O
DDR0_CLK_DP[0]	D55	SSTL	O
DDR0_CLK_DP[1]	B55	SSTL	O
DDR0_CLK_DP[2]	G56	SSTL	O
DDR0_CLK_DP[3]	B57	SSTL	O
DDR0_CS_N[0]	G52	SSTL	O
DDR0_CS_N[1]	F49	SSTL	O
DDR0_CS_N[2]	D47	SSTL	O
DDR0_CS_N[3]	F47	SSTL	O
DDR0_CS_N[4]	B51	SSTL	O
DDR0_CS_N[5]	D49	SSTL	O
DDR0_CS_N[6]	F45	SSTL	O
DDR0_CS_N[7]	K45	SSTL	O
DDR0_DQ[0]	AN86	SSTL	I/O
DDR0_DQ[1]	AN84	SSTL	I/O
DDR0_DQ[10]	L86	SSTL	I/O

Table A-1. Pin List By Name (Sheet 4 of 90)

Pin Name	Location	Type	I/O
DDR0_DQ[11]	L84	SSTL	I/O
DDR0_DQ[12]	AA86	SSTL	I/O
DDR0_DQ[13]	AA84	SSTL	I/O
DDR0_DQ[14]	N86	SSTL	I/O
DDR0_DQ[15]	N84	SSTL	I/O
DDR0_DQ[16]	V81	SSTL	I/O
DDR0_DQ[17]	T79	SSTL	I/O
DDR0_DQ[18]	N82	SSTL	I/O
DDR0_DQ[19]	M81	SSTL	I/O
DDR0_DQ[2]	AE86	SSTL	I/O
DDR0_DQ[20]	W80	SSTL	I/O
DDR0_DQ[21]	V79	SSTL	I/O
DDR0_DQ[22]	R82	SSTL	I/O
DDR0_DQ[23]	N80	SSTL	I/O
DDR0_DQ[24]	L76	SSTL	I/O
DDR0_DQ[25]	R76	SSTL	I/O
DDR0_DQ[26]	M73	SSTL	I/O
DDR0_DQ[27]	P73	SSTL	I/O
DDR0_DQ[28]	M77	SSTL	I/O
DDR0_DQ[29]	P77	SSTL	I/O
DDR0_DQ[3]	AE84	SSTL	I/O
DDR0_DQ[30]	L74	SSTL	I/O
DDR0_DQ[31]	R74	SSTL	I/O
DDR0_DQ[32]	C42	SSTL	I/O
DDR0_DQ[33]	B41	SSTL	I/O
DDR0_DQ[34]	C38	SSTL	I/O
DDR0_DQ[35]	E38	SSTL	I/O
DDR0_DQ[36]	E42	SSTL	I/O
DDR0_DQ[37]	F41	SSTL	I/O
DDR0_DQ[38]	B39	SSTL	I/O
DDR0_DQ[39]	F39	SSTL	I/O
DDR0_DQ[4]	AR86	SSTL	I/O
DDR0_DQ[40]	K37	SSTL	I/O
DDR0_DQ[41]	P37	SSTL	I/O
DDR0_DQ[42]	L34	SSTL	I/O
DDR0_DQ[43]	N34	SSTL	I/O
DDR0_DQ[44]	L38	SSTL	I/O
DDR0_DQ[45]	N38	SSTL	I/O
DDR0_DQ[46]	K35	SSTL	I/O
DDR0_DQ[47]	P35	SSTL	I/O
DDR0_DQ[48]	K31	SSTL	I/O

Table A-1. Pin List By Name (Sheet 5 of 90)

Pin Name	Location	Type	I/O
DDR0_DQ[49]	P31	SSTL	I/O
DDR0_DQ[5]	AR84	SSTL	I/O
DDR0_DQ[50]	L28	SSTL	I/O
DDR0_DQ[51]	N28	SSTL	I/O
DDR0_DQ[52]	L32	SSTL	I/O
DDR0_DQ[53]	N32	SSTL	I/O
DDR0_DQ[54]	K29	SSTL	I/O
DDR0_DQ[55]	P29	SSTL	I/O
DDR0_DQ[56]	K25	SSTL	I/O
DDR0_DQ[57]	P25	SSTL	I/O
DDR0_DQ[58]	P23	SSTL	I/O
DDR0_DQ[59]	T23	SSTL	I/O
DDR0_DQ[6]	AG86	SSTL	I/O
DDR0_DQ[60]	L26	SSTL	I/O
DDR0_DQ[61]	N26	SSTL	I/O
DDR0_DQ[62]	H23	SSTL	I/O
DDR0_DQ[63]	K23	SSTL	I/O
DDR0_DQ[7]	AG84	SSTL	I/O
DDR0_DQ[8]	W86	SSTL	I/O
DDR0_DQ[9]	W84	SSTL	I/O
DDR0_DQS_DN[0]	AJ84	SSTL	I/O
DDR0_DQS_DN[1]	R84	SSTL	I/O
DDR0_DQS_DN[10]	U84	SSTL	I/O
DDR0_DQS_DN[11]	U82	SSTL	I/O
DDR0_DQS_DN[12]	K75	SSTL	I/O
DDR0_DQS_DN[13]	A40	SSTL	I/O
DDR0_DQS_DN[14]	J36	SSTL	I/O
DDR0_DQS_DN[15]	J30	SSTL	I/O
DDR0_DQS_DN[16]	J24	SSTL	I/O
DDR0_DQS_DN[17]	AB67	SSTL	I/O
DDR0_DQS_DN[2]	P79	SSTL	I/O
DDR0_DQS_DN[3]	T75	SSTL	I/O
DDR0_DQS_DN[4]	G40	SSTL	I/O
DDR0_DQS_DN[5]	R36	SSTL	I/O
DDR0_DQS_DN[6]	R30	SSTL	I/O
DDR0_DQS_DN[7]	N24	SSTL	I/O
DDR0_DQS_DN[8]	AH67	SSTL	I/O
DDR0_DQS_DN[9]	AL84	SSTL	I/O
DDR0_DQS_DP[0]	AH85	SSTL	I/O
DDR0_DQS_DP[1]	P85	SSTL	I/O
DDR0_DQS_DP[10]	V85	SSTL	I/O

Table A-1. Pin List By Name (Sheet 6 of 90)

Pin Name	Location	Type	I/O
DDR0_DQS_DP[11]	T81	SSTL	I/O
DDR0_DQS_DP[12]	M75	SSTL	I/O
DDR0_DQS_DP[13]	C40	SSTL	I/O
DDR0_DQS_DP[14]	L36	SSTL	I/O
DDR0_DQS_DP[15]	L30	SSTL	I/O
DDR0_DQS_DP[16]	L24	SSTL	I/O
DDR0_DQS_DP[17]	AD67	SSTL	I/O
DDR0_DQS_DP[2]	R80	SSTL	I/O
DDR0_DQS_DP[3]	P75	SSTL	I/O
DDR0_DQS_DP[4]	E40	SSTL	I/O
DDR0_DQS_DP[5]	N36	SSTL	I/O
DDR0_DQS_DP[6]	N30	SSTL	I/O
DDR0_DQS_DP[7]	R24	SSTL	I/O
DDR0_DQS_DP[8]	AF67	SSTL	I/O
DDR0_DQS_DP[9]	AM85	SSTL	I/O
DDR0_ECC[0]	AC68	SSTL	I/O
DDR0_ECC[1]	AG68	SSTL	I/O
DDR0_ECC[2]	AD65	SSTL	I/O
DDR0_ECC[3]	AF65	SSTL	I/O
DDR0_ECC[4]	AD69	SSTL	I/O
DDR0_ECC[5]	AF69	SSTL	I/O
DDR0_ECC[6]	AC66	SSTL	I/O
DDR0_ECC[7]	AG66	SSTL	I/O
DDR0_MA[0]	F53	SSTL	O
DDR0_MA[1]	F57	SSTL	O
DDR0_MA[10]	J54	SSTL	O
DDR0_MA[11]	G62	SSTL	O
DDR0_MA[12]	J64	SSTL	O
DDR0_MA[13]	J48	SSTL	O
DDR0_MA[14]	F51	SSTL	O
DDR0_MA[15]	K49	SSTL	O
DDR0_MA[16]	D51	SSTL	O
DDR0_MA[17]	K47	SSTL	O
DDR0_MA[2]	D57	SSTL	O
DDR0_MA[3]	C58	SSTL	O
DDR0_MA[4]	G58	SSTL	O
DDR0_MA[5]	F59	SSTL	O
DDR0_MA[6]	D59	SSTL	O
DDR0_MA[7]	G60	SSTL	O
DDR0_MA[8]	C60	SSTL	O
DDR0_MA[9]	F61	SSTL	O

Table A-1. Pin List By Name (Sheet 7 of 90)

Pin Name	Location	Type	I/O
DDR0_ODT[0]	C50	SSTL	O
DDR0_ODT[1]	C48	SSTL	O
DDR0_ODT[2]	G50	SSTL	O
DDR0_ODT[3]	G48	SSTL	O
DDR0_PAR	D53	SSTL	O
DDR012_DRAM_PWR_OK	AN30	CMOS	I
DDR012_RCOMP[0]	Y43		
DDR012_RCOMP[1]	AB43		
DDR012_RCOMP[2]	AC42		
DDR012_RESET_N	U64	CMOS	O
DDR012_SPDSCL	AJ18	ODCMOS	I/O
DDR012_SPDSDA	AF17	ODCMOS	I/O
DDR1_ACT_N	T63	SSTL	O
DDR1_ALERT_N	W62	SSTL	I
DDR1_BA[0]	T53	SSTL	O
DDR1_BA[1]	K55	SSTL	O
DDR1_BG[0]	M61	SSTL	O
DDR1_BG[1]	N60	SSTL	O
DDR1_CAVREF	AK63	SSTL	O
DDR1_CID[2]	M47	SSTL	O
DDR1_CKE[0]	N62	SSTL	O
DDR1_CKE[1]	R64	SSTL	O
DDR1_CKE[2]	K63	SSTL	O
DDR1_CKE[3]	L64	SSTL	O
DDR1_CLK_DN[0]	M53	SSTL	O
DDR1_CLK_DN[1]	R54	SSTL	O
DDR1_CLK_DN[2]	N56	SSTL	O
DDR1_CLK_DN[3]	R56	SSTL	O
DDR1_CLK_DP[0]	N54	SSTL	O
DDR1_CLK_DP[1]	T55	SSTL	O
DDR1_CLK_DP[2]	M57	SSTL	O
DDR1_CLK_DP[3]	T57	SSTL	O
DDR1_CS_N[0]	K51	SSTL	O
DDR1_CS_N[1]	R50	SSTL	O
DDR1_CS_N[2]	N46	SSTL	O
DDR1_CS_N[3]	V47	SSTL	O
DDR1_CS_N[4]	J50	SSTL	O
DDR1_CS_N[5]	T49	SSTL	O
DDR1_CS_N[6]	M45	SSTL	O
DDR1_CS_N[7]	R46	SSTL	O
DDR1_DQ[0]	AV81	SSTL	I/O

Table A-1. Pin List By Name (Sheet 8 of 90)

Pin Name	Location	Type	I/O
DDR1_DQ[1]	AT79	SSTL	I/O
DDR1_DQ[10]	AC82	SSTL	I/O
DDR1_DQ[11]	AB81	SSTL	I/O
DDR1_DQ[12]	AJ80	SSTL	I/O
DDR1_DQ[13]	AH79	SSTL	I/O
DDR1_DQ[14]	AE82	SSTL	I/O
DDR1_DQ[15]	AC80	SSTL	I/O
DDR1_DQ[16]	E80	SSTL	I/O
DDR1_DQ[17]	J80	SSTL	I/O
DDR1_DQ[18]	F77	SSTL	I/O
DDR1_DQ[19]	H77	SSTL	I/O
DDR1_DQ[2]	AN82	SSTL	I/O
DDR1_DQ[20]	F81	SSTL	I/O
DDR1_DQ[21]	H81	SSTL	I/O
DDR1_DQ[22]	E78	SSTL	I/O
DDR1_DQ[23]	J78	SSTL	I/O
DDR1_DQ[24]	D75	SSTL	I/O
DDR1_DQ[25]	C74	SSTL	I/O
DDR1_DQ[26]	D71	SSTL	I/O
DDR1_DQ[27]	F71	SSTL	I/O
DDR1_DQ[28]	F75	SSTL	I/O
DDR1_DQ[29]	G74	SSTL	I/O
DDR1_DQ[3]	AM81	SSTL	I/O
DDR1_DQ[30]	C72	SSTL	I/O
DDR1_DQ[31]	G72	SSTL	I/O
DDR1_DQ[32]	K43	SSTL	I/O
DDR1_DQ[33]	H43	SSTL	I/O
DDR1_DQ[34]	L40	SSTL	I/O
DDR1_DQ[35]	N40	SSTL	I/O
DDR1_DQ[36]	P43	SSTL	I/O
DDR1_DQ[37]	T43	SSTL	I/O
DDR1_DQ[38]	K41	SSTL	I/O
DDR1_DQ[39]	P41	SSTL	I/O
DDR1_DQ[4]	AW80	SSTL	I/O
DDR1_DQ[40]	C36	SSTL	I/O
DDR1_DQ[41]	B35	SSTL	I/O
DDR1_DQ[42]	C32	SSTL	I/O
DDR1_DQ[43]	E32	SSTL	I/O
DDR1_DQ[44]	E36	SSTL	I/O
DDR1_DQ[45]	F35	SSTL	I/O
DDR1_DQ[46]	B33	SSTL	I/O

Table A-1. Pin List By Name (Sheet 9 of 90)

Pin Name	Location	Type	I/O
DDR1_DQ[47]	F33	SSTL	I/O
DDR1_DQ[48]	C30	SSTL	I/O
DDR1_DQ[49]	B29	SSTL	I/O
DDR1_DQ[5]	AV79	SSTL	I/O
DDR1_DQ[50]	C26	SSTL	I/O
DDR1_DQ[51]	E26	SSTL	I/O
DDR1_DQ[52]	E30	SSTL	I/O
DDR1_DQ[53]	F29	SSTL	I/O
DDR1_DQ[54]	B27	SSTL	I/O
DDR1_DQ[55]	F27	SSTL	I/O
DDR1_DQ[56]	U28	SSTL	I/O
DDR1_DQ[57]	AA28	SSTL	I/O
DDR1_DQ[58]	V25	SSTL	I/O
DDR1_DQ[59]	Y25	SSTL	I/O
DDR1_DQ[6]	AR82	SSTL	I/O
DDR1_DQ[60]	V29	SSTL	I/O
DDR1_DQ[61]	Y29	SSTL	I/O
DDR1_DQ[62]	U26	SSTL	I/O
DDR1_DQ[63]	AA26	SSTL	I/O
DDR1_DQ[7]	AN80	SSTL	I/O
DDR1_DQ[8]	AH81	SSTL	I/O
DDR1_DQ[9]	AF79	SSTL	I/O
DDR1_DQS_DN[0]	AP79	SSTL	I/O
DDR1_DQS_DN[1]	AD79	SSTL	I/O
DDR1_DQS_DN[10]	AG82	SSTL	I/O
DDR1_DQS_DN[11]	D79	SSTL	I/O
DDR1_DQS_DN[12]	B73	SSTL	I/O
DDR1_DQS_DN[13]	J42	SSTL	I/O
DDR1_DQS_DN[14]	A34	SSTL	I/O
DDR1_DQS_DN[15]	A28	SSTL	I/O
DDR1_DQS_DN[16]	T27	SSTL	I/O
DDR1_DQS_DN[17]	G68	SSTL	I/O
DDR1_DQS_DN[2]	K79	SSTL	I/O
DDR1_DQS_DN[3]	H73	SSTL	I/O
DDR1_DQS_DN[4]	N42	SSTL	I/O
DDR1_DQS_DN[5]	G34	SSTL	I/O
DDR1_DQS_DN[6]	G28	SSTL	I/O
DDR1_DQS_DN[7]	AB27	SSTL	I/O
DDR1_DQS_DN[8]	N68	SSTL	I/O
DDR1_DQS_DN[9]	AU82	SSTL	I/O
DDR1_DQS_DP[0]	AR80	SSTL	I/O

Table A-1. Pin List By Name (Sheet 10 of 90)

Pin Name	Location	Type	I/O
DDR1_DQS_DP[1]	AE80	SSTL	I/O
DDR1_DQS_DP[10]	AF81	SSTL	I/O
DDR1_DQS_DP[11]	F79	SSTL	I/O
DDR1_DQS_DP[12]	D73	SSTL	I/O
DDR1_DQS_DP[13]	L42	SSTL	I/O
DDR1_DQS_DP[14]	C34	SSTL	I/O
DDR1_DQS_DP[15]	C28	SSTL	I/O
DDR1_DQS_DP[16]	V27	SSTL	I/O
DDR1_DQS_DP[17]	J68	SSTL	I/O
DDR1_DQS_DP[2]	H79	SSTL	I/O
DDR1_DQS_DP[3]	F73	SSTL	I/O
DDR1_DQS_DP[4]	R42	SSTL	I/O
DDR1_DQS_DP[5]	E34	SSTL	I/O
DDR1_DQS_DP[6]	E28	SSTL	I/O
DDR1_DQS_DP[7]	Y27	SSTL	I/O
DDR1_DQS_DP[8]	L68	SSTL	I/O
DDR1_DQS_DP[9]	AT81	SSTL	I/O
DDR1_ECC[0]	J70	SSTL	I/O
DDR1_ECC[1]	H69	SSTL	I/O
DDR1_ECC[2]	J66	SSTL	I/O
DDR1_ECC[3]	L66	SSTL	I/O
DDR1_ECC[4]	L70	SSTL	I/O
DDR1_ECC[5]	M69	SSTL	I/O
DDR1_ECC[6]	H67	SSTL	I/O
DDR1_ECC[7]	M67	SSTL	I/O
DDR1_MA[0]	J52	SSTL	O
DDR1_MA[1]	J58	SSTL	O
DDR1_MA[10]	M55	SSTL	O
DDR1_MA[11]	R60	SSTL	O
DDR1_MA[12]	T61	SSTL	O
DDR1_MA[13]	M51	SSTL	O
DDR1_MA[14]	T51	SSTL	O
DDR1_MA[15]	N52	SSTL	O
DDR1_MA[16]	R52	SSTL	O
DDR1_MA[17]	N48	SSTL	O
DDR1_MA[2]	K57	SSTL	O
DDR1_MA[3]	N58	SSTL	O
DDR1_MA[4]	M59	SSTL	O
DDR1_MA[5]	R58	SSTL	O
DDR1_MA[6]	T59	SSTL	O
DDR1_MA[7]	V61	SSTL	O

Table A-1. Pin List By Name (Sheet 11 of 90)

Pin Name	Location	Type	I/O
DDR1_MA[8]	W60	SSTL	O
DDR1_MA[9]	K59	SSTL	O
DDR1_ODT[0]	N50	SSTL	O
DDR1_ODT[1]	R48	SSTL	O
DDR1_ODT[2]	M49	SSTL	O
DDR1_ODT[3]	T47	SSTL	O
DDR1_PAR	K53	SSTL	O
DDR2_ACT_N	AB61	SSTL	O
DDR2_ALERT_N	AD61	SSTL	I
DDR2_BA[0]	W52	SSTL	O
DDR2_BA[1]	AE56	SSTL	O
DDR2_BG[0]	AA60	SSTL	O
DDR2_BG[1]	AE62	SSTL	O
DDR2_CAVREF	AH63	SSTL	O
DDR2_CID[2]	AB45	SSTL	O
DDR2_CKE[0]	AA62	SSTL	O
DDR2_CKE[1]	AD63	SSTL	O
DDR2_CKE[2]	V63	SSTL	O
DDR2_CKE[3]	AB63	SSTL	O
DDR2_CLK_DN[0]	AA54	SSTL	O
DDR2_CLK_DN[1]	W54	SSTL	O
DDR2_CLK_DN[2]	AA56	SSTL	O
DDR2_CLK_DN[3]	W56	SSTL	O
DDR2_CLK_DP[0]	AB55	SSTL	O
DDR2_CLK_DP[1]	V55	SSTL	O
DDR2_CLK_DP[2]	AB57	SSTL	O
DDR2_CLK_DP[3]	V57	SSTL	O
DDR2_CS_N[0]	V51	SSTL	O
DDR2_CS_N[1]	AB49	SSTL	O
DDR2_CS_N[2]	W46	SSTL	O
DDR2_CS_N[3]	AA46	SSTL	O
DDR2_CS_N[4]	AB51	SSTL	O
DDR2_CS_N[5]	W48	SSTL	O
DDR2_CS_N[6]	T45	SSTL	O
DDR2_CS_N[7]	V45	SSTL	O
DDR2_DQ[0]	AR76	SSTL	I/O
DDR2_DQ[1]	AN74	SSTL	I/O
DDR2_DQ[10]	Y77	SSTL	I/O
DDR2_DQ[11]	W76	SSTL	I/O
DDR2_DQ[12]	AF75	SSTL	I/O
DDR2_DQ[13]	AE74	SSTL	I/O

Table A-1. Pin List By Name (Sheet 12 of 90)

Pin Name	Location	Type	I/O
DDR2_DQ[14]	AB77	SSTL	I/O
DDR2_DQ[15]	Y75	SSTL	I/O
DDR2_DQ[16]	W72	SSTL	I/O
DDR2_DQ[17]	AA70	SSTL	I/O
DDR2_DQ[18]	R70	SSTL	I/O
DDR2_DQ[19]	T69	SSTL	I/O
DDR2_DQ[2]	AK77	SSTL	I/O
DDR2_DQ[20]	AA72	SSTL	I/O
DDR2_DQ[21]	AB71	SSTL	I/O
DDR2_DQ[22]	T71	SSTL	I/O
DDR2_DQ[23]	V69	SSTL	I/O
DDR2_DQ[24]	AM67	SSTL	I/O
DDR2_DQ[25]	AT67	SSTL	I/O
DDR2_DQ[26]	AN64	SSTL	I/O
DDR2_DQ[27]	AR64	SSTL	I/O
DDR2_DQ[28]	AN68	SSTL	I/O
DDR2_DQ[29]	AR68	SSTL	I/O
DDR2_DQ[3]	AJ76	SSTL	I/O
DDR2_DQ[30]	AM65	SSTL	I/O
DDR2_DQ[31]	AT65	SSTL	I/O
DDR2_DQ[32]	U40	SSTL	I/O
DDR2_DQ[33]	AA40	SSTL	I/O
DDR2_DQ[34]	V37	SSTL	I/O
DDR2_DQ[35]	Y37	SSTL	I/O
DDR2_DQ[36]	V41	SSTL	I/O
DDR2_DQ[37]	Y41	SSTL	I/O
DDR2_DQ[38]	U38	SSTL	I/O
DDR2_DQ[39]	AA38	SSTL	I/O
DDR2_DQ[4]	AT75	SSTL	I/O
DDR2_DQ[40]	U34	SSTL	I/O
DDR2_DQ[41]	AA34	SSTL	I/O
DDR2_DQ[42]	V31	SSTL	I/O
DDR2_DQ[43]	Y31	SSTL	I/O
DDR2_DQ[44]	V35	SSTL	I/O
DDR2_DQ[45]	Y35	SSTL	I/O
DDR2_DQ[46]	U32	SSTL	I/O
DDR2_DQ[47]	AA32	SSTL	I/O
DDR2_DQ[48]	AD31	SSTL	I/O
DDR2_DQ[49]	AH31	SSTL	I/O
DDR2_DQ[5]	AR74	SSTL	I/O
DDR2_DQ[50]	AE28	SSTL	I/O

Table A-1. Pin List By Name (Sheet 13 of 90)

Pin Name	Location	Type	I/O
DDR2_DQ[51]	AG28	SSTL	I/O
DDR2_DQ[52]	AE32	SSTL	I/O
DDR2_DQ[53]	AG32	SSTL	I/O
DDR2_DQ[54]	AD29	SSTL	I/O
DDR2_DQ[55]	AH29	SSTL	I/O
DDR2_DQ[56]	AD25	SSTL	I/O
DDR2_DQ[57]	AH25	SSTL	I/O
DDR2_DQ[58]	AE22	SSTL	I/O
DDR2_DQ[59]	AG22	SSTL	I/O
DDR2_DQ[6]	AM77	SSTL	I/O
DDR2_DQ[60]	AE26	SSTL	I/O
DDR2_DQ[61]	AG26	SSTL	I/O
DDR2_DQ[62]	AD23	SSTL	I/O
DDR2_DQ[63]	AH23	SSTL	I/O
DDR2_DQ[7]	AK75	SSTL	I/O
DDR2_DQ[8]	AE76	SSTL	I/O
DDR2_DQ[9]	AC74	SSTL	I/O
DDR2_DQS_DN[0]	AL74	SSTL	I/O
DDR2_DQS_DN[1]	AA74	SSTL	I/O
DDR2_DQS_DN[10]	AD77	SSTL	I/O
DDR2_DQS_DN[11]	U72	SSTL	I/O
DDR2_DQS_DN[12]	AL66	SSTL	I/O
DDR2_DQS_DN[13]	T39	SSTL	I/O
DDR2_DQS_DN[14]	T33	SSTL	I/O
DDR2_DQS_DN[15]	AC30	SSTL	I/O
DDR2_DQS_DN[16]	AC24	SSTL	I/O
DDR2_DQS_DN[17]	AT71	SSTL	I/O
DDR2_DQS_DN[2]	Y69	SSTL	I/O
DDR2_DQS_DN[3]	AU66	SSTL	I/O
DDR2_DQS_DN[4]	AB39	SSTL	I/O
DDR2_DQS_DN[5]	AB33	SSTL	I/O
DDR2_DQS_DN[6]	AJ30	SSTL	I/O
DDR2_DQS_DN[7]	AJ24	SSTL	I/O
DDR2_DQS_DN[8]	BB71	SSTL	I/O
DDR2_DQS_DN[9]	AP77	SSTL	I/O
DDR2_DQS_DP[0]	AM75	SSTL	I/O
DDR2_DQS_DP[1]	AB75	SSTL	I/O
DDR2_DQS_DP[10]	AC76	SSTL	I/O
DDR2_DQS_DP[11]	V71	SSTL	I/O
DDR2_DQS_DP[12]	AN66	SSTL	I/O
DDR2_DQS_DP[13]	V39	SSTL	I/O

Table A-1. Pin List By Name (Sheet 14 of 90)

Pin Name	Location	Type	I/O
DDR2_DQS_DP[14]	V33	SSTL	I/O
DDR2_DQS_DP[15]	AE30	SSTL	I/O
DDR2_DQS_DP[16]	AE24	SSTL	I/O
DDR2_DQS_DP[17]	AV71	SSTL	I/O
DDR2_DQS_DP[2]	W70	SSTL	I/O
DDR2_DQS_DP[3]	AR66	SSTL	I/O
DDR2_DQS_DP[4]	Y39	SSTL	I/O
DDR2_DQS_DP[5]	Y33	SSTL	I/O
DDR2_DQS_DP[6]	AG30	SSTL	I/O
DDR2_DQS_DP[7]	AG24	SSTL	I/O
DDR2_DQS_DP[8]	AY71	SSTL	I/O
DDR2_DQS_DP[9]	AN76	SSTL	I/O
DDR2_ECC[0]	AU72	SSTL	I/O
DDR2_ECC[1]	BA72	SSTL	I/O
DDR2_ECC[2]	AV69	SSTL	I/O
DDR2_ECC[3]	AY69	SSTL	I/O
DDR2_ECC[4]	AV73	SSTL	I/O
DDR2_ECC[5]	AY73	SSTL	I/O
DDR2_ECC[6]	AU70	SSTL	I/O
DDR2_ECC[7]	BA70	SSTL	I/O
DDR2_MA[0]	AB53	SSTL	O
DDR2_MA[1]	AE58	SSTL	O
DDR2_MA[10]	AD55	SSTL	O
DDR2_MA[11]	AG60	SSTL	O
DDR2_MA[12]	AG62	SSTL	O
DDR2_MA[13]	AD53	SSTL	O
DDR2_MA[14]	W50	SSTL	O
DDR2_MA[15]	AE54	SSTL	O
DDR2_MA[16]	AA52	SSTL	O
DDR2_MA[17]	AC46	SSTL	O
DDR2_MA[2]	AD57	SSTL	O
DDR2_MA[3]	W58	SSTL	O
DDR2_MA[4]	AA58	SSTL	O
DDR2_MA[5]	V59	SSTL	O
DDR2_MA[6]	AB59	SSTL	O
DDR2_MA[7]	AE60	SSTL	O
DDR2_MA[8]	AD59	SSTL	O
DDR2_MA[9]	AG58	SSTL	O
DDR2_ODT[0]	AA50	SSTL	O
DDR2_ODT[1]	AA48	SSTL	O
DDR2_ODT[2]	V49	SSTL	O

Table A-1. Pin List By Name (Sheet 15 of 90)

Pin Name	Location	Type	I/O
DDR2_ODT[3]	AB47	SSTL	O
DDR2_PAR	V53	SSTL	O
DDR3_ACT_N	DW60	SSTL	O
DDR3_ALERT_N	ED63	SSTL	I
DDR3_BA[0]	EE52	SSTL	O
DDR3_BA[1]	EA54	SSTL	O
DDR3_BG[0]	ED61	SSTL	O
DDR3_BG[1]	DW62	SSTL	O
DDR3_CAVREF	CP61	SSTL	O
DDR3_CID[2]	DV47	SSTL	O
DDR3_CKE[0]	EE62	SSTL	O
DDR3_CKE[1]	EF63	SSTL	O
DDR3_CKE[2]	EA62	SSTL	O
DDR3_CKE[3]	EB63	SSTL	O
DDR3_CLK_DN[0]	ED55	SSTL	O
DDR3_CLK_DN[1]	EF55	SSTL	O
DDR3_CLK_DN[2]	DW56	SSTL	O
DDR3_CLK_DN[3]	EF57	SSTL	O
DDR3_CLK_DP[0]	EB55	SSTL	O
DDR3_CLK_DP[1]	EE54	SSTL	O
DDR3_CLK_DP[2]	EA56	SSTL	O
DDR3_CLK_DP[3]	EE56	SSTL	O
DDR3_CS_N[0]	EF51	SSTL	O
DDR3_CS_N[1]	ED49	SSTL	O
DDR3_CS_N[2]	ED47	SSTL	O
DDR3_CS_N[3]	EB47	SSTL	O
DDR3_CS_N[4]	EB51	SSTL	O
DDR3_CS_N[5]	EB49	SSTL	O
DDR3_CS_N[6]	DV45	SSTL	O
DDR3_CS_N[7]	EB45	SSTL	O
DDR3_DQ[0]	CN84	SSTL	I/O
DDR3_DQ[1]	CN86	SSTL	I/O
DDR3_DQ[10]	DV83	SSTL	I/O
DDR3_DQ[11]	DY83	SSTL	I/O
DDR3_DQ[12]	DD85	SSTL	I/O
DDR3_DQ[13]	DE84	SSTL	I/O
DDR3_DQ[14]	DR84	SSTL	I/O
DDR3_DQ[15]	DV85	SSTL	I/O
DDR3_DQ[16]	DM79	SSTL	I/O
DDR3_DQ[17]	DK81	SSTL	I/O
DDR3_DQ[18]	DT81	SSTL	I/O

Table A-1. Pin List By Name (Sheet 16 of 90)

Pin Name	Location	Type	I/O
DDR3_DQ[19]	DR82	SSTL	I/O
DDR3_DQ[2]	DA86	SSTL	I/O
DDR3_DQ[20]	DK79	SSTL	I/O
DDR3_DQ[21]	DJ80	SSTL	I/O
DDR3_DQ[22]	DR80	SSTL	I/O
DDR3_DQ[23]	DN82	SSTL	I/O
DDR3_DQ[24]	DN76	SSTL	I/O
DDR3_DQ[25]	DU76	SSTL	I/O
DDR3_DQ[26]	DP73	SSTL	I/O
DDR3_DQ[27]	DT73	SSTL	I/O
DDR3_DQ[28]	DP77	SSTL	I/O
DDR3_DQ[29]	DT77	SSTL	I/O
DDR3_DQ[3]	DA84	SSTL	I/O
DDR3_DQ[30]	DN74	SSTL	I/O
DDR3_DQ[31]	DU74	SSTL	I/O
DDR3_DQ[32]	EC40	SSTL	I/O
DDR3_DQ[33]	ED39	SSTL	I/O
DDR3_DQ[34]	EA36	SSTL	I/O
DDR3_DQ[35]	EC36	SSTL	I/O
DDR3_DQ[36]	DY39	SSTL	I/O
DDR3_DQ[37]	EA40	SSTL	I/O
DDR3_DQ[38]	DY37	SSTL	I/O
DDR3_DQ[39]	ED37	SSTL	I/O
DDR3_DQ[4]	CL84	SSTL	I/O
DDR3_DQ[40]	DN36	SSTL	I/O
DDR3_DQ[41]	DU36	SSTL	I/O
DDR3_DQ[42]	DP33	SSTL	I/O
DDR3_DQ[43]	DT33	SSTL	I/O
DDR3_DQ[44]	DP37	SSTL	I/O
DDR3_DQ[45]	DT37	SSTL	I/O
DDR3_DQ[46]	DN34	SSTL	I/O
DDR3_DQ[47]	DU34	SSTL	I/O
DDR3_DQ[48]	DN30	SSTL	I/O
DDR3_DQ[49]	DU30	SSTL	I/O
DDR3_DQ[5]	CL86	SSTL	I/O
DDR3_DQ[50]	DP27	SSTL	I/O
DDR3_DQ[51]	DT27	SSTL	I/O
DDR3_DQ[52]	DP31	SSTL	I/O
DDR3_DQ[53]	DT31	SSTL	I/O
DDR3_DQ[54]	DN28	SSTL	I/O
DDR3_DQ[55]	DU28	SSTL	I/O

Table A-1. Pin List By Name (Sheet 17 of 90)

Pin Name	Location	Type	I/O
DDR3_DQ[56]	DN24	SSTL	I/O
DDR3_DQ[57]	DU24	SSTL	I/O
DDR3_DQ[58]	DY21	SSTL	I/O
DDR3_DQ[59]	EB21	SSTL	I/O
DDR3_DQ[6]	CW86	SSTL	I/O
DDR3_DQ[60]	DP25	SSTL	I/O
DDR3_DQ[61]	DT25	SSTL	I/O
DDR3_DQ[62]	EC22	SSTL	I/O
DDR3_DQ[63]	DW22	SSTL	I/O
DDR3_DQ[7]	CW84	SSTL	I/O
DDR3_DQ[8]	DG84	SSTL	I/O
DDR3_DQ[9]	DH85	SSTL	I/O
DDR3_DQS_DN[0]	CU84	SSTL	I/O
DDR3_DQS_DN[1]	DN84	SSTL	I/O
DDR3_DQS_DN[10]	DM85	SSTL	I/O
DDR3_DQS_DN[11]	DN80	SSTL	I/O
DDR3_DQS_DN[12]	DP75	SSTL	I/O
DDR3_DQS_DN[13]	EA38	SSTL	I/O
DDR3_DQS_DN[14]	DP35	SSTL	I/O
DDR3_DQS_DN[15]	DM29	SSTL	I/O
DDR3_DQS_DN[16]	DM23	SSTL	I/O
DDR3_DQS_DN[17]	DB67	SSTL	I/O
DDR3_DQS_DN[2]	DL82	SSTL	I/O
DDR3_DQS_DN[3]	DV75	SSTL	I/O
DDR3_DQS_DN[4]	EE38	SSTL	I/O
DDR3_DQS_DN[5]	DV35	SSTL	I/O
DDR3_DQS_DN[6]	DV29	SSTL	I/O
DDR3_DQS_DN[7]	DV23	SSTL	I/O
DDR3_DQS_DN[8]	DF67	SSTL	I/O
DDR3_DQS_DN[9]	CR84	SSTL	I/O
DDR3_DQS_DP[0]	CV85	SSTL	I/O
DDR3_DQS_DP[1]	DP85	SSTL	I/O
DDR3_DQS_DP[10]	DL84	SSTL	I/O
DDR3_DQS_DP[11]	DP79	SSTL	I/O
DDR3_DQS_DP[12]	DM75	SSTL	I/O
DDR3_DQS_DP[13]	DW38	SSTL	I/O
DDR3_DQS_DP[14]	DM35	SSTL	I/O
DDR3_DQS_DP[15]	DP29	SSTL	I/O
DDR3_DQS_DP[16]	DP23	SSTL	I/O
DDR3_DQS_DP[17]	CY67	SSTL	I/O
DDR3_DQS_DP[2]	DM81	SSTL	I/O

Table A-1. Pin List By Name (Sheet 18 of 90)

Pin Name	Location	Type	I/O
DDR3_DQS_DP[3]	DT75	SSTL	I/O
DDR3_DQS_DP[4]	EC38	SSTL	I/O
DDR3_DQS_DP[5]	DT35	SSTL	I/O
DDR3_DQS_DP[6]	DT29	SSTL	I/O
DDR3_DQS_DP[7]	DT23	SSTL	I/O
DDR3_DQS_DP[8]	DD67	SSTL	I/O
DDR3_DQS_DP[9]	CP85	SSTL	I/O
DDR3_ECC[0]	DA68	SSTL	I/O
DDR3_ECC[1]	DE68	SSTL	I/O
DDR3_ECC[2]	DB65	SSTL	I/O
DDR3_ECC[3]	DD65	SSTL	I/O
DDR3_ECC[4]	DB69	SSTL	I/O
DDR3_ECC[5]	DD69	SSTL	I/O
DDR3_ECC[6]	DA66	SSTL	I/O
DDR3_ECC[7]	DE66	SSTL	I/O
DDR3_MA[0]	EB53	SSTL	O
DDR3_MA[1]	ED57	SSTL	O
DDR3_MA[10]	DW54	SSTL	O
DDR3_MA[11]	EB61	SSTL	O
DDR3_MA[12]	DT63	SSTL	O
DDR3_MA[13]	DW48	SSTL	O
DDR3_MA[14]	ED51	SSTL	O
DDR3_MA[15]	DV49	SSTL	O
DDR3_MA[16]	EA52	SSTL	O
DDR3_MA[17]	EA46	SSTL	O
DDR3_MA[2]	EE58	SSTL	O
DDR3_MA[3]	EB57	SSTL	O
DDR3_MA[4]	ED59	SSTL	O
DDR3_MA[5]	EA58	SSTL	O
DDR3_MA[6]	EE60	SSTL	O
DDR3_MA[7]	EA60	SSTL	O
DDR3_MA[8]	EB59	SSTL	O
DDR3_MA[9]	EF61	SSTL	O
DDR3_ODT[0]	EE50	SSTL	O
DDR3_ODT[1]	EE48	SSTL	O
DDR3_ODT[2]	EA50	SSTL	O
DDR3_ODT[3]	EA48	SSTL	O
DDR3_PAR	ED53	SSTL	O
DDR345_DRAM_PWR_OK	CR28	CMOS	I
DDR345_RCOMP[0]	DC48		
DDR345_RCOMP[1]	DD47		

Table A-1. Pin List By Name (Sheet 19 of 90)

Pin Name	Location	Type	I/O
DDR345_RCOMP[2]	DD49		
DDR345_RESET_N	DV63	CMOS	O
DDR345_SPDSCL	AE18	ODCMOS	I/O
DDR345_SPDSDA	AD17	ODCMOS	I/O
DDR4_ACT_N	DR62	SSTL	O
DDR4_ALERT_N	DT61	SSTL	I
DDR4_BA[0]	DM53	SSTL	O
DDR4_BA[1]	DV55	SSTL	O
DDR4_BG[0]	DJ62	SSTL	O
DDR4_BG[1]	DM61	SSTL	O
DDR4_CAVREF	CT61	SSTL	O
DDR4_CID[2]	DT47	SSTL	O
DDR4_CKE[0]	DM63	SSTL	O
DDR4_CKE[1]	DN64	SSTL	O
DDR4_CKE[2]	DL64	SSTL	O
DDR4_CKE[3]	DR64	SSTL	O
DDR4_CLK_DN[0]	DM55	SSTL	O
DDR4_CLK_DN[1]	DR54	SSTL	O
DDR4_CLK_DN[2]	DM57	SSTL	O
DDR4_CLK_DN[3]	DT57	SSTL	O
DDR4_CLK_DP[0]	DN54	SSTL	O
DDR4_CLK_DP[1]	DT53	SSTL	O
DDR4_CLK_DP[2]	DN56	SSTL	O
DDR4_CLK_DP[3]	DR56	SSTL	O
DDR4_CS_N[0]	DV51	SSTL	O
DDR4_CS_N[1]	DN50	SSTL	O
DDR4_CS_N[2]	DR46	SSTL	O
DDR4_CS_N[3]	DK47	SSTL	O
DDR4_CS_N[4]	DW50	SSTL	O
DDR4_CS_N[5]	DM49	SSTL	O
DDR4_CS_N[6]	DT45	SSTL	O
DDR4_CS_N[7]	DN46	SSTL	O
DDR4_DQ[0]	CM79	SSTL	I/O
DDR4_DQ[1]	CK81	SSTL	I/O
DDR4_DQ[10]	DE80	SSTL	I/O
DDR4_DQ[11]	DF81	SSTL	I/O
DDR4_DQ[12]	CY79	SSTL	I/O
DDR4_DQ[13]	CW80	SSTL	I/O
DDR4_DQ[14]	DC82	SSTL	I/O
DDR4_DQ[15]	DE82	SSTL	I/O
DDR4_DQ[16]	DW80	SSTL	I/O

Table A-1. Pin List By Name (Sheet 20 of 90)

Pin Name	Location	Type	I/O
DDR4_DQ[17]	EC80	SSTL	I/O
DDR4_DQ[18]	DY77	SSTL	I/O
DDR4_DQ[19]	EB77	SSTL	I/O
DDR4_DQ[2]	CT81	SSTL	I/O
DDR4_DQ[20]	DY81	SSTL	I/O
DDR4_DQ[21]	EB81	SSTL	I/O
DDR4_DQ[22]	DW78	SSTL	I/O
DDR4_DQ[23]	EC78	SSTL	I/O
DDR4_DQ[24]	ED75	SSTL	I/O
DDR4_DQ[25]	EE74	SSTL	I/O
DDR4_DQ[26]	EB71	SSTL	I/O
DDR4_DQ[27]	ED71	SSTL	I/O
DDR4_DQ[28]	EA74	SSTL	I/O
DDR4_DQ[29]	EB75	SSTL	I/O
DDR4_DQ[3]	CR82	SSTL	I/O
DDR4_DQ[30]	EA72	SSTL	I/O
DDR4_DQ[31]	EE72	SSTL	I/O
DDR4_DQ[32]	DU42	SSTL	I/O
DDR4_DQ[33]	DW42	SSTL	I/O
DDR4_DQ[34]	DP39	SSTL	I/O
DDR4_DQ[35]	DT39	SSTL	I/O
DDR4_DQ[36]	DL42	SSTL	I/O
DDR4_DQ[37]	DN42	SSTL	I/O
DDR4_DQ[38]	DN40	SSTL	I/O
DDR4_DQ[39]	DU40	SSTL	I/O
DDR4_DQ[4]	CK79	SSTL	I/O
DDR4_DQ[40]	EC34	SSTL	I/O
DDR4_DQ[41]	ED33	SSTL	I/O
DDR4_DQ[42]	EA30	SSTL	I/O
DDR4_DQ[43]	EC30	SSTL	I/O
DDR4_DQ[44]	DY33	SSTL	I/O
DDR4_DQ[45]	EA34	SSTL	I/O
DDR4_DQ[46]	DY31	SSTL	I/O
DDR4_DQ[47]	ED31	SSTL	I/O
DDR4_DQ[48]	EC28	SSTL	I/O
DDR4_DQ[49]	ED27	SSTL	I/O
DDR4_DQ[5]	CJ80	SSTL	I/O
DDR4_DQ[50]	EA24	SSTL	I/O
DDR4_DQ[51]	EC24	SSTL	I/O
DDR4_DQ[52]	DY27	SSTL	I/O
DDR4_DQ[53]	EA28	SSTL	I/O

Table A-1. Pin List By Name (Sheet 21 of 90)

Pin Name	Location	Type	I/O
DDR4_DQ[54]	DY25	SSTL	I/O
DDR4_DQ[55]	ED25	SSTL	I/O
DDR4_DQ[56]	DF27	SSTL	I/O
DDR4_DQ[57]	DK27	SSTL	I/O
DDR4_DQ[58]	DD25	SSTL	I/O
DDR4_DQ[59]	DJ24	SSTL	I/O
DDR4_DQ[6]	CR80	SSTL	I/O
DDR4_DQ[60]	DG28	SSTL	I/O
DDR4_DQ[61]	DJ28	SSTL	I/O
DDR4_DQ[62]	DF25	SSTL	I/O
DDR4_DQ[63]	DK25	SSTL	I/O
DDR4_DQ[7]	CN82	SSTL	I/O
DDR4_DQ[8]	DB79	SSTL	I/O
DDR4_DQ[9]	CY81	SSTL	I/O
DDR4_DQS_DN[0]	CL82	SSTL	I/O
DDR4_DQS_DN[1]	DA82	SSTL	I/O
DDR4_DQS_DN[10]	DC80	SSTL	I/O
DDR4_DQS_DN[11]	DY79	SSTL	I/O
DDR4_DQS_DN[12]	EB73	SSTL	I/O
DDR4_DQS_DN[13]	DP41	SSTL	I/O
DDR4_DQS_DN[14]	EA32	SSTL	I/O
DDR4_DQS_DN[15]	EA26	SSTL	I/O
DDR4_DQS_DN[16]	DG26	SSTL	I/O
DDR4_DQS_DN[17]	DV67	SSTL	I/O
DDR4_DQS_DN[2]	ED79	SSTL	I/O
DDR4_DQS_DN[3]	EF73	SSTL	I/O
DDR4_DQS_DN[4]	DV41	SSTL	I/O
DDR4_DQS_DN[5]	EE32	SSTL	I/O
DDR4_DQS_DN[6]	EE26	SSTL	I/O
DDR4_DQS_DN[7]	DL26	SSTL	I/O
DDR4_DQS_DN[8]	EB67	SSTL	I/O
DDR4_DQS_DN[9]	CN80	SSTL	I/O
DDR4_DQS_DP[0]	CM81	SSTL	I/O
DDR4_DQS_DP[1]	DB81	SSTL	I/O
DDR4_DQS_DP[10]	DD79	SSTL	I/O
DDR4_DQS_DP[11]	DV79	SSTL	I/O
DDR4_DQS_DP[12]	DY73	SSTL	I/O
DDR4_DQS_DP[13]	DM41	SSTL	I/O
DDR4_DQS_DP[14]	DW32	SSTL	I/O
DDR4_DQS_DP[15]	DW26	SSTL	I/O
DDR4_DQS_DP[16]	DE26	SSTL	I/O

Table A-1. Pin List By Name (Sheet 22 of 90)

Pin Name	Location	Type	I/O
DDR4_DQS_DP[17]	DT67	SSTL	I/O
DDR4_DQS_DP[2]	EB79	SSTL	I/O
DDR4_DQS_DP[3]	ED73	SSTL	I/O
DDR4_DQS_DP[4]	DT41	SSTL	I/O
DDR4_DQS_DP[5]	EC32	SSTL	I/O
DDR4_DQS_DP[6]	EC26	SSTL	I/O
DDR4_DQS_DP[7]	DJ26	SSTL	I/O
DDR4_DQS_DP[8]	DY67	SSTL	I/O
DDR4_DQS_DP[9]	CP79	SSTL	I/O
DDR4_ECC[0]	DY69	SSTL	I/O
DDR4_ECC[1]	EA68	SSTL	I/O
DDR4_ECC[2]	DV65	SSTL	I/O
DDR4_ECC[3]	DY65	SSTL	I/O
DDR4_ECC[4]	DU68	SSTL	I/O
DDR4_ECC[5]	DV69	SSTL	I/O
DDR4_ECC[6]	DU66	SSTL	I/O
DDR4_ECC[7]	EA66	SSTL	I/O
DDR4_MA[0]	DW52	SSTL	O
DDR4_MA[1]	DW58	SSTL	O
DDR4_MA[10]	DT55	SSTL	O
DDR4_MA[11]	DR60	SSTL	O
DDR4_MA[12]	DN60	SSTL	O
DDR4_MA[13]	DT51	SSTL	O
DDR4_MA[14]	DM51	SSTL	O
DDR4_MA[15]	DR52	SSTL	O
DDR4_MA[16]	DN52	SSTL	O
DDR4_MA[17]	DR48	SSTL	O
DDR4_MA[2]	DV57	SSTL	O
DDR4_MA[3]	DR58	SSTL	O
DDR4_MA[4]	DT59	SSTL	O
DDR4_MA[5]	DN58	SSTL	O
DDR4_MA[6]	DM59	SSTL	O
DDR4_MA[7]	DK61	SSTL	O
DDR4_MA[8]	DJ60	SSTL	O
DDR4_MA[9]	DV59	SSTL	O
DDR4_ODT[0]	DR50	SSTL	O
DDR4_ODT[1]	DN48	SSTL	O
DDR4_ODT[2]	DT49	SSTL	O
DDR4_ODT[3]	DM47	SSTL	O
DDR4_PAR	DV53	SSTL	O
DDR5_ACT_N	DC62	SSTL	O

Table A-1. Pin List By Name (Sheet 23 of 90)

Pin Name	Location	Type	I/O
DDR5_ALERT_N	DD61	SSTL	I
DDR5_BA[0]	DJ52	SSTL	O
DDR5_BA[1]	DC56	SSTL	O
DDR5_BG[0]	DA62	SSTL	O
DDR5_BG[1]	DF61	SSTL	O
DDR5_CAVREF	CV61	SSTL	O
DDR5_CID[2]	DF45	SSTL	O
DDR5_CKE[0]	DG62	SSTL	O
DDR5_CKE[1]	DD63	SSTL	O
DDR5_CKE[2]	DK63	SSTL	O
DDR5_CKE[3]	DF63	SSTL	O
DDR5_CLK_DN[0]	DK55	SSTL	O
DDR5_CLK_DN[1]	DF55	SSTL	O
DDR5_CLK_DN[2]	DK57	SSTL	O
DDR5_CLK_DN[3]	DF57	SSTL	O
DDR5_CLK_DP[0]	DJ54	SSTL	O
DDR5_CLK_DP[1]	DG54	SSTL	O
DDR5_CLK_DP[2]	DJ56	SSTL	O
DDR5_CLK_DP[3]	DG56	SSTL	O
DDR5_CS_N[0]	DK51	SSTL	O
DDR5_CS_N[1]	DF49	SSTL	O
DDR5_CS_N[2]	DJ46	SSTL	O
DDR5_CS_N[3]	DG46	SSTL	O
DDR5_CS_N[4]	DF51	SSTL	O
DDR5_CS_N[5]	DJ48	SSTL	O
DDR5_CS_N[6]	DM45	SSTL	O
DDR5_CS_N[7]	DK45	SSTL	O
DDR5_DQ[0]	CR74	SSTL	I/O
DDR5_DQ[1]	CN76	SSTL	I/O
DDR5_DQ[10]	DH75	SSTL	I/O
DDR5_DQ[11]	DJ76	SSTL	I/O
DDR5_DQ[12]	DC74	SSTL	I/O
DDR5_DQ[13]	DB75	SSTL	I/O
DDR5_DQ[14]	DF77	SSTL	I/O
DDR5_DQ[15]	DH77	SSTL	I/O
DDR5_DQ[16]	DG70	SSTL	I/O
DDR5_DQ[17]	DJ72	SSTL	I/O
DDR5_DQ[18]	DM69	SSTL	I/O
DDR5_DQ[19]	DN70	SSTL	I/O
DDR5_DQ[2]	CW76	SSTL	I/O
DDR5_DQ[20]	DF71	SSTL	I/O

Table A-1. Pin List By Name (Sheet 24 of 90)

Pin Name	Location	Type	I/O
DDR5_DQ[21]	DG72	SSTL	I/O
DDR5_DQ[22]	DK69	SSTL	I/O
DDR5_DQ[23]	DM71	SSTL	I/O
DDR5_DQ[24]	CN66	SSTL	I/O
DDR5_DQ[25]	CU66	SSTL	I/O
DDR5_DQ[26]	CP63	SSTL	I/O
DDR5_DQ[27]	CT63	SSTL	I/O
DDR5_DQ[28]	CP67	SSTL	I/O
DDR5_DQ[29]	CT67	SSTL	I/O
DDR5_DQ[3]	CV77	SSTL	I/O
DDR5_DQ[30]	CN64	SSTL	I/O
DDR5_DQ[31]	CU64	SSTL	I/O
DDR5_DQ[32]	DD41	SSTL	I/O
DDR5_DQ[33]	DG42	SSTL	I/O
DDR5_DQ[34]	DE38	SSTL	I/O
DDR5_DQ[35]	DG38	SSTL	I/O
DDR5_DQ[36]	DA42	SSTL	I/O
DDR5_DQ[37]	DE42	SSTL	I/O
DDR5_DQ[38]	DD39	SSTL	I/O
DDR5_DQ[39]	DH39	SSTL	I/O
DDR5_DQ[4]	CN74	SSTL	I/O
DDR5_DQ[40]	DF33	SSTL	I/O
DDR5_DQ[41]	DK33	SSTL	I/O
DDR5_DQ[42]	DG30	SSTL	I/O
DDR5_DQ[43]	DJ30	SSTL	I/O
DDR5_DQ[44]	DG34	SSTL	I/O
DDR5_DQ[45]	DJ34	SSTL	I/O
DDR5_DQ[46]	DF31	SSTL	I/O
DDR5_DQ[47]	DK31	SSTL	I/O
DDR5_DQ[48]	CW36	SSTL	I/O
DDR5_DQ[49]	DC36	SSTL	I/O
DDR5_DQ[5]	CM75	SSTL	I/O
DDR5_DQ[50]	CY33	SSTL	I/O
DDR5_DQ[51]	DB33	SSTL	I/O
DDR5_DQ[52]	CY37	SSTL	I/O
DDR5_DQ[53]	DB37	SSTL	I/O
DDR5_DQ[54]	CW34	SSTL	I/O
DDR5_DQ[55]	DC34	SSTL	I/O
DDR5_DQ[56]	CW30	SSTL	I/O
DDR5_DQ[57]	DC30	SSTL	I/O
DDR5_DQ[58]	CY27	SSTL	I/O

Table A-1. Pin List By Name (Sheet 25 of 90)

Pin Name	Location	Type	I/O
DDR5_DQ[59]	DB27	SSTL	I/O
DDR5_DQ[6]	CV75	SSTL	I/O
DDR5_DQ[60]	CY31	SSTL	I/O
DDR5_DQ[61]	DB31	SSTL	I/O
DDR5_DQ[62]	CW28	SSTL	I/O
DDR5_DQ[63]	DC28	SSTL	I/O
DDR5_DQ[7]	CT77	SSTL	I/O
DDR5_DQ[8]	DE74	SSTL	I/O
DDR5_DQ[9]	DC76	SSTL	I/O
DDR5_DQS_DN[0]	CP77	SSTL	I/O
DDR5_DQS_DN[1]	DD77	SSTL	I/O
DDR5_DQS_DN[10]	DF75	SSTL	I/O
DDR5_DQS_DN[11]	DJ70	SSTL	I/O
DDR5_DQS_DN[12]	CP65	SSTL	I/O
DDR5_DQS_DN[13]	DE40	SSTL	I/O
DDR5_DQS_DN[14]	DG32	SSTL	I/O
DDR5_DQS_DN[15]	CY35	SSTL	I/O
DDR5_DQS_DN[16]	CY29	SSTL	I/O
DDR5_DQS_DN[17]	CJ70	SSTL	I/O
DDR5_DQS_DN[2]	DL72	SSTL	I/O
DDR5_DQS_DN[3]	CV65	SSTL	I/O
DDR5_DQS_DN[4]	DG40	SSTL	I/O
DDR5_DQS_DN[5]	DL32	SSTL	I/O
DDR5_DQS_DN[6]	DD35	SSTL	I/O
DDR5_DQS_DN[7]	DD29	SSTL	I/O
DDR5_DQS_DN[8]	CN70	SSTL	I/O
DDR5_DQS_DN[9]	CT75	SSTL	I/O
DDR5_DQS_DP[0]	CR76	SSTL	I/O
DDR5_DQS_DP[1]	DE76	SSTL	I/O
DDR5_DQS_DP[10]	DG74	SSTL	I/O
DDR5_DQS_DP[11]	DH69	SSTL	I/O
DDR5_DQS_DP[12]	CM65	SSTL	I/O
DDR5_DQS_DP[13]	DC40	SSTL	I/O
DDR5_DQS_DP[14]	DE32	SSTL	I/O
DDR5_DQS_DP[15]	CV35	SSTL	I/O
DDR5_DQS_DP[16]	CV29	SSTL	I/O
DDR5_DQS_DP[17]	CG70	SSTL	I/O
DDR5_DQS_DP[2]	DK71	SSTL	I/O
DDR5_DQS_DP[3]	CT65	SSTL	I/O
DDR5_DQS_DP[4]	DJ40	SSTL	I/O
DDR5_DQS_DP[5]	DJ32	SSTL	I/O

Table A-1. Pin List By Name (Sheet 26 of 90)

Pin Name	Location	Type	I/O
DDR5_DQS_DP[6]	DB35	SSTL	I/O
DDR5_DQS_DP[7]	DB29	SSTL	I/O
DDR5_DQS_DP[8]	CL70	SSTL	I/O
DDR5_DQS_DP[9]	CU74	SSTL	I/O
DDR5_ECC[0]	CH71	SSTL	I/O
DDR5_ECC[1]	CM71	SSTL	I/O
DDR5_ECC[2]	CJ68	SSTL	I/O
DDR5_ECC[3]	CL68	SSTL	I/O
DDR5_ECC[4]	CJ72	SSTL	I/O
DDR5_ECC[5]	CL72	SSTL	I/O
DDR5_ECC[6]	CH69	SSTL	I/O
DDR5_ECC[7]	CM69	SSTL	I/O
DDR5_MA[0]	DF53	SSTL	O
DDR5_MA[1]	DC58	SSTL	O
DDR5_MA[10]	DD55	SSTL	O
DDR5_MA[11]	DA60	SSTL	O
DDR5_MA[12]	DG60	SSTL	O
DDR5_MA[13]	DD53	SSTL	O
DDR5_MA[14]	DJ50	SSTL	O
DDR5_MA[15]	DC54	SSTL	O
DDR5_MA[16]	DG52	SSTL	O
DDR5_MA[17]	DE46	SSTL	O
DDR5_MA[2]	DD57	SSTL	O
DDR5_MA[3]	DG58	SSTL	O
DDR5_MA[4]	DJ58	SSTL	O
DDR5_MA[5]	DF59	SSTL	O
DDR5_MA[6]	DK59	SSTL	O
DDR5_MA[7]	DC60	SSTL	O
DDR5_MA[8]	DD59	SSTL	O
DDR5_MA[9]	DA58	SSTL	O
DDR5_ODT[0]	DG50	SSTL	O
DDR5_ODT[1]	DG48	SSTL	O
DDR5_ODT[2]	DK49	SSTL	O
DDR5_ODT[3]	DF47	SSTL	O
DDR5_PAR	DK53	SSTL	O
DEBUG_EN_N	AV21	CMOS	I/O
DMI_RX_DN[0]	CK9	PCIEX	I
DMI_RX_DN[1]	CM11	PCIEX	I
DMI_RX_DN[2]	CR12	PCIEX	I
DMI_RX_DN[3]	CT11	PCIEX	I
DMI_RX_DP[0]	CL10	PCIEX	I

Table A-1. Pin List By Name (Sheet 27 of 90)

Pin Name	Location	Type	I/O
DMI_RX_DP[1]	CN10	PCIEX	I
DMI_RX_DP[2]	CP11	PCIEX	I
DMI_RX_DP[3]	CV11	PCIEX	I
DMI_TX_DN[0]	CG4	PCIEX	O
DMI_TX_DN[1]	CJ4	PCIEX	O
DMI_TX_DN[2]	CN4	PCIEX	O
DMI_TX_DN[3]	CP5	PCIEX	O
DMI_TX_DP[0]	CH5	PCIEX	O
DMI_TX_DP[1]	CL4	PCIEX	O
DMI_TX_DP[2]	CM3	PCIEX	O
DMI_TX_DP[3]	CR4	PCIEX	O
DMIMODE_OVERRIDE	AW12	CMOS	I/O
EAR_N	AJ14	CMOS	I
ERROR_N[0]	AJ12	OD	O
ERROR_N[1]	AK11	OD	O
ERROR_N[2]	AL12	OD	O
FIVR_FAULT	AU14	CMOS	O
FRMAGENT	AV17	CMOS	I
LEGACY_SKT	AE20	CMOS	I
MCP01_RBIAS	CT31		
MCP01_RBIAS	CU32		
MEM_HOT_C012_N	AH13	ODCMOS	I/O
MEM_HOT_C345_N	AF13	ODCMOS	I/O
MSMI_N	AN20	CMOS	I/O
NMI	AP11	CMOS	I
PE_HP_SCL	AM19	ODCMOS	I/O
PE_HP_SDA	AL18	ODCMOS	I/O
PE012_RBIAS	CL30		
PE012_RBIAS	CN30		
PE1_RX_DN[0]	CW8	PCIEX3	I
PE1_RX_DN[1]	DA8	PCIEX3	I
PE1_RX_DN[10]	DT11	PCIEX3	I
PE1_RX_DN[11]	DT13	PCIEX3	I
PE1_RX_DN[12]	DV13	PCIEX3	I
PE1_RX_DN[13]	DW14	PCIEX3	I
PE1_RX_DN[14]	DY15	PCIEX3	I
PE1_RX_DN[15]	DU16	PCIEX3	I
PE1_RX_DN[2]	DC8	PCIEX3	I
PE1_RX_DN[3]	DC10	PCIEX3	I
PE1_RX_DN[4]	DE10	PCIEX3	I
PE1_RX_DN[5]	DH9	PCIEX3	I

Table A-1. Pin List By Name (Sheet 28 of 90)

Pin Name	Location	Type	I/O
PE1_RX_DN[6]	DK9	PCIEX3	I
PE1_RX_DN[7]	DM9	PCIEX3	I
PE1_RX_DN[8]	DM11	PCIEX3	I
PE1_RX_DN[9]	DP11	PCIEX3	I
PE1_RX_DP[0]	CU8	PCIEX3	I
PE1_RX_DP[1]	CY7	PCIEX3	I
PE1_RX_DP[10]	DR12	PCIEX3	I
PE1_RX_DP[11]	DP13	PCIEX3	I
PE1_RX_DP[12]	DU12	PCIEX3	I
PE1_RX_DP[13]	DY13	PCIEX3	I
PE1_RX_DP[14]	DV15	PCIEX3	I
PE1_RX_DP[15]	DT15	PCIEX3	I
PE1_RX_DP[2]	DB9	PCIEX3	I
PE1_RX_DP[3]	DA10	PCIEX3	I
PE1_RX_DP[4]	DD9	PCIEX3	I
PE1_RX_DP[5]	DF9	PCIEX3	I
PE1_RX_DP[6]	DJ8	PCIEX3	I
PE1_RX_DP[7]	DL10	PCIEX3	I
PE1_RX_DP[8]	DK11	PCIEX3	I
PE1_RX_DP[9]	DN10	PCIEX3	I
PE1_TX_DN[0]	DA2	PCIEX3	O
PE1_TX_DN[1]	DC2	PCIEX3	O
PE1_TX_DN[10]	DW4	PCIEX3	O
PE1_TX_DN[11]	DU6	PCIEX3	O
PE1_TX_DN[12]	DV7	PCIEX3	O
PE1_TX_DN[13]	DY7	PCIEX3	O
PE1_TX_DN[14]	EA8	PCIEX3	O
PE1_TX_DN[15]	ED9	PCIEX3	O
PE1_TX_DN[2]	DE2	PCIEX3	O
PE1_TX_DN[3]	DE4	PCIEX3	O
PE1_TX_DN[4]	DG4	PCIEX3	O
PE1_TX_DN[5]	DK3	PCIEX3	O
PE1_TX_DN[6]	DM3	PCIEX3	O
PE1_TX_DN[7]	DN4	PCIEX3	O
PE1_TX_DN[8]	DT5	PCIEX3	O
PE1_TX_DN[9]	DV3	PCIEX3	O
PE1_TX_DP[0]	CW2	PCIEX3	O
PE1_TX_DP[1]	DB1	PCIEX3	O
PE1_TX_DP[10]	DU4	PCIEX3	O
PE1_TX_DP[11]	DV5	PCIEX3	O
PE1_TX_DP[12]	DT7	PCIEX3	O

Table A-1. Pin List By Name (Sheet 29 of 90)

Pin Name	Location	Type	I/O
PE1_TX_DP[13]	DW6	PCIEX3	O
PE1_TX_DP[14]	EB7	PCIEX3	O
PE1_TX_DP[15]	EC8	PCIEX3	O
PE1_TX_DP[2]	DD3	PCIEX3	O
PE1_TX_DP[3]	DC4	PCIEX3	O
PE1_TX_DP[4]	DF3	PCIEX3	O
PE1_TX_DP[5]	DH3	PCIEX3	O
PE1_TX_DP[6]	DL2	PCIEX3	O
PE1_TX_DP[7]	DP3	PCIEX3	O
PE1_TX_DP[8]	DR4	PCIEX3	O
PE1_TX_DP[9]	DU2	PCIEX3	O
PE2_RX_DN[0]	CT9	PCIEX3	I
PE2_RX_DN[1]	CP9	PCIEX3	I
PE2_RX_DN[10]	BV7	PCIEX3	I
PE2_RX_DN[11]	BT7	PCIEX3	I
PE2_RX_DN[12]	BR8	PCIEX3	I
PE2_RX_DN[13]	BN8	PCIEX3	I
PE2_RX_DN[14]	BL8	PCIEX3	I
PE2_RX_DN[15]	BK9	PCIEX3	I
PE2_RX_DN[2]	CP7	PCIEX3	I
PE2_RX_DN[3]	CM7	PCIEX3	I
PE2_RX_DN[4]	CK7	PCIEX3	I
PE2_RX_DN[5]	CG8	PCIEX3	I
PE2_RX_DN[6]	CE6	PCIEX3	I
PE2_RX_DN[7]	CE8	PCIEX3	I
PE2_RX_DN[8]	BY9	PCIEX3	I
PE2_RX_DN[9]	BY7	PCIEX3	I
PE2_RX_DP[0]	CR8	PCIEX3	I
PE2_RX_DP[1]	CM9	PCIEX3	I
PE2_RX_DP[10]	BU6	PCIEX3	I
PE2_RX_DP[11]	BP7	PCIEX3	I
PE2_RX_DP[12]	BP9	PCIEX3	I
PE2_RX_DP[13]	BM7	PCIEX3	I
PE2_RX_DP[14]	BJ8	PCIEX3	I
PE2_RX_DP[15]	BJ10	PCIEX3	I
PE2_RX_DP[2]	CN8	PCIEX3	I
PE2_RX_DP[3]	CL6	PCIEX3	I
PE2_RX_DP[4]	CH7	PCIEX3	I
PE2_RX_DP[5]	CF7	PCIEX3	I
PE2_RX_DP[6]	CD7	PCIEX3	I
PE2_RX_DP[7]	CC8	PCIEX3	I

Table A-1. Pin List By Name (Sheet 30 of 90)

Pin Name	Location	Type	I/O
PE2_RX_DP[8]	BV9	PCIEX3	I
PE2_RX_DP[9]	BW8	PCIEX3	I
PE2_TX_DN[0]	CY3	PCIEX3	O
PE2_TX_DN[1]	CV3	PCIEX3	O
PE2_TX_DN[10]	CA4	PCIEX3	O
PE2_TX_DN[11]	BW4	PCIEX3	O
PE2_TX_DN[12]	BU4	PCIEX3	O
PE2_TX_DN[13]	BP5	PCIEX3	O
PE2_TX_DN[14]	BL4	PCIEX3	O
PE2_TX_DN[15]	BM5	PCIEX3	O
PE2_TX_DN[2]	CT1	PCIEX3	O
PE2_TX_DN[3]	CT3	PCIEX3	O
PE2_TX_DN[4]	CM1	PCIEX3	O
PE2_TX_DN[5]	CL2	PCIEX3	O
PE2_TX_DN[6]	CG2	PCIEX3	O
PE2_TX_DN[7]	CF3	PCIEX3	O
PE2_TX_DN[8]	CC2	PCIEX3	O
PE2_TX_DN[9]	CB3	PCIEX3	O
PE2_TX_DP[0]	CW4	PCIEX3	O
PE2_TX_DP[1]	CU2	PCIEX3	O
PE2_TX_DP[10]	BY5	PCIEX3	O
PE2_TX_DP[11]	BV3	PCIEX3	O
PE2_TX_DP[12]	BR4	PCIEX3	O
PE2_TX_DP[13]	BN4	PCIEX3	O
PE2_TX_DP[14]	BM3	PCIEX3	O
PE2_TX_DP[15]	BK5	PCIEX3	O
PE2_TX_DP[2]	CR2	PCIEX3	O
PE2_TX_DP[3]	CP3	PCIEX3	O
PE2_TX_DP[4]	CK1	PCIEX3	O
PE2_TX_DP[5]	CK3	PCIEX3	O
PE2_TX_DP[6]	CE2	PCIEX3	O
PE2_TX_DP[7]	CE4	PCIEX3	O
PE2_TX_DP[8]	CD3	PCIEX3	O
PE2_TX_DP[9]	BY3	PCIEX3	O
PE3_RBIAS	CP29	PCIEX3	I
PE3_RBIAS	CR30	PCIEX3	I
PE3_RX_DN[0]	EA18	PCIEX3	I
PE3_RX_DN[1]	DW18	PCIEX3	I
PE3_RX_DN[10]	DG12	PCIEX3	I
PE3_RX_DN[11]	DG10	PCIEX3	I
PE3_RX_DN[12]	DD13	PCIEX3	I

Table A-1. Pin List By Name (Sheet 31 of 90)

Pin Name	Location	Type	I/O
PE3_RX_DN[13]	DB11	PCIEX3	I
PE3_RX_DN[14]	CY11	PCIEX3	I
PE3_RX_DN[15]	CV9	PCIEX3	I
PE3_RX_DN[2]	DW16	PCIEX3	I
PE3_RX_DN[3]	DT19	PCIEX3	I
PE3_RX_DN[4]	DR16	PCIEX3	I
PE3_RX_DN[5]	DR14	PCIEX3	I
PE3_RX_DN[6]	DN14	PCIEX3	I
PE3_RX_DN[7]	DL14	PCIEX3	I
PE3_RX_DN[8]	DL12	PCIEX3	I
PE3_RX_DN[9]	DJ12	PCIEX3	I
PE3_RX_DP[0]	DY17	PCIEX3	I
PE3_RX_DP[1]	DU18	PCIEX3	I
PE3_RX_DP[10]	DE12	PCIEX3	I
PE3_RX_DP[11]	DF11	PCIEX3	I
PE3_RX_DP[12]	DC12	PCIEX3	I
PE3_RX_DP[13]	DA12	PCIEX3	I
PE3_RX_DP[14]	CW10	PCIEX3	I
PE3_RX_DP[15]	CU10	PCIEX3	I
PE3_RX_DP[2]	DV17	PCIEX3	I
PE3_RX_DP[3]	DR18	PCIEX3	I
PE3_RX_DP[4]	DN16	PCIEX3	I
PE3_RX_DP[5]	DP15	PCIEX3	I
PE3_RX_DP[6]	DM13	PCIEX3	I
PE3_RX_DP[7]	DJ14	PCIEX3	I
PE3_RX_DP[8]	DK13	PCIEX3	I
PE3_RX_DP[9]	DH11	PCIEX3	I
PE3_TX_DN[0]	EE14	PCIEX3	O
PE3_TX_DN[1]	EE12	PCIEX3	O
PE3_TX_DN[10]	DL6	PCIEX3	O
PE3_TX_DN[11]	DJ4	PCIEX3	O
PE3_TX_DN[12]	DJ6	PCIEX3	O
PE3_TX_DN[13]	DD5	PCIEX3	O
PE3_TX_DN[14]	DB5	PCIEX3	O
PE3_TX_DN[15]	CY5	PCIEX3	O
PE3_TX_DN[2]	EC12	PCIEX3	O
PE3_TX_DN[3]	DY11	PCIEX3	O
PE3_TX_DN[4]	EB9	PCIEX3	O
PE3_TX_DN[5]	DW10	PCIEX3	O
PE3_TX_DN[6]	DU8	PCIEX3	O
PE3_TX_DN[7]	DR8	PCIEX3	O

Table A-1. Pin List By Name (Sheet 32 of 90)

Pin Name	Location	Type	I/O
PE3_TX_DN[8]	DM7	PCIEX3	O
PE3_TX_DN[9]	DP5	PCIEX3	O
PE3_TX_DP[0]	EC14	PCIEX3	O
PE3_TX_DP[1]	ED13	PCIEX3	O
PE3_TX_DP[10]	DK5	PCIEX3	O
PE3_TX_DP[11]	DH5	PCIEX3	O
PE3_TX_DP[12]	DG6	PCIEX3	O
PE3_TX_DP[13]	DC6	PCIEX3	O
PE3_TX_DP[14]	DA4	PCIEX3	O
PE3_TX_DP[15]	CV5	PCIEX3	O
PE3_TX_DP[2]	EB11	PCIEX3	O
PE3_TX_DP[3]	EA10	PCIEX3	O
PE3_TX_DP[4]	DY9	PCIEX3	O
PE3_TX_DP[5]	DV9	PCIEX3	O
PE3_TX_DP[6]	DT9	PCIEX3	O
PE3_TX_DP[7]	DP7	PCIEX3	O
PE3_TX_DP[8]	DN6	PCIEX3	O
PE3_TX_DP[9]	DM5	PCIEX3	O
PECI	AU12	PECI	I/O
PIROM_ADDR[0]	CU58		I/O
PIROM_ADDR[1]	CV57		I/O
PIROM_ADDR[2]	CW56		I/O
PKGID[0]	DC72		
PKGID[1]	CW72		
PKGID[2]	DA72		
PM_FAST_WAKE_N	AF15	ODCMOS	I/O
PMSYNC	AR14	CMOS	I
PMSYNC_CLK	AT19	CMOS	I
PRDY_N	AG16	OD	O
PREQ_N	AR12	GTL	I
PROC_ID[0]	CY71	N/A	O
PROC_ID[1]	DB71	N/A	O
PROCDIS_N	AB17	CMOS	I
PROCHOT_N	AC16	ODCMOS	I/O
PWR_DEBUG_N	AP17	CMOS	I
PWRGOOD	BC24	CMOS	I
RC_ENET_CLK_DN	AL26		
RC_ENET_CLK_DP	AK27		
RC_ERROR_N	Y23		
RC_GPIO[0]	AE48		I/O
RC_GPIO[1]	AG56		I/O

Table A-1. Pin List By Name (Sheet 33 of 90)

Pin Name	Location	Type	I/O
RC_GPIO[10]	AF53		I/O
RC_GPIO[11]	AE50		I/O
RC_GPIO[12]	AG48		I/O
RC_GPIO[13]	AG54		I/O
RC_GPIO[14]	AD49		I/O
RC_GPIO[15]	AE52		I/O
RC_GPIO[2]	AH55		
RC_GPIO[3]	AG50		I/O
RC_GPIO[4]	AD51		I/O
RC_GPIO[5]	AG52		I/O
RC_GPIO[6]	AK57		
RC_GPIO[7]	AJ56		
RC_GPIO[8]	AF51		I/O
RC_GPIO[9]	AF49		I/O
RC_REFCLK[0]_DN	AP27		
RC_REFCLK[0]_DP	AM27		
RC_REFCLK[1]_DN	BB25		
RC_REFCLK[1]_DP	BD25		
RC_VCC_CORE	AM21	PWR	
RC_VCC_CORE	AM25	PWR	
RC_VCC_CORE	AN18	PWR	
RC_VCC_CORE	AN22	PWR	
RC_VCC_CORE	AN24	PWR	
RC_VCC_CORE	AN26	PWR	
RC_VCC_CORE	AP23	PWR	
RC_VCC_CORE	AP25	PWR	
RC_VCC_CORE	AR20	PWR	
RC_VCC_CORE	AR22	PWR	
RC_VCC_CORE	AR26	PWR	
RC_VCC_CORE	AT23	PWR	
RC_VCC_CORE	AT25	PWR	
RC_VCC_CORE	BH19	PWR	
RC_VCC_CORE	BJ16	PWR	
RC_VCC_CORE	BJ18	PWR	
RC_VCC_CORE	BJ20	PWR	
RC_VCC_CORE	BK17	PWR	
RC_VCC_CORE	BL20	PWR	
RC_VCC_CORE	BM19	PWR	
RC_VCC_CORE	BP21	PWR	
RC_VCC_CORE	BR22	PWR	
RC_VCC_CORE	BR24	PWR	

Table A-1. Pin List By Name (Sheet 34 of 90)

Pin Name	Location	Type	I/O
RC_VCC_CORE	BU20	PWR	
RC_VCC_CORE	BU22	PWR	
RC_VCC_CORE	BV19	PWR	
RC_VCC_CORE	BV21	PWR	
RC_VCC_CORE	BW20	PWR	
RC_VCC_CORE	BY19	PWR	
RC_VCC_CORE	CA22	PWR	
RC_VCC_CORE	CB19	PWR	
RC_VCC_CORE	CB21	PWR	
RC_VCC_CORE	CC20	PWR	
RC_VCC_CORE	CD19	PWR	
RC_VCC_CORE	CD21	PWR	
RC_VCC_CORE	CE22	PWR	
RC_VCC_CORE	CF19	PWR	
RC_VCC_CORE	CF21	PWR	
RC_VCC_CORE	CF23	PWR	
RC_VCC_CORE	CG20	PWR	
RC_VCC_CORE	CG26	PWR	
RC_VCC_CORE	CH21	PWR	
RC_VCC_CORE	CH23	PWR	
RC_VCC_CORE	CJ20	PWR	
RC_VCC_CORE	CJ22	PWR	
RC_VCC_CORE	CJ24	PWR	
RC_VCC_CORE	CJ26	PWR	
RC_VCC_CORE	CK23	PWR	
RC_VCC_CORE	CK25	PWR	
RC_VCC_CORE	CL24	PWR	
RC_VCC_CORE	CL26	PWR	
RC_VCC_CORE	CM23	PWR	
RC_VCC_CORE	CM25	PWR	
RC_VCC_CORE	CN24	PWR	
RC_VCC_CORE	CP23	PWR	
RC_VCC_CORE	CT23	PWR	
RC_VCC_CORE	CU24	PWR	
RC_VCC_CORE	CV23	PWR	
RC_VCC_CORE	CW24	PWR	
RC_VCC_CORE	CY25	PWR	
RC_VCC_CORE	DA24	PWR	
RC_VCCALG_R	BL18	PWR	
RC_VCCALG_R	BM17	PWR	
RC_VCCALG_R	BN18	PWR	

Table A-1. Pin List By Name (Sheet 35 of 90)

Pin Name	Location	Type	I/O
RC_VCCALG_R	BP17	PWR	
RC_VCCALG_R	BU18	PWR	
RC_VCCH	A14	PWR	
RC_VCCH	A16	PWR	
RC_VCCH	B13	PWR	
RC_VCCH	B15	PWR	
RC_VCCH	B17	PWR	
RC_VCCH_SENSE_DP	AK21		
RC_VSS_VCCH_SENSE_DN	AL20		
RESET_N	AP21	CMOS	I
RFID_VCC	A8	PWR	
RSVD	A24		
RSVD	A6		
RSVD	AD47		
RSVD	AE46		
RSVD	AE72		
RSVD	AF19		
RSVD	AF47		
RSVD	AF71		
RSVD	AG20		
RSVD	AG72		
RSVD	AH15		
RSVD	AH19		
RSVD	AH57		
RSVD	AH71		
RSVD	AH73		
RSVD	AJ20		
RSVD	AJ58		
RSVD	AJ60		
RSVD	AJ62		
RSVD	AJ70		
RSVD	AK59		
RSVD	AK61		
RSVD	AK69		
RSVD	AL22		
RSVD	AL58		
RSVD	AL60		
RSVD	AL62		
RSVD	AM23		
RSVD	AM59		
RSVD	AM61		

Table A-1. Pin List By Name (Sheet 36 of 90)

Pin Name	Location	Type	I/O
RSVD	AN60		
RSVD	AN62		
RSVD	AP61		
RSVD	AR62		
RSVD	AT13		
RSVD	AV77		
RSVD	AW64		
RSVD	AW76		
RSVD	AY65		
RSVD	AY67		
RSVD	AY75		
RSVD	AY77		
RSVD	AY83		
RSVD	B7		
RSVD	B77		
RSVD	B81		
RSVD	BA14		
RSVD	BA16		
RSVD	BA18		
RSVD	BA22		
RSVD	BA64		
RSVD	BA66		
RSVD	BA76		
RSVD	BA78		
RSVD	BA82		
RSVD	BB13		
RSVD	BB15		
RSVD	BB17		
RSVD	BB21		
RSVD	BB65		
RSVD	BB67		
RSVD	BC14		
RSVD	BC18		
RSVD	BC20		
RSVD	BC22		
RSVD	BC64		
RSVD	BC66		
RSVD	BC68		
RSVD	BD17		
RSVD	BD19		
RSVD	BD65		

Table A-1. Pin List By Name (Sheet 37 of 90)

Pin Name	Location	Type	I/O
RSVD	BD67		
RSVD	BD69		
RSVD	BE18		
RSVD	BE20		
RSVD	BE22		
RSVD	BF21		
RSVD	BG18		
RSVD	BG20		
RSVD	BV23		
RSVD	BW10		
RSVD	BW22		
RSVD	BY25		
RSVD	C18		
RSVD	C24		
RSVD	C6		
RSVD	C82		
RSVD	CA24		
RSVD	CB25		
RSVD	CB5		
RSVD	CC6		
RSVD	CD25		
RSVD	CE78		
RSVD	CE80		
RSVD	CF79		
RSVD	CF81		
RSVD	CG10		
RSVD	CG24	RSVD	
RSVD	CG78		
RSVD	CG82		
RSVD	CH25		
RSVD	CH77		
RSVD	CK19		
RSVD	CK77		
RSVD	CN22		
RSVD	CN28		
RSVD	CP31		
RSVD	CR60		
RSVD	CT5		
RSVD	CT69		
RSVD	CU6		
RSVD	CU60		

Table A-1. Pin List By Name (Sheet 38 of 90)

Pin Name	Location	Type	I/O
RSVD	CV69		
RSVD	CW22		
RSVD	CW60		
RSVD	CW62		
RSVD	CY23		
RSVD	CY39		
RSVD	CY53		
RSVD	CY57		
RSVD	CY63		
RSVD	CY73		
RSVD	D17		
RSVD	D5		
RSVD	D65		
RSVD	D83		
RSVD	DA40		
RSVD	DA52		
RSVD	DA54		
RSVD	DA56		
RSVD	DC46		
RSVD	DC52		
RSVD	DD51		
RSVD	DG36		
RSVD	DG64		
RSVD	DH65		
RSVD	DJ36		
RSVD	DJ66		
RSVD	DK15		
RSVD	DK37		
RSVD	DK65		
RSVD	DK67		
RSVD	DL38		
RSVD	DL66		
RSVD	DM67		
RSVD	DN62		
RSVD	DN66		
RSVD	DP17		
RSVD	DP65		
RSVD	DR44		
RSVD	DT71		
RSVD	DU44		
RSVD	DV61		

Table A-1. Pin List By Name (Sheet 39 of 90)

Pin Name	Location	Type	I/O
RSVD	DV71		
RSVD	DW44		
RSVD	DW46		
RSVD	DY3		
RSVD	E2		
RSVD	E24		
RSVD	E4		
RSVD	E84		
RSVD	EA4		
RSVD	EA44		
RSVD	EB3		
RSVD	EB5		
RSVD	EB85		
RSVD	EC16		
RSVD	EC4		
RSVD	EC44		
RSVD	EC84		
RSVD	ED45		
RSVD	ED5		
RSVD	ED83		
RSVD	EE16		
RSVD	EE46		
RSVD	EE6		
RSVD	EE82		
RSVD	EE84		
RSVD	EF47		
RSVD	EF77		
RSVD	EF81		
RSVD	EF83		
RSVD	F23		
RSVD	F3		
RSVD	F65		
RSVD	F83		
RSVD	G2		
RSVD	G64		
RSVD	G84		
RSVD	H1		
RSVD	H83		
RSVD	H85		
RSVD	J46		
RSVD	J62		

Table A-1. Pin List By Name (Sheet 40 of 90)

Pin Name	Location	Type	I/O
RSVD	K61		
RSVD	M63		
RSVD	P65		
RSVD	R62		
RSVD	R66		
RSVD	T67		
RSVD	U66		
RSVD	V65		
RSVD	V67		
RSVD	W66		
RSVD	Y65		
SAFE_MODE_BOOT	AR18	CMOS	I
SKTOCC_N	AB13	NA	O
SM_WP	CV59	PIROM	I
SMBCLK	CT59	PIROM	I/O
SMBDAT	CW58	PIROM	I/O
SOCKET_ID[0]	AU22	CMOS	I
SOCKET_ID[1]	AU16	CMOS	I
SOCKET_ID2	AU20	CMOS	I
SVIDALERT_N[0]	DE44	CMOS	I
SVIDALERT_N[1]	DL44	CMOS	I
SVIDCLK[0]	DC44	OD	O
SVIDCLK[1]	DG44	OD	O
SVIDDATA[0]	DB45	ODCMOS	I/O
SVIDDATA[1]	DJ44	ODCMOS	I/O
TCK	AA14	CMOS	I
TDI	AC14	GTL	I
TDO	AE14	OD	O
TEST_1	AF45		
TEST_10	AW22		
TEST_11	AY13		
TEST_12	AY19		
TEST_13	DB51		
TEST_14	DC50		
TEST_15	AW14		
TEST_16	B3		
TEST_17	A4		
TEST_2	AG46		
TEST_3	AM13		
TEST_4	AN12		
TEST_5	AN14		

Table A-1. Pin List By Name (Sheet 41 of 90)

Pin Name	Location	Type	I/O
TEST_6	AR16		
TEST_7	AU18		
TEST_8	AW16		
TEST_9	AW20		
THERMTRIP_N	AB15	OD	O
TMS	W14	GTL	I
TRST_N	Y13	GTL	I
TSC_SYNC	AM11	ODCMOS	I/O
TXT_AGENT	AW18	CMOS	I
TXT_PLTEN	AV15	CMOS	I
UPI0_RX_DN[0]	AC10	UPI	I
UPI0_RX_DN[1]	AA8	UPI	I
UPI0_RX_DN[10]	AP7	UPI	I
UPI0_RX_DN[11]	AR8	UPI	I
UPI0_RX_DN[12]	AU10	UPI	I
UPI0_RX_DN[13]	BA8	UPI	I
UPI0_RX_DN[14]	BC6	UPI	I
UPI0_RX_DN[15]	BD7	UPI	I
UPI0_RX_DN[16]	AW8	UPI	I
UPI0_RX_DN[17]	AY9	UPI	I
UPI0_RX_DN[18]	BD9	UPI	I
UPI0_RX_DN[19]	BB11	UPI	I
UPI0_RX_DN[2]	AB7	UPI	I
UPI0_RX_DN[3]	AD5	UPI	I
UPI0_RX_DN[4]	AE6	UPI	I
UPI0_RX_DN[5]	AG8	UPI	I
UPI0_RX_DN[6]	AJ6	UPI	I
UPI0_RX_DN[7]	AL6	UPI	I
UPI0_RX_DN[8]	AK7	UPI	I
UPI0_RX_DN[9]	AM9	UPI	I
UPI0_RX_DP[0]	AB9	UPI	I
UPI0_RX_DP[1]	AC8	UPI	I
UPI0_RX_DP[10]	AN8	UPI	I
UPI0_RX_DP[11]	AU8	UPI	I
UPI0_RX_DP[12]	AT9	UPI	I
UPI0_RX_DP[13]	AY7	UPI	I
UPI0_RX_DP[14]	BB7	UPI	I
UPI0_RX_DP[15]	BF7	UPI	I
UPI0_RX_DP[16]	AV9	UPI	I
UPI0_RX_DP[17]	BB9	UPI	I
UPI0_RX_DP[18]	BC10	UPI	I

Table A-1. Pin List By Name (Sheet 42 of 90)

Pin Name	Location	Type	I/O
UPI0_RX_DP[19]	BA10	UPI	I
UPI0_RX_DP[2]	AA6	UPI	I
UPI0_RX_DP[3]	AC6	UPI	I
UPI0_RX_DP[4]	AG6	UPI	I
UPI0_RX_DP[5]	AF7	UPI	I
UPI0_RX_DP[6]	AH7	UPI	I
UPI0_RX_DP[7]	AK5	UPI	I
UPI0_RX_DP[8]	AM7	UPI	I
UPI0_RX_DP[9]	AL8	UPI	I
UPI0_TX_DN[0]	N2	UPI	I
UPI0_TX_DN[1]	P1	UPI	I
UPI0_TX_DN[10]	AM3	UPI	I
UPI0_TX_DN[11]	AN4	UPI	I
UPI0_TX_DN[12]	AT1	UPI	I
UPI0_TX_DN[13]	AT3	UPI	I
UPI0_TX_DN[14]	AU4	UPI	I
UPI0_TX_DN[15]	AV5	UPI	I
UPI0_TX_DN[16]	BA4	UPI	I
UPI0_TX_DN[17]	BB3	UPI	I
UPI0_TX_DN[18]	BF3	UPI	I
UPI0_TX_DN[19]	BG4	UPI	I
UPI0_TX_DN[2]	V3	UPI	I
UPI0_TX_DN[3]	Y1	UPI	I
UPI0_TX_DN[4]	AB3	UPI	I
UPI0_TX_DN[5]	AC2	UPI	I
UPI0_TX_DN[6]	AG4	UPI	I
UPI0_TX_DN[7]	AE2	UPI	I
UPI0_TX_DN[8]	AH3	UPI	I
UPI0_TX_DN[9]	AL2	UPI	I
UPI0_TX_DP[0]	M1	UPI	I
UPI0_TX_DP[1]	T1	UPI	I
UPI0_TX_DP[10]	AK3	UPI	I
UPI0_TX_DP[11]	AP3	UPI	I
UPI0_TX_DP[12]	AP1	UPI	I
UPI0_TX_DP[13]	AR2	UPI	I
UPI0_TX_DP[14]	AR4	UPI	I
UPI0_TX_DP[15]	AW4	UPI	I
UPI0_TX_DP[16]	AY3	UPI	I
UPI0_TX_DP[17]	BC2	UPI	I
UPI0_TX_DP[18]	BD3	UPI	I
UPI0_TX_DP[19]	BH3	UPI	I

Table A-1. Pin List By Name (Sheet 43 of 90)

Pin Name	Location	Type	I/O
UPI0_TX_DP[2]	Y3	UPI	I
UPI0_TX_DP[3]	W2	UPI	I
UPI0_TX_DP[4]	AA2	UPI	I
UPI0_TX_DP[5]	AD1	UPI	I
UPI0_TX_DP[6]	AF3	UPI	I
UPI0_TX_DP[7]	AG2	UPI	I
UPI0_TX_DP[8]	AJ2	UPI	I
UPI0_TX_DP[9]	AK1	UPI	I
UPI01_RBIAS	AP29	UPI	I
UPI01_RBIAS	AT29	UPI	I
UPI1_RX_DN[0]	T5	UPI	I
UPI1_RX_DN[1]	P7	UPI	I
UPI1_RX_DN[10]	R16	UPI	I
UPI1_RX_DN[11]	P17	UPI	I
UPI1_RX_DN[12]	U16	UPI	I
UPI1_RX_DN[13]	W18	UPI	I
UPI1_RX_DN[14]	R20	UPI	I
UPI1_RX_DN[15]	U18	UPI	I
UPI1_RX_DN[16]	P21	UPI	I
UPI1_RX_DN[17]	V19	UPI	I
UPI1_RX_DN[18]	Y21	UPI	I
UPI1_RX_DN[19]	AB19	UPI	I
UPI1_RX_DN[2]	V7	UPI	I
UPI1_RX_DN[3]	T9	UPI	I
UPI1_RX_DN[4]	P9	UPI	I
UPI1_RX_DN[5]	R10	UPI	I
UPI1_RX_DN[6]	U12	UPI	I
UPI1_RX_DN[7]	L12	UPI	I
UPI1_RX_DN[8]	N14	UPI	I
UPI1_RX_DN[9]	R12	UPI	I
UPI1_RX_DP[0]	R6	UPI	I
UPI1_RX_DP[1]	T7	UPI	I
UPI1_RX_DP[10]	T15	UPI	I
UPI1_RX_DP[11]	N16	UPI	I
UPI1_RX_DP[12]	W16	UPI	I
UPI1_RX_DP[13]	V17	UPI	I
UPI1_RX_DP[14]	P19	UPI	I
UPI1_RX_DP[15]	T19	UPI	I
UPI1_RX_DP[16]	T21	UPI	I
UPI1_RX_DP[17]	Y19	UPI	I
UPI1_RX_DP[18]	W20	UPI	I

Table A-1. Pin List By Name (Sheet 44 of 90)

Pin Name	Location	Type	I/O
UPI1_RX_DP[19]	AA20	UPI	I
UPI1_RX_DP[2]	U8	UPI	I
UPI1_RX_DP[3]	R8	UPI	I
UPI1_RX_DP[4]	N10	UPI	I
UPI1_RX_DP[5]	U10	UPI	I
UPI1_RX_DP[6]	T11	UPI	I
UPI1_RX_DP[7]	N12	UPI	I
UPI1_RX_DP[8]	M13	UPI	I
UPI1_RX_DP[9]	P13	UPI	I
UPI1_TX_DN[0]	M3	UPI	O
UPI1_TX_DN[1]	L4	UPI	O
UPI1_TX_DN[10]	E12	UPI	O
UPI1_TX_DN[11]	G14	UPI	O
UPI1_TX_DN[12]	D15	UPI	O
UPI1_TX_DN[13]	F15	UPI	O
UPI1_TX_DN[14]	H17	UPI	O
UPI1_TX_DN[15]	K19	UPI	O
UPI1_TX_DN[16]	G18	UPI	O
UPI1_TX_DN[17]	J20	UPI	O
UPI1_TX_DN[18]	F21	UPI	O
UPI1_TX_DN[19]	H21	UPI	O
UPI1_TX_DN[2]	K5	UPI	O
UPI1_TX_DN[3]	J6	UPI	O
UPI1_TX_DN[4]	G6	UPI	O
UPI1_TX_DN[5]	H7	UPI	O
UPI1_TX_DN[6]	K9	UPI	O
UPI1_TX_DN[7]	D9	UPI	O
UPI1_TX_DN[8]	F11	UPI	O
UPI1_TX_DN[9]	G10	UPI	O
UPI1_TX_DP[0]	P3	UPI	O
UPI1_TX_DP[1]	K3	UPI	O
UPI1_TX_DP[10]	G12	UPI	O
UPI1_TX_DP[11]	F13	UPI	O
UPI1_TX_DP[12]	E14	UPI	O
UPI1_TX_DP[13]	H15	UPI	O
UPI1_TX_DP[14]	G16	UPI	O
UPI1_TX_DP[15]	L18	UPI	O
UPI1_TX_DP[16]	J18	UPI	O
UPI1_TX_DP[17]	H19	UPI	O
UPI1_TX_DP[18]	G20	UPI	O
UPI1_TX_DP[19]	K21	UPI	O

Table A-1. Pin List By Name (Sheet 45 of 90)

Pin Name	Location	Type	I/O
UPI1_TX_DP[2]	M5	UPI	O
UPI1_TX_DP[3]	H5	UPI	O
UPI1_TX_DP[4]	F7	UPI	O
UPI1_TX_DP[5]	K7	UPI	O
UPI1_TX_DP[6]	J8	UPI	O
UPI1_TX_DP[7]	F9	UPI	O
UPI1_TX_DP[8]	E10	UPI	O
UPI1_TX_DP[9]	H9	UPI	O
UPI2_RBIAS	CK29		
UPI2_RBIAS	CL28		
UPI2_RX_DN[0]	DF23	UPI	I
UPI2_RX_DN[1]	DE22	UPI	I
UPI2_RX_DN[10]	CN20	UPI	I
UPI2_RX_DN[11]	CP21	UPI	I
UPI2_RX_DN[12]	CL16	UPI	I
UPI2_RX_DN[13]	CJ18	UPI	I
UPI2_RX_DN[14]	CH17	UPI	I
UPI2_RX_DN[15]	CE16	UPI	I
UPI2_RX_DN[16]	CD15	UPI	I
UPI2_RX_DN[17]	CF17	UPI	I
UPI2_RX_DN[18]	CB15	UPI	I
UPI2_RX_DN[19]	BY17	UPI	I
UPI2_RX_DN[2]	DC22	UPI	I
UPI2_RX_DN[3]	DB21	UPI	I
UPI2_RX_DN[4]	DD19	UPI	I
UPI2_RX_DN[5]	DA20	UPI	I
UPI2_RX_DN[6]	CW20	UPI	I
UPI2_RX_DN[7]	CV19	UPI	I
UPI2_RX_DN[8]	CT21	UPI	I
UPI2_RX_DN[9]	CR18	UPI	I
UPI2_RX_DP[0]	DG22	UPI	I
UPI2_RX_DP[1]	DD21	UPI	I
UPI2_RX_DP[10]	CP19	UPI	I
UPI2_RX_DP[11]	CM21	UPI	I
UPI2_RX_DP[12]	CJ16	UPI	I
UPI2_RX_DP[13]	CK17	UPI	I
UPI2_RX_DP[14]	CG16	UPI	I
UPI2_RX_DP[15]	CF15	UPI	I
UPI2_RX_DP[16]	CC14	UPI	I
UPI2_RX_DP[17]	CD17	UPI	I
UPI2_RX_DP[18]	BY15	UPI	I

Table A-1. Pin List By Name (Sheet 46 of 90)

Pin Name	Location	Type	I/O
UPI2_RX_DP[19]	CA16	UPI	I
UPI2_RX_DP[2]	DA22	UPI	I
UPI2_RX_DP[3]	DC20	UPI	I
UPI2_RX_DP[4]	DB19	UPI	I
UPI2_RX_DP[5]	CY19	UPI	I
UPI2_RX_DP[6]	CU20	UPI	I
UPI2_RX_DP[7]	CW18	UPI	I
UPI2_RX_DP[8]	CR20	UPI	I
UPI2_RX_DP[9]	CN18	UPI	I
UPI2_TX_DN[0]	DT21	UPI	O
UPI2_TX_DN[1]	DM21	UPI	O
UPI2_TX_DN[10]	DA16	UPI	O
UPI2_TX_DN[11]	CW14	UPI	O
UPI2_TX_DN[12]	CU14	UPI	O
UPI2_TX_DN[13]	CM13	UPI	O
UPI2_TX_DN[14]	CJ14	UPI	O
UPI2_TX_DN[15]	CF13	UPI	O
UPI2_TX_DN[16]	CH11	UPI	O
UPI2_TX_DN[17]	CE12	UPI	O
UPI2_TX_DN[18]	CC10	UPI	O
UPI2_TX_DN[19]	CC12	UPI	O
UPI2_TX_DN[2]	DL20	UPI	O
UPI2_TX_DN[3]	DG20	UPI	O
UPI2_TX_DN[4]	DH19	UPI	O
UPI2_TX_DN[5]	DK17	UPI	O
UPI2_TX_DN[6]	DG18	UPI	O
UPI2_TX_DN[7]	DD17	UPI	O
UPI2_TX_DN[8]	DF15	UPI	O
UPI2_TX_DN[9]	DC16	UPI	O
UPI2_TX_DP[0]	DP21	UPI	O
UPI2_TX_DP[1]	DN20	UPI	O
UPI2_TX_DP[10]	CW16	UPI	O
UPI2_TX_DP[11]	CV13	UPI	O
UPI2_TX_DP[12]	CR14	UPI	O
UPI2_TX_DP[13]	CK13	UPI	O
UPI2_TX_DP[14]	CH13	UPI	O
UPI2_TX_DP[15]	CG12	UPI	O
UPI2_TX_DP[16]	CF11	UPI	O
UPI2_TX_DP[17]	CD11	UPI	O
UPI2_TX_DP[18]	CB11	UPI	O
UPI2_TX_DP[19]	CA12	UPI	O

Table A-1. Pin List By Name (Sheet 47 of 90)

Pin Name	Location	Type	I/O
UPI2_TX_DP[2]	DK19	UPI	O
UPI2_TX_DP[3]	DJ20	UPI	O
UPI2_TX_DP[4]	DJ18	UPI	O
UPI2_TX_DP[5]	DH17	UPI	O
UPI2_TX_DP[6]	DF17	UPI	O
UPI2_TX_DP[7]	DE16	UPI	O
UPI2_TX_DP[8]	DD15	UPI	O
UPI2_TX_DP[9]	DB15	UPI	O
VCC33	CY55	PWR	
VCCD012	AD45	PWR	
VCCD012	AF55	PWR	
VCCD012	AF57	PWR	
VCCD012	AF59	PWR	
VCCD012	AF61	PWR	
VCCD012	AF63	PWR	
VCCD012	B47	PWR	
VCCD012	B49	PWR	
VCCD012	B53	PWR	
VCCD012	B59	PWR	
VCCD012	C46	PWR	
VCCD012	D45	PWR	
VCCD012	E46	PWR	
VCCD012	E48	PWR	
VCCD012	E50	PWR	
VCCD012	E52	PWR	
VCCD012	E54	PWR	
VCCD012	E56	PWR	
VCCD012	E58	PWR	
VCCD012	E60	PWR	
VCCD012	E62	PWR	
VCCD012	E64	PWR	
VCCD012	L46	PWR	
VCCD012	L48	PWR	
VCCD012	L50	PWR	
VCCD012	L52	PWR	
VCCD012	L54	PWR	
VCCD012	L56	PWR	
VCCD012	L58	PWR	
VCCD012	L60	PWR	
VCCD012	L62	PWR	
VCCD012	N64	PWR	

Table A-1. Pin List By Name (Sheet 48 of 90)

Pin Name	Location	Type	I/O
VCCD012	U46	PWR	
VCCD012	U48	PWR	
VCCD012	U50	PWR	
VCCD012	U52	PWR	
VCCD012	U54	PWR	
VCCD012	U56	PWR	
VCCD012	U58	PWR	
VCCD012	U60	PWR	
VCCD012	U62	PWR	
VCCD012	W64	PWR	
VCCD012	Y45	PWR	
VCCD012	Y47	PWR	
VCCD012	Y49	PWR	
VCCD012	Y51	PWR	
VCCD012	Y53	PWR	
VCCD012	Y55	PWR	
VCCD012	Y57	PWR	
VCCD012	Y59	PWR	
VCCD012	Y61	PWR	
VCCD012	Y63	PWR	
VCCD345	DB53	PWR	
VCCD345	DB55	PWR	
VCCD345	DB57	PWR	
VCCD345	DB59	PWR	
VCCD345	DB61	PWR	
VCCD345	DB63	PWR	
VCCD345	DD45	PWR	
VCCD345	DH45	PWR	
VCCD345	DH47	PWR	
VCCD345	DH49	PWR	
VCCD345	DH51	PWR	
VCCD345	DH53	PWR	
VCCD345	DH55	PWR	
VCCD345	DH57	PWR	
VCCD345	DH59	PWR	
VCCD345	DH61	PWR	
VCCD345	DH63	PWR	
VCCD345	DJ64	PWR	
VCCD345	DL46	PWR	
VCCD345	DL48	PWR	
VCCD345	DL50	PWR	

Table A-1. Pin List By Name (Sheet 49 of 90)

Pin Name	Location	Type	I/O
VCCD345	DL52	PWR	
VCCD345	DL54	PWR	
VCCD345	DL56	PWR	
VCCD345	DL58	PWR	
VCCD345	DL60	PWR	
VCCD345	DL62	PWR	
VCCD345	DU46	PWR	
VCCD345	DU48	PWR	
VCCD345	DU50	PWR	
VCCD345	DU52	PWR	
VCCD345	DU54	PWR	
VCCD345	DU56	PWR	
VCCD345	DU58	PWR	
VCCD345	DU60	PWR	
VCCD345	DU62	PWR	
VCCD345	DU64	PWR	
VCCD345	EC46	PWR	
VCCD345	EC48	PWR	
VCCD345	EC50	PWR	
VCCD345	EC52	PWR	
VCCD345	EC54	PWR	
VCCD345	EC56	PWR	
VCCD345	EC58	PWR	
VCCD345	EC60	PWR	
VCCD345	EC62	PWR	
VCCD345	EE44	PWR	
VCCD345	EF45	PWR	
VCCD345	EF49	PWR	
VCCD345	EF53	PWR	
VCCD345	EF59	PWR	
VCCIN	AF43	PWR	
VCCIN	AG38	PWR	
VCCIN	AG40	PWR	
VCCIN	AG42	PWR	
VCCIN	AH37	PWR	
VCCIN	AH39	PWR	
VCCIN	AH41	PWR	
VCCIN	AJ36	PWR	
VCCIN	AK35	PWR	
VCCIN	AK45	PWR	
VCCIN	AK47	PWR	

Table A-1. Pin List By Name (Sheet 50 of 90)

Pin Name	Location	Type	I/O
VCCIN	AK49	PWR	
VCCIN	AK51	PWR	
VCCIN	AK53	PWR	
VCCIN	AL34	PWR	
VCCIN	AL46	PWR	
VCCIN	AL48	PWR	
VCCIN	AL50	PWR	
VCCIN	AL52	PWR	
VCCIN	AL54	PWR	
VCCIN	AM33	PWR	
VCCIN	AM53	PWR	
VCCIN	AM55	PWR	
VCCIN	AN32	PWR	
VCCIN	AN54	PWR	
VCCIN	AN56	PWR	
VCCIN	AP55	PWR	
VCCIN	AP57	PWR	
VCCIN	AR56	PWR	
VCCIN	AR58	PWR	
VCCIN	AT57	PWR	
VCCIN	AT59	PWR	
VCCIN	AU58	PWR	
VCCIN	AU60	PWR	
VCCIN	AV59	PWR	
VCCIN	AV61	PWR	
VCCIN	AW60	PWR	
VCCIN	AY61	PWR	
VCCIN	BA60	PWR	
VCCIN	BB61	PWR	
VCCIN	BB85	PWR	
VCCIN	BC60	PWR	
VCCIN	BC62	PWR	
VCCIN	BC84	PWR	
VCCIN	BD61	PWR	
VCCIN	BD73	PWR	
VCCIN	BD75	PWR	
VCCIN	BD77	PWR	
VCCIN	BD79	PWR	
VCCIN	BD81	PWR	
VCCIN	BD83	PWR	
VCCIN	BD85	PWR	

Table A-1. Pin List By Name (Sheet 51 of 90)

Pin Name	Location	Type	I/O
VCCIN	BE60	PWR	
VCCIN	BE62	PWR	
VCCIN	BE72	PWR	
VCCIN	BE74	PWR	
VCCIN	BE76	PWR	
VCCIN	BE78	PWR	
VCCIN	BE80	PWR	
VCCIN	BE82	PWR	
VCCIN	BE84	PWR	
VCCIN	BF61	PWR	
VCCIN	BF73	PWR	
VCCIN	BF75	PWR	
VCCIN	BF77	PWR	
VCCIN	BF79	PWR	
VCCIN	BF81	PWR	
VCCIN	BF83	PWR	
VCCIN	BF85	PWR	
VCCIN	BG60	PWR	
VCCIN	BG62	PWR	
VCCIN	BG64	PWR	
VCCIN	BG66	PWR	
VCCIN	BG68	PWR	
VCCIN	BG70	PWR	
VCCIN	BG84	PWR	
VCCIN	BH61	PWR	
VCCIN	BH63	PWR	
VCCIN	BH65	PWR	
VCCIN	BH67	PWR	
VCCIN	BH69	PWR	
VCCIN	BH71	PWR	
VCCIN	BH73	PWR	
VCCIN	BH75	PWR	
VCCIN	BH77	PWR	
VCCIN	BH79	PWR	
VCCIN	BH81	PWR	
VCCIN	BH83	PWR	
VCCIN	BJ60	PWR	
VCCIN	BJ62	PWR	
VCCIN	BJ64	PWR	
VCCIN	BJ66	PWR	
VCCIN	BJ68	PWR	

Table A-1. Pin List By Name (Sheet 52 of 90)

Pin Name	Location	Type	I/O
VCCIN	BJ70	PWR	
VCCIN	BJ72	PWR	
VCCIN	BJ74	PWR	
VCCIN	BJ76	PWR	
VCCIN	BJ78	PWR	
VCCIN	BJ80	PWR	
VCCIN	BJ82	PWR	
VCCIN	BJ84	PWR	
VCCIN	BK61	PWR	
VCCIN	BK63	PWR	
VCCIN	BK65	PWR	
VCCIN	BK67	PWR	
VCCIN	BK69	PWR	
VCCIN	BK71	PWR	
VCCIN	BK73	PWR	
VCCIN	BK75	PWR	
VCCIN	BK77	PWR	
VCCIN	BK79	PWR	
VCCIN	BK81	PWR	
VCCIN	BK83	PWR	
VCCIN	BL60	PWR	
VCCIN	BL62	PWR	
VCCIN	BL84	PWR	
VCCIN	BM61	PWR	
VCCIN	BM63	PWR	
VCCIN	BM65	PWR	
VCCIN	BM67	PWR	
VCCIN	BM69	PWR	
VCCIN	BM71	PWR	
VCCIN	BM73	PWR	
VCCIN	BM75	PWR	
VCCIN	BM77	PWR	
VCCIN	BM79	PWR	
VCCIN	BM81	PWR	
VCCIN	BM83	PWR	
VCCIN	BN60	PWR	
VCCIN	BN62	PWR	
VCCIN	BN64	PWR	
VCCIN	BN66	PWR	
VCCIN	BN68	PWR	
VCCIN	BN70	PWR	

Table A-1. Pin List By Name (Sheet 53 of 90)

Pin Name	Location	Type	I/O
VCCIN	BN72	PWR	
VCCIN	BN74	PWR	
VCCIN	BN76	PWR	
VCCIN	BN78	PWR	
VCCIN	BN80	PWR	
VCCIN	BN82	PWR	
VCCIN	BN84	PWR	
VCCIN	BP61	PWR	
VCCIN	BP63	PWR	
VCCIN	BP65	PWR	
VCCIN	BP67	PWR	
VCCIN	BP69	PWR	
VCCIN	BP71	PWR	
VCCIN	BP73	PWR	
VCCIN	BP75	PWR	
VCCIN	BP77	PWR	
VCCIN	BP79	PWR	
VCCIN	BP81	PWR	
VCCIN	BP83	PWR	
VCCIN	BR60	PWR	
VCCIN	BR62	PWR	
VCCIN	BR84	PWR	
VCCIN	BT61	PWR	
VCCIN	BT63	PWR	
VCCIN	BT65	PWR	
VCCIN	BT67	PWR	
VCCIN	BT69	PWR	
VCCIN	BT71	PWR	
VCCIN	BT73	PWR	
VCCIN	BT75	PWR	
VCCIN	BT77	PWR	
VCCIN	BT79	PWR	
VCCIN	BT81	PWR	
VCCIN	BT83	PWR	
VCCIN	BU60	PWR	
VCCIN	BU62	PWR	
VCCIN	BU64	PWR	
VCCIN	BU66	PWR	
VCCIN	BU68	PWR	
VCCIN	BU70	PWR	
VCCIN	BU72	PWR	

Table A-1. Pin List By Name (Sheet 54 of 90)

Pin Name	Location	Type	I/O
VCCIN	BU74	PWR	
VCCIN	BU76	PWR	
VCCIN	BU78	PWR	
VCCIN	BU80	PWR	
VCCIN	BU82	PWR	
VCCIN	BU84	PWR	
VCCIN	BV61	PWR	
VCCIN	BV63	PWR	
VCCIN	BV65	PWR	
VCCIN	BV67	PWR	
VCCIN	BV69	PWR	
VCCIN	BV71	PWR	
VCCIN	BV73	PWR	
VCCIN	BV75	PWR	
VCCIN	BV77	PWR	
VCCIN	BV79	PWR	
VCCIN	BV81	PWR	
VCCIN	BV83	PWR	
VCCIN	BW60	PWR	
VCCIN	BW62	PWR	
VCCIN	BW64	PWR	
VCCIN	BW66	PWR	
VCCIN	BW68	PWR	
VCCIN	BW70	PWR	
VCCIN	BW84	PWR	
VCCIN	BY61	PWR	
VCCIN	BY73	PWR	
VCCIN	BY75	PWR	
VCCIN	BY77	PWR	
VCCIN	BY79	PWR	
VCCIN	BY81	PWR	
VCCIN	BY83	PWR	
VCCIN	CA60	PWR	
VCCIN	CA62	PWR	
VCCIN	CA72	PWR	
VCCIN	CA74	PWR	
VCCIN	CA76	PWR	
VCCIN	CA78	PWR	
VCCIN	CA80	PWR	
VCCIN	CA82	PWR	
VCCIN	CA84	PWR	

Table A-1. Pin List By Name (Sheet 55 of 90)

Pin Name	Location	Type	I/O
VCCIN	CB61	PWR	
VCCIN	CB73	PWR	
VCCIN	CB75	PWR	
VCCIN	CB77	PWR	
VCCIN	CB79	PWR	
VCCIN	CB81	PWR	
VCCIN	CB83	PWR	
VCCIN	CC60	PWR	
VCCIN	CC62	PWR	
VCCIN	CC84	PWR	
VCCIN	CD61	PWR	
VCCIN	CD83	PWR	
VCCIN	CD85	PWR	
VCCIN	CE60	PWR	
VCCIN	CE84	PWR	
VCCIN	CF61	PWR	
VCCIN	CF85	PWR	
VCCIN	CG60	PWR	
VCCIN	CG84	PWR	
VCCIN	CH61	PWR	
VCCIN	CH85	PWR	
VCCIN	CJ60	PWR	
VCCIN	CK59	PWR	
VCCIN	CK61	PWR	
VCCIN	CL58	PWR	
VCCIN	CL60	PWR	
VCCIN	CM57	PWR	
VCCIN	CM59	PWR	
VCCIN	CN56	PWR	
VCCIN	CN58	PWR	
VCCIN	CP33	PWR	
VCCIN	CP55	PWR	
VCCIN	CP57	PWR	
VCCIN	CR34	PWR	
VCCIN	CR54	PWR	
VCCIN	CR56	PWR	
VCCIN	CT37	PWR	
VCCIN	CT39	PWR	
VCCIN	CT41	PWR	
VCCIN	CT53	PWR	
VCCIN	CT55	PWR	

Table A-1. Pin List By Name (Sheet 56 of 90)

Pin Name	Location	Type	I/O
VCCIN	CU38	PWR	
VCCIN	CU40	PWR	
VCCIN	CU42	PWR	
VCCIN	CU52	PWR	
VCCIN	CU54	PWR	
VCCIN	CV51	PWR	
VCCIN	CW46	PWR	
VCCIN	CW48	PWR	
VCCIN	CW50	PWR	
VCCIN	CY47	PWR	
VCCIN	CY49	PWR	
VCCIN_SENSE	BA86	PWR	
VCCINPMAX	AV85	PWR	
VCCINPMAX	AW86	PWR	
VCCIO	AA10	PWR	
VCCIO	AC20	PWR	
VCCIO	AC36	PWR	
VCCIO	AC4	PWR	
VCCIO	AD35	PWR	
VCCIO	AD37	PWR	
VCCIO	AE10	PWR	
VCCIO	AE34	PWR	
VCCIO	AE36	PWR	
VCCIO	AF35	PWR	
VCCIO	AF5	PWR	
VCCIO	AG34	PWR	
VCCIO	AH9	PWR	
VCCIO	AL28	PWR	
VCCIO	AM29	PWR	
VCCIO	AM5	PWR	
VCCIO	AN10	PWR	
VCCIO	AR28	PWR	
VCCIO	AT11	PWR	
VCCIO	AT5	PWR	
VCCIO	AT7	PWR	
VCCIO	AV27	PWR	
VCCIO	AW26	PWR	
VCCIO	AW6	PWR	
VCCIO	AY11	PWR	
VCCIO	AY27	PWR	
VCCIO	BA24	PWR	

Table A-1. Pin List By Name (Sheet 57 of 90)

Pin Name	Location	Type	I/O
VCCIO	BA26	PWR	
VCCIO	BB27	PWR	
VCCIO	BB5	PWR	
VCCIO	BC26	PWR	
VCCIO	BE24	PWR	
VCCIO	BF23	PWR	
VCCIO	BF27	PWR	
VCCIO	BG26	PWR	
VCCIO	BH25	PWR	
VCCIO	BH27	PWR	
VCCIO	BJ24	PWR	
VCCIO	BJ26	PWR	
VCCIO	BK25	PWR	
VCCIO	BK27	PWR	
VCCIO	BL26	PWR	
VCCIO	BM27	PWR	
VCCIO	BP25	PWR	
VCCIO	CB13	PWR	
VCCIO	CB17	PWR	
VCCIO	CC26	PWR	
VCCIO	CD27	PWR	
VCCIO	CD9	PWR	
VCCIO	CE18	PWR	
VCCIO	CF27	PWR	
VCCIO	CF5	PWR	
VCCIO	CG14	PWR	
VCCIO	CH27	PWR	
VCCIO	CH9	PWR	
VCCIO	CJ28	PWR	
VCCIO	CK5	PWR	
VCCIO	CL12	PWR	
VCCIO	CL20	PWR	
VCCIO	CM15	PWR	
VCCIO	CN6	PWR	
VCCIO	CP13	PWR	
VCCIO	CU12	PWR	
VCCIO	CU18	PWR	
VCCIO	CV21	PWR	
VCCIO	CV7	PWR	
VCCIO	CY17	PWR	
VCCIO	D7	PWR	

Table A-1. Pin List By Name (Sheet 58 of 90)

Pin Name	Location	Type	I/O
VCCIO	DA14	PWR	
VCCIO	DC18	PWR	
VCCIO	DD7	PWR	
VCCIO	DE14	PWR	
VCCIO	DF13	PWR	
VCCIO	DF21	PWR	
VCCIO	DG8	PWR	
VCCIO	DH7	PWR	
VCCIO	DJ16	PWR	
VCCIO	DK21	PWR	
VCCIO	DM17	PWR	
VCCIO	DN8	PWR	
VCCIO	DP19	PWR	
VCCIO	DR10	PWR	
VCCIO	DR2	PWR	
VCCIO	DU20	PWR	
VCCIO	DV11	PWR	
VCCIO	EA12	PWR	
VCCIO	EB15	PWR	
VCCIO	EE10	PWR	
VCCIO	H13	PWR	
VCCIO	J10	PWR	
VCCIO	J2	PWR	
VCCIO	K15	PWR	
VCCIO	L14	PWR	
VCCIO	L16	PWR	
VCCIO	M11	PWR	
VCCIO	M21	PWR	
VCCIO	M7	PWR	
VCCIO	M9	PWR	
VCCIO	N18	PWR	
VCCIO	P5	PWR	
VCCIO	T3	PWR	
VCCIO	U14	PWR	
VCCIO	W10	PWR	
VCCIO	W4	PWR	
VCCIO	W6	PWR	
VCCIO_SENSE	BH5	PWR	
VCCSA	CB65	PWR	
VCCSA	CB67	PWR	
VCCSA	CB69	PWR	

Table A-1. Pin List By Name (Sheet 59 of 90)

Pin Name	Location	Type	I/O
VCCSA	CC66	PWR	
VCCSA	CC68	PWR	
VCCSA	CC70	PWR	
VCCSA	CD65	PWR	
VCCSA	CD67	PWR	
VCCSA	CD69	PWR	
VCCSA	CD71	PWR	
VCCSA	CE64	PWR	
VCCSA	CE66	PWR	
VCCSA	CE68	PWR	
VCCSA	CE72	PWR	
VCCSA	CE74	PWR	
VCCSA	CF65	PWR	
VCCSA	CF67	PWR	
VCCSA	CF73	PWR	
VCCSA	CF75	PWR	
VCCSA	CG64	PWR	
VCCSA	CG66	PWR	
VCCSA	CG74	PWR	
VCCSA	CH65	PWR	
VCCSA	CH75	PWR	
VCCSA	CJ64	PWR	
VCCSA	CJ66	PWR	
VCCSA_SENSE	CE76	PWR	
VSENSEPMAX	AD41		
VSS	A26	PWR	
VSS	A30	PWR	
VSS	A32	PWR	
VSS	A36	PWR	
VSS	A38	PWR	
VSS	A42	PWR	
VSS	AA16	PWR	
VSS	AA18	PWR	
VSS	AA22	PWR	
VSS	AA24	PWR	
VSS	AA30	PWR	
VSS	AA36	PWR	
VSS	AA4	PWR	
VSS	AA42	PWR	
VSS	AA64	PWR	
VSS	AA66	PWR	

Table A-1. Pin List By Name (Sheet 60 of 90)

Pin Name	Location	Type	I/O
VSS	AA68	PWR	
VSS	AA76	PWR	
VSS	AA78	PWR	
VSS	AA80	PWR	
VSS	AA82	PWR	
VSS	AB1	PWR	
VSS	AB11	PWR	
VSS	AB21	PWR	
VSS	AB23	PWR	
VSS	AB25	PWR	
VSS	AB29	PWR	
VSS	AB31	PWR	
VSS	AB35	PWR	
VSS	AB37	PWR	
VSS	AB41	PWR	
VSS	AB5	PWR	
VSS	AB65	PWR	
VSS	AB69	PWR	
VSS	AB73	PWR	
VSS	AB79	PWR	
VSS	AB83	PWR	
VSS	AB85	PWR	
VSS	AC18	PWR	
VSS	AC22	PWR	
VSS	AC26	PWR	
VSS	AC28	PWR	
VSS	AC32	PWR	
VSS	AC34	PWR	
VSS	AC38	PWR	
VSS	AC40	PWR	
VSS	AC48	PWR	
VSS	AC50	PWR	
VSS	AC52	PWR	
VSS	AC54	PWR	
VSS	AC56	PWR	
VSS	AC58	PWR	
VSS	AC60	PWR	
VSS	AC62	PWR	
VSS	AC64	PWR	
VSS	AC70	PWR	
VSS	AC72	PWR	

Table A-1. Pin List By Name (Sheet 61 of 90)

Pin Name	Location	Type	I/O
VSS	AC78	PWR	
VSS	AC84	PWR	
VSS	AC86	PWR	
VSS	AD11	PWR	
VSS	AD13	PWR	
VSS	AD15	PWR	
VSS	AD19	PWR	
VSS	AD21	PWR	
VSS	AD27	PWR	
VSS	AD3	PWR	
VSS	AD33	PWR	
VSS	AD39	PWR	
VSS	AD43	PWR	
VSS	AD7	PWR	
VSS	AD71	PWR	
VSS	AD73	PWR	
VSS	AD75	PWR	
VSS	AD81	PWR	
VSS	AD83	PWR	
VSS	AD85	PWR	
VSS	AD9	PWR	
VSS	AE16	PWR	
VSS	AE38	PWR	
VSS	AE4	PWR	
VSS	AE40	PWR	
VSS	AE42	PWR	
VSS	AE64	PWR	
VSS	AE66	PWR	
VSS	AE68	PWR	
VSS	AE70	PWR	
VSS	AE78	PWR	
VSS	AE8	PWR	
VSS	AF1	PWR	
VSS	AF21	PWR	
VSS	AF23	PWR	
VSS	AF25	PWR	
VSS	AF27	PWR	
VSS	AF29	PWR	
VSS	AF31	PWR	
VSS	AF33	PWR	
VSS	AF37	PWR	

Table A-1. Pin List By Name (Sheet 62 of 90)

Pin Name	Location	Type	I/O
VSS	AF39	PWR	
VSS	AF41	PWR	
VSS	AF73	PWR	
VSS	AF77	PWR	
VSS	AF83	PWR	
VSS	AF85	PWR	
VSS	AF9	PWR	
VSS	AG12	PWR	
VSS	AG14	PWR	
VSS	AG18	PWR	
VSS	AG36	PWR	
VSS	AG64	PWR	
VSS	AG70	PWR	
VSS	AG74	PWR	
VSS	AG76	PWR	
VSS	AG78	PWR	
VSS	AG80	PWR	
VSS	AH1	PWR	
VSS	AH21	PWR	
VSS	AH27	PWR	
VSS	AH33	PWR	
VSS	AH35	PWR	
VSS	AH45	PWR	
VSS	AH47	PWR	
VSS	AH49	PWR	
VSS	AH5	PWR	
VSS	AH51	PWR	
VSS	AH53	PWR	
VSS	AH59	PWR	
VSS	AH61	PWR	
VSS	AH65	PWR	
VSS	AH69	PWR	
VSS	AH75	PWR	
VSS	AH77	PWR	
VSS	AH83	PWR	
VSS	AJ22	PWR	
VSS	AJ26	PWR	
VSS	AJ28	PWR	
VSS	AJ32	PWR	
VSS	AJ34	PWR	
VSS	AJ4	PWR	

Table A-1. Pin List By Name (Sheet 63 of 90)

Pin Name	Location	Type	I/O
VSS	AJ46	PWR	
VSS	AJ48	PWR	
VSS	AJ50	PWR	
VSS	AJ52	PWR	
VSS	AJ54	PWR	
VSS	AJ66	PWR	
VSS	AJ68	PWR	
VSS	AJ74	PWR	
VSS	AJ78	PWR	
VSS	AJ8	PWR	
VSS	AJ82	PWR	
VSS	AJ86	PWR	
VSS	AK13	PWR	
VSS	AK19	PWR	
VSS	AK23	PWR	
VSS	AK25	PWR	
VSS	AK29	PWR	
VSS	AK31	PWR	
VSS	AK33	PWR	
VSS	AK55	PWR	
VSS	AK65	PWR	
VSS	AK67	PWR	
VSS	AK73	PWR	
VSS	AK79	PWR	
VSS	AK81	PWR	
VSS	AK83	PWR	
VSS	AK85	PWR	
VSS	AK9	PWR	
VSS	AL10	PWR	
VSS	AL24	PWR	
VSS	AL30	PWR	
VSS	AL32	PWR	
VSS	AL4	PWR	
VSS	AL56	PWR	
VSS	AL64	PWR	
VSS	AL68	PWR	
VSS	AL76	PWR	
VSS	AL78	PWR	
VSS	AL80	PWR	
VSS	AL82	PWR	
VSS	AL86	PWR	

Table A-1. Pin List By Name (Sheet 64 of 90)

Pin Name	Location	Type	I/O
VSS	AM1	PWR	
VSS	AM31	PWR	
VSS	AM57	PWR	
VSS	AM63	PWR	
VSS	AM69	PWR	
VSS	AM73	PWR	
VSS	AM79	PWR	
VSS	AM83	PWR	
VSS	AN2	PWR	
VSS	AN28	PWR	
VSS	AN58	PWR	
VSS	AN6	PWR	
VSS	AN78	PWR	
VSS	AP13	PWR	
VSS	AP19	PWR	
VSS	AP31	PWR	
VSS	AP5	PWR	
VSS	AP59	PWR	
VSS	AP63	PWR	
VSS	AP65	PWR	
VSS	AP67	PWR	
VSS	AP69	PWR	
VSS	AP73	PWR	
VSS	AP75	PWR	
VSS	AP81	PWR	
VSS	AP83	PWR	
VSS	AP85	PWR	
VSS	AP9	PWR	
VSS	AR10	PWR	
VSS	AR24	PWR	
VSS	AR30	PWR	
VSS	AR6	PWR	
VSS	AR60	PWR	
VSS	AR72	PWR	
VSS	AR78	PWR	
VSS	AT15	PWR	
VSS	AT17	PWR	
VSS	AT21	PWR	
VSS	AT27	PWR	
VSS	AT61	PWR	
VSS	AT63	PWR	

Table A-1. Pin List By Name (Sheet 65 of 90)

Pin Name	Location	Type	I/O
VSS	AT69	PWR	
VSS	AT73	PWR	
VSS	AT77	PWR	
VSS	AT83	PWR	
VSS	AT85	PWR	
VSS	AU2	PWR	
VSS	AU26	PWR	
VSS	AU28	PWR	
VSS	AU6	PWR	
VSS	AU62	PWR	
VSS	AU64	PWR	
VSS	AU68	PWR	
VSS	AU74	PWR	
VSS	AU76	PWR	
VSS	AU78	PWR	
VSS	AU80	PWR	
VSS	AU84	PWR	
VSS	AU86	PWR	
VSS	AV1	PWR	
VSS	AV11	PWR	
VSS	AV13	PWR	
VSS	AV19	PWR	
VSS	AV23	PWR	
VSS	AV25	PWR	
VSS	AV3	PWR	
VSS	AV63	PWR	
VSS	AV65	PWR	
VSS	AV67	PWR	
VSS	AV7	PWR	
VSS	AV75	PWR	
VSS	AV83	PWR	
VSS	AW10	PWR	
VSS	AW2	PWR	
VSS	AW62	PWR	
VSS	AW66	PWR	
VSS	AW68	PWR	
VSS	AW70	PWR	
VSS	AW72	PWR	
VSS	AW74	PWR	
VSS	AW78	PWR	
VSS	AW82	PWR	

Table A-1. Pin List By Name (Sheet 66 of 90)

Pin Name	Location	Type	I/O
VSS	AW84	PWR	
VSS	AY15	PWR	
VSS	AY17	PWR	
VSS	AY21	PWR	
VSS	AY23	PWR	
VSS	AY25	PWR	
VSS	AY5	PWR	
VSS	AY63	PWR	
VSS	AY79	PWR	
VSS	AY81	PWR	
VSS	B25	PWR	
VSS	B31	PWR	
VSS	B37	PWR	
VSS	B43	PWR	
VSS	B5	PWR	
VSS	B71	PWR	
VSS	B75	PWR	
VSS	B79	PWR	
VSS	B9	POWER	
VSS	BA12	PWR	
VSS	BA2	PWR	
VSS	BA6	PWR	
VSS	BA62	PWR	
VSS	BA68	PWR	
VSS	BA74	PWR	
VSS	BA80	PWR	
VSS	BA84	PWR	
VSS	BB19	PWR	
VSS	BB23	PWR	
VSS	BB63	PWR	
VSS	BB69	PWR	
VSS	BB73	PWR	
VSS	BB75	PWR	
VSS	BB77	PWR	
VSS	BB79	PWR	
VSS	BB81	PWR	
VSS	BB83	PWR	
VSS	BC12	PWR	
VSS	BC16	PWR	
VSS	BC4	PWR	
VSS	BC70	PWR	

Table A-1. Pin List By Name (Sheet 67 of 90)

Pin Name	Location	Type	I/O
VSS	BC72	PWR	
VSS	BC74	PWR	
VSS	BC76	PWR	
VSS	BC78	PWR	
VSS	BC8	PWR	
VSS	BC80	PWR	
VSS	BC82	PWR	
VSS	BD11	PWR	
VSS	BD15	PWR	
VSS	BD21	PWR	
VSS	BD27	PWR	
VSS	BD5	PWR	
VSS	BD63	PWR	
VSS	BD71	PWR	
VSS	BE10	PWR	
VSS	BE26	PWR	
VSS	BE4	PWR	
VSS	BE6	PWR	
VSS	BE64	PWR	
VSS	BE66	PWR	
VSS	BE68	PWR	
VSS	BE70	PWR	
VSS	BE8	PWR	
VSS	BF15	PWR	
VSS	BF17	PWR	
VSS	BF19	PWR	
VSS	BF25	PWR	
VSS	BF63	PWR	
VSS	BF65	PWR	
VSS	BF67	PWR	
VSS	BF69	PWR	
VSS	BF71	PWR	
VSS	BF9	PWR	
VSS	BG10	PWR	
VSS	BG22	PWR	
VSS	BG24	PWR	
VSS	BG6	PWR	
VSS	BG72	PWR	
VSS	BG74	PWR	
VSS	BG76	PWR	
VSS	BG78	PWR	

Table A-1. Pin List By Name (Sheet 68 of 90)

Pin Name	Location	Type	I/O
VSS	BG8	PWR	
VSS	BG80	PWR	
VSS	BG82	PWR	
VSS	BH11	PWR	
VSS	BH15	PWR	
VSS	BH17	PWR	
VSS	BH21	PWR	
VSS	BH7	PWR	
VSS	BH9	PWR	
VSS	BJ4	PWR	
VSS	BJ6	PWR	
VSS	BK11	PWR	
VSS	BK19	PWR	
VSS	BK3	PWR	
VSS	BK7	PWR	
VSS	BL10	PWR	
VSS	BL12	PWR	
VSS	BL22	PWR	
VSS	BL24	PWR	
VSS	BL6	PWR	
VSS	BL64	PWR	
VSS	BL66	PWR	
VSS	BL68	PWR	
VSS	BL70	PWR	
VSS	BL72	PWR	
VSS	BL74	PWR	
VSS	BL76	PWR	
VSS	BL78	PWR	
VSS	BL80	PWR	
VSS	BL82	PWR	
VSS	BM13	PWR	
VSS	BM15	PWR	
VSS	BM25	PWR	
VSS	BM9	PWR	
VSS	BN10	PWR	
VSS	BN20	PWR	
VSS	BN26	PWR	
VSS	BN6	PWR	
VSS	BP27	PWR	
VSS	BP3	PWR	
VSS	BR10	PWR	

Table A-1. Pin List By Name (Sheet 69 of 90)

Pin Name	Location	Type	I/O
VSS	BR16	PWR	
VSS	BR18	PWR	
VSS	BR26	PWR	
VSS	BR6	PWR	
VSS	BR64	PWR	
VSS	BR66	PWR	
VSS	BR68	PWR	
VSS	BR70	PWR	
VSS	BR72	PWR	
VSS	BR74	PWR	
VSS	BR76	PWR	
VSS	BR78	PWR	
VSS	BR80	PWR	
VSS	BR82	PWR	
VSS	BT21	PWR	
VSS	BT23	PWR	
VSS	BT25	PWR	
VSS	BT3	PWR	
VSS	BT5	PWR	
VSS	BT9	PWR	
VSS	BU10	PWR	
VSS	BU8	PWR	
VSS	BV17	PWR	
VSS	BV25	PWR	
VSS	BV5	PWR	
VSS	BW12	PWR	
VSS	BW14	PWR	
VSS	BW16	PWR	
VSS	BW18	PWR	
VSS	BW26	PWR	
VSS	BW6	PWR	
VSS	BW72	PWR	
VSS	BW74	PWR	
VSS	BW76	PWR	
VSS	BW78	PWR	
VSS	BW80	PWR	
VSS	BW82	PWR	
VSS	BY11	PWR	
VSS	BY13	PWR	
VSS	BY23	PWR	
VSS	BY63	PWR	

Table A-1. Pin List By Name (Sheet 70 of 90)

Pin Name	Location	Type	I/O
VSS	BY65	PWR	
VSS	BY67	PWR	
VSS	BY69	PWR	
VSS	BY71	PWR	
VSS	C10	PWR	
VSS	C12	PWR	
VSS	C14	PWR	
VSS	C16	PWR	
VSS	C4	PWR	
VSS	C76	PWR	
VSS	C78	PWR	
VSS	C8	PWR	
VSS	C80	PWR	
VSS	CA10	PWR	
VSS	CA14	PWR	
VSS	CA18	PWR	
VSS	CA2	PWR	
VSS	CA20	PWR	
VSS	CA26	PWR	
VSS	CA6	PWR	
VSS	CA64	PWR	
VSS	CA66	PWR	
VSS	CA68	PWR	
VSS	CA70	PWR	
VSS	CA8	PWR	
VSS	CB27	PWR	
VSS	CB63	PWR	
VSS	CB7	PWR	
VSS	CB71	PWR	
VSS	CB9	PWR	
VSS	CC16	PWR	
VSS	CC18	PWR	
VSS	CC24	PWR	
VSS	CC4	PWR	
VSS	CC64	PWR	
VSS	CC72	PWR	
VSS	CC74	PWR	
VSS	CC76	PWR	
VSS	CC78	PWR	
VSS	CC80	PWR	
VSS	CC82	PWR	

Table A-1. Pin List By Name (Sheet 71 of 90)

Pin Name	Location	Type	I/O
VSS	CD13	PWR	
VSS	CD5	PWR	
VSS	CD63	PWR	
VSS	CD73	PWR	
VSS	CD75	PWR	
VSS	CD77	PWR	
VSS	CD79	PWR	
VSS	CD81	PWR	
VSS	CE10	PWR	
VSS	CE14	PWR	
VSS	CE20	PWR	
VSS	CE26	PWR	
VSS	CE62	PWR	
VSS	CE70	PWR	
VSS	CE82	PWR	
VSS	CF63	PWR	
VSS	CF69	PWR	
VSS	CF71	PWR	
VSS	CF77	PWR	
VSS	CF83	PWR	
VSS	CF9	PWR	
VSS	CG18	PWR	
VSS	CG22	PWR	
VSS	CG6	PWR	
VSS	CG62	PWR	
VSS	CG68	PWR	
VSS	CG72	PWR	
VSS	CG80	PWR	
VSS	CH1	PWR	
VSS	CH15	PWR	
VSS	CH19	PWR	
VSS	CH3	PWR	
VSS	CH63	PWR	
VSS	CH67	PWR	
VSS	CH73	PWR	
VSS	CH79	PWR	
VSS	CH81	PWR	
VSS	CH83	PWR	
VSS	CJ10	PWR	
VSS	CJ12	PWR	
VSS	CJ2	PWR	

Table A-1. Pin List By Name (Sheet 72 of 90)

Pin Name	Location	Type	I/O
VSS	CJ6	PWR	
VSS	CJ62	PWR	
VSS	CJ74	PWR	
VSS	CJ76	PWR	
VSS	CJ78	PWR	
VSS	CJ8	PWR	
VSS	CJ82	PWR	
VSS	CJ84	PWR	
VSS	CJ86	PWR	
VSS	CK11	PWR	
VSS	CK15	PWR	
VSS	CK21	PWR	
VSS	CK27	PWR	
VSS	CK63	PWR	
VSS	CK65	PWR	
VSS	CK67	PWR	
VSS	CK69	PWR	
VSS	CK71	PWR	
VSS	CK73	PWR	
VSS	CK75	PWR	
VSS	CK83	PWR	
VSS	CK85	PWR	
VSS	CL14	PWR	
VSS	CL18	PWR	
VSS	CL22	PWR	
VSS	CL62	PWR	
VSS	CL64	PWR	
VSS	CL66	PWR	
VSS	CL74	PWR	
VSS	CL76	PWR	
VSS	CL78	PWR	
VSS	CL8	PWR	
VSS	CL80	PWR	
VSS	CM19	PWR	
VSS	CM27	PWR	
VSS	CM29	PWR	
VSS	CM31	PWR	
VSS	CM5	PWR	
VSS	CM61	PWR	
VSS	CM63	PWR	
VSS	CM67	PWR	

Table A-1. Pin List By Name (Sheet 73 of 90)

Pin Name	Location	Type	I/O
VSS	CM73	PWR	
VSS	CM77	PWR	
VSS	CM83	PWR	
VSS	CM85	PWR	
VSS	CN12	PWR	
VSS	CN14	PWR	
VSS	CN2	PWR	
VSS	CN26	PWR	
VSS	CN32	PWR	
VSS	CN60	PWR	
VSS	CN62	PWR	
VSS	CN68	PWR	
VSS	CN78	PWR	
VSS	CP1	PWR	
VSS	CP25	PWR	
VSS	CP59	PWR	
VSS	CP69	PWR	
VSS	CP73	PWR	
VSS	CP75	PWR	
VSS	CP81	PWR	
VSS	CP83	PWR	
VSS	CR10	PWR	
VSS	CR22	PWR	
VSS	CR24	PWR	
VSS	CR32	PWR	
VSS	CR58	PWR	
VSS	CR6	PWR	
VSS	CR62	PWR	
VSS	CR64	PWR	
VSS	CR66	PWR	
VSS	CR68	PWR	
VSS	CR78	PWR	
VSS	CR86	PWR	
VSS	CT13	PWR	
VSS	CT19	PWR	
VSS	CT27	PWR	
VSS	CT29	PWR	
VSS	CT33	PWR	
VSS	CT35	PWR	
VSS	CT57	PWR	
VSS	CT7	PWR	

Table A-1. Pin List By Name (Sheet 74 of 90)

Pin Name	Location	Type	I/O
VSS	CT73	PWR	
VSS	CT79	PWR	
VSS	CT83	PWR	
VSS	CT85	PWR	
VSS	CU22	PWR	
VSS	CU28	PWR	
VSS	CU30	PWR	
VSS	CU34	PWR	
VSS	CU36	PWR	
VSS	CU4	PWR	
VSS	CU56	PWR	
VSS	CU62	PWR	
VSS	CU68	PWR	
VSS	CU76	PWR	
VSS	CU78	PWR	
VSS	CU80	PWR	
VSS	CU82	PWR	
VSS	CU86	PWR	
VSS	CV1	PWR	
VSS	CV17	PWR	
VSS	CV25	PWR	
VSS	CV27	PWR	
VSS	CV31	PWR	
VSS	CV33	PWR	
VSS	CV37	PWR	
VSS	CV39	PWR	
VSS	CV41	PWR	
VSS	CV53	PWR	
VSS	CV55	PWR	
VSS	CV63	PWR	
VSS	CV67	PWR	
VSS	CV73	PWR	
VSS	CV79	PWR	
VSS	CV81	PWR	
VSS	CV83	PWR	
VSS	CW12	PWR	
VSS	CW26	PWR	
VSS	CW32	PWR	
VSS	CW38	PWR	
VSS	CW40	PWR	
VSS	CW42	PWR	

Table A-1. Pin List By Name (Sheet 75 of 90)

Pin Name	Location	Type	I/O
VSS	CW52	PWR	
VSS	CW54	PWR	
VSS	CW6	PWR	
VSS	CW64	PWR	
VSS	CW66	PWR	
VSS	CW68	PWR	
VSS	CW74	PWR	
VSS	CW78	PWR	
VSS	CW82	PWR	
VSS	CY1	PWR	
VSS	CY13	PWR	
VSS	CY15	PWR	
VSS	CY21	PWR	
VSS	CY41	PWR	
VSS	CY45	PWR	
VSS	CY51	PWR	
VSS	CY59	PWR	
VSS	CY61	PWR	
VSS	CY65	PWR	
VSS	CY69	PWR	
VSS	CY75	PWR	
VSS	CY77	PWR	
VSS	CY83	PWR	
VSS	CY85	PWR	
VSS	CY9	PWR	
VSS	D11	PWR	
VSS	D13	PWR	
VSS	D25	PWR	
VSS	D27	PWR	
VSS	D29	PWR	
VSS	D3	PWR	
VSS	D31	PWR	
VSS	D33	PWR	
VSS	D35	PWR	
VSS	D37	PWR	
VSS	D39	PWR	
VSS	D41	PWR	
VSS	D43	PWR	
VSS	D77	PWR	
VSS	D81	PWR	
VSS	DA18	PWR	

Table A-1. Pin List By Name (Sheet 76 of 90)

Pin Name	Location	Type	I/O
VSS	DA26	PWR	
VSS	DA28	PWR	
VSS	DA30	PWR	
VSS	DA32	PWR	
VSS	DA34	PWR	
VSS	DA36	PWR	
VSS	DA38	PWR	
VSS	DA44	PWR	
VSS	DA46	PWR	
VSS	DA48	PWR	
VSS	DA50	PWR	
VSS	DA6	PWR	
VSS	DA64	PWR	
VSS	DA70	PWR	
VSS	DA74	PWR	
VSS	DA76	PWR	
VSS	DA78	PWR	
VSS	DA80	PWR	
VSS	DB13	PWR	
VSS	DB17	PWR	
VSS	DB23	PWR	
VSS	DB25	PWR	
VSS	DB3	PWR	
VSS	DB39	PWR	
VSS	DB41	PWR	
VSS	DB47	PWR	
VSS	DB49	PWR	
VSS	DB7	PWR	
VSS	DB73	PWR	
VSS	DB77	PWR	
VSS	DB83	PWR	
VSS	DB85	PWR	
VSS	DC14	PWR	
VSS	DC24	PWR	
VSS	DC26	PWR	
VSS	DC32	PWR	
VSS	DC38	PWR	
VSS	DC42	PWR	
VSS	DC64	PWR	
VSS	DC66	PWR	
VSS	DC68	PWR	

Table A-1. Pin List By Name (Sheet 77 of 90)

Pin Name	Location	Type	I/O
VSS	DC70	PWR	
VSS	DC78	PWR	
VSS	DC84	PWR	
VSS	DC86	PWR	
VSS	DD11	PWR	
VSS	DD23	PWR	
VSS	DD27	PWR	
VSS	DD31	PWR	
VSS	DD33	PWR	
VSS	DD37	PWR	
VSS	DD71	PWR	
VSS	DD73	PWR	
VSS	DD75	PWR	
VSS	DD81	PWR	
VSS	DD83	PWR	
VSS	DE18	PWR	
VSS	DE20	PWR	
VSS	DE24	PWR	
VSS	DE28	PWR	
VSS	DE30	PWR	
VSS	DE34	PWR	
VSS	DE36	PWR	
VSS	DE48	PWR	
VSS	DE50	PWR	
VSS	DE52	PWR	
VSS	DE54	PWR	
VSS	DE56	PWR	
VSS	DE58	PWR	
VSS	DE6	PWR	
VSS	DE60	PWR	
VSS	DE62	PWR	
VSS	DE64	PWR	
VSS	DE70	PWR	
VSS	DE72	PWR	
VSS	DE78	PWR	
VSS	DE8	PWR	
VSS	DF19	PWR	
VSS	DF29	PWR	
VSS	DF35	PWR	
VSS	DF37	PWR	
VSS	DF39	PWR	

Table A-1. Pin List By Name (Sheet 78 of 90)

Pin Name	Location	Type	I/O
VSS	DF41	PWR	
VSS	DF5	PWR	
VSS	DF65	PWR	
VSS	DF69	PWR	
VSS	DF7	PWR	
VSS	DF73	PWR	
VSS	DF79	PWR	
VSS	DF83	PWR	
VSS	DF85	PWR	
VSS	DG14	PWR	
VSS	DG16	PWR	
VSS	DG2	PWR	
VSS	DG24	PWR	
VSS	DG66	PWR	
VSS	DG68	PWR	
VSS	DG76	PWR	
VSS	DG78	PWR	
VSS	DG80	PWR	
VSS	DG82	PWR	
VSS	DH13	PWR	
VSS	DH15	PWR	
VSS	DH21	PWR	
VSS	DH23	PWR	
VSS	DH25	PWR	
VSS	DH27	PWR	
VSS	DH29	PWR	
VSS	DH31	PWR	
VSS	DH33	PWR	
VSS	DH35	PWR	
VSS	DH37	PWR	
VSS	DH41	PWR	
VSS	DH67	PWR	
VSS	DH71	PWR	
VSS	DH73	PWR	
VSS	DH79	PWR	
VSS	DH81	PWR	
VSS	DH83	PWR	
VSS	DJ10	PWR	
VSS	DJ2	PWR	
VSS	DJ22	PWR	
VSS	DJ38	PWR	

Table A-1. Pin List By Name (Sheet 79 of 90)

Pin Name	Location	Type	I/O
VSS	DJ42	PWR	
VSS	DJ68	PWR	
VSS	DJ74	PWR	
VSS	DJ78	PWR	
VSS	DJ82	PWR	
VSS	DJ84	PWR	
VSS	DK23	PWR	
VSS	DK29	PWR	
VSS	DK35	PWR	
VSS	DK39	PWR	
VSS	DK41	PWR	
VSS	DK7	PWR	
VSS	DK73	PWR	
VSS	DK75	PWR	
VSS	DK77	PWR	
VSS	DK83	PWR	
VSS	DK85	PWR	
VSS	DL16	PWR	
VSS	DL18	PWR	
VSS	DL22	PWR	
VSS	DL24	PWR	
VSS	DL28	PWR	
VSS	DL30	PWR	
VSS	DL34	PWR	
VSS	DL36	PWR	
VSS	DL4	PWR	
VSS	DL40	PWR	
VSS	DL68	PWR	
VSS	DL70	PWR	
VSS	DL74	PWR	
VSS	DL76	PWR	
VSS	DL78	PWR	
VSS	DL8	PWR	
VSS	DL80	PWR	
VSS	DM15	PWR	
VSS	DM19	PWR	
VSS	DM25	PWR	
VSS	DM27	PWR	
VSS	DM31	PWR	
VSS	DM33	PWR	
VSS	DM37	PWR	

Table A-1. Pin List By Name (Sheet 80 of 90)

Pin Name	Location	Type	I/O
VSS	DM39	PWR	
VSS	DM65	PWR	
VSS	DM73	PWR	
VSS	DM77	PWR	
VSS	DM83	PWR	
VSS	DN12	PWR	
VSS	DN18	PWR	
VSS	DN2	PWR	
VSS	DN22	PWR	
VSS	DN26	PWR	
VSS	DN32	PWR	
VSS	DN38	PWR	
VSS	DN44	PWR	
VSS	DN68	PWR	
VSS	DN72	PWR	
VSS	DN78	PWR	
VSS	DP45	PWR	
VSS	DP47	PWR	
VSS	DP49	PWR	
VSS	DP51	PWR	
VSS	DP53	PWR	
VSS	DP55	PWR	
VSS	DP57	PWR	
VSS	DP59	PWR	
VSS	DP61	PWR	
VSS	DP63	PWR	
VSS	DP67	PWR	
VSS	DP69	PWR	
VSS	DP71	PWR	
VSS	DP81	PWR	
VSS	DP83	PWR	
VSS	DP9	PWR	
VSS	DR20	PWR	
VSS	DR22	PWR	
VSS	DR24	PWR	
VSS	DR26	PWR	
VSS	DR28	PWR	
VSS	DR30	PWR	
VSS	DR32	PWR	
VSS	DR34	PWR	
VSS	DR36	PWR	

Table A-1. Pin List By Name (Sheet 81 of 90)

Pin Name	Location	Type	I/O
VSS	DR38	PWR	
VSS	DR40	PWR	
VSS	DR42	PWR	
VSS	DR6	PWR	
VSS	DR66	PWR	
VSS	DR68	PWR	
VSS	DR70	PWR	
VSS	DR72	PWR	
VSS	DR74	PWR	
VSS	DR76	PWR	
VSS	DR78	PWR	
VSS	DT17	PWR	
VSS	DT3	PWR	
VSS	DT65	PWR	
VSS	DT69	PWR	
VSS	DT79	PWR	
VSS	DT83	PWR	
VSS	DT85	PWR	
VSS	DU10	PWR	
VSS	DU14	PWR	
VSS	DU22	PWR	
VSS	DU26	PWR	
VSS	DU32	PWR	
VSS	DU38	PWR	
VSS	DU70	PWR	
VSS	DU72	PWR	
VSS	DU78	PWR	
VSS	DU80	PWR	
VSS	DU82	PWR	
VSS	DU84	PWR	
VSS	DV19	PWR	
VSS	DV21	PWR	
VSS	DV25	PWR	
VSS	DV27	PWR	
VSS	DV31	PWR	
VSS	DV33	PWR	
VSS	DV37	PWR	
VSS	DV39	PWR	
VSS	DV73	PWR	
VSS	DV77	PWR	
VSS	DV81	PWR	

Table A-1. Pin List By Name (Sheet 82 of 90)

Pin Name	Location	Type	I/O
VSS	DW12	PWR	
VSS	DW2	PWR	
VSS	DW20	PWR	
VSS	DW24	PWR	
VSS	DW28	PWR	
VSS	DW30	PWR	
VSS	DW34	PWR	
VSS	DW36	PWR	
VSS	DW40	PWR	
VSS	DW64	PWR	
VSS	DW66	PWR	
VSS	DW68	PWR	
VSS	DW70	PWR	
VSS	DW72	PWR	
VSS	DW74	PWR	
VSS	DW76	PWR	
VSS	DW8	PWR	
VSS	DW82	PWR	
VSS	DW84	PWR	
VSS	DY19	PWR	
VSS	DY23	PWR	
VSS	DY29	PWR	
VSS	DY35	PWR	
VSS	DY41	PWR	
VSS	DY45	PWR	
VSS	DY47	PWR	
VSS	DY49	PWR	
VSS	DY5	PWR	
VSS	DY51	PWR	
VSS	DY53	PWR	
VSS	DY55	PWR	
VSS	DY57	PWR	
VSS	DY59	PWR	
VSS	DY61	PWR	
VSS	DY63	PWR	
VSS	DY71	PWR	
VSS	DY75	PWR	
VSS	DY85	PWR	
VSS	E16	PWR	
VSS	E18	PWR	
VSS	E20	PWR	

Table A-1. Pin List By Name (Sheet 83 of 90)

Pin Name	Location	Type	I/O
VSS	E22	PWR	
VSS	E6	PWR	
VSS	E66	PWR	
VSS	E72	PWR	
VSS	E74	PWR	
VSS	E76	PWR	
VSS	E8	PWR	
VSS	E82	PWR	
VSS	EA14	PWR	
VSS	EA16	PWR	
VSS	EA20	PWR	
VSS	EA22	PWR	
VSS	EA42	PWR	
VSS	EA6	PWR	
VSS	EA64	PWR	
VSS	EA70	PWR	
VSS	EA76	PWR	
VSS	EA78	PWR	
VSS	EA80	PWR	
VSS	EA82	PWR	
VSS	EA84	PWR	
VSS	EB13	PWR	
VSS	EB23	PWR	
VSS	EB25	PWR	
VSS	EB27	PWR	
VSS	EB29	PWR	
VSS	EB31	PWR	
VSS	EB33	PWR	
VSS	EB35	PWR	
VSS	EB37	PWR	
VSS	EB39	PWR	
VSS	EB41	PWR	
VSS	EB65	PWR	
VSS	EB69	PWR	
VSS	EB83	PWR	
VSS	EC10	PWR	
VSS	EC42	PWR	
VSS	EC6	PWR	
VSS	EC70	PWR	
VSS	EC72	PWR	
VSS	EC74	PWR	

Table A-1. Pin List By Name (Sheet 84 of 90)

Pin Name	Location	Type	I/O
VSS	EC76	PWR	
VSS	EC82	PWR	
VSS	ED11	PWR	
VSS	ED15	PWR	
VSS	ED23	PWR	
VSS	ED29	PWR	
VSS	ED35	PWR	
VSS	ED41	PWR	
VSS	ED69	PWR	
VSS	ED7	PWR	
VSS	ED77	PWR	
VSS	ED81	PWR	
VSS	EE24	PWR	
VSS	EE28	PWR	
VSS	EE30	PWR	
VSS	EE34	PWR	
VSS	EE36	PWR	
VSS	EE40	PWR	
VSS	EE70	PWR	
VSS	EE76	PWR	
VSS	EE78	PWR	
VSS	EE8	PWR	
VSS	EE80	PWR	
VSS	EF71	PWR	
VSS	EF75	PWR	
VSS	EF79	PWR	
VSS	F17	PWR	
VSS	F19	PWR	
VSS	F25	PWR	
VSS	F31	PWR	
VSS	F37	PWR	
VSS	F43	PWR	
VSS	F5	PWR	
VSS	F67	PWR	
VSS	F69	PWR	
VSS	G22	PWR	
VSS	G24	PWR	
VSS	G26	PWR	
VSS	G30	PWR	
VSS	G32	PWR	
VSS	G36	PWR	

Table A-1. Pin List By Name (Sheet 85 of 90)

Pin Name	Location	Type	I/O
VSS	G38	PWR	
VSS	G4	PWR	
VSS	G42	PWR	
VSS	G66	PWR	
VSS	G70	PWR	
VSS	G76	PWR	
VSS	G78	PWR	
VSS	G8	PWR	
VSS	G80	PWR	
VSS	G82	PWR	
VSS	H11	PWR	
VSS	H25	PWR	
VSS	H27	PWR	
VSS	H29	PWR	
VSS	H3	PWR	
VSS	H31	PWR	
VSS	H33	PWR	
VSS	H35	PWR	
VSS	H37	PWR	
VSS	H39	PWR	
VSS	H41	PWR	
VSS	H45	PWR	
VSS	H47	PWR	
VSS	H49	PWR	
VSS	H51	PWR	
VSS	H53	PWR	
VSS	H55	PWR	
VSS	H57	PWR	
VSS	H59	PWR	
VSS	H61	PWR	
VSS	H63	PWR	
VSS	H65	PWR	
VSS	H71	PWR	
VSS	H75	PWR	
VSS	J12	PWR	
VSS	J14	PWR	
VSS	J16	PWR	
VSS	J22	PWR	
VSS	J26	PWR	
VSS	J28	PWR	
VSS	J32	PWR	

Table A-1. Pin List By Name (Sheet 86 of 90)

Pin Name	Location	Type	I/O
VSS	J34	PWR	
VSS	J38	PWR	
VSS	J4	PWR	
VSS	J40	PWR	
VSS	J72	PWR	
VSS	J74	PWR	
VSS	J76	PWR	
VSS	J82	PWR	
VSS	J84	PWR	
VSS	J86	PWR	
VSS	K1	PWR	
VSS	K11	PWR	
VSS	K13	PWR	
VSS	K17	PWR	
VSS	K27	PWR	
VSS	K33	PWR	
VSS	K39	PWR	
VSS	K65	PWR	
VSS	K67	PWR	
VSS	K69	PWR	
VSS	K71	PWR	
VSS	K73	PWR	
VSS	K77	PWR	
VSS	K81	PWR	
VSS	K83	PWR	
VSS	K85	PWR	
VSS	L10	PWR	
VSS	L2	PWR	
VSS	L20	PWR	
VSS	L22	PWR	
VSS	L6	PWR	
VSS	L72	PWR	
VSS	L78	PWR	
VSS	L8	PWR	
VSS	L80	PWR	
VSS	L82	PWR	
VSS	M15	PWR	
VSS	M17	PWR	
VSS	M19	PWR	
VSS	M23	PWR	
VSS	M25	PWR	

Table A-1. Pin List By Name (Sheet 87 of 90)

Pin Name	Location	Type	I/O
VSS	M27	PWR	
VSS	M29	PWR	
VSS	M31	PWR	
VSS	M33	PWR	
VSS	M35	PWR	
VSS	M37	PWR	
VSS	M39	PWR	
VSS	M41	PWR	
VSS	M43	PWR	
VSS	M65	PWR	
VSS	M71	PWR	
VSS	M79	PWR	
VSS	M83	PWR	
VSS	M85	PWR	
VSS	N20	PWR	
VSS	N22	PWR	
VSS	N4	PWR	
VSS	N6	PWR	
VSS	N66	PWR	
VSS	N70	PWR	
VSS	N72	PWR	
VSS	N74	PWR	
VSS	N76	PWR	
VSS	N78	PWR	
VSS	N8	PWR	
VSS	P11	PWR	
VSS	P15	PWR	
VSS	P27	PWR	
VSS	P33	PWR	
VSS	P39	PWR	
VSS	P45	PWR	
VSS	P47	PWR	
VSS	P49	PWR	
VSS	P51	PWR	
VSS	P53	PWR	
VSS	P55	PWR	
VSS	P57	PWR	
VSS	P59	PWR	
VSS	P61	PWR	
VSS	P63	PWR	
VSS	P67	PWR	

Table A-1. Pin List By Name (Sheet 88 of 90)

Pin Name	Location	Type	I/O
VSS	P69	PWR	
VSS	P71	PWR	
VSS	P81	PWR	
VSS	P83	PWR	
VSS	R14	PWR	
VSS	R18	PWR	
VSS	R2	PWR	
VSS	R22	PWR	
VSS	R26	PWR	
VSS	R28	PWR	
VSS	R32	PWR	
VSS	R34	PWR	
VSS	R38	PWR	
VSS	R4	PWR	
VSS	R40	PWR	
VSS	R68	PWR	
VSS	R72	PWR	
VSS	R78	PWR	
VSS	R86	PWR	
VSS	T13	PWR	
VSS	T17	PWR	
VSS	T25	PWR	
VSS	T29	PWR	
VSS	T31	PWR	
VSS	T35	PWR	
VSS	T37	PWR	
VSS	T41	PWR	
VSS	T65	PWR	
VSS	T73	PWR	
VSS	T77	PWR	
VSS	T83	PWR	
VSS	T85	PWR	
VSS	U2	PWR	
VSS	U20	PWR	
VSS	U22	PWR	
VSS	U24	PWR	
VSS	U30	PWR	
VSS	U36	PWR	
VSS	U4	PWR	
VSS	U42	PWR	
VSS	U6	PWR	

Table A-1. Pin List By Name (Sheet 89 of 90)

Pin Name	Location	Type	I/O
VSS	U68	PWR	
VSS	U70	PWR	
VSS	U74	PWR	
VSS	U76	PWR	
VSS	U78	PWR	
VSS	U80	PWR	
VSS	U86	PWR	
VSS	V1	PWR	
VSS	V11	PWR	
VSS	V13	PWR	
VSS	V15	PWR	
VSS	V21	PWR	
VSS	V23	PWR	
VSS	V43	PWR	
VSS	V5	PWR	
VSS	V73	PWR	
VSS	V75	PWR	
VSS	V77	PWR	
VSS	V83	PWR	
VSS	V9	PWR	
VSS	W12	PWR	
VSS	W22	PWR	
VSS	W24	PWR	
VSS	W26	PWR	
VSS	W28	PWR	
VSS	W30	PWR	
VSS	W32	PWR	
VSS	W34	PWR	
VSS	W36	PWR	
VSS	W38	PWR	
VSS	W40	PWR	
VSS	W42	PWR	
VSS	W68	PWR	
VSS	W74	PWR	
VSS	W78	PWR	
VSS	W8	PWR	
VSS	W82	PWR	
VSS	Y15	PWR	
VSS	Y17	PWR	
VSS	Y5	PWR	
VSS	Y67	PWR	

Table A-1. Pin List By Name (Sheet 90 of 90)

Pin Name	Location	Type	I/O
VSS	Y7	PWR	
VSS	Y71	PWR	
VSS	Y73	PWR	
VSS	Y79	PWR	
VSS	Y81	PWR	
VSS	Y83	PWR	
VSS	Y85	PWR	
VSS	Y9	PWR	
VSS_VCCIN_SENSE	AY85	PWR	
VSS_VCCIO_SENSE	BF5	PWR	
VSS_VCCSA_SENSE	CG76	PWR	

§